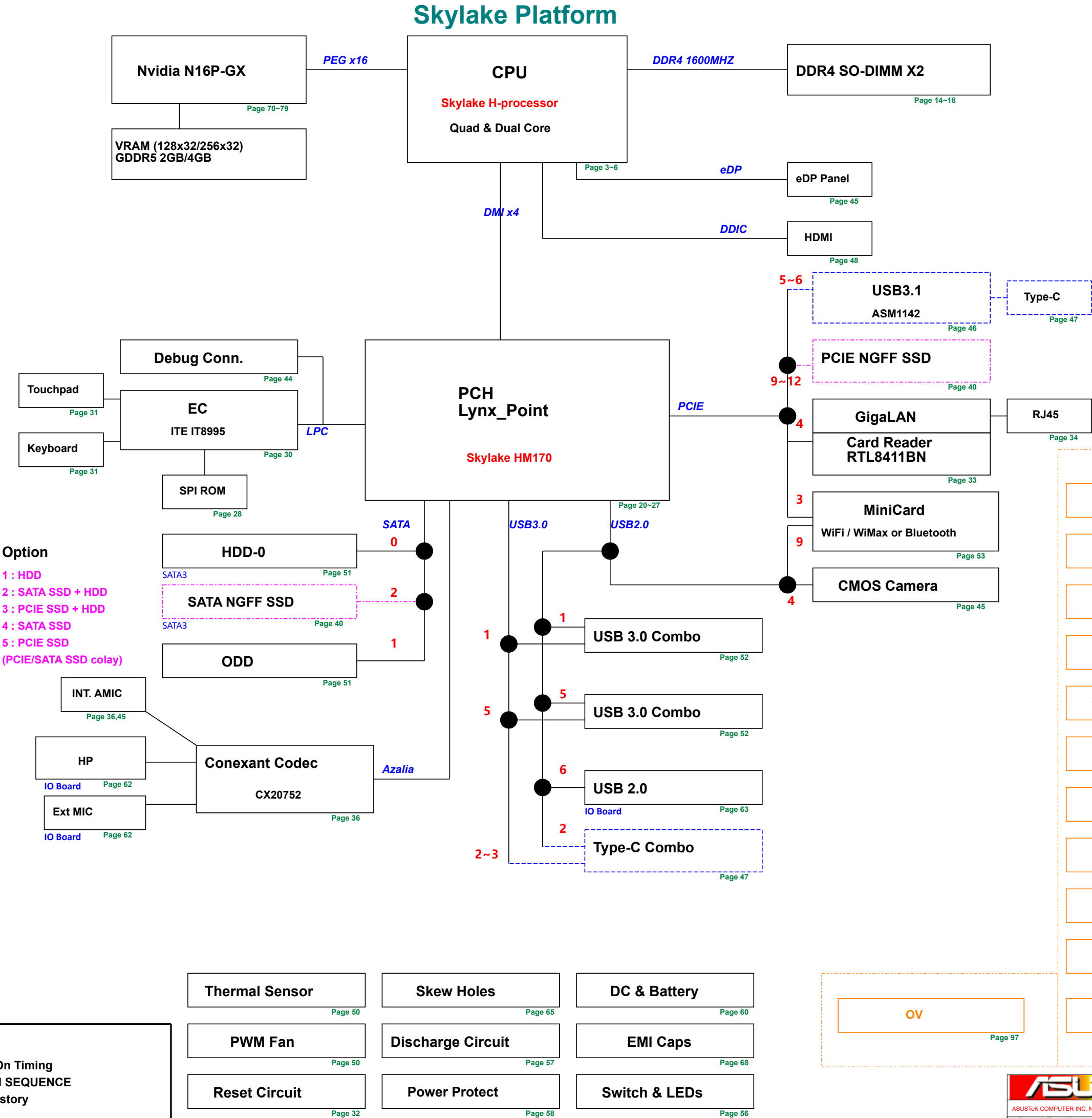
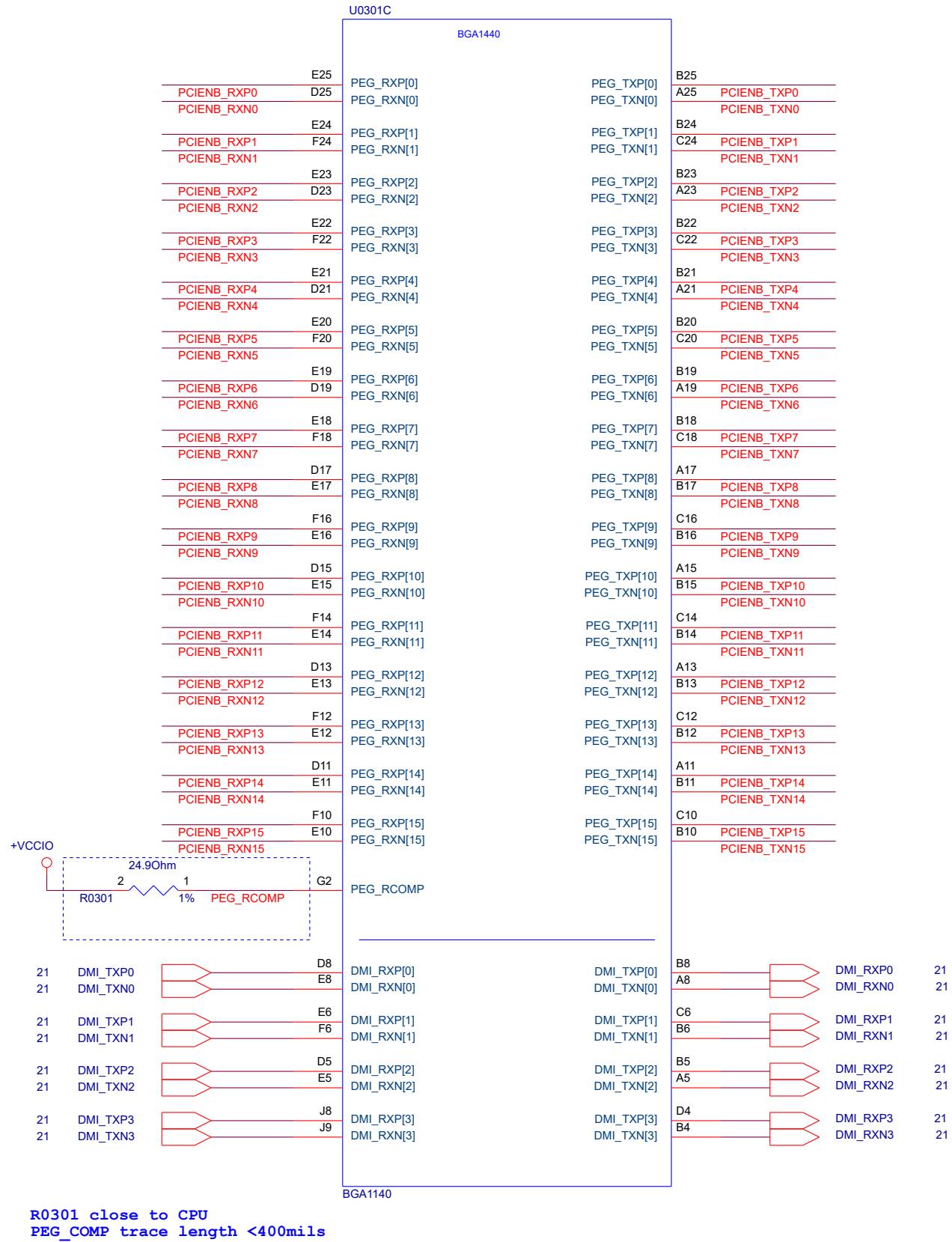


- 001_Block Diagram
002_System Setting
003_CPU_DMI,PEG,eDP,DDI
004_CPU_DDR4
005_CPU_GND
006_CPU_CFG,RSVD
007_CPU_XDP
008_CPU_PWR
009_CPU_PWR
010_CPU_POWER_CAP
016_DIM_DDR4 SO-DIMM A(0) TOP
017_DIM_DDR4 SO-DIMM B(0) TOP
018_DIM_CA/DQ Voltage
019_Silego_Green_CLK_Gen
020_PCH_HDA,SMBUS,SYS PWR,JTAG
021_PCH-CPT(2)_PCIE,USB2,MISC
022_PCH-CPT(3)_CLK,LPC,USB3
023_PCH-CPT(4)_eDP,PCI,DP
024_PCH-CPT(5)_SPI
025_PCH-CPT(6)_GPIO
026_PCH-CPT(7)_POWER,GND
027_PCH-CPT(8)_POWER,GND
028_PCH-SPI ROM,OTH
029_PCH-XDP
030_KBC_IT8995
031_KBC_KB & TP
032_RST_Reset Circuit
033_LAN_CR_RTL8411BN
034_LAN RJ45
036-AUD-CX20752
037-AUD-AMP
038_AUD-SPEAKER Connector
040_NGFF_SSD
044_DEBUG_LPC
045_CRT_eDP
046_USB 3.1 ASM1142
047_USB 3.1 MB Type-C
048_HDMI
050_FAN_Thermal Sensor & Fan
051_HDD & ODD CON
052_USB_Port
053_WiFi/WiMax
055_Lid_SW_BD
056_LED
057_DSG_Discharge
058_Power Protect
059_MB_to_I/O_CONN.
060_DC & BAT IN
062_>>>>>I/O board(1)_MIC/HP
063_>>>>>I/O board(2)_USB
065_ME_NUT
069_OTH_EMI
070_VGA_PCI-EXPRESS(1)
071_GPU_FB-IF_GDDR5(2)
072_FRAME BUFFER-A(3)
073_FRAME BUFFER-B(4)
074_VGA_CRT/LVDS(5)
075_VGA_GPIO/DVI/DP(6)
076_VGA_XTAL/STRAPPING(7)
077_VGA_PWG/GND(8)
078_VRAM Cap
080_PW_SKYLAKE (1)
081_PW_SKYLAKE (2)
083_PW_+1.0VSUS
084_PW_+VCCIO
086_PW_1.2V/+VTT/2.5V
087_PW_+3VADSW/+5VSUS
088_PW_LOAD SWITCH
089_PW_CHARGER
090_PW_PROTECTION
091_PW_+NVVDD
092_PW_+PEX_VDD
093_PW_+FBVDDQ
099_PW_FLOW CHART
- 100_AC Power On Timing
101_POWER-ON SEQUENCE
102_Revision History

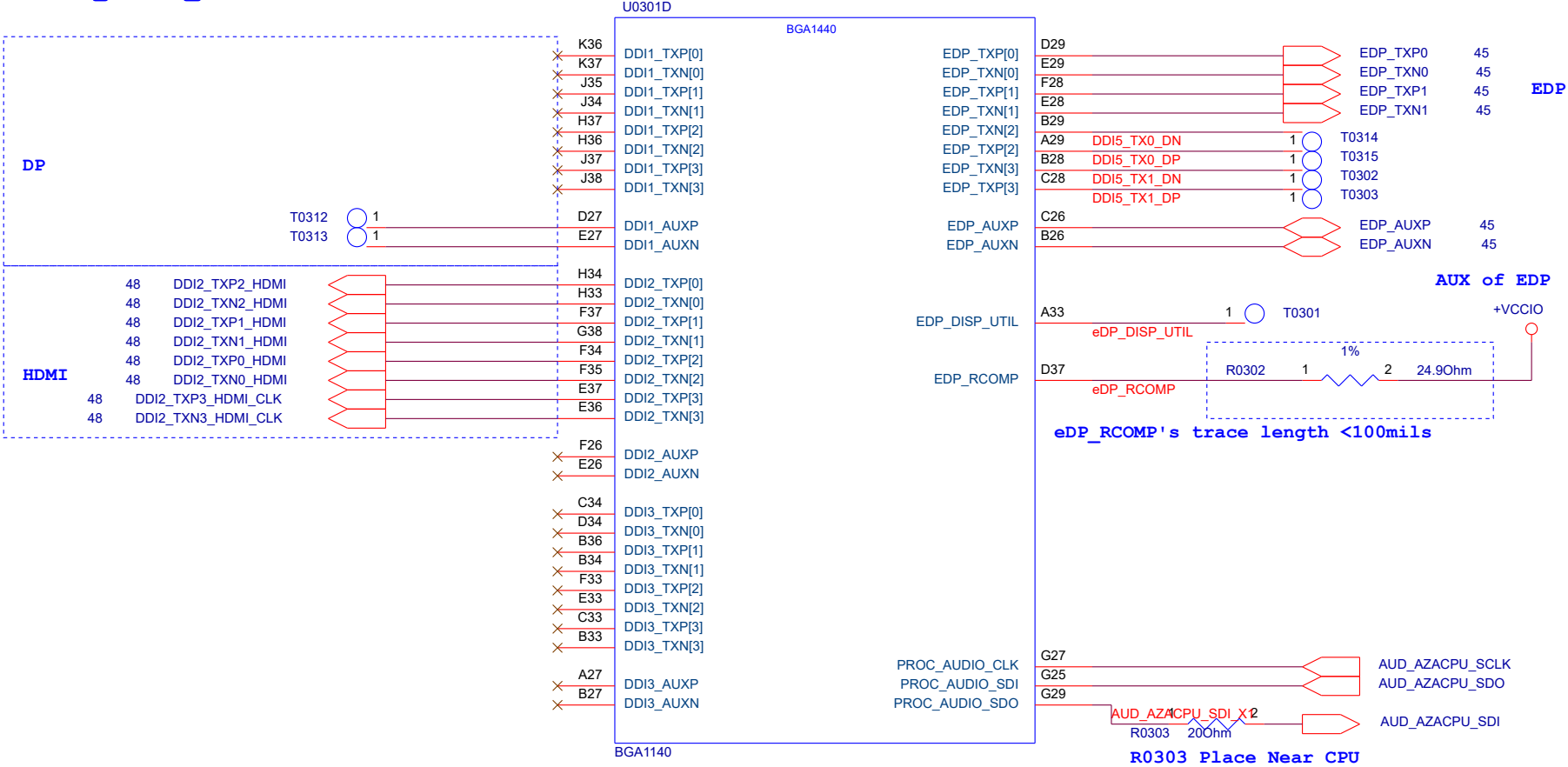
Asus GL552VW Block Diagram



PCIEG



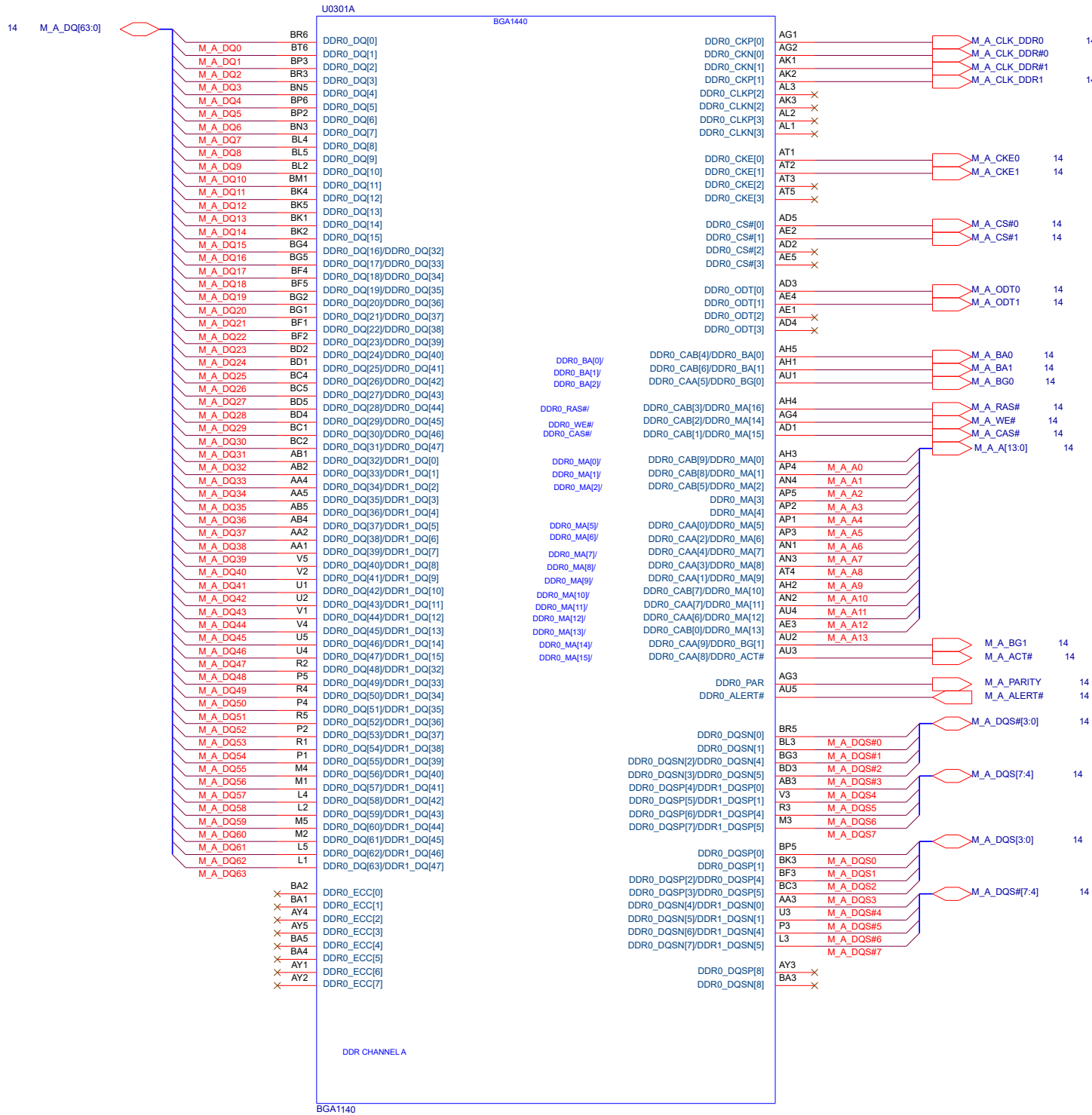
Display



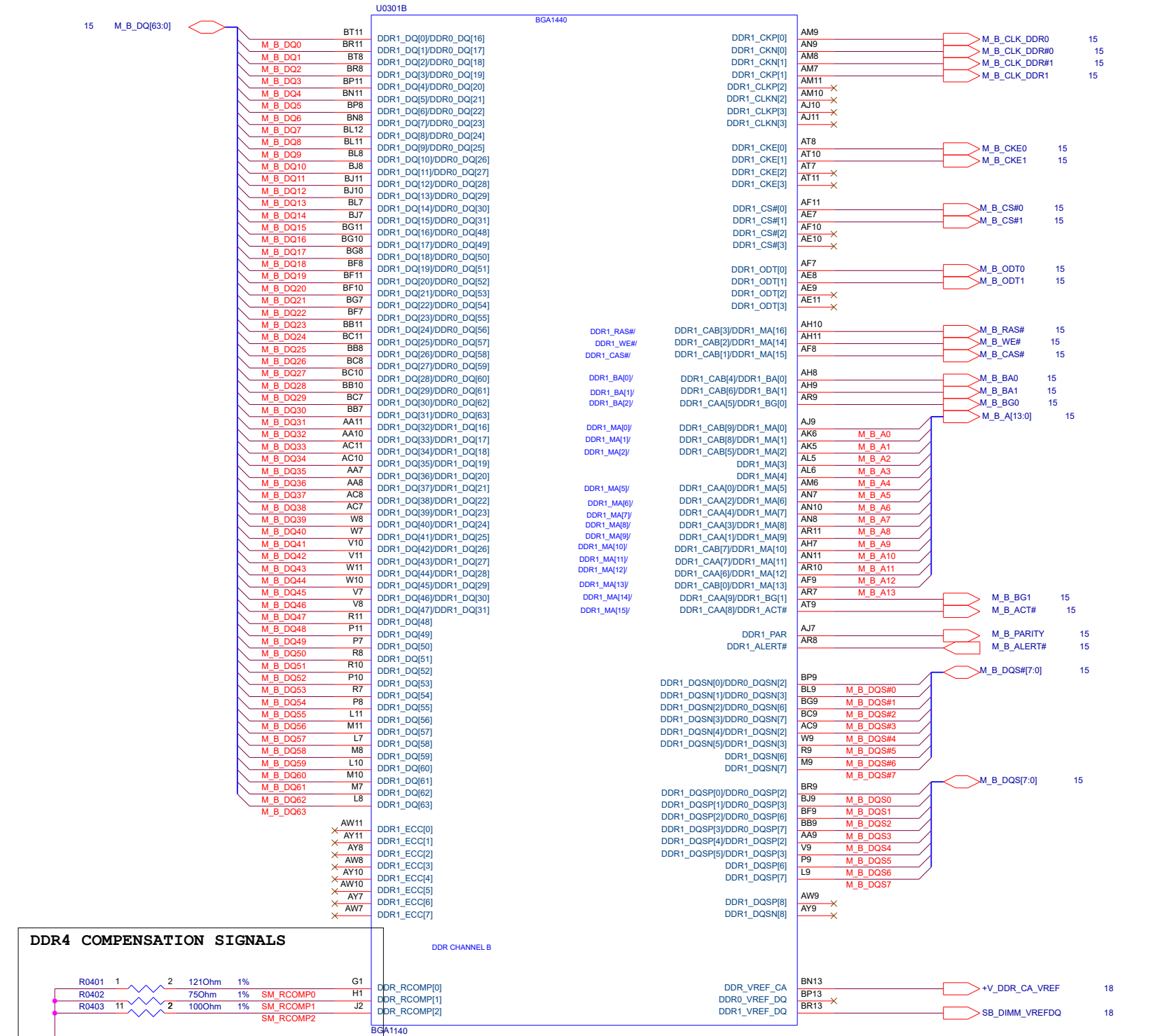
Intel CPU	ASUS P/N	規格
Quad Core (QS)	01001-01150500	I7-6700HQ 2.8G/8M QJJR 45W BGA
Dual Core (QS)	01001-01150400	I5-6300HQ 2.3G/6M QJJQ 45W BGA

Project Name		Rev
ASUS GL552VW		2.0
Title : CPU_DMI,PEG,FDI,eDP,DDI		
Size	Dept.:	Engineer:
B	ASUSTek COMPUTER INC.	Mario_Jhu
Date: Tuesday, June 23, 2015	Sheet	103

Memory Channel A

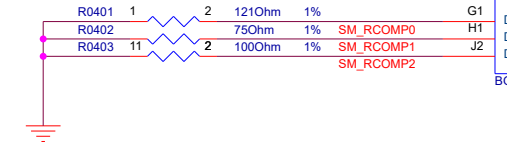


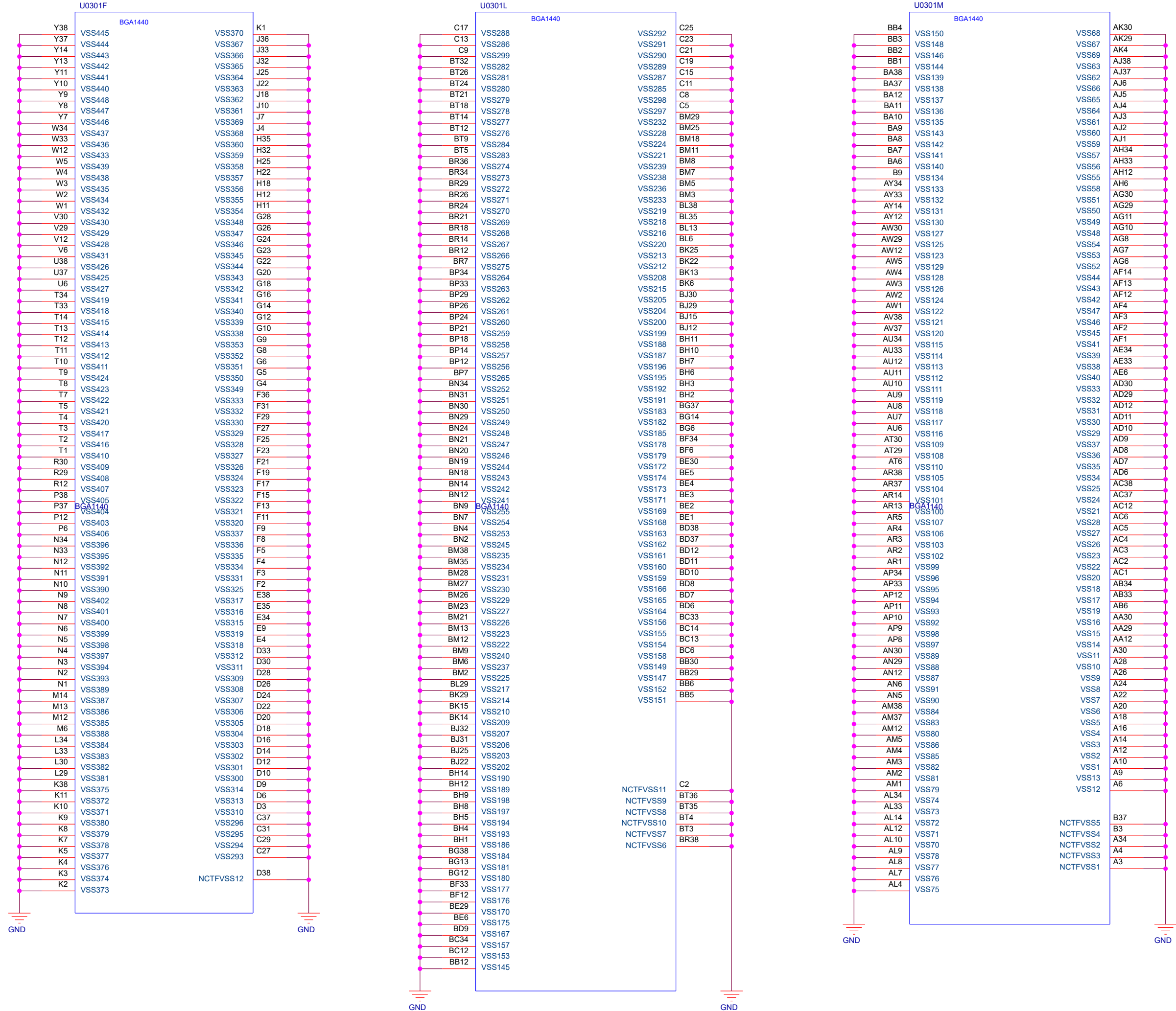
Memory Channel B



Main Board

DDR4 COMPENSATION SIGNALS



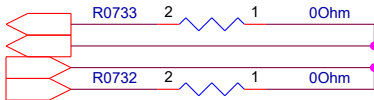


CPU XDP connector

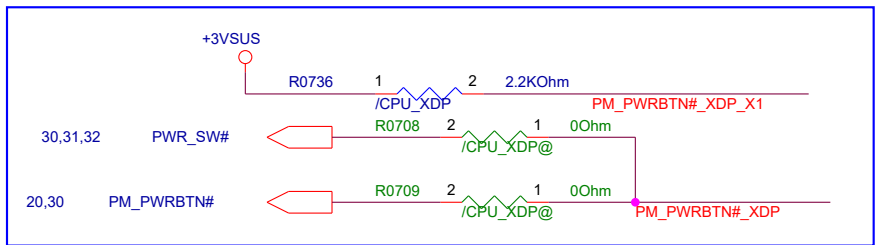
Main Board

R1.1-4/13-1

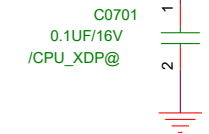
27	XDP_PREQ#_PCH
6	XDP_PREQ#
6	XDP_PRDY#
27	XDP_PRDY#_PCH



R1.1-5/8-1

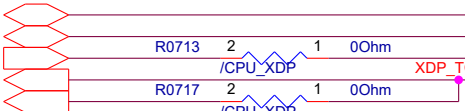


+1.0VSUS

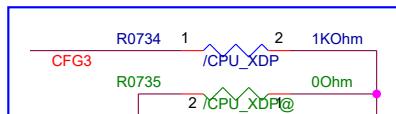


14,15,28	SMB_DAT_S
14,15,28	SMB_CLK_S
20	PCH_JTAG_TCK
6	XDP_TCLK_CPU
20	PCH_JTAGX

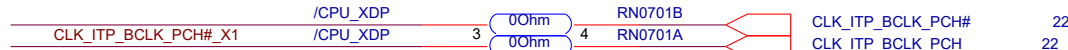
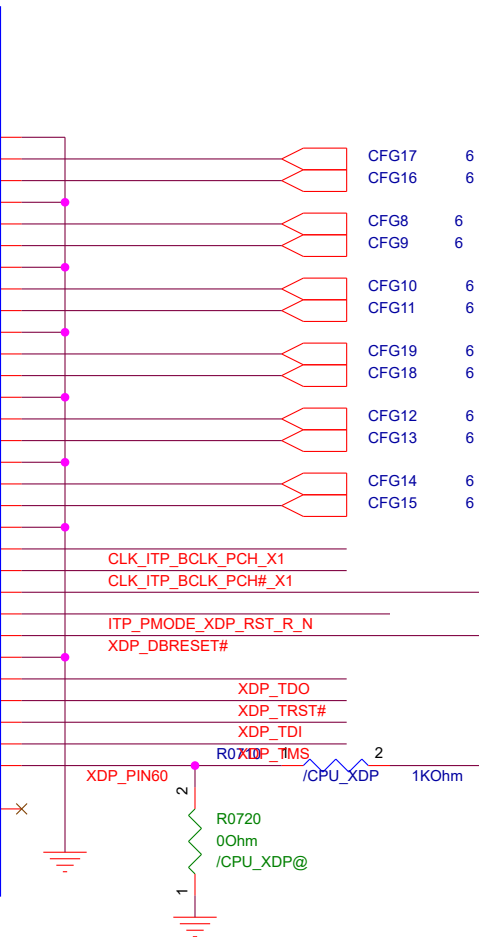
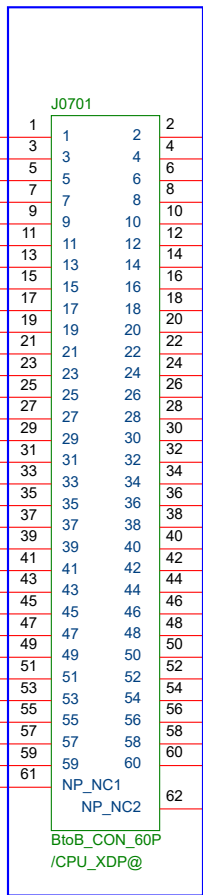
R1.1-5/20-2



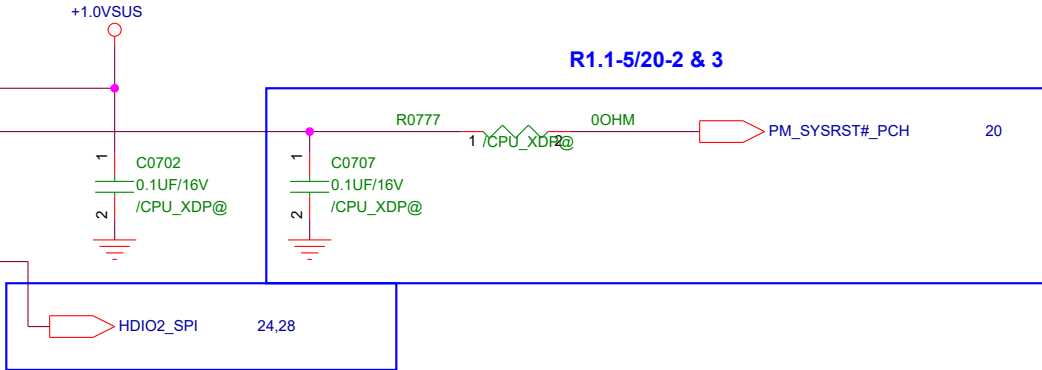
R1.1-5/8-1



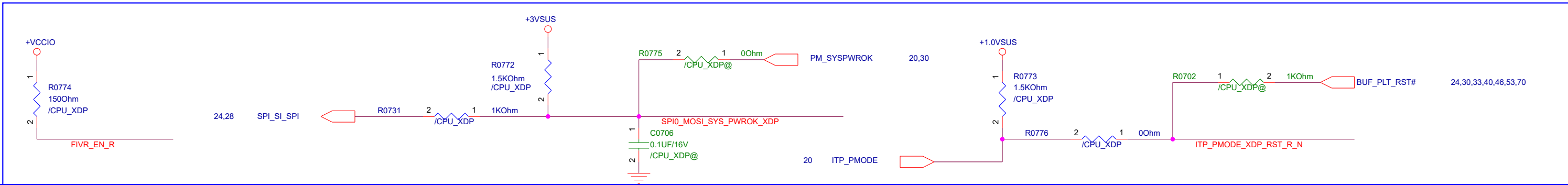
R1.1-5/12-10



R1.1-5/20-2 & 3



R1.1-5/8-1



Boundary Scan TP (CPU)

XDP_TMS_CPU	1	T0705	XDP_TDO_CPU	1	T0704
XDP_TRST_CPU#	1	T0706	XDP_PREQ#	1	T0701
XDP_TDI_CPU	1	T0707	XDP_PRDY#	1	T0702
XDP_TCLK_CPU	1	T0708	CFG3	1	T0703

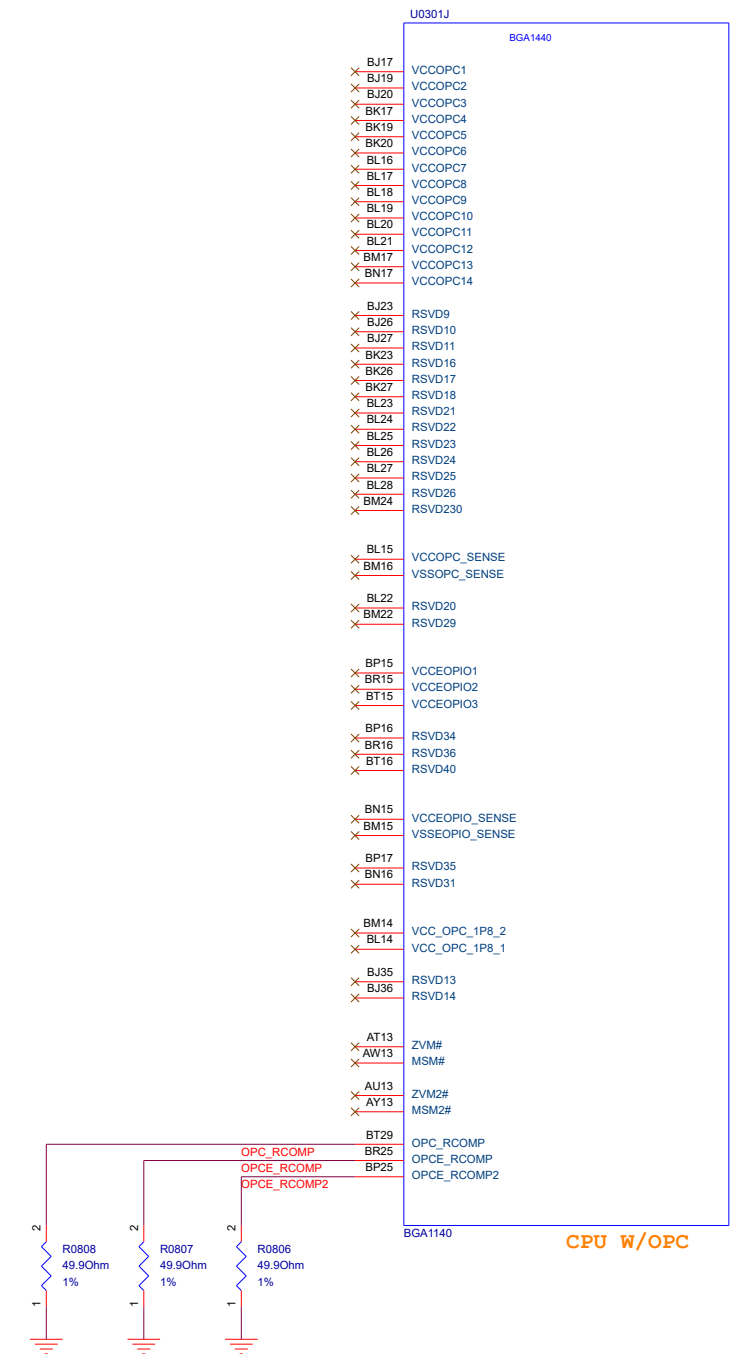
R1.1-5/11-10

Boundary Scan TP (PCH)


24	HDIO2_PCH	1	T0712	PCH_JTAG_TDO	1	T0713
20	PM_RSMRST#_X1	1	T0709	PCH_JTAG_TMS	1	T0714
		1	T0715	PM_SYSRST#_PCH	1	T0710
		1	T0716	ITP_PMODE	1	T0711

BOM

		Title : CPU_XDP	
ASUSTeK COMPUTER INC. NB1		Engineer: Mario_Jhu	
Size B	Project Name GL552VW	Rev 2.0	
Date: Tuesday, June 23, 2015	Sheet 7	of 103	



CPU W/OPC

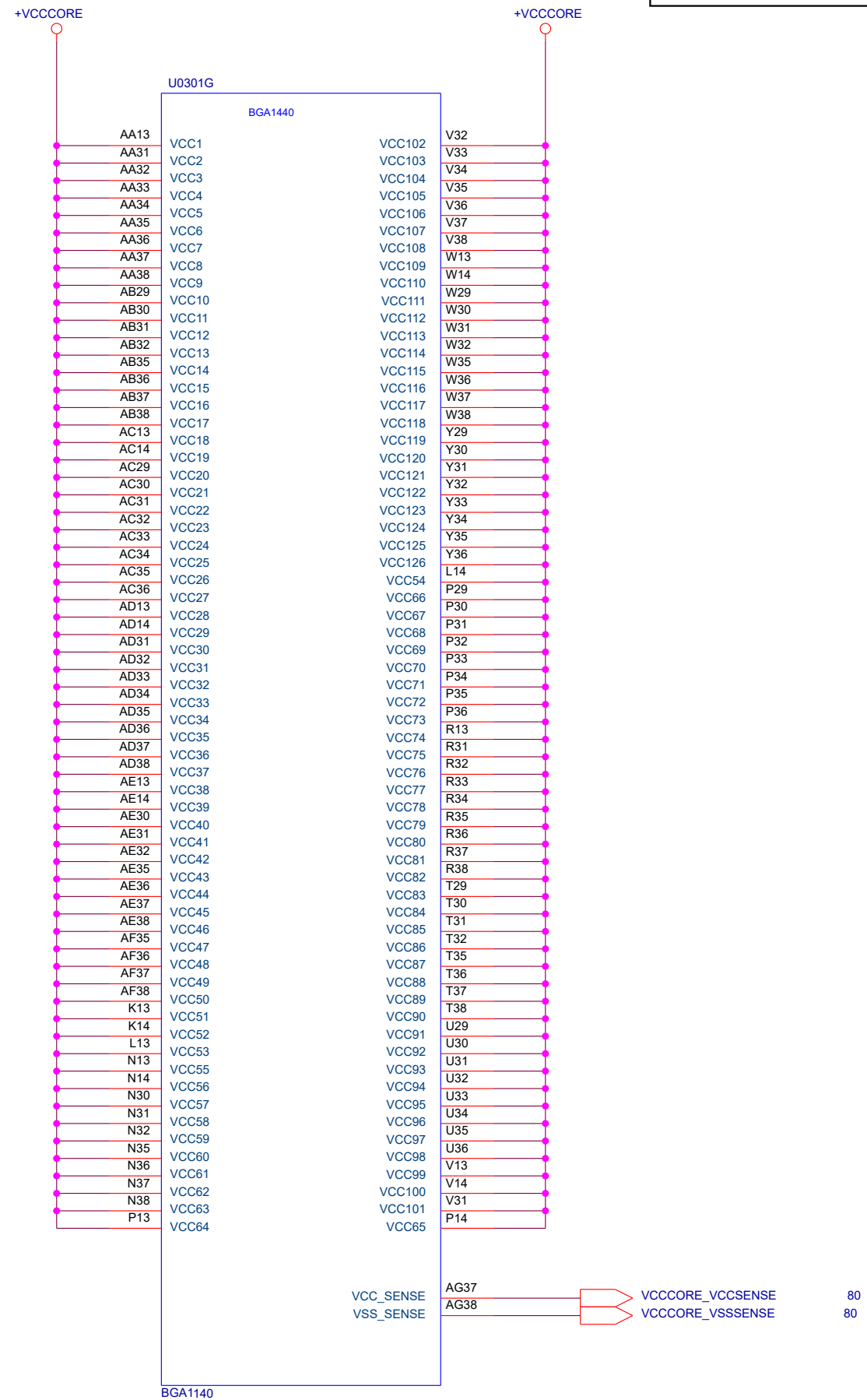
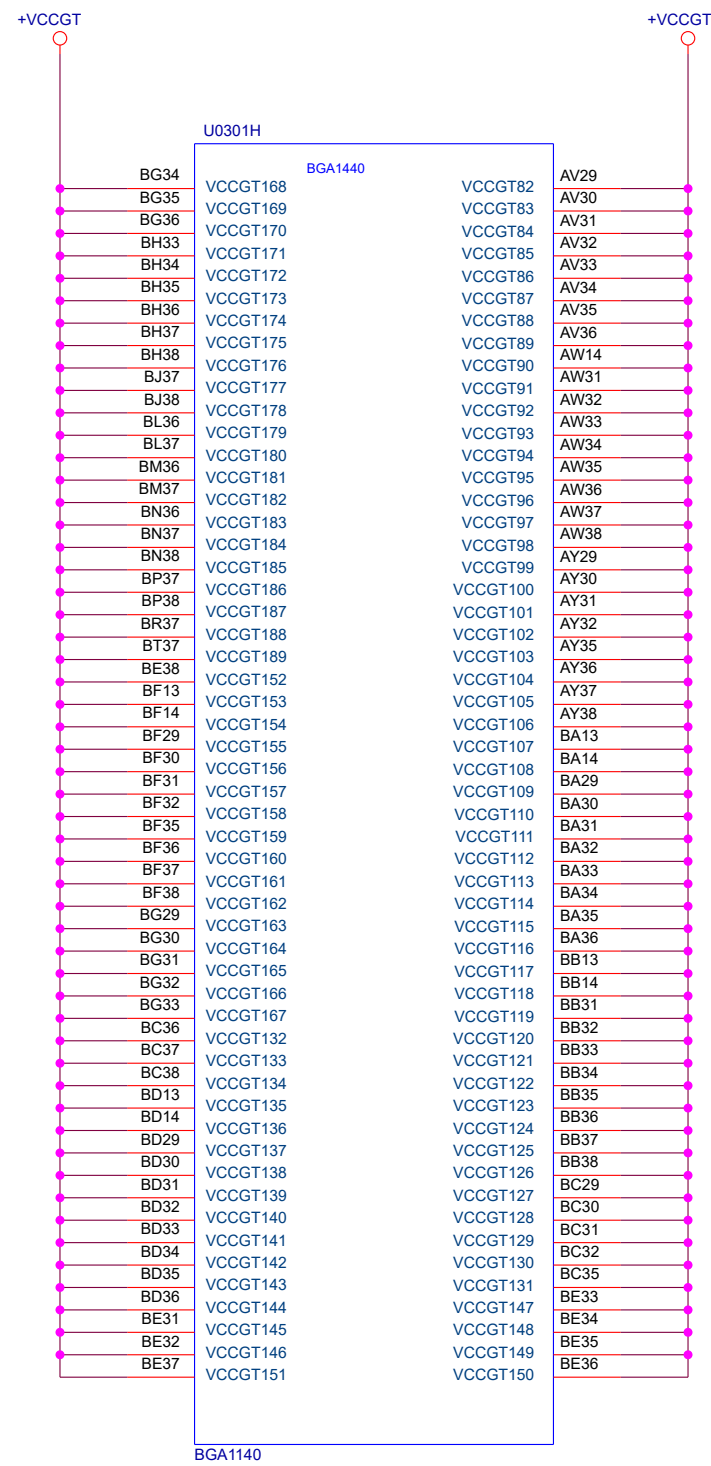
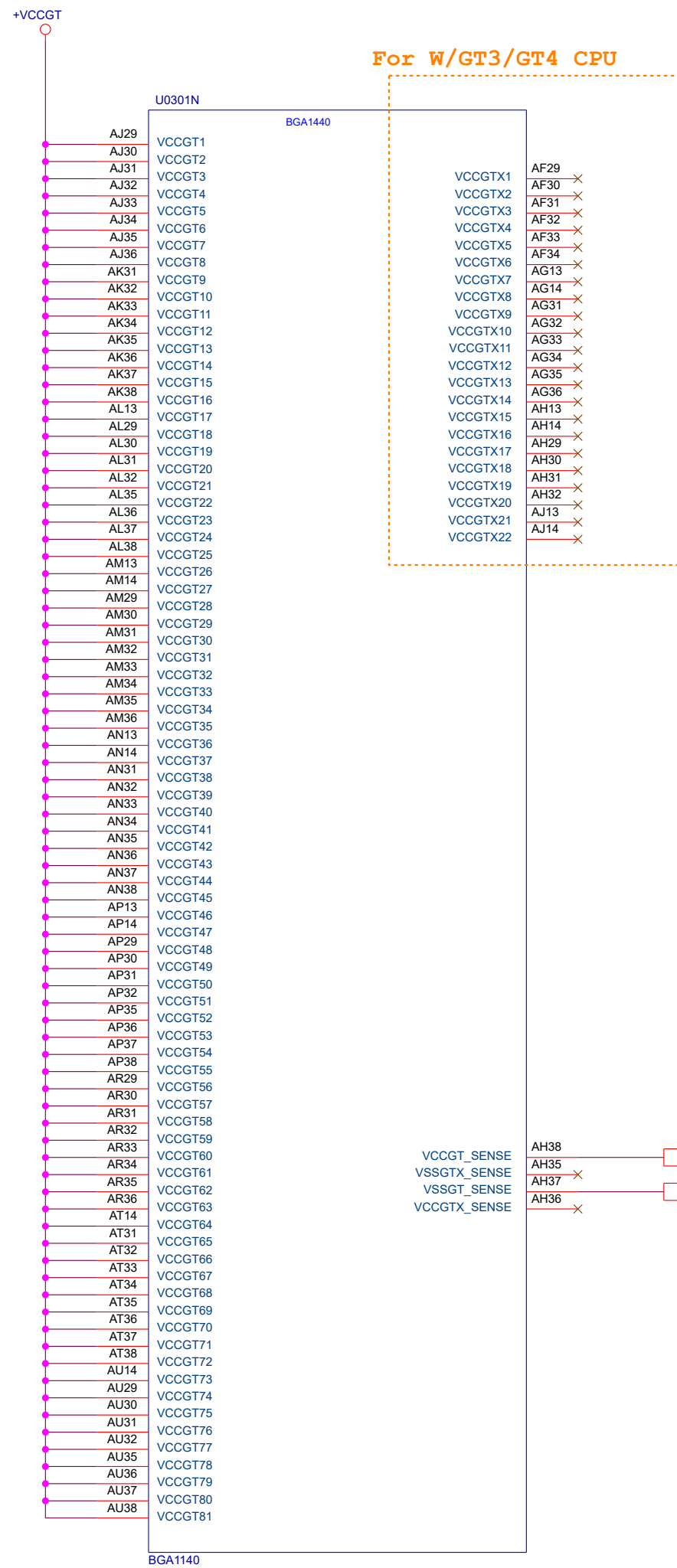
		Project Name GL552VW	Rev 2.0
Title : CPU_PWR			
Size C	Dept.: ASUSTek COMPUTER INC. Engineer: Mario_Jhu		
Date: Tuesday, June 23, 2015		Sheet 8 of 103	

The schematic diagram shows the PLL and VCO circuit. It is powered by +VCCST and +1.0V_VCCPLL. The circuit includes two resistors, R0805 and R0809, both labeled '00hm'. Two capacitors, C0805 and C0818, are both labeled '1UF/6.3V'. The circuit is connected to a microcontroller pin labeled 'nbs_r0603_h24_000s'.

The diagram shows a 10-stage RC ladder network. A +1.2V source is connected to the first stage. The network consists of 10 identical stages in series. Each stage has a 10uF capacitor (C0806 to C0834) in parallel with a 2A current source. The output is taken from the final stage. The total capacitance is 10uF x 10.

The schematic diagram illustrates the power supply section of the TMS320C6701 evaluation module. It features a +VCCSA input connected to a 10UF x 7 capacitor network and a 2.2UF x 3 capacitor network. The 10UF x 7 network includes capacitors C0807, C0808, C0809, C0803, C0813, C0810, and C0814. The 2.2UF x 3 network includes capacitors C0815, C0811, and C0816. The capacitors are connected to ground and labeled with their values and tolerances.

Main Board



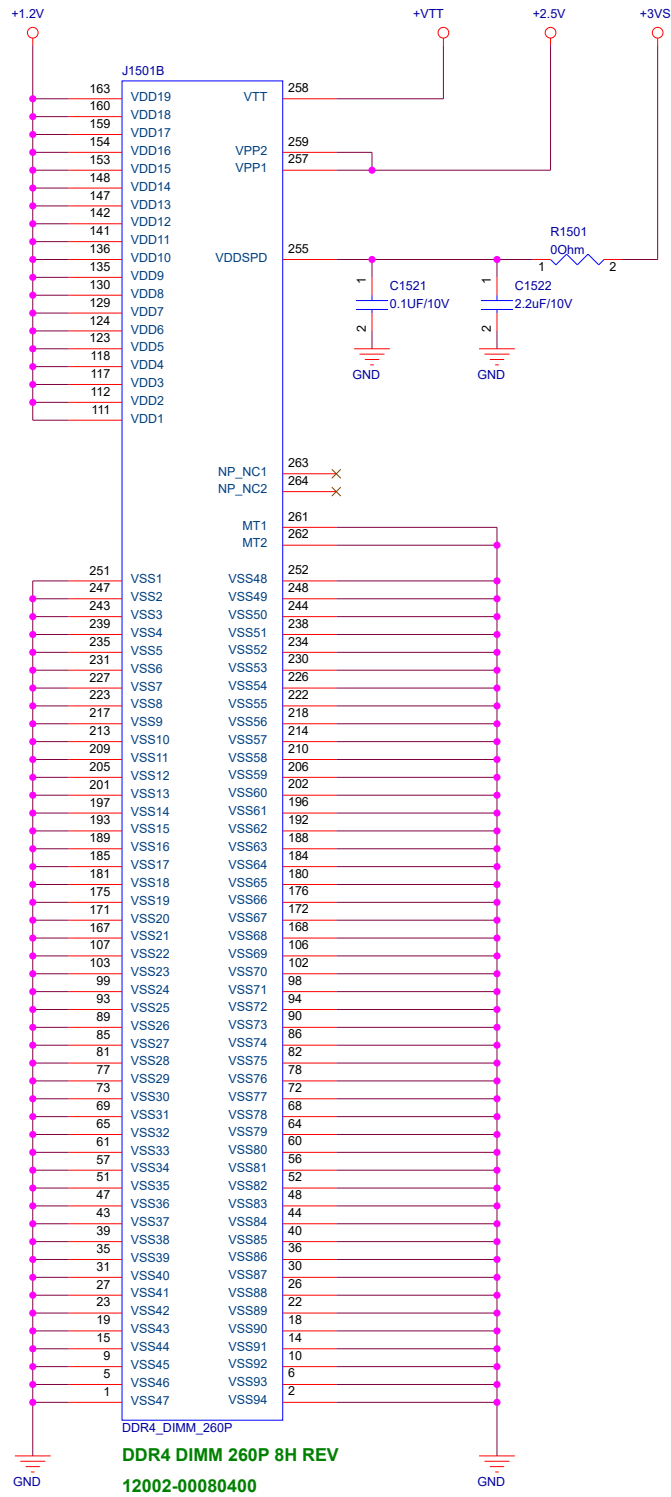
+VCCORE DECAPS Place Back Side (TOP)



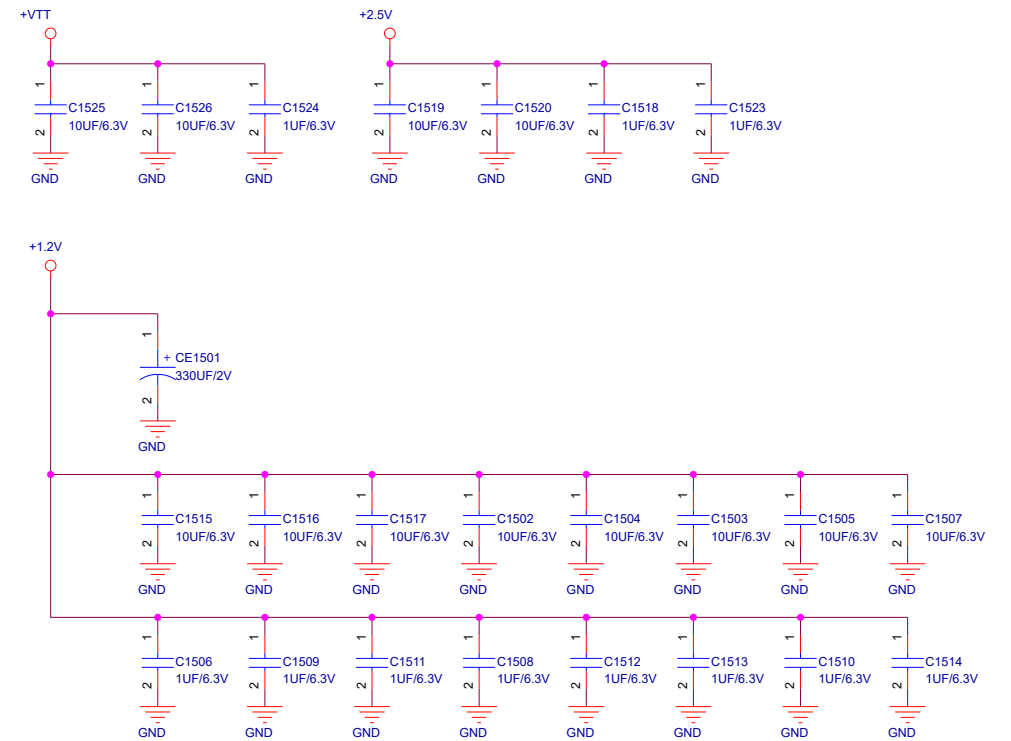
+VCCGT DECAPS Place Back Side (TOP)



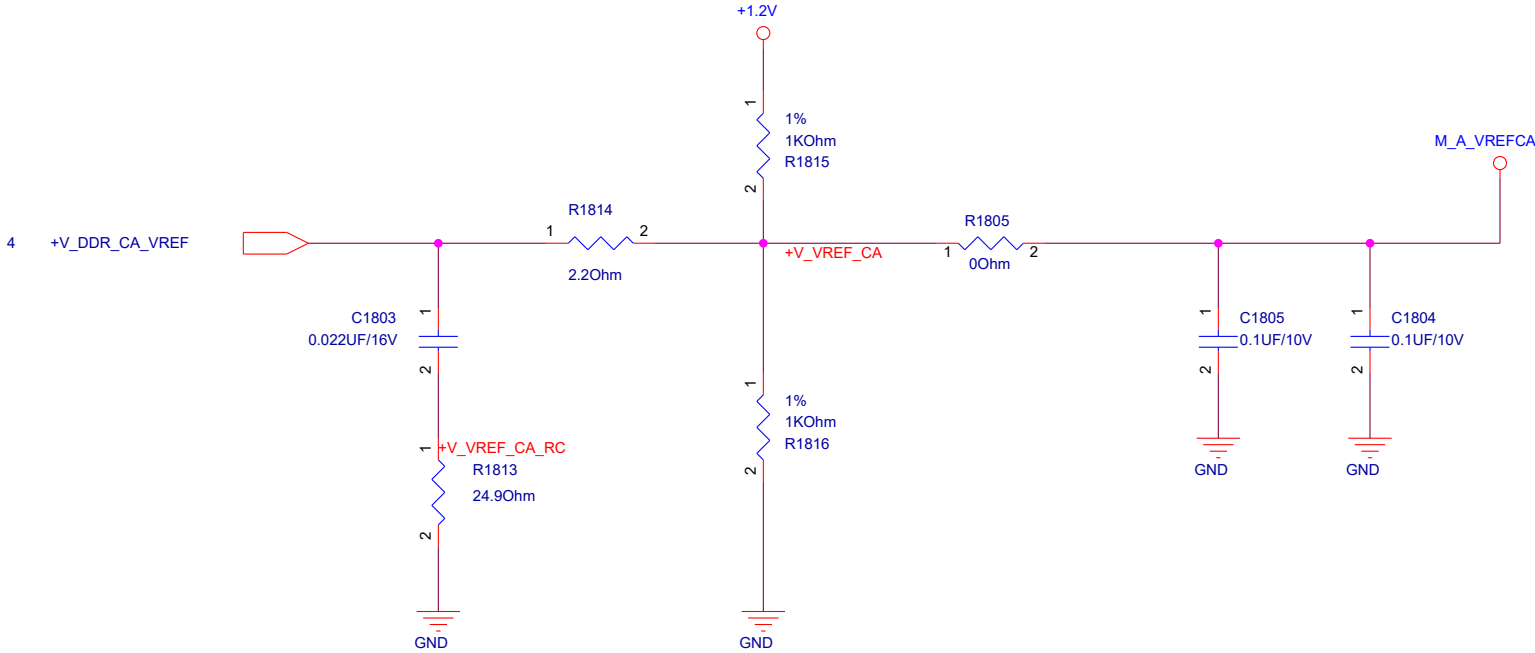
12002-00080400
DDR4 DIMM 260P 8H REV



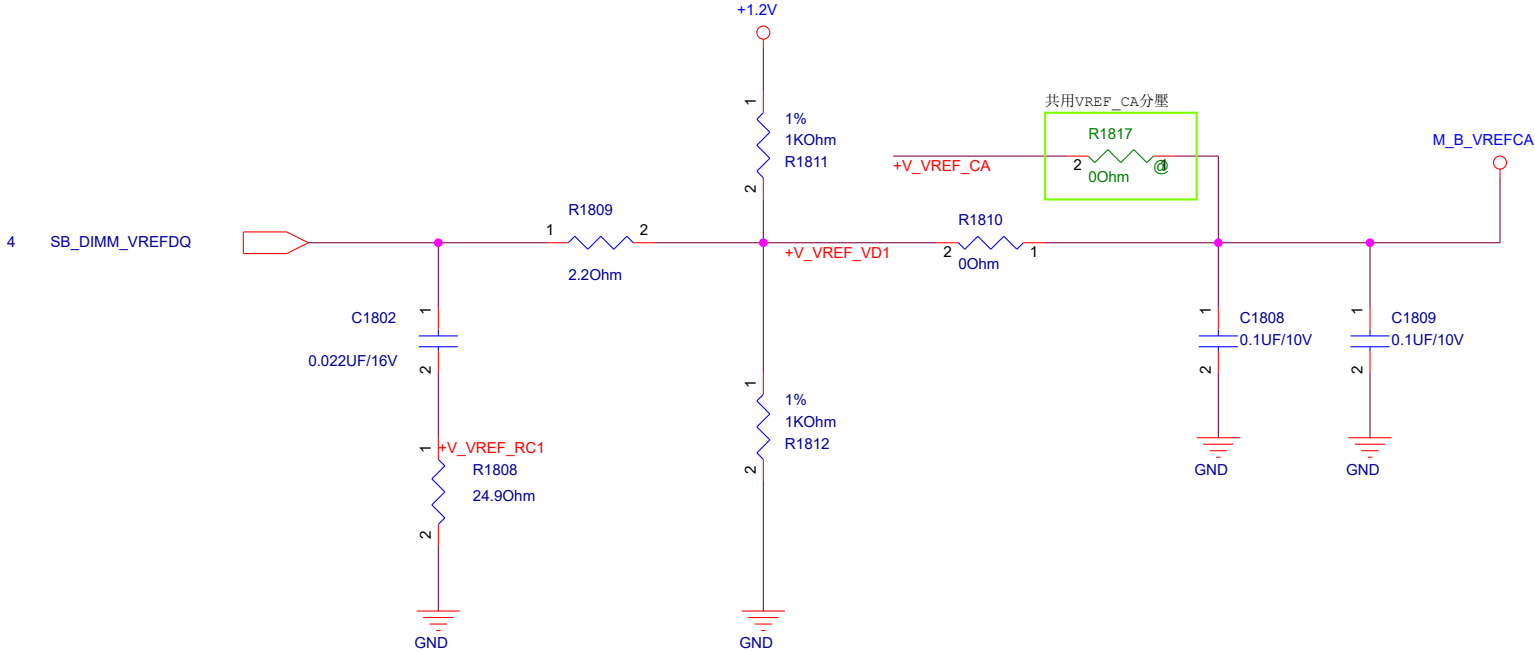
EVENT# ON ECC DIMM: KEEP A PULL UP IF NO PIN IN PCH



SO-DIMM0 Vref



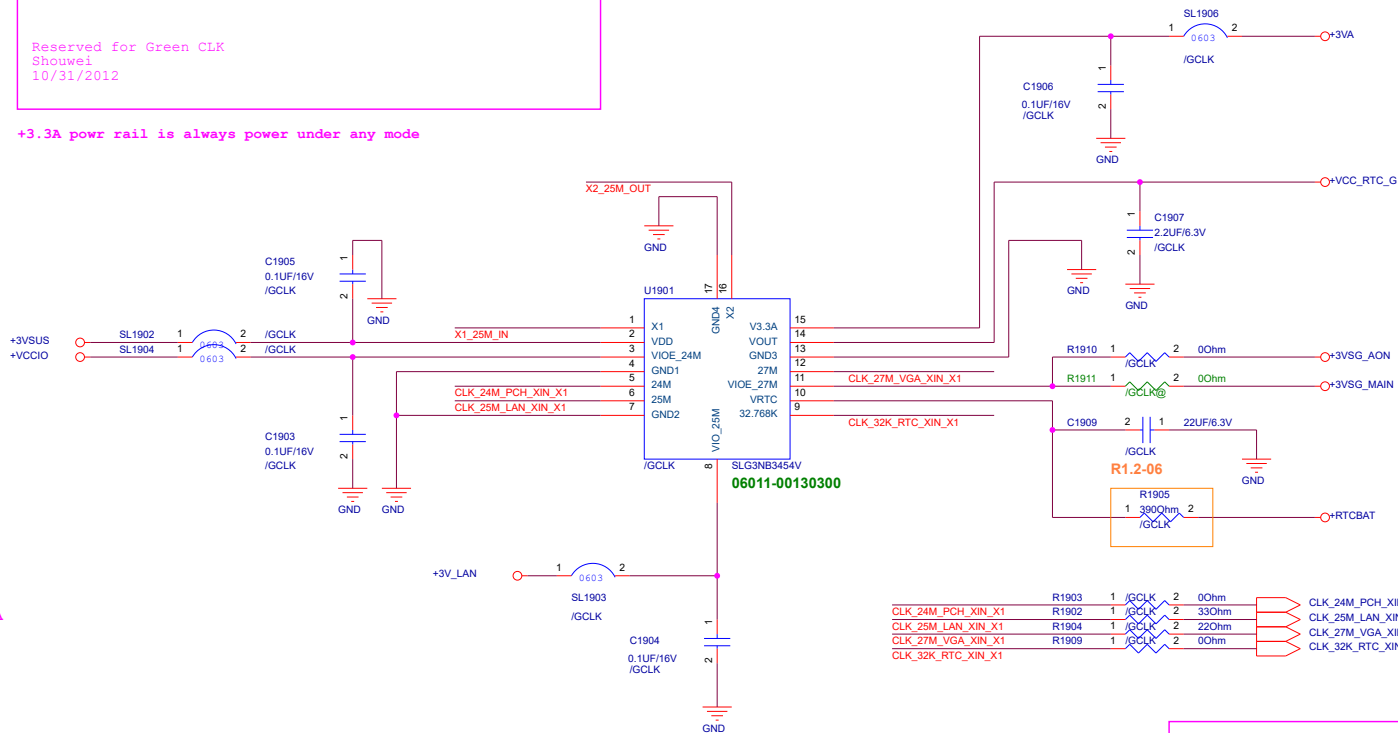
SO-DIMM1 Vref



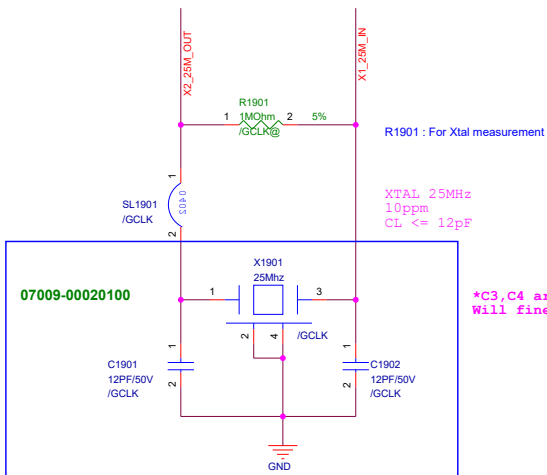
Silego Green CLK

Reserved for Green CLK
Shouwei
10/31/2012

+3.3A powr rail is always power under any mode



VDD must supply same power rail or prior to VDDIO_25M_A & VDDIO_25M_B for Wake function
VDDIO_25M_A MUST supply same power rail as LAN 3.3V
VDDIO_25M_B MUST supply same power rail as PCH of XTALIN_25M



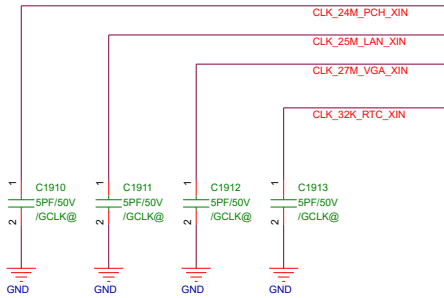
R1.1-4/13-5

X1901: 25MHZ +/-20ppm/10pF (3225)
1st: P/N:07009-00020700 HOSONIC/E3FB25.0000F10E22
2nd: P/N:07009-00020800 TXC/7V25000036
3rd: P/N:07009-00020100 EPSON/FA-238G

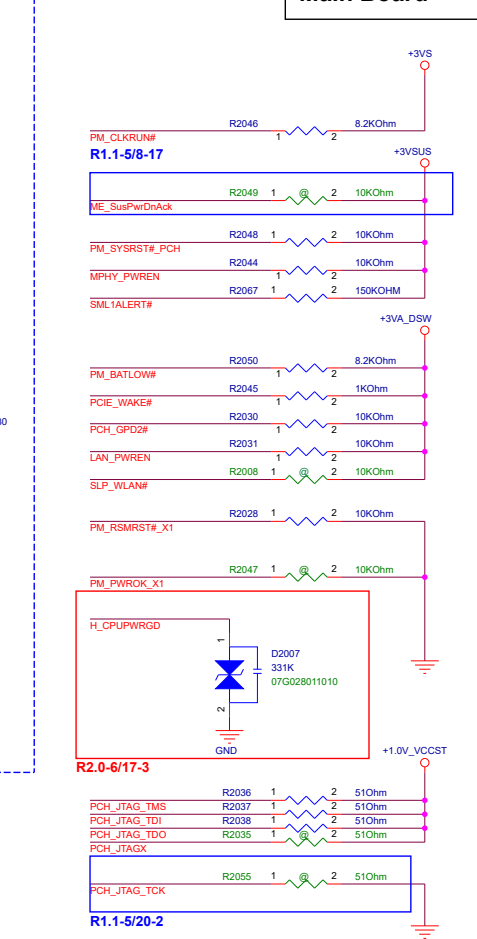
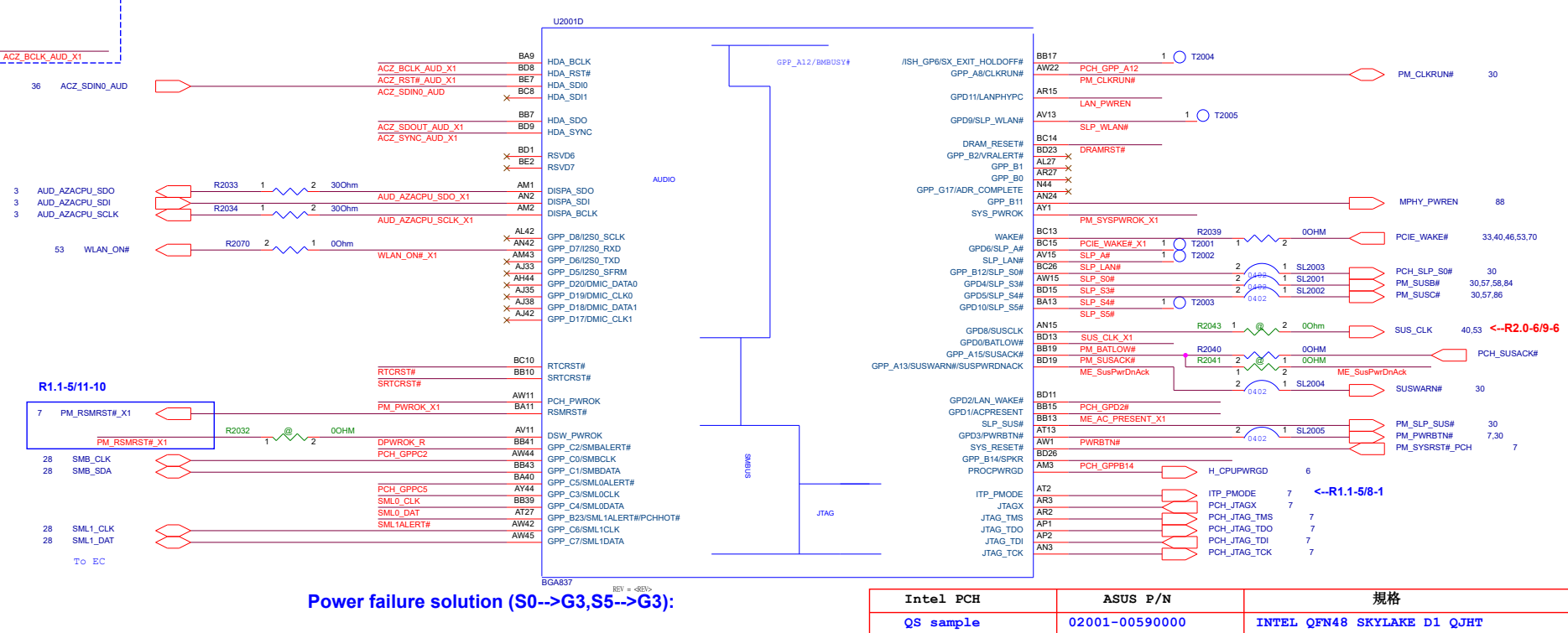
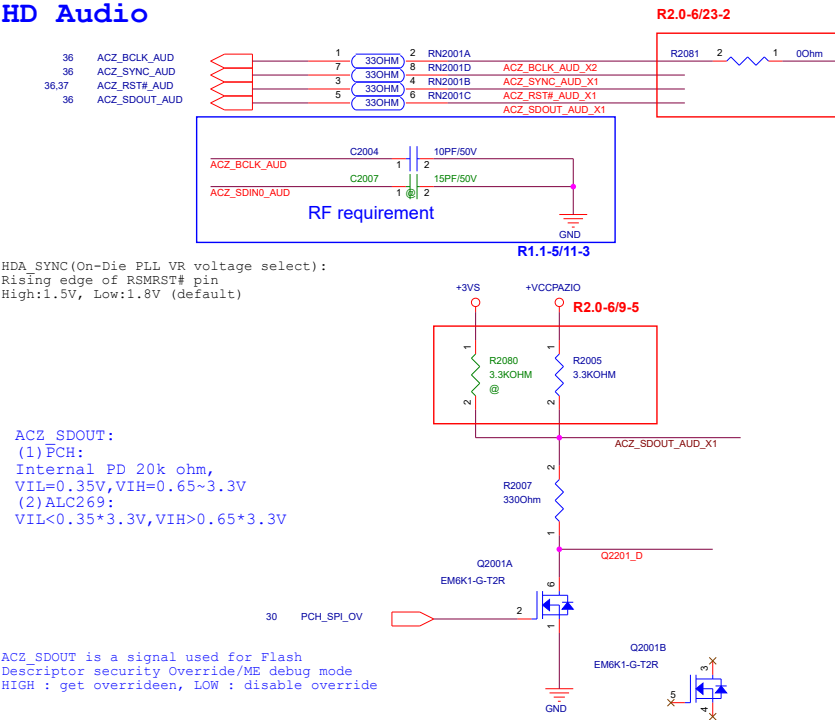
R1.1-4/13-5

*C3,C4 are recommended for CL=12pF, Will fine tune them by real application

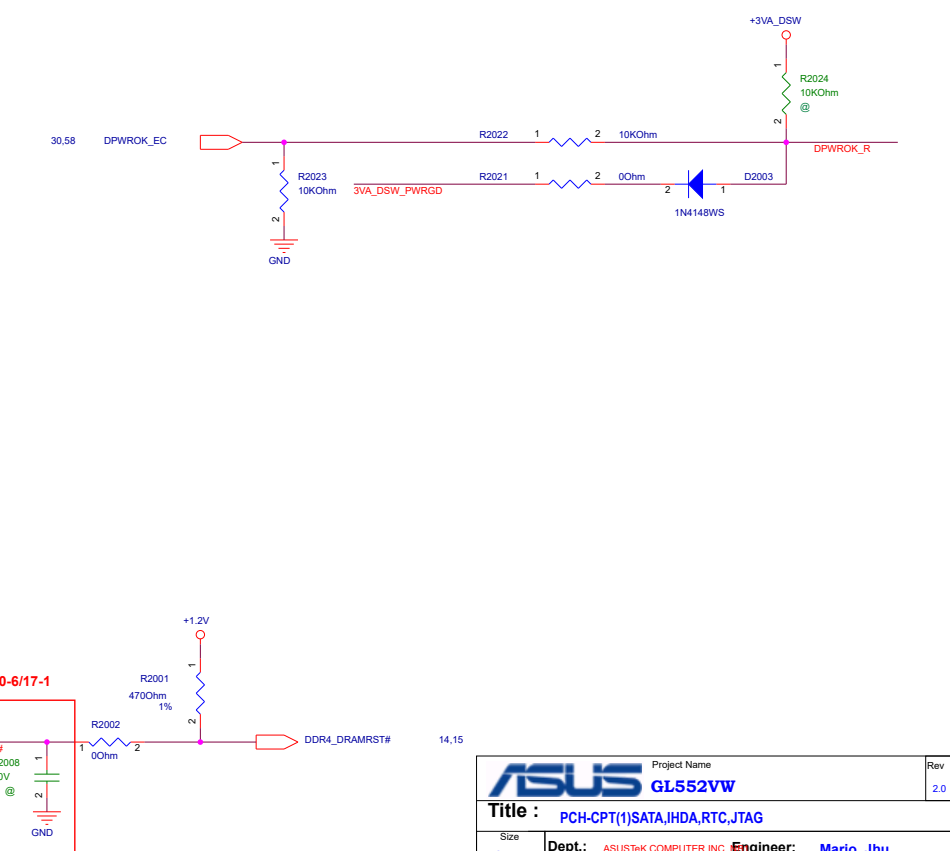
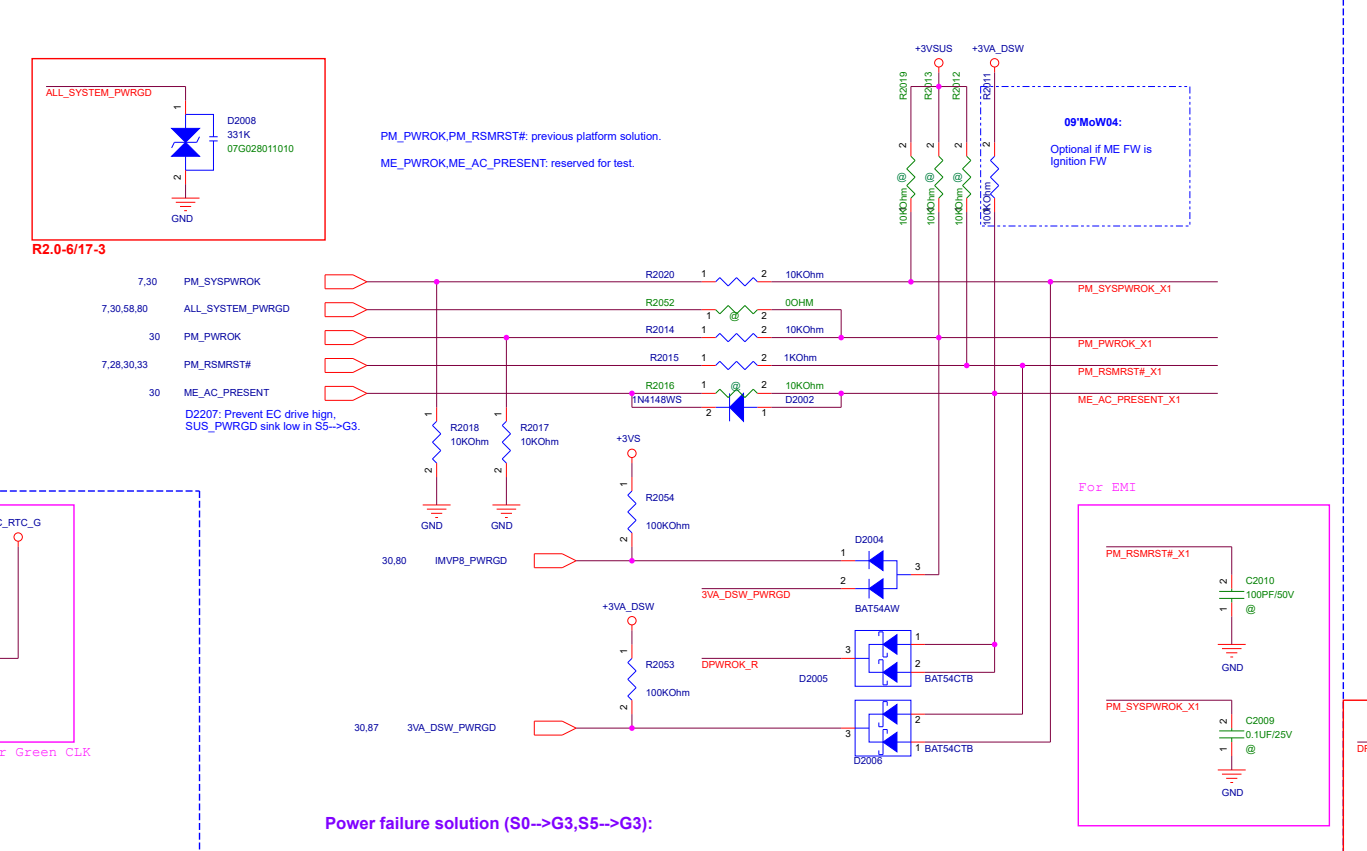
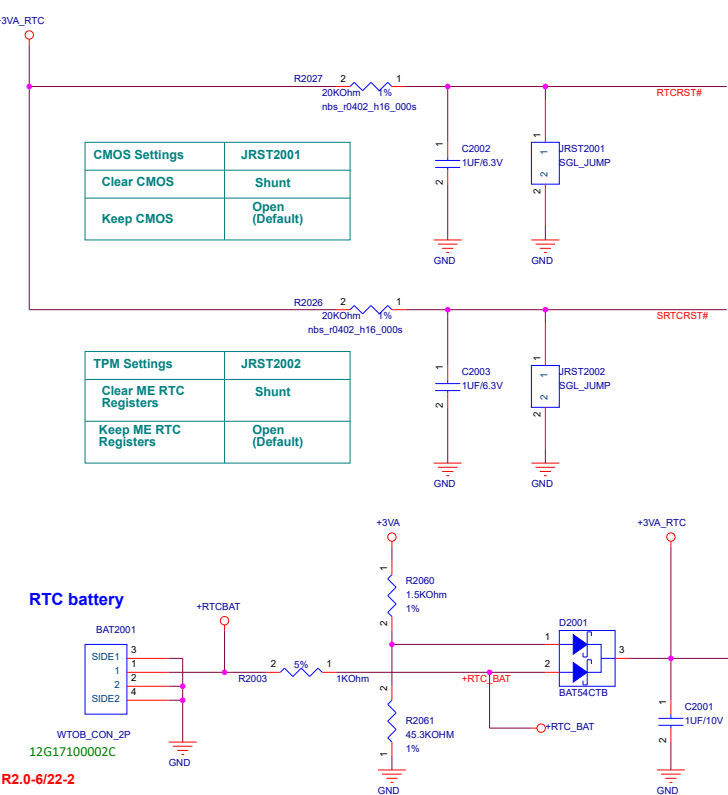
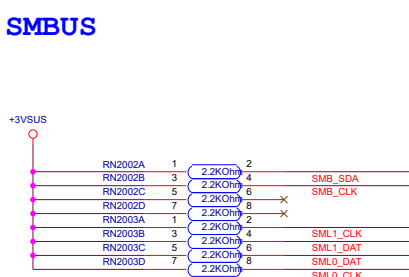
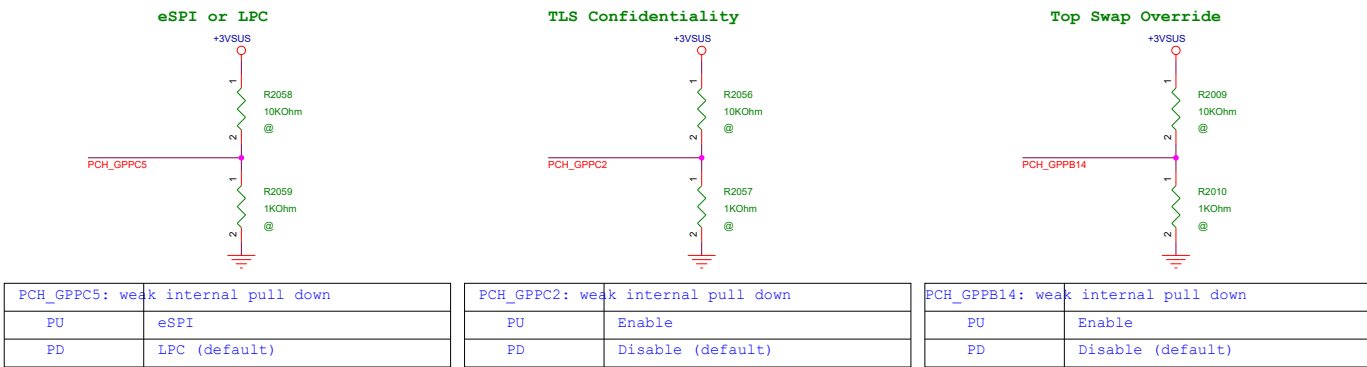
For EMI Request



HD Audio



Main Source	1th PWR	2nd PWR	3rd PWR	4th
+RTCBAT	+RTC_BAT	+3VA_RTC		
AC_BAT_SYS	+1.0VSUS	+VCCST	+1.0V_VCCST	
	+1.2V			
	+3VAO	+3VA	+3VA_EC	
	+3VA_DSW	+3VSUS	+3VSUS_PCH	+VCCPAZIO
		+3VS		



PCIe Setting

GL552VW PCIe Function define
Skylake HM170

HSIO	HSIO Capabilities	Function	SRC
	PCIEG (From GPU)	dGPU	SRC0
01	USB3#01	USB3_IO	
02	USB3#02 / SSIC#01	USB3.0 IO colay USB3.1	
03	USB3#03 / SSIC#02	USB3.0 IO colay USB3.1	
04	USB3#04		
05	USB3#05	USB3_IO	
06	USB3#06		
07	USB3#07 / PCIE#01		
08	USB3#08 / PCIE#02		
09	PCIE#03	WLAN	SRC3
10	PCIE#04 / GBE	GLAN & CardReader	SRC4
11	PCIE#05 / GBE	USB 3.1	SRC5
12	PCIE#06		
13	PCIE#07		
14	PCIE#08	PCIE*4 SSD	SRC6
15	PCIE#09 / SATA#0 / GBE		
16	PCIE#10 / SATA#1		
17	PCIE#11		
18	PCIE#12 / GBE		
19	PCIE#13 / SATA#0 / GBE	1st HDD	
20	PCIE#14 / SATA#1	ODD	
21	PCIE#15 / SATA#2	SATA SSD	
22	PCIE#16 / SATA#3		
23			
24			
25			
26			

USB Setting

GL552VW USB Function define
Skylake HM170

USB 2.0	Function	USB 3.0	Function
USB2_01	USB3.0 IO	USB3_01	USB3.0 IO
USB2_02	USB3.0 IO colay USB3.1	USB3_02	USB3.0 IO colay USB3.1
USB2_03		USB3_03	USB3.0 IO colay USB3.1
USB2_04	Camera	USB3_04	
USB2_05	USB3.0 IO	USB3_05	USB3.0 IO
USB2_06	USB2.0 IO	USB3_06	
USB2_07		USB3_07	
USB2_08		USB3_08	
USB2_09	BT/WLAN		
USB2_10			
USB2_11			
USB2_12			

PCIEx4 SSD

40	PCIE11_TXP_NGFF1_L2
40	PCIE11_TXN_NGFF1_L2
40	PCIE11_RXP_NGFF1_L2
40	PCIE11_RXN_NGFF1_L2

ODD

51	SATA1_TXN_ODD
51	SATA1_TXP_ODD
51	SATA1_RXN_ODD
51	SATA1_RXP_ODD

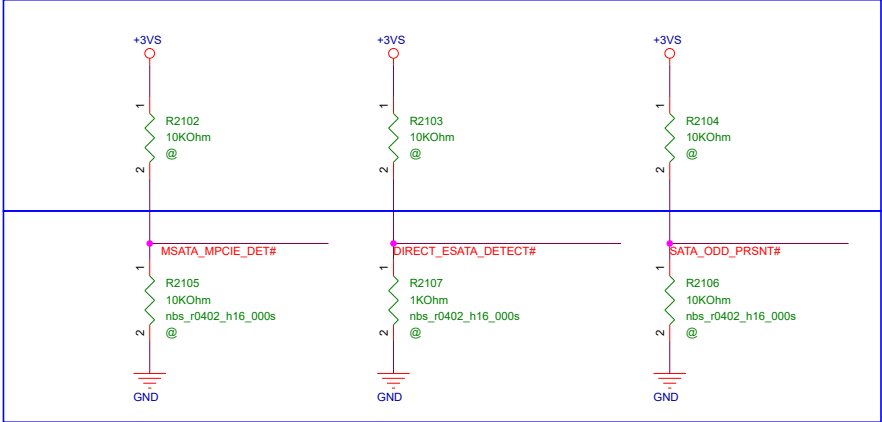
HDD

51	SATA0_TXN_HDD
51	SATA0_TXP_HDD
51	SATA0_RXN_HDD
51	SATA0_RXP_HDD

PCIEx4 SSD

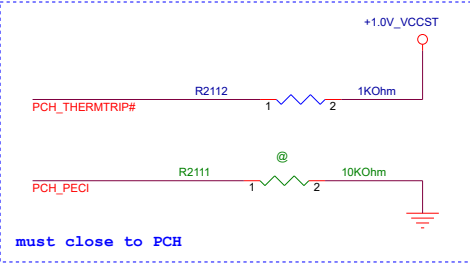
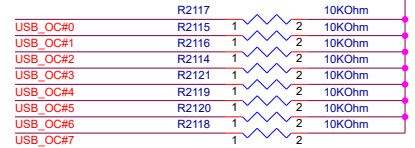
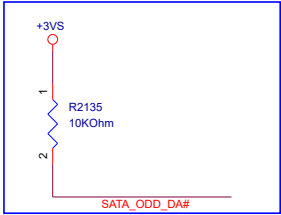
40	PCIE12_TXP_NGFF1_L3
40	PCIE12_TXN_NGFF1_L3
40	PCIE12_RXP_NGFF1_L3
40	PCIE12_RXN_NGFF1_L3

R1.1-5/14-1

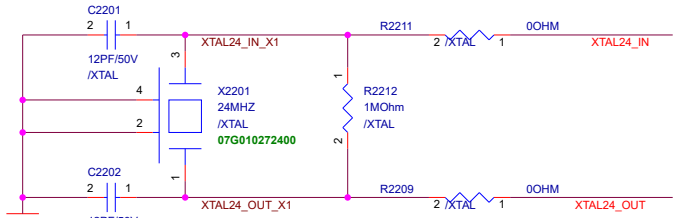


R1.1-5/8-7

R1.1-5/8-10

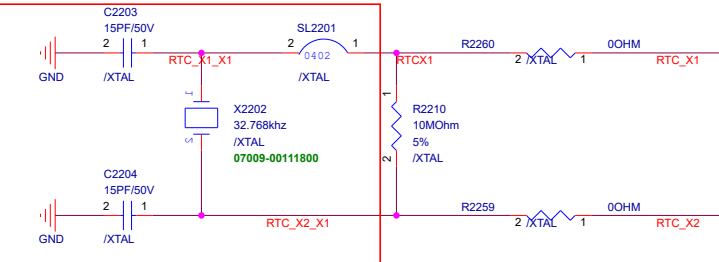


XTAL 24MHz



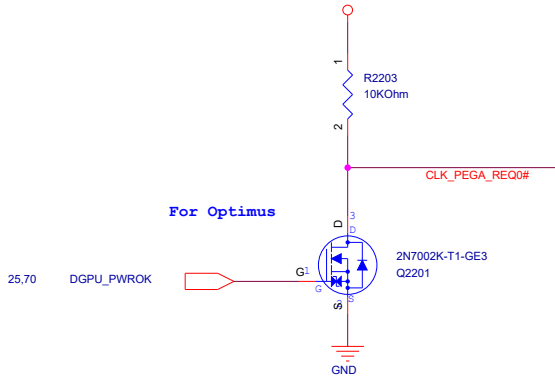
R1.1-4/13-5

RTC CRYSTAL 32.768KHZ

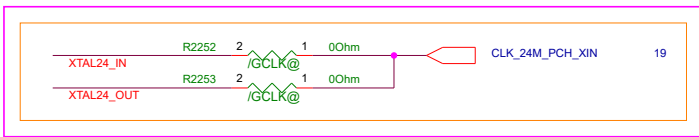
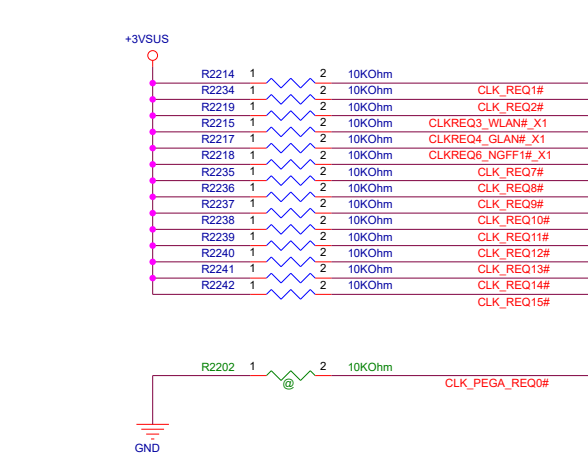


R1.1-4/13-5

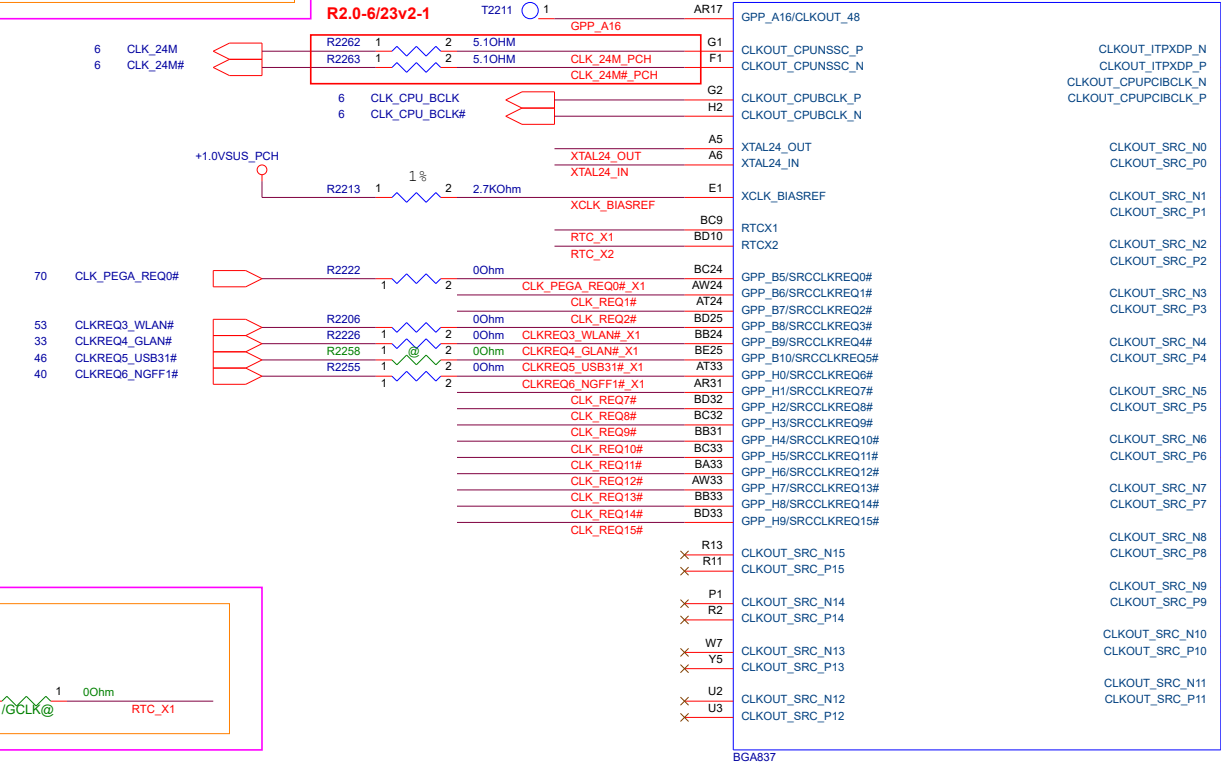
DGPU CLKReq#



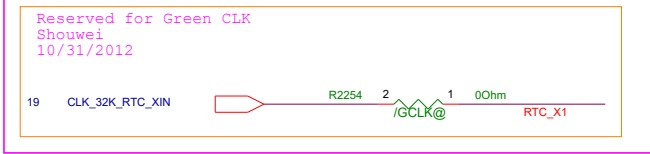
PCH CLKREQ Setting:



R1.0-2/9-4



R1.0-2/9-4



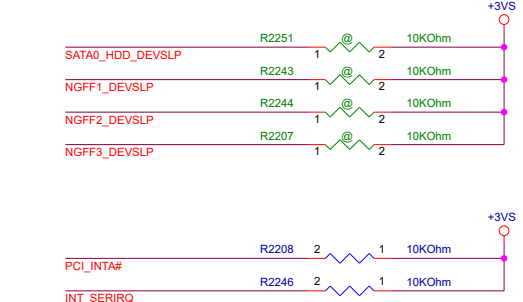
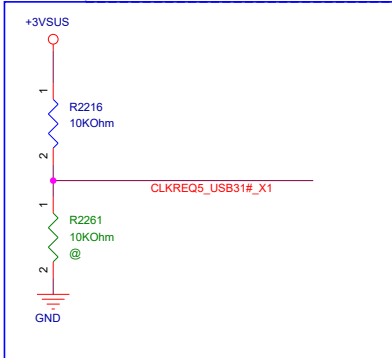
USB3.0 Port1 : J5202

USB3.0 Port1 : J4701

USB3.0 Port2 : J5201

USB3.0 Port2 : J4701

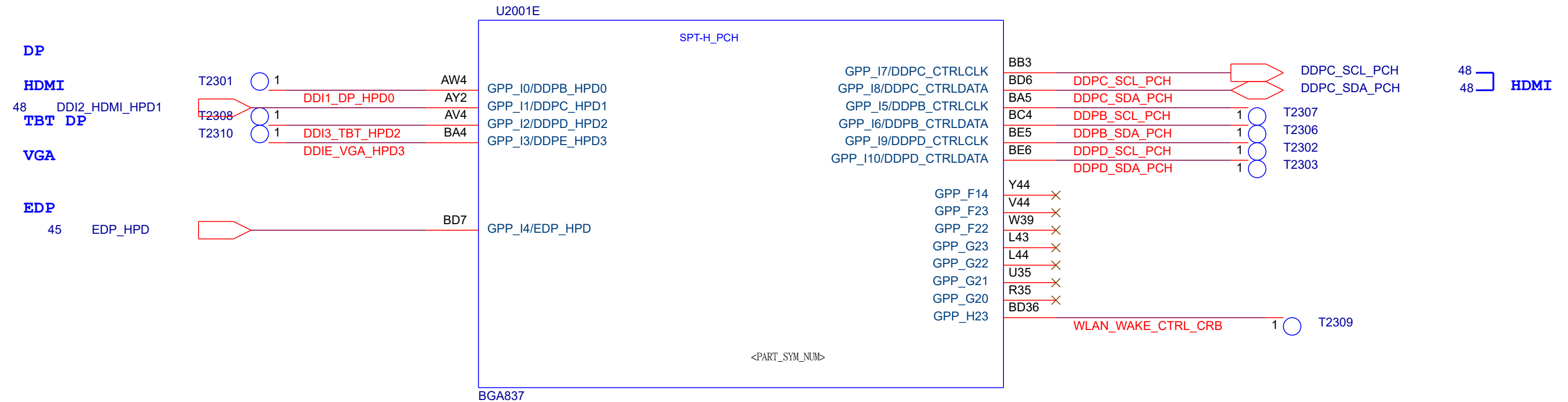
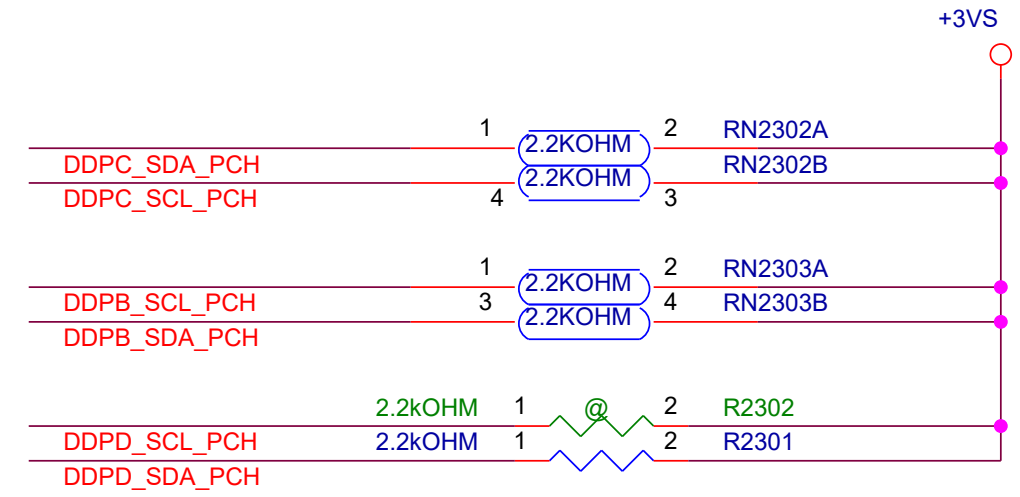
R1.1-5/11-2

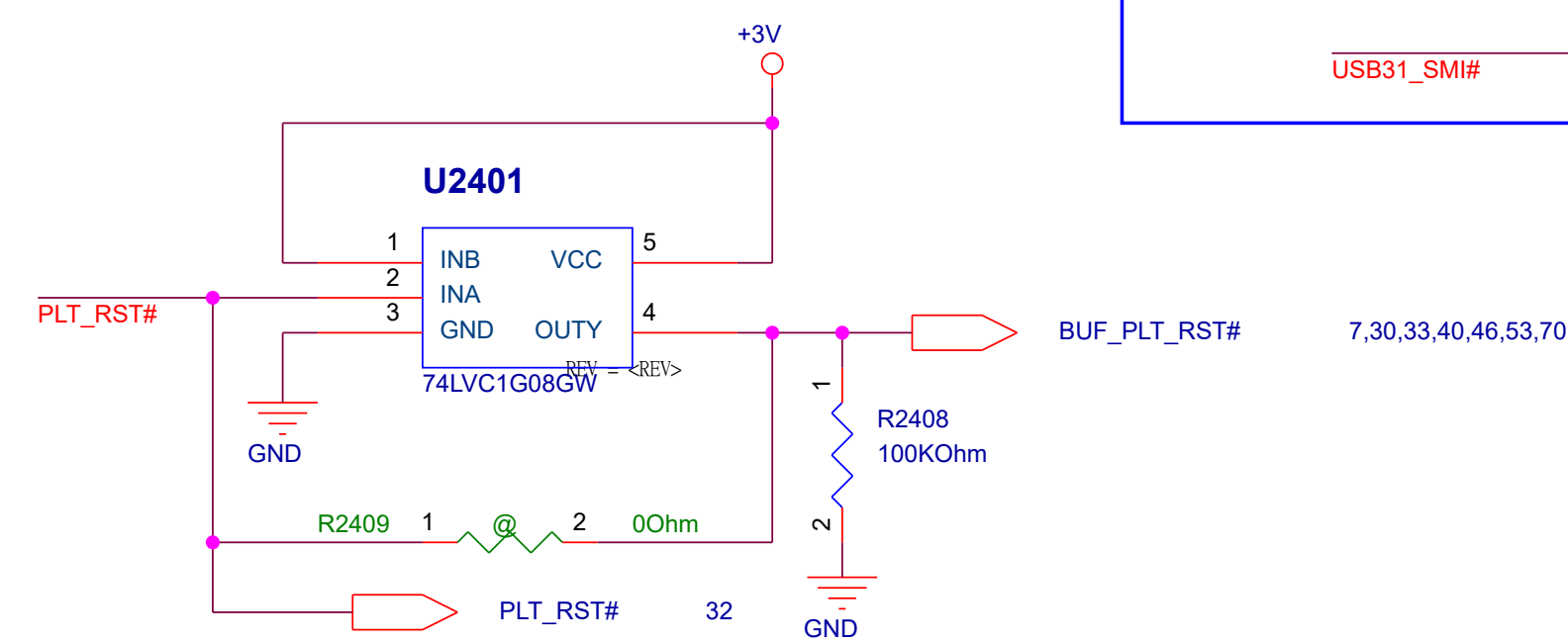
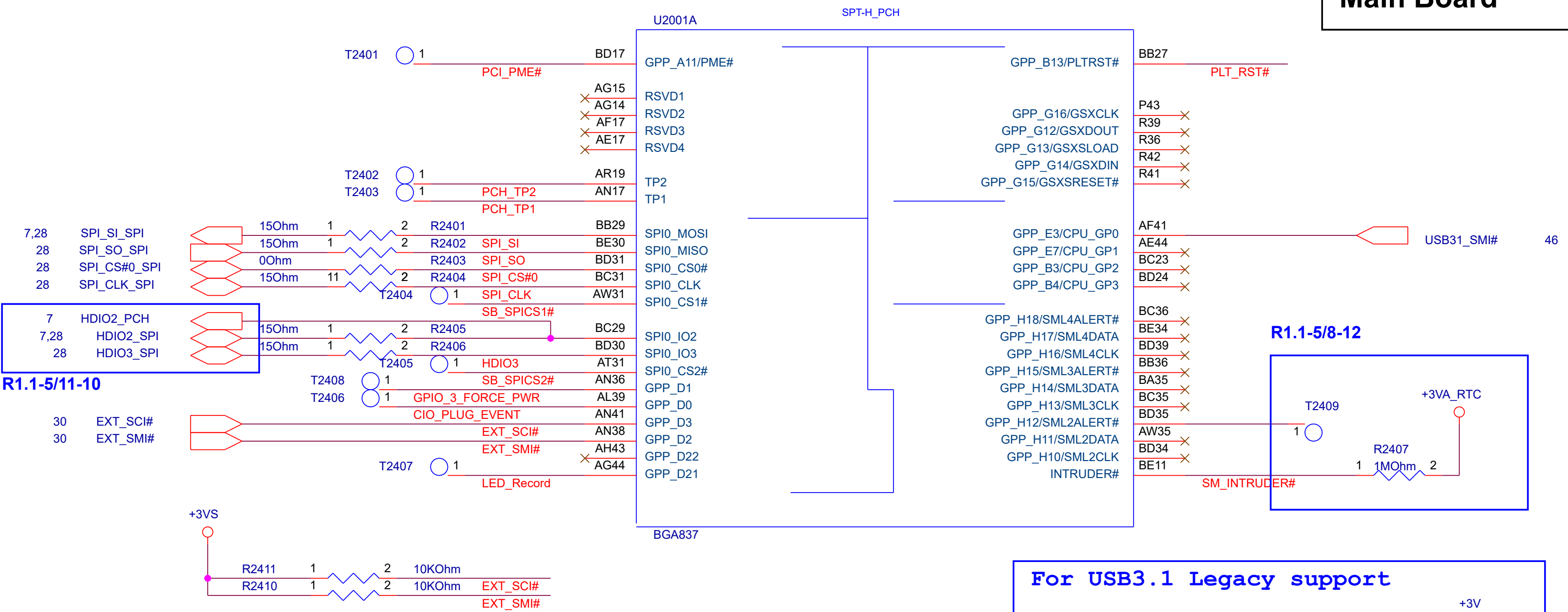


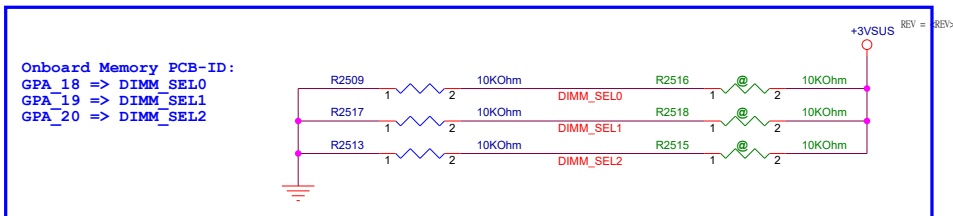
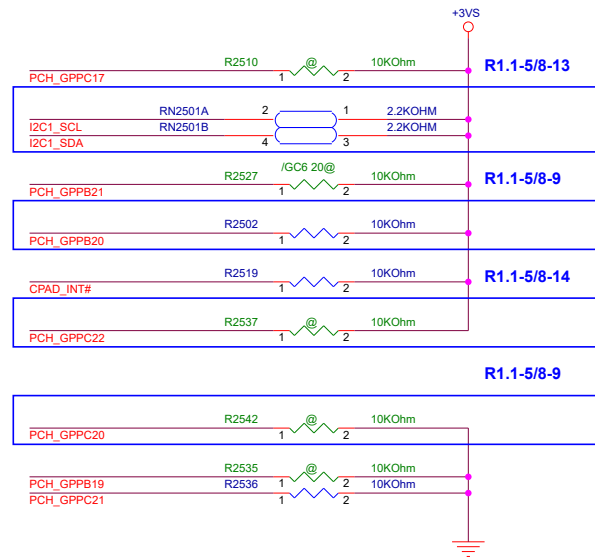
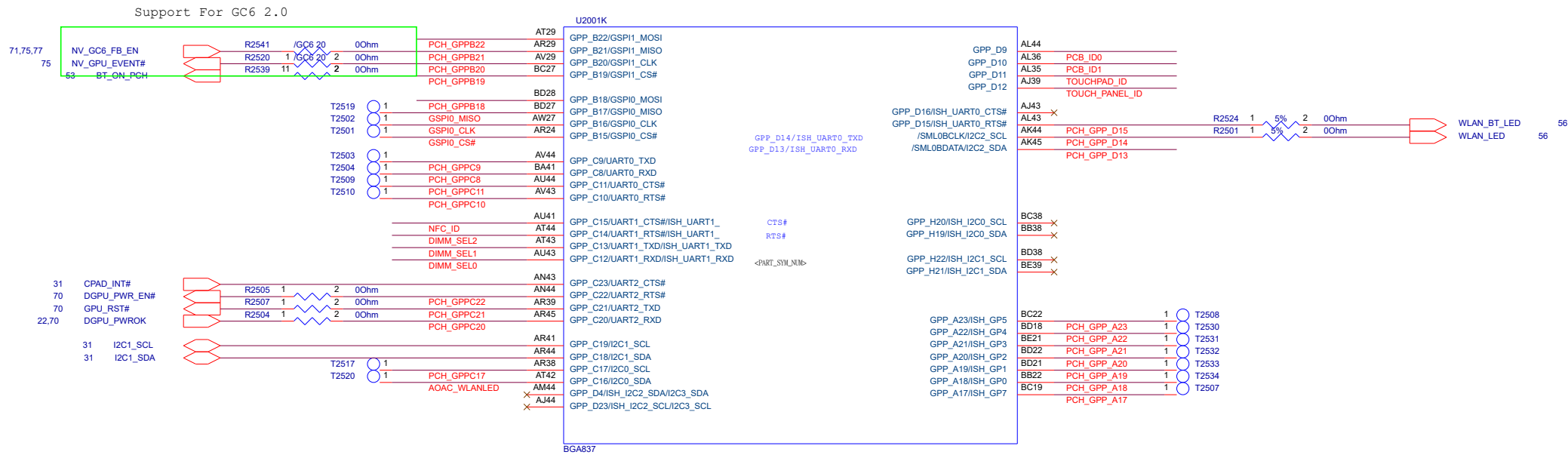
Main Board

HPD4 to EDP Panel

```
DDPD Strap Setting Update :
0 = Port D is not detected (Default)
1 = Port D is detected
20150309
```

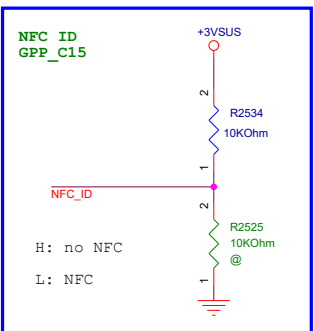
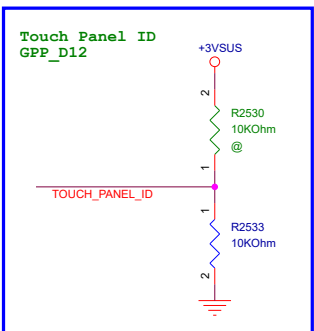
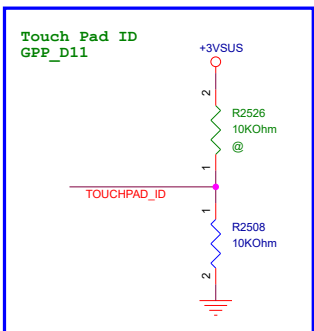
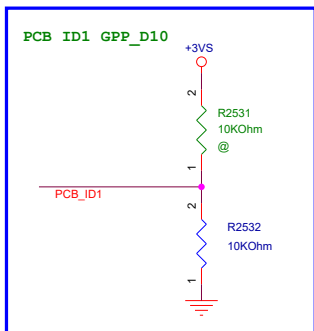
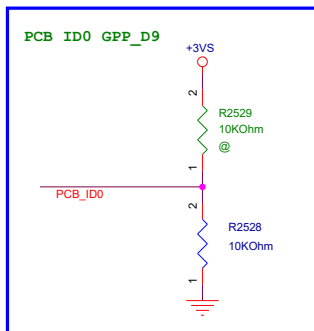
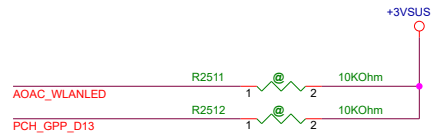
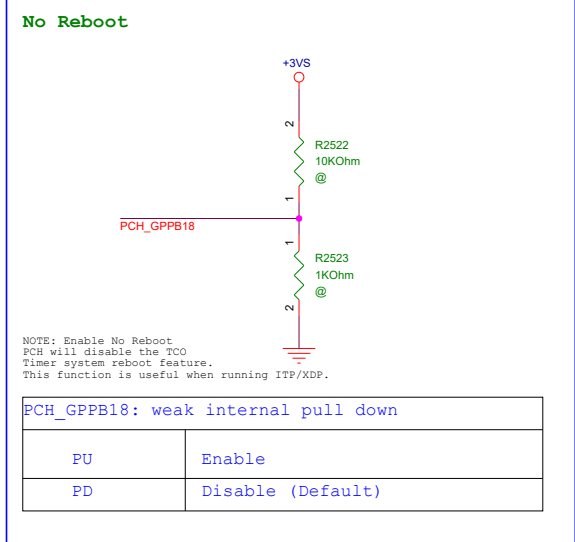
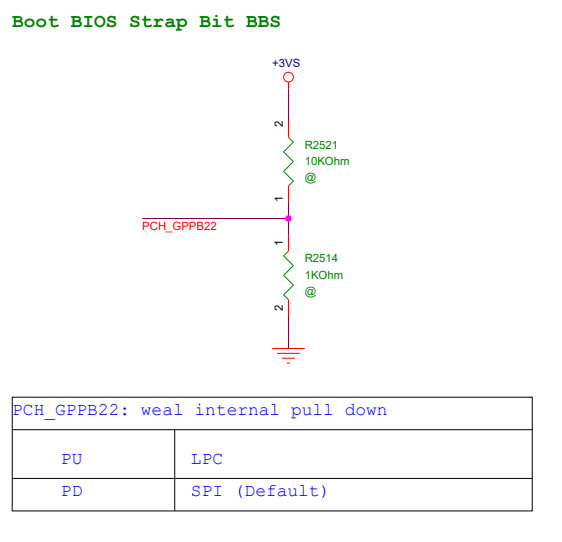


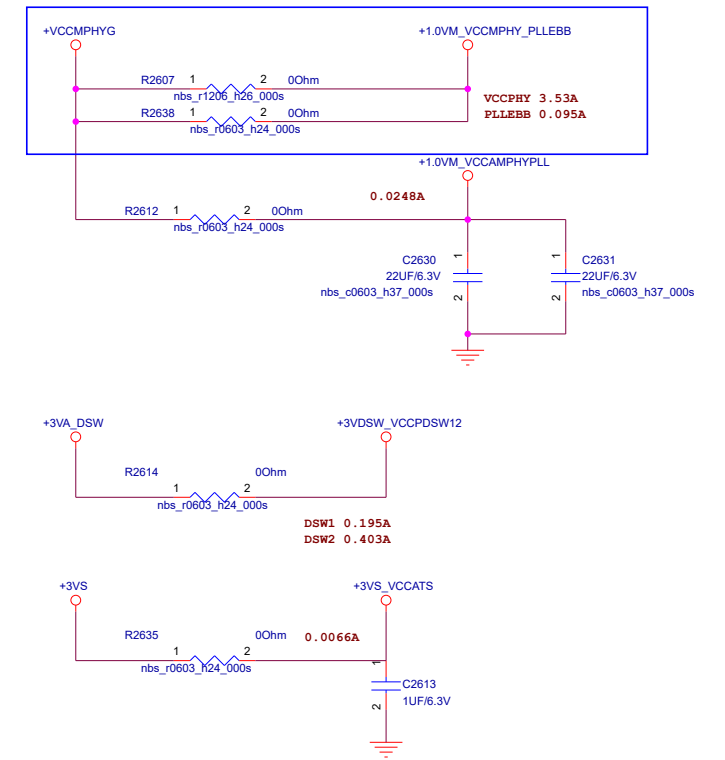
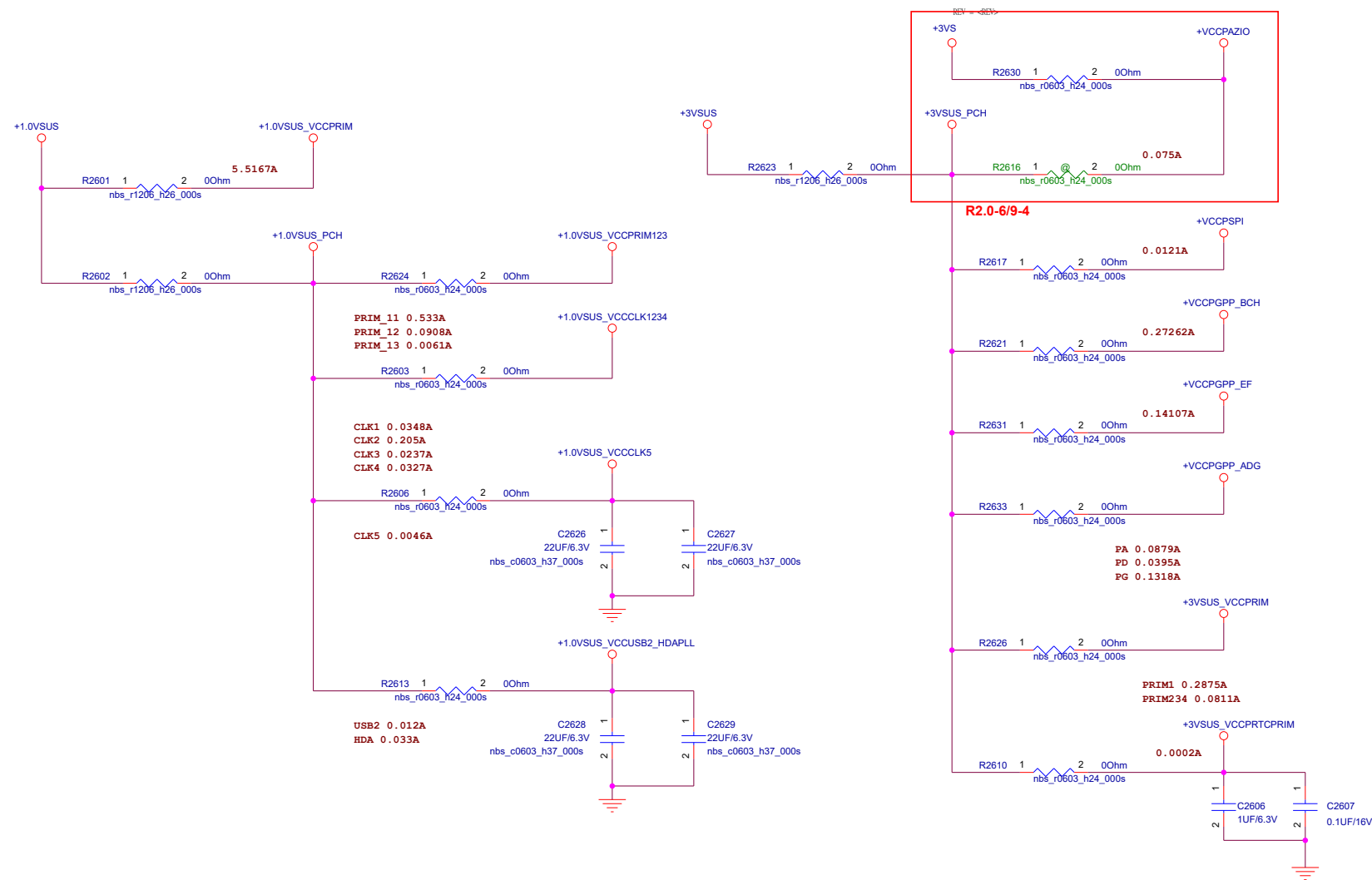
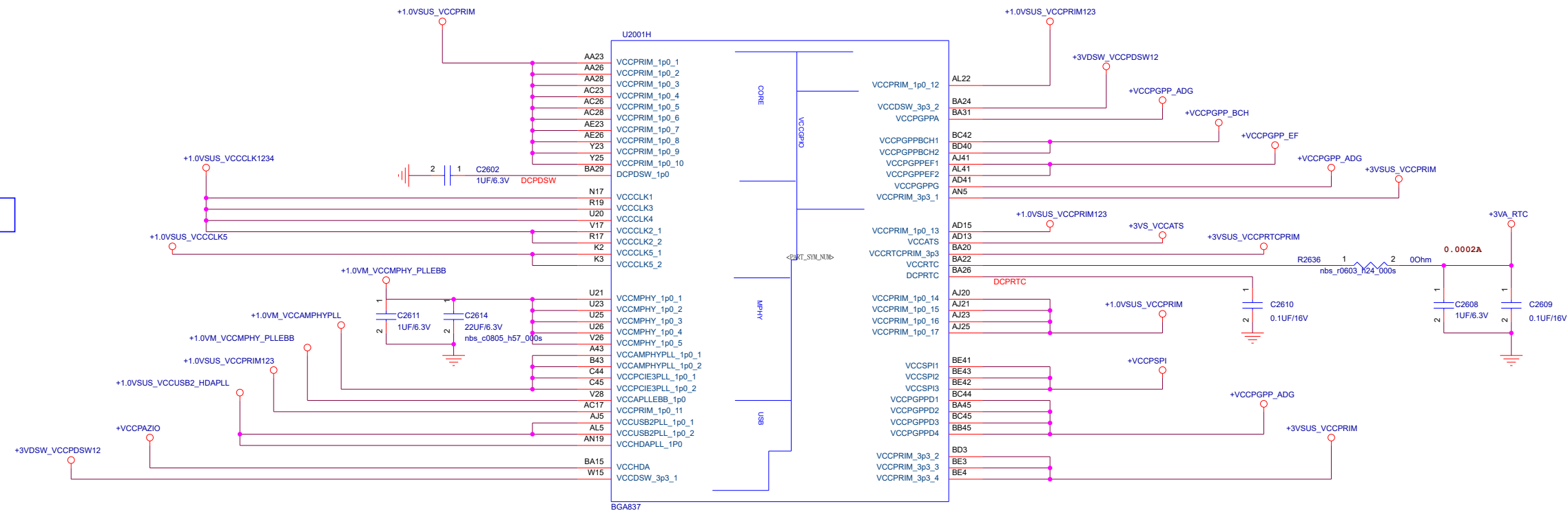




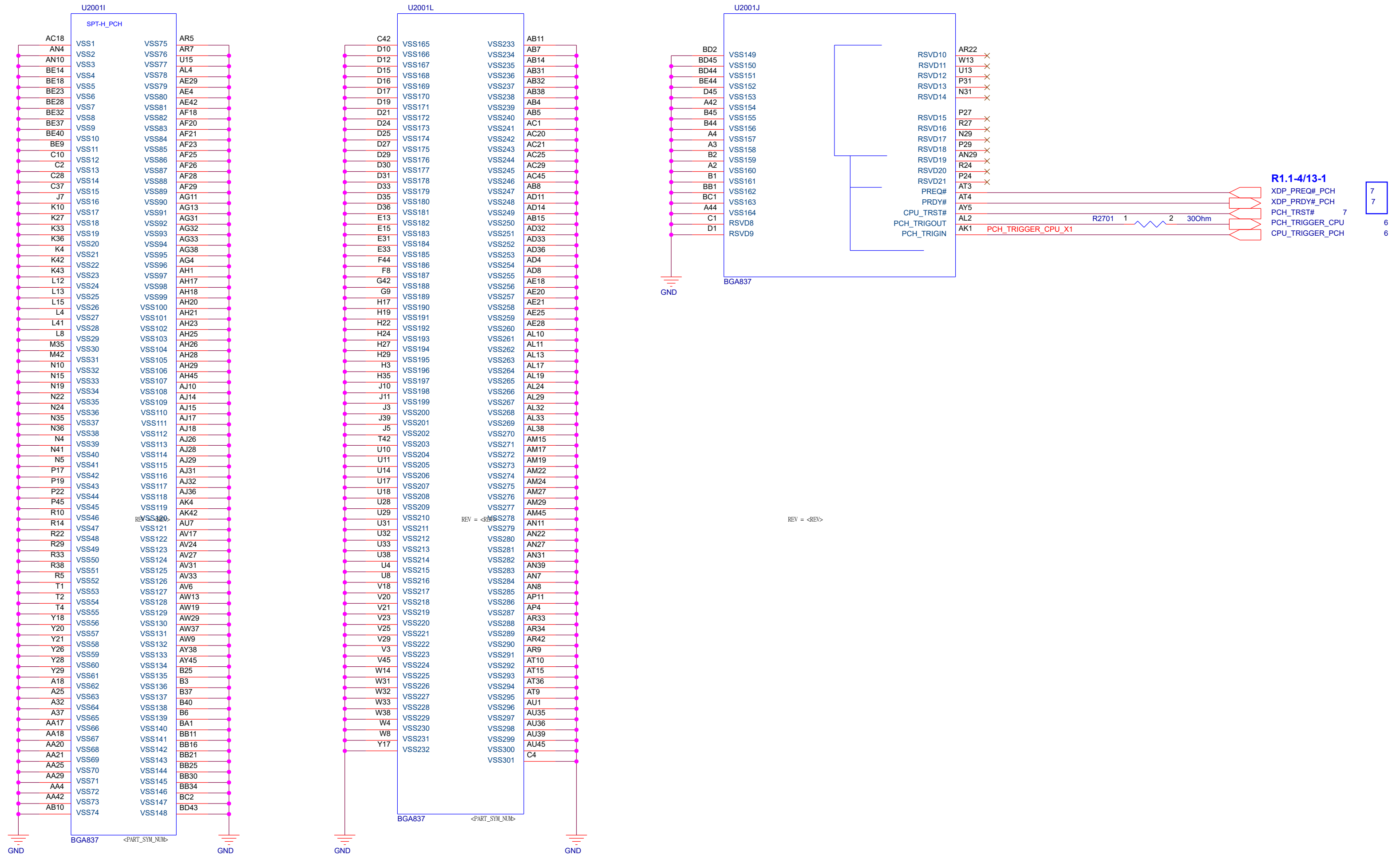
	Hynix (2Gb)	XXX (2Gb)	Micron (2Gb)	
DIMM_SEL0				
DIMM_SEL1				
DIMM_SEL2				

	HYNIX (4Gb) 03006-00011600 DDR3L 1600 512M*8 1.35V HYNIX/H5TC4083AFR-PBA	ELPIDA (4Gb)	Micron(4Gb) 03006-00011400 DDR3L 1600 512M*8 1.35V MICRON/MT41K512M8BH-123.E	
DIMM_SEL0	L		L	
DIMM_SEL1	L		L	
DIMM_SEL2	H		L	

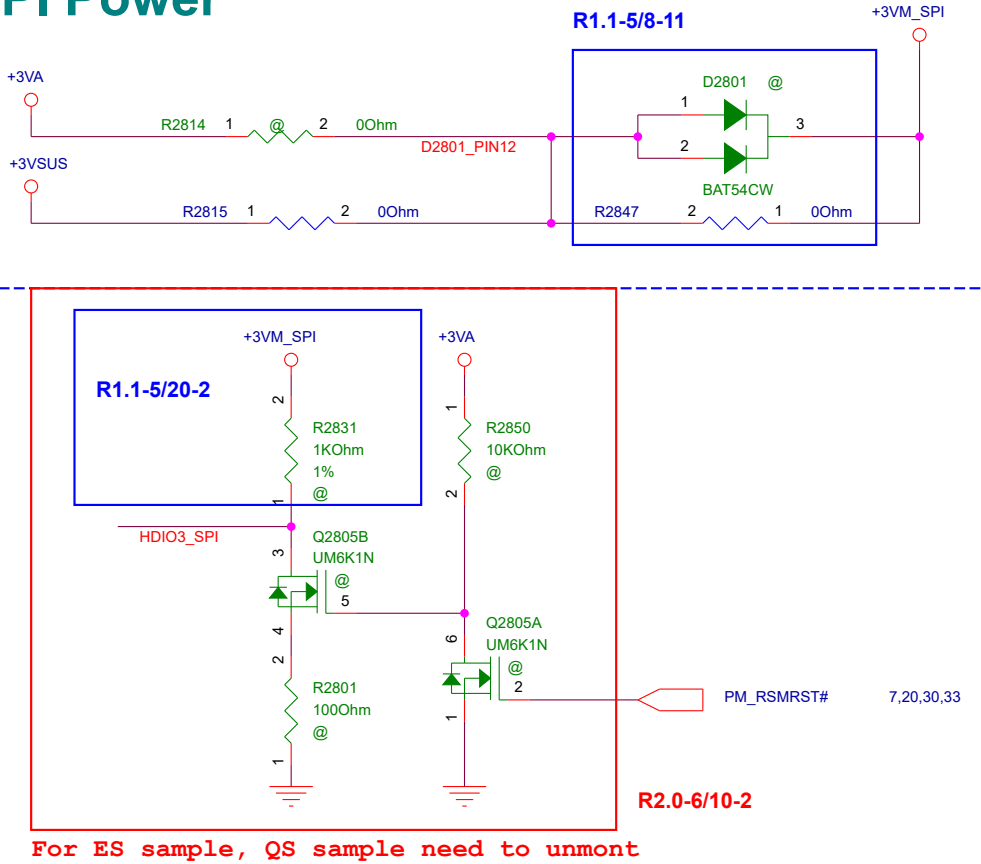




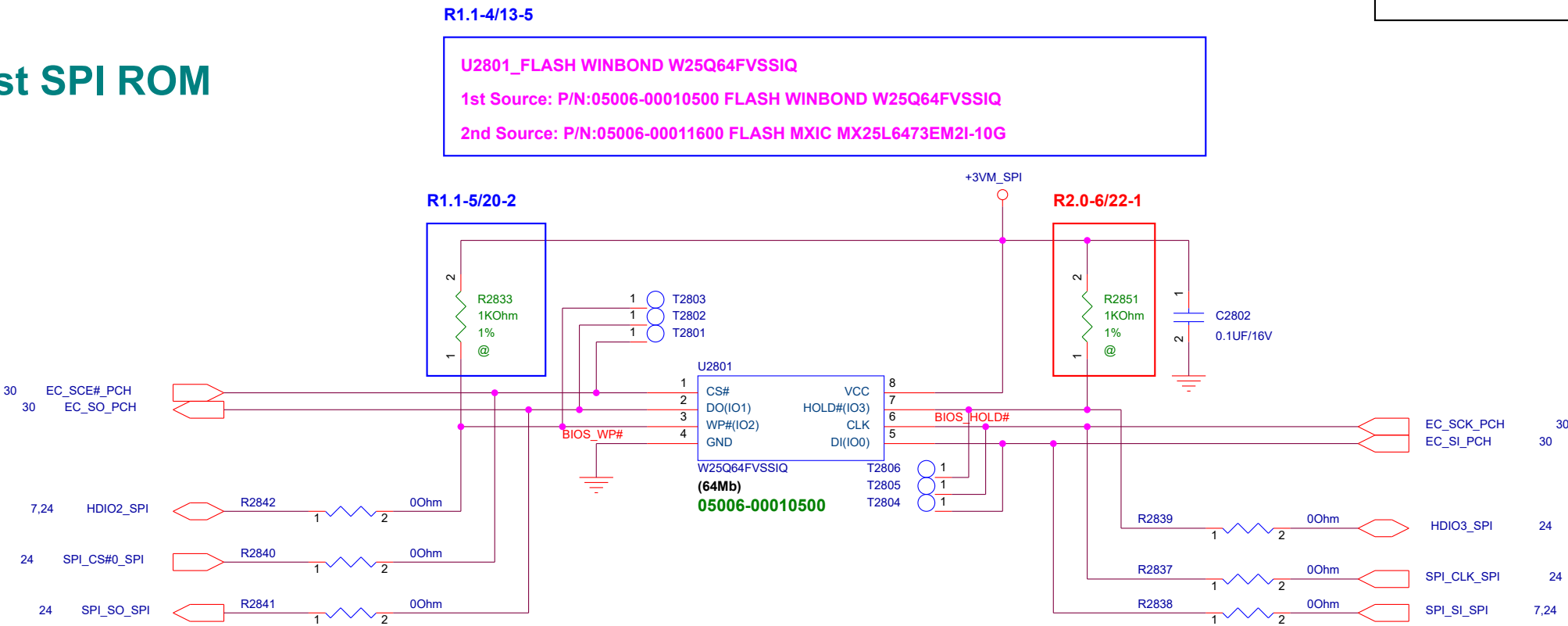
Main Board



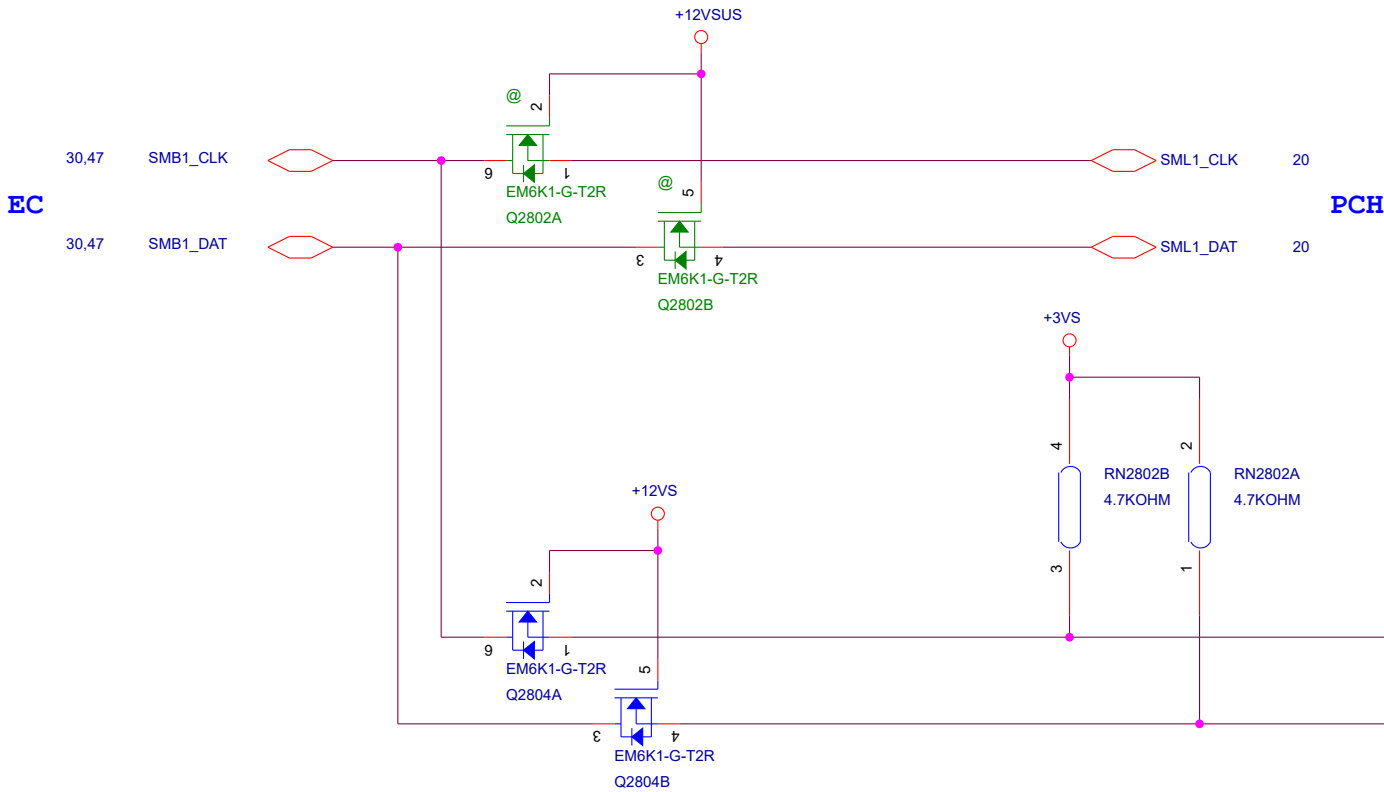
SPI Power



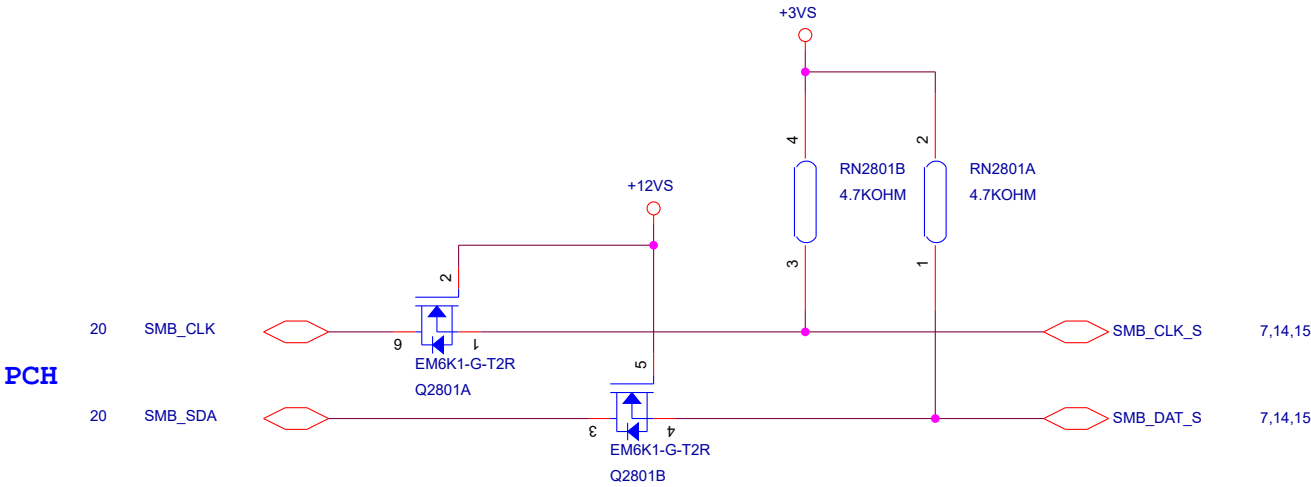
1st SPI ROM



System Management Interface



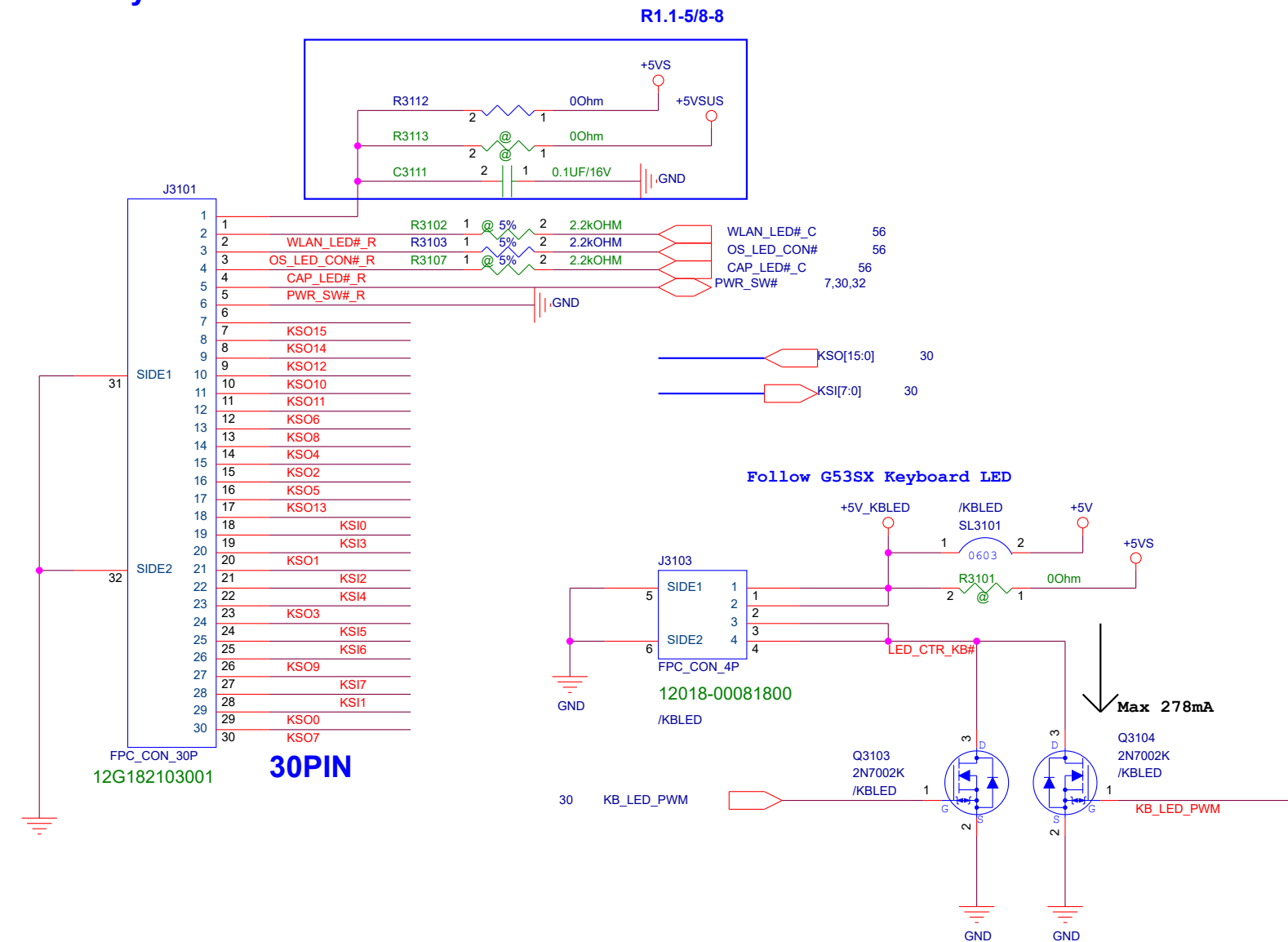
SMBus Interface



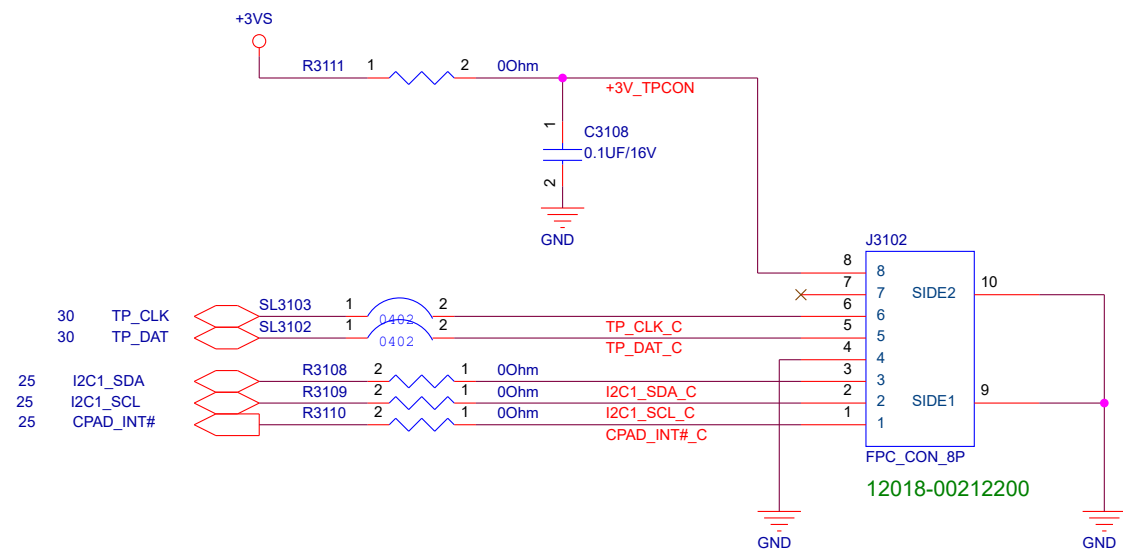
R2.0-6/9-3

CPU ,VGA & Power Thermal Sensor

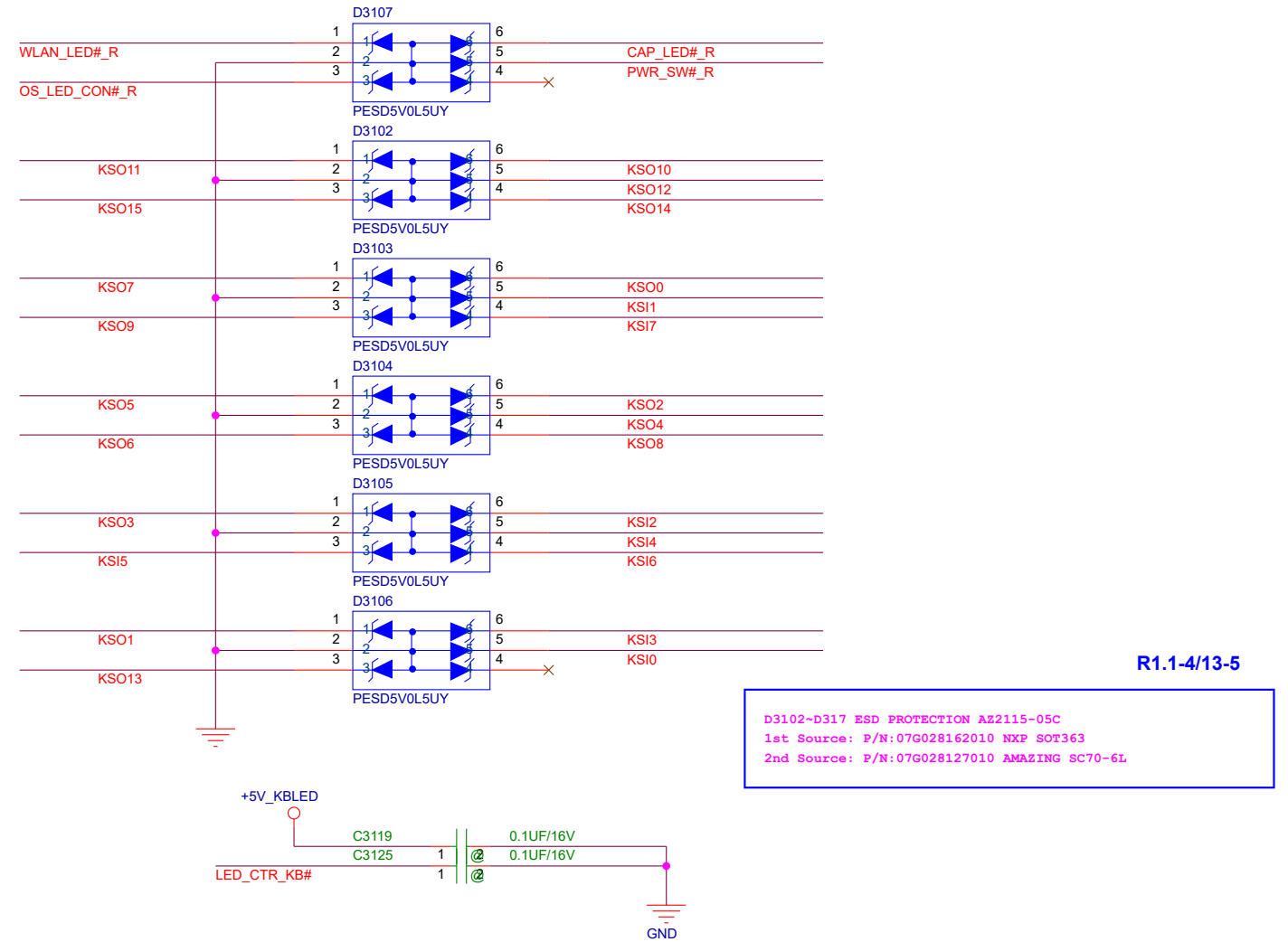
Keyboard Connector



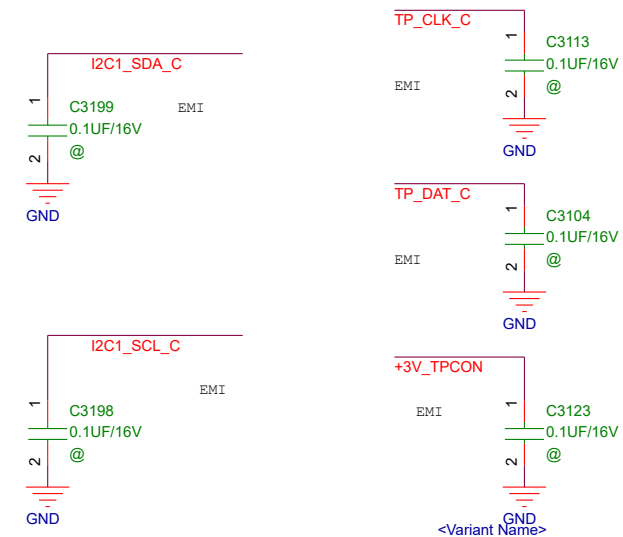
Click touch Pad Connector



For EMI

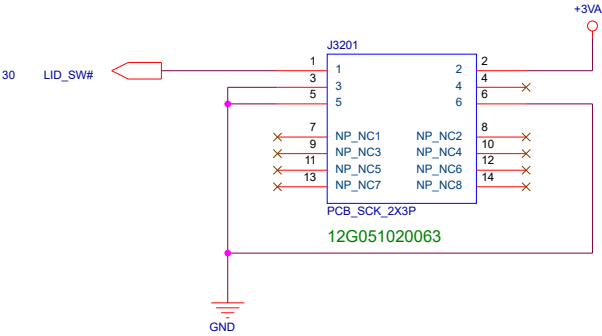
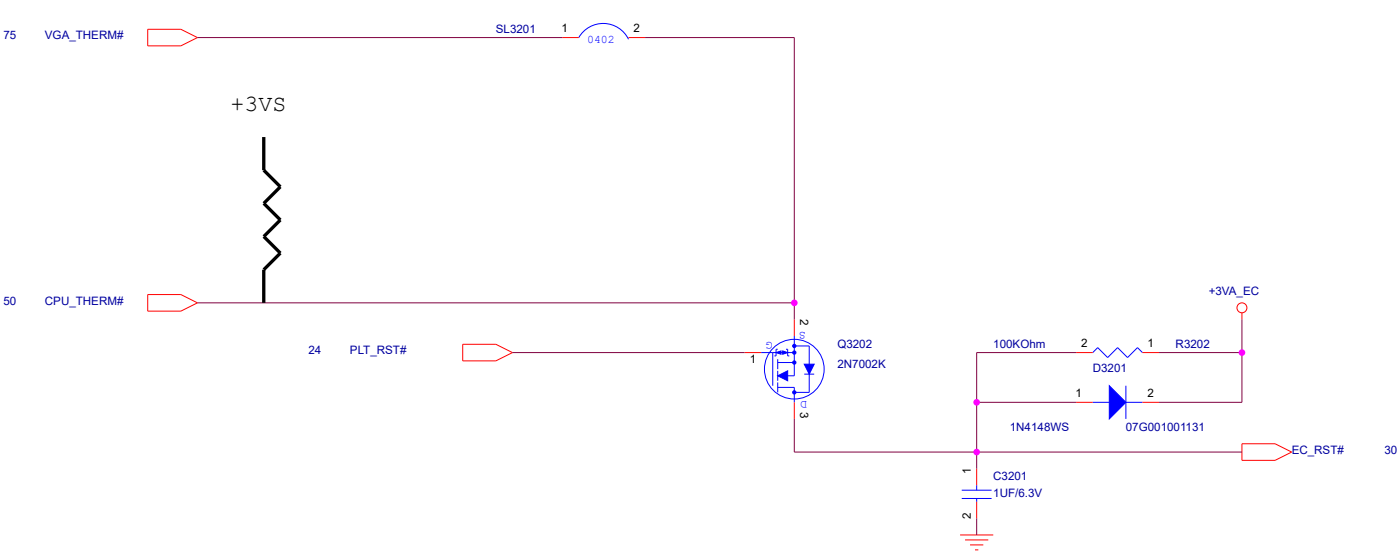


Reserved for EMI

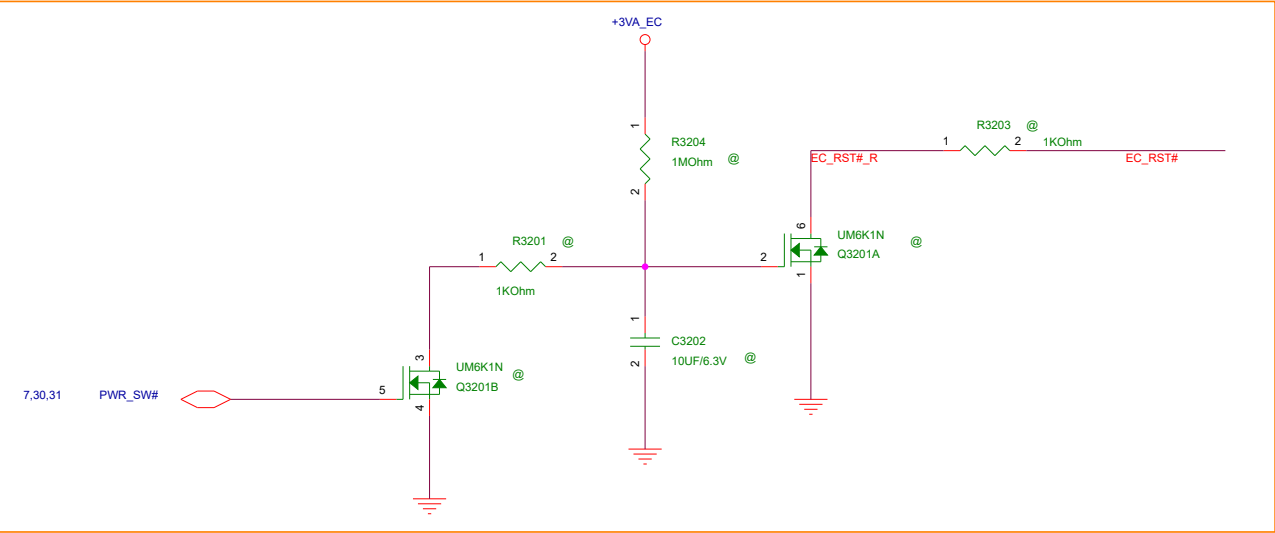


Reset Circuit

Pull up +3VSG through R7507(10kOhm=>100kOhm)
When +3VSG ready, R7507(10kOhm) and R5006(7.5kOhm) will be in parelle.
The CPU temperature point is protected ahead of time.
Increasing R7507 value can reduce to affect R5006.



For battery embedded case (press pwr_sw 10sec, then reset ec) (need to modify)



<Variant Name>

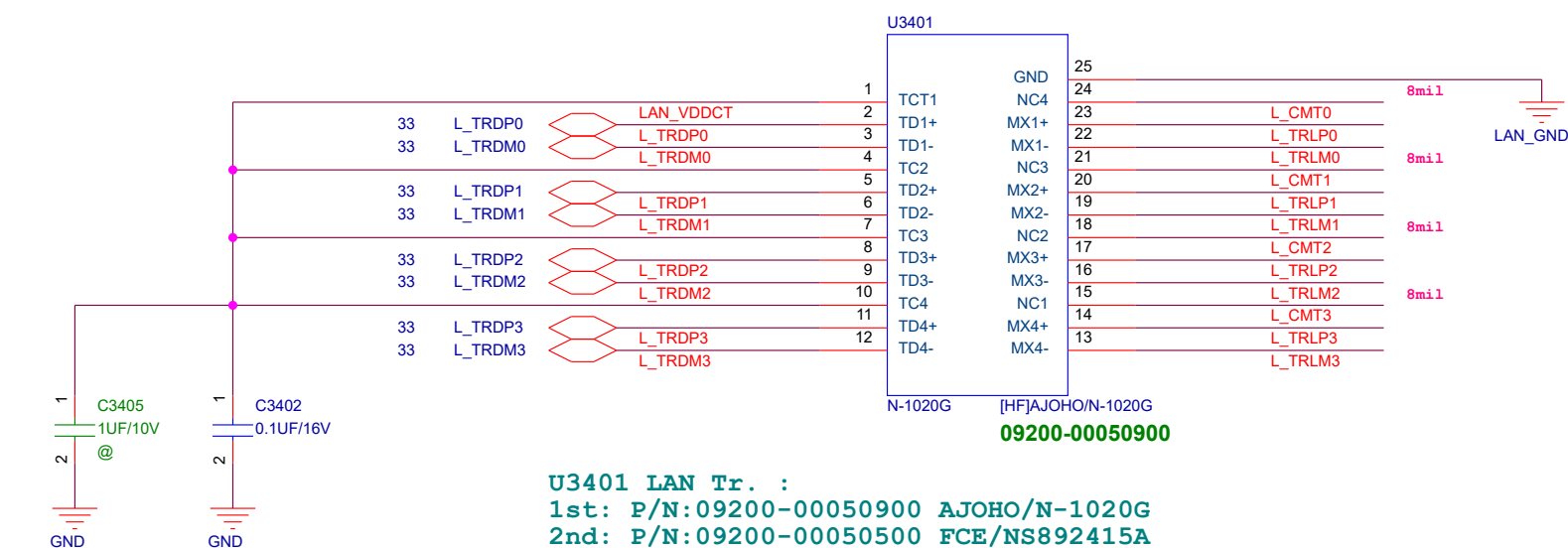
ASUS®		Title : RST_Reset Circuit	
ASUSTeK COMPUTER INC. NB1		Engineer: Mario_Jhu	
Size B	Project Name GL552VW		Rev 2.0
Date: Tuesday, June 23, 2015		Sheet 32 of 103	

R1.1-4/13-5

D3401,D3402 ESD Diode

1st Source: P/N:07024-00200200 AMAZING/AZC099-04SP.R7G

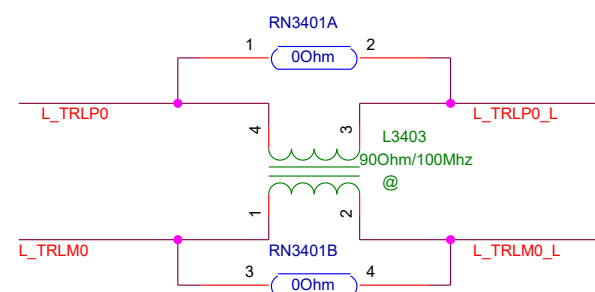
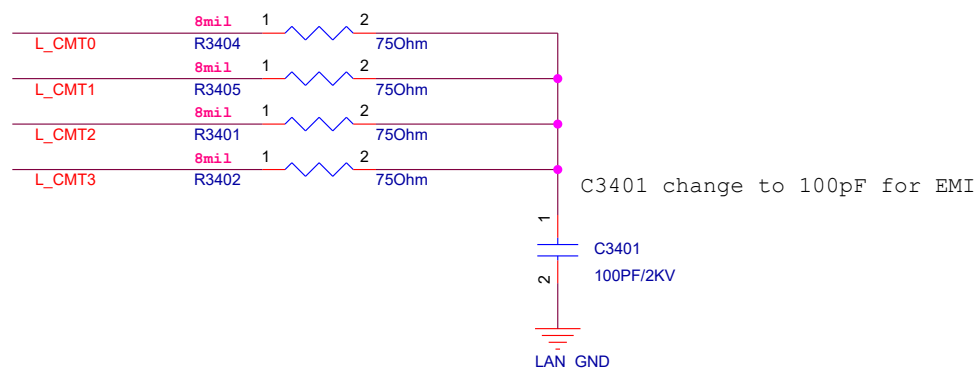
2nd Source: P/N:07024-00710000 NXP/PUSB2X4D



U3401 LAN Tr. :
1st: P/N:09200-00050900 AJOHO/N-1020G
2nd: P/N:09200-00050500 FCE/NS892415A
3rd: P/N:09G051059A20 BOTHHAND/GST5009BMLF

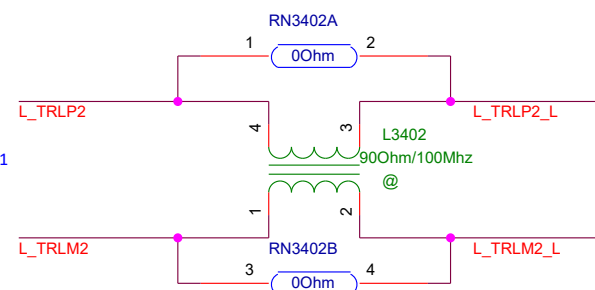
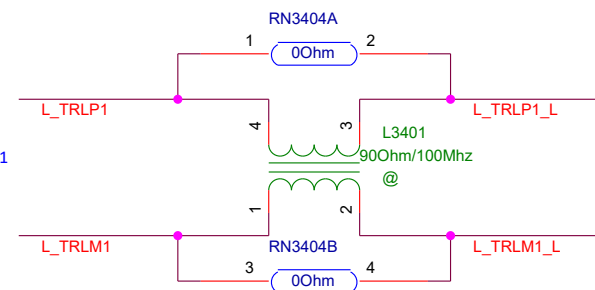
Test Point_LAN Tr.

拿掉ATE測點, 改由layout主動加

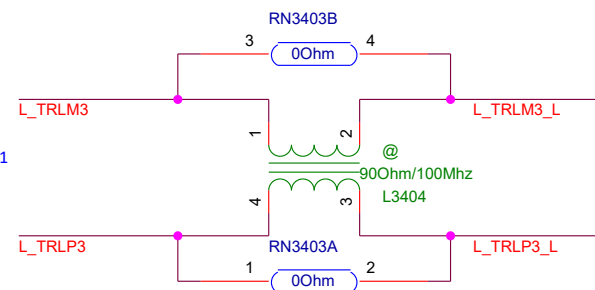


R1.0-5

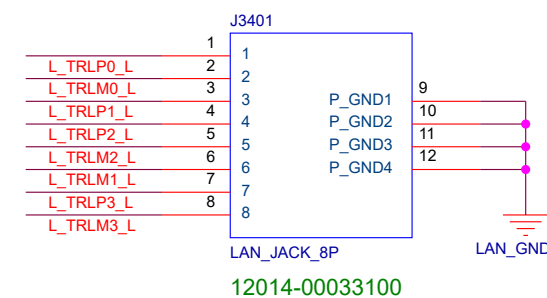
SWAP 20140211



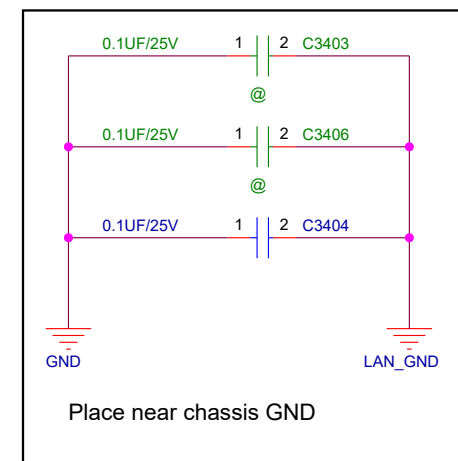
SWAP 20140211



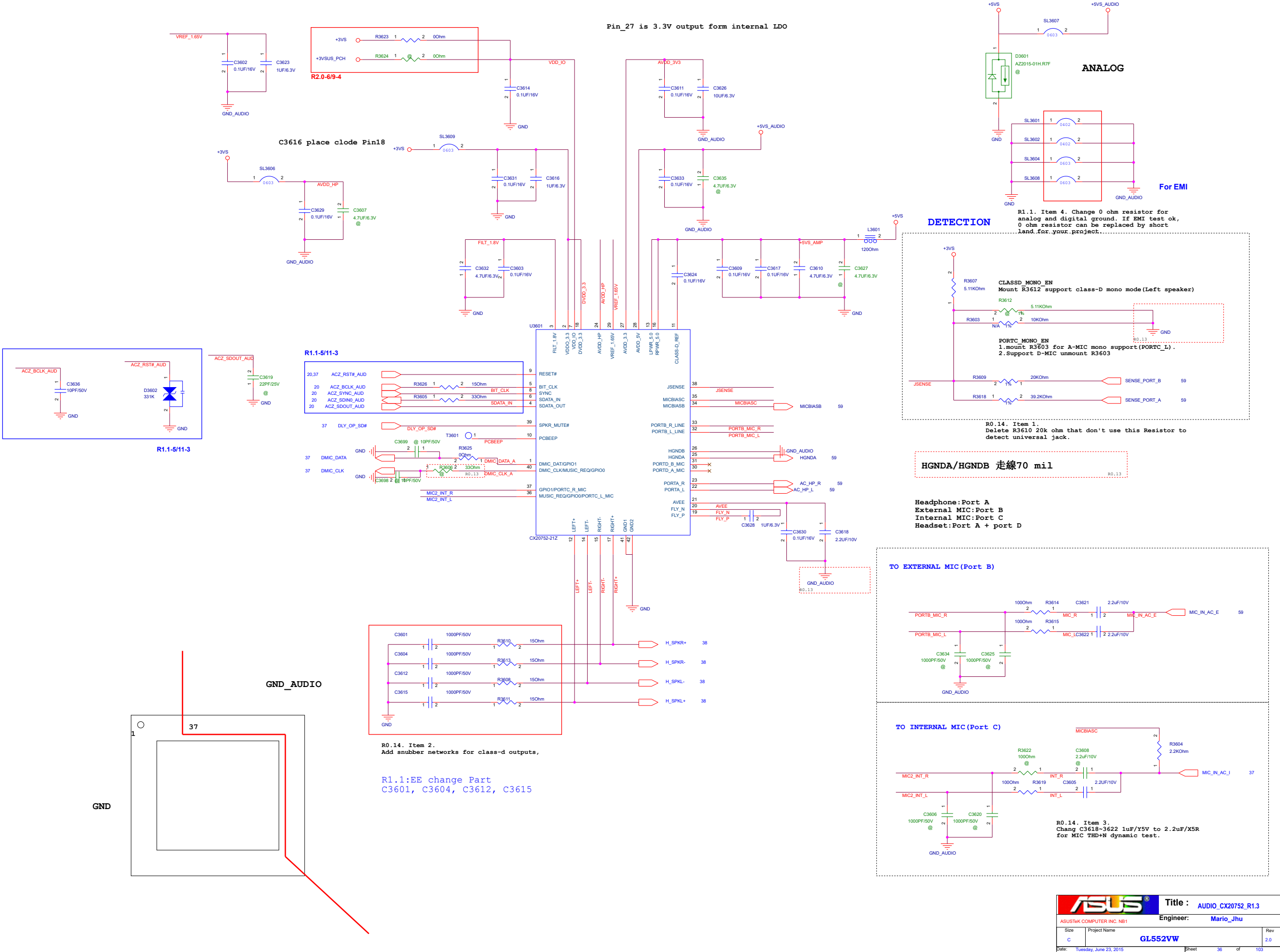
SWAP 20140211



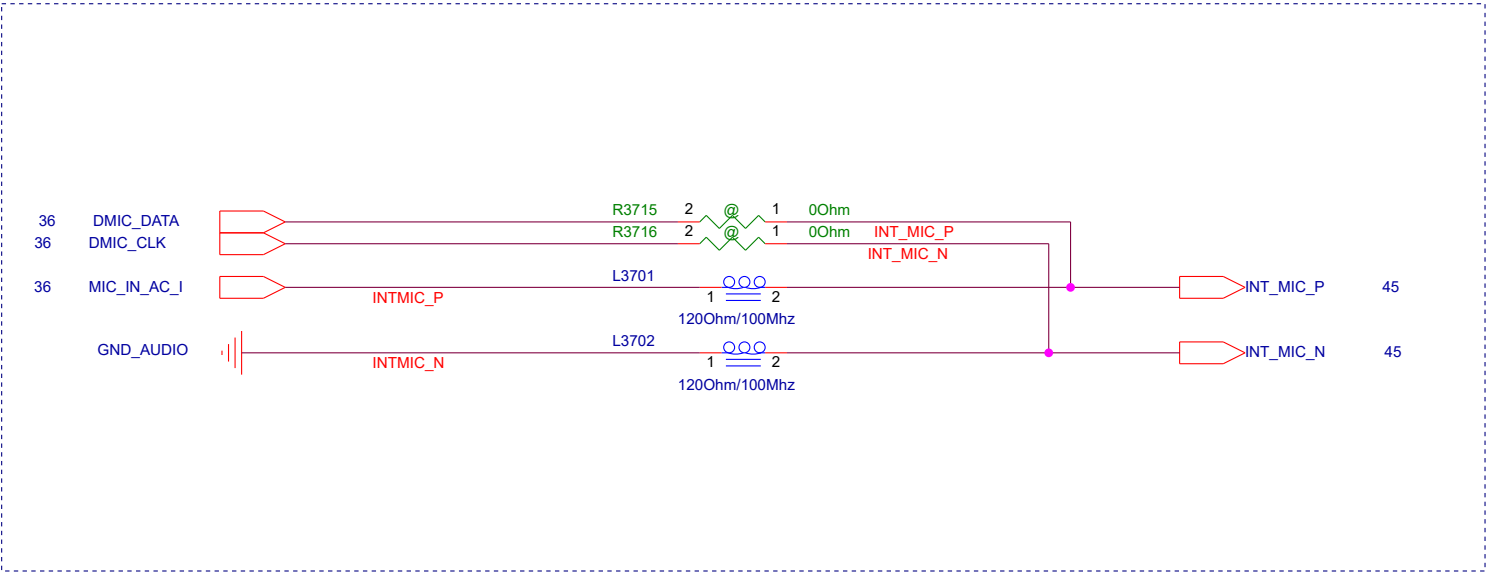
Change GND TO LAN GND FOR EMI



<Variant Name>

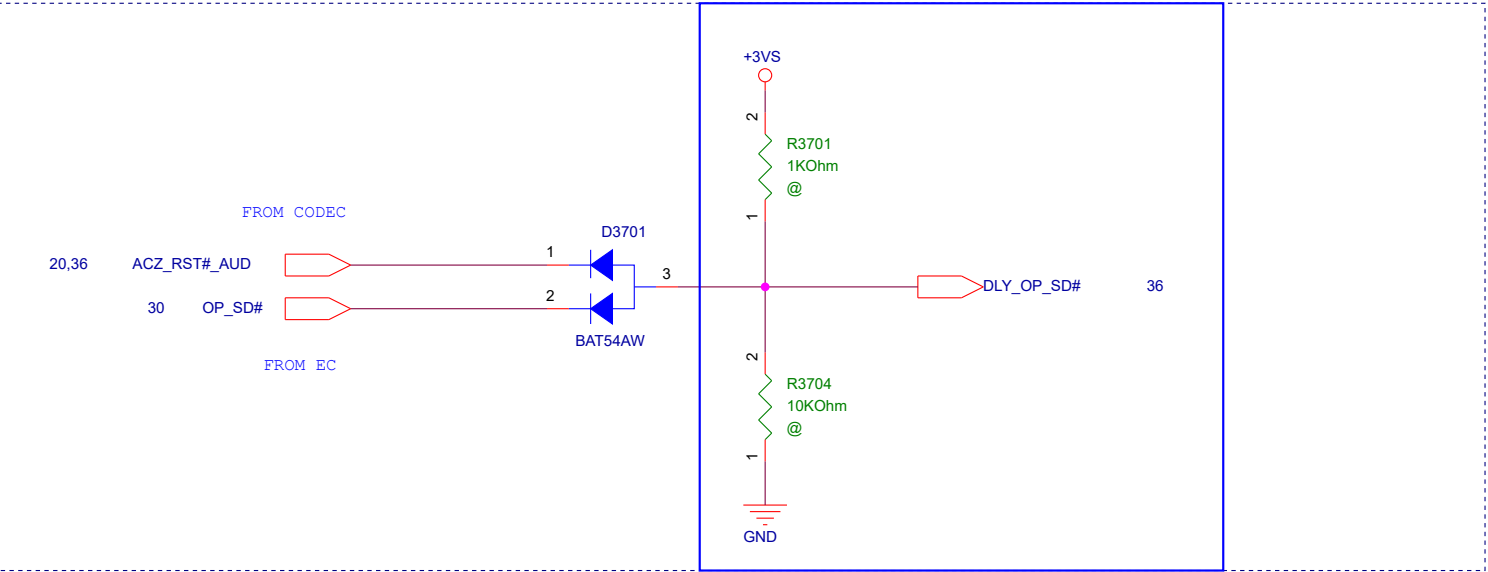


INTERNAL MICROPHONE

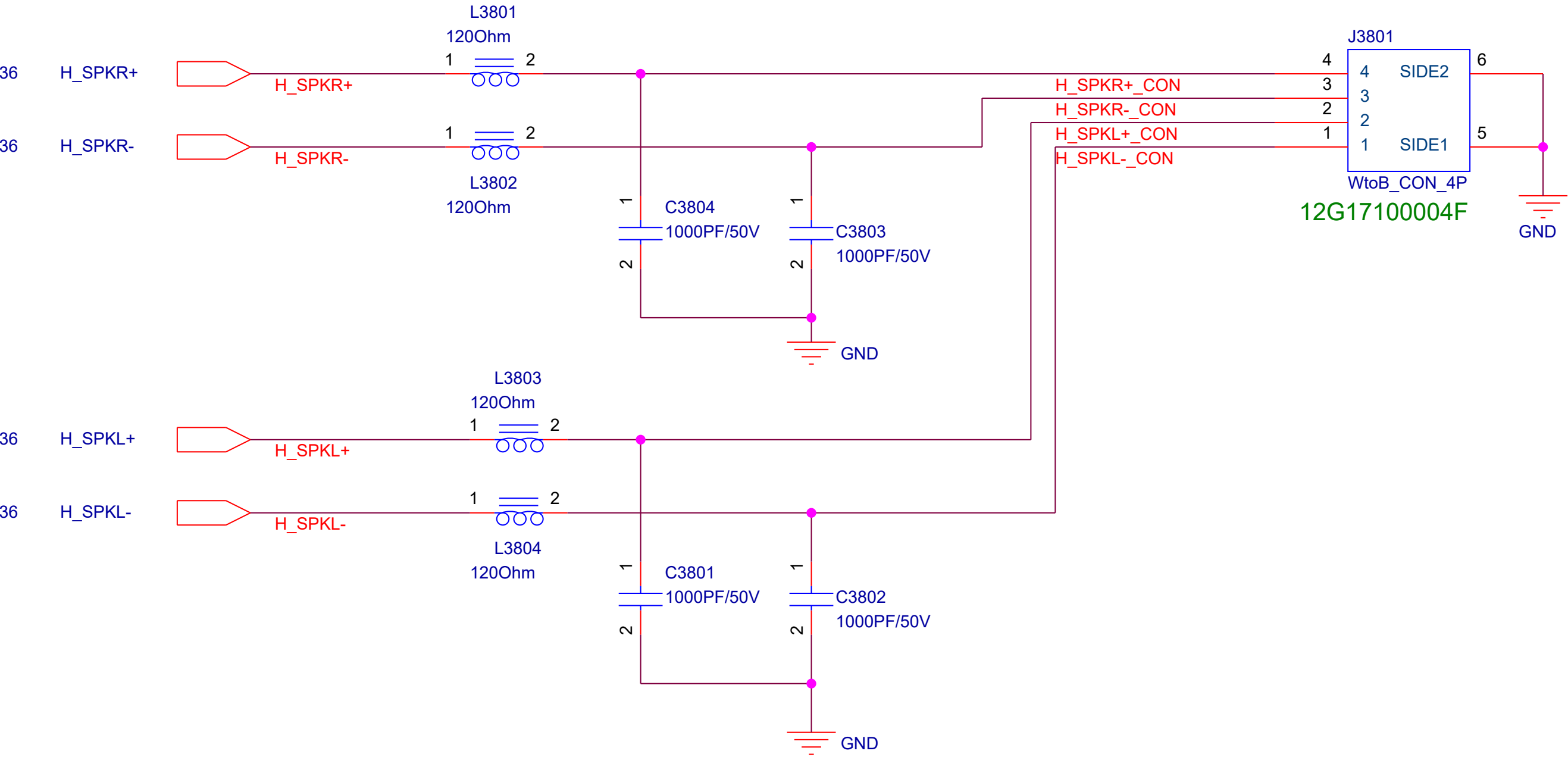


MUTE CONTROL

R1.1-5/12-9



Mount C3801~C3804 and change SL to
L3801~L3804 in ER 20141121



Title : AUD-MIC-IN_R1.4

ASUSTeK COMPUTER INC. NB1

Engineer: Mario_Jhu

Size

Project Name

Rev

A

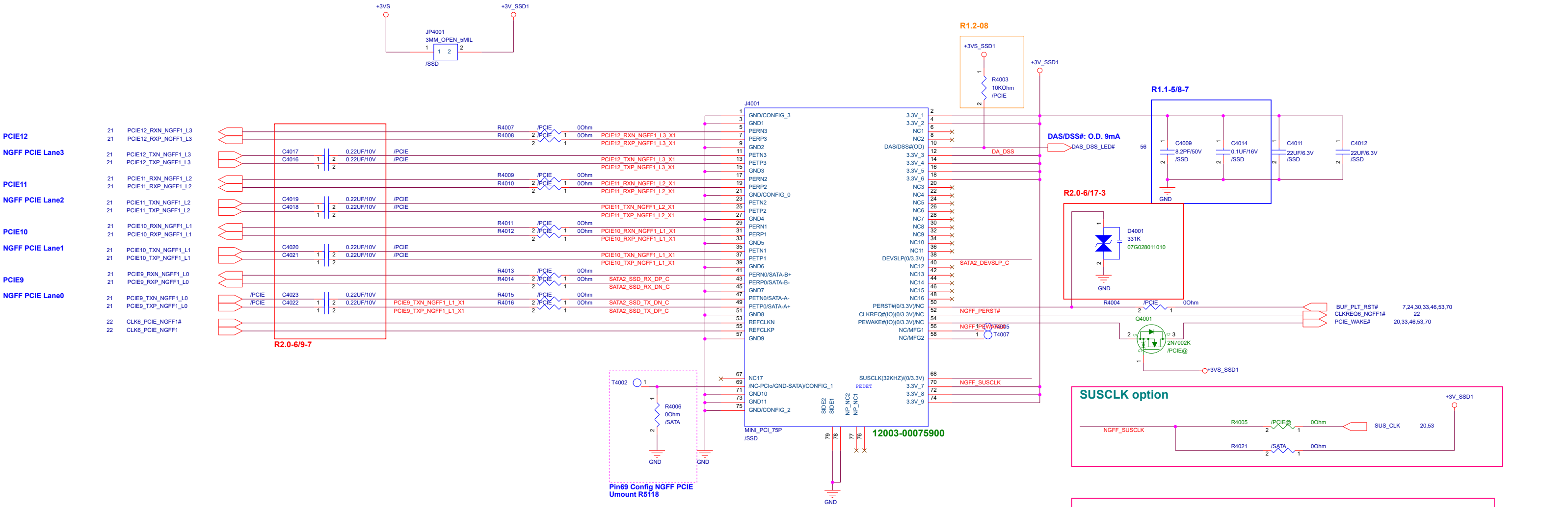
GL552VW

2.0

Date: Tuesday, June 23, 2015

Sheet 38 of 103

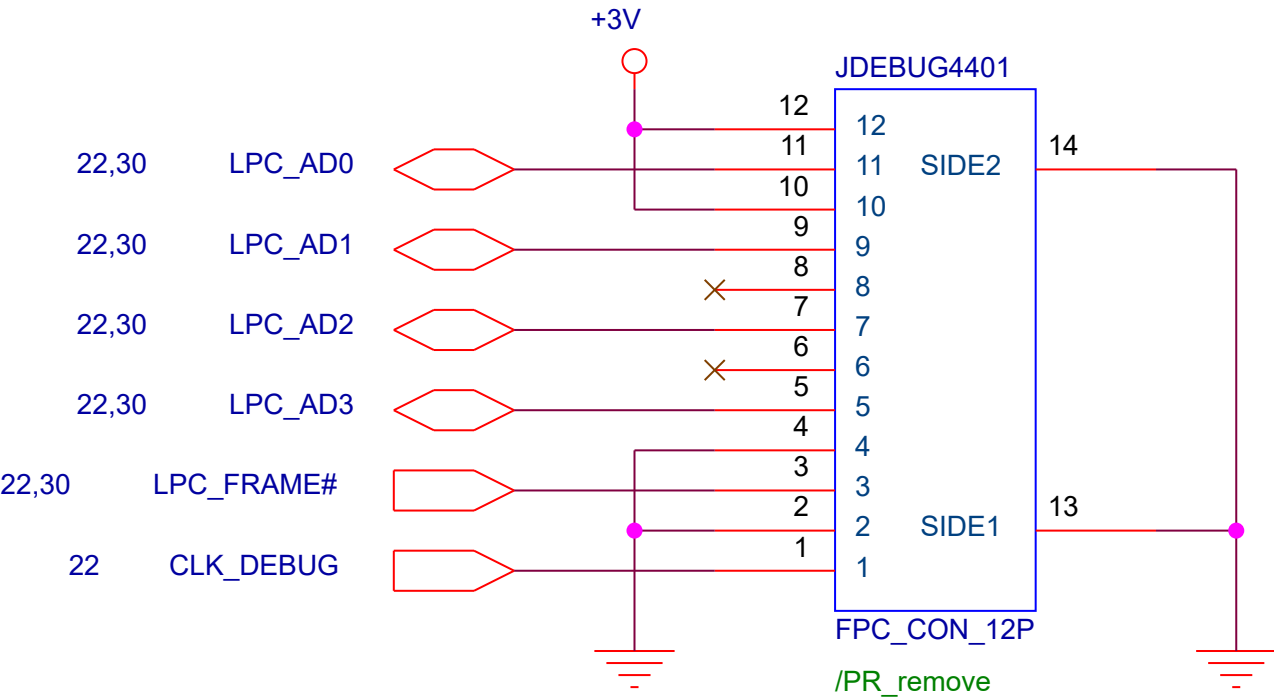
NGFF_SSD



HW Disable SSD Devslp	Mount R4002=0ohm, Unmount R4001=0ohm
HW Enable SSD Devslp	Unmount R4002=0ohm, Mount R4001=0ohm

<Variant Name>

LPC Debug Port



R1.1-4/13-5

JDEBUG4401 Connector (MP USE)

1st Source: P/N:12018-00102400 P-TWO/196479-12041-3

2nd Source: P/N:12018-00102100 ENTERY/6705K-Y12N-00L

3rd Source: P/N:12018-00102300 ACES/51578-01201-001


R1.1-4/13-5

JDEBUG4401 Connector (NPI USE)

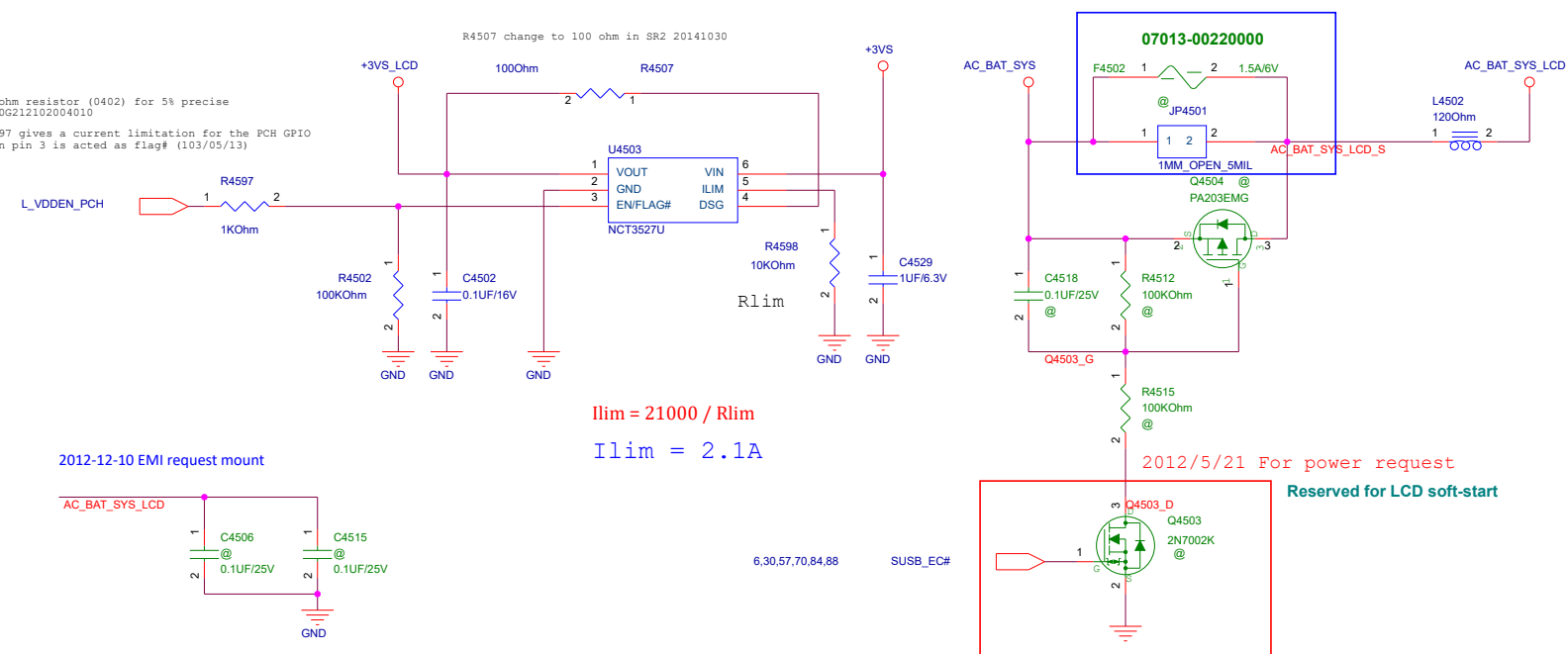
1st Source: P/N:12018-00102900 ENTERY/6705K-Y12N-20L

2nd Source: P/N:12018-00103000 ACES/51578-01201-002

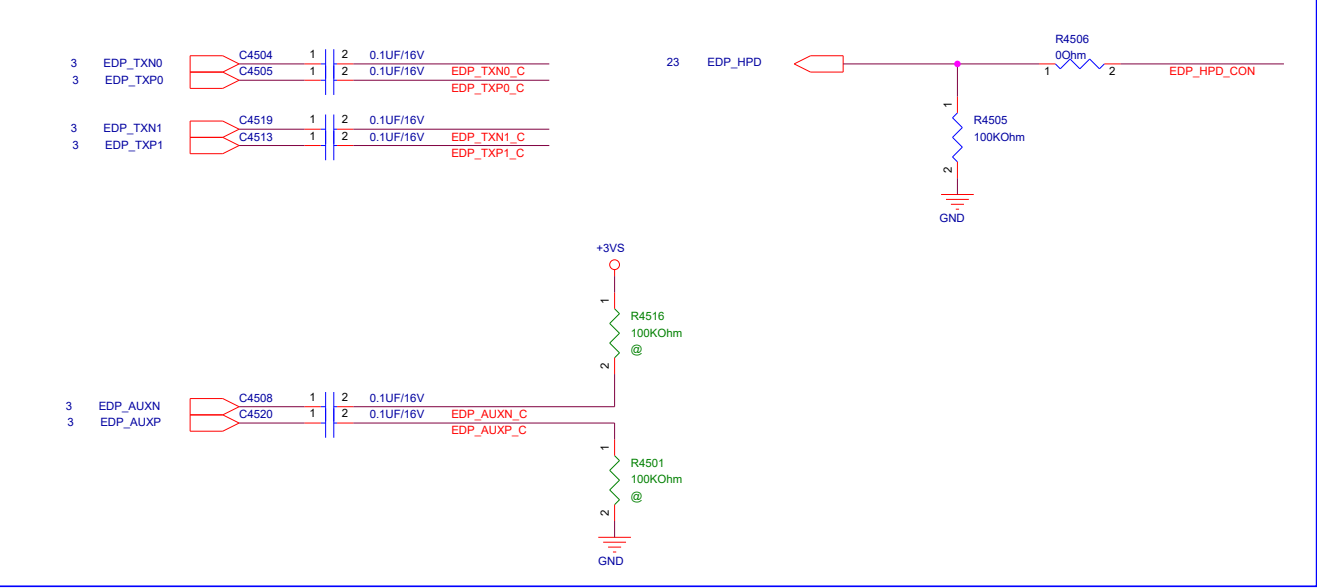
<Variant Name>

		Title : DEBUG_LPC	
ASUSTeK COMPUTER INC. NB1		Engineer: Mario_Jhu	
Size A	Project Name GL552VW		Rev 2.0
Date: Tuesday, June 23, 2015	Sheet 44 of 103		

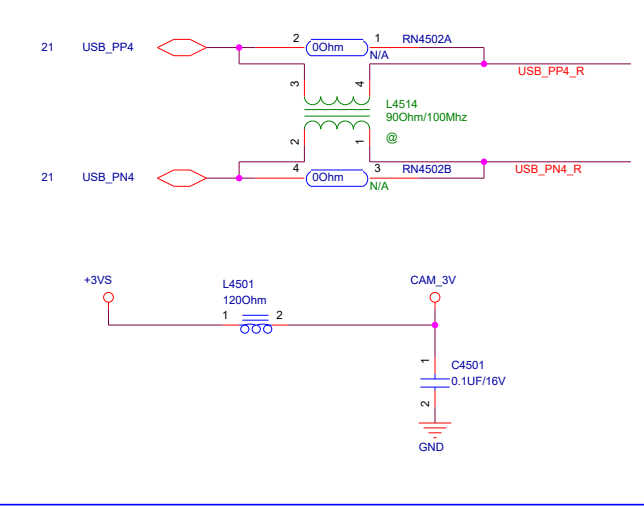
LCD Power switch



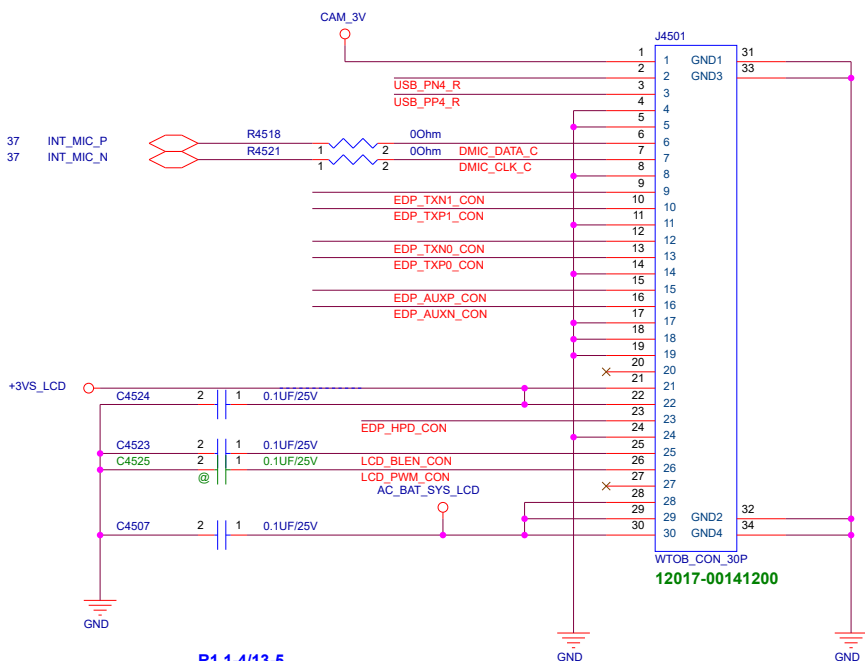
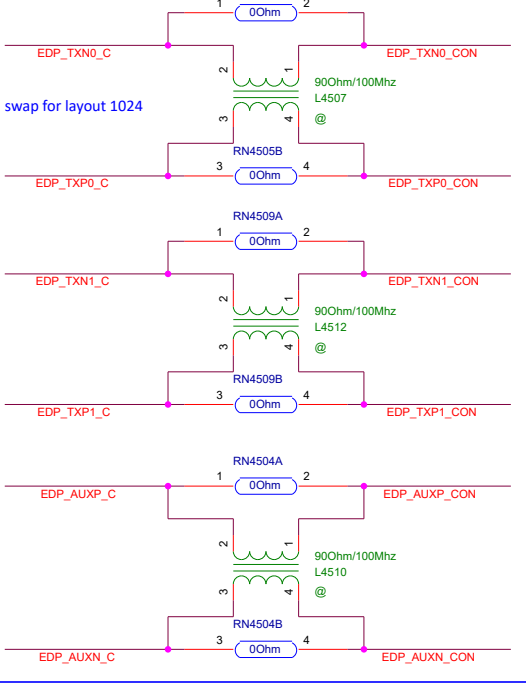
eDP from CPU



Camera module



For EMI



R1.1-4/13-5

J4501 WtoB CON 30P 0.5MM 1.0H RA SMT

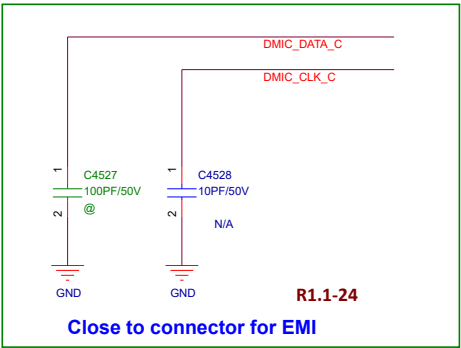
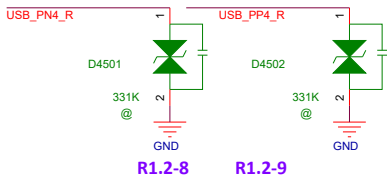
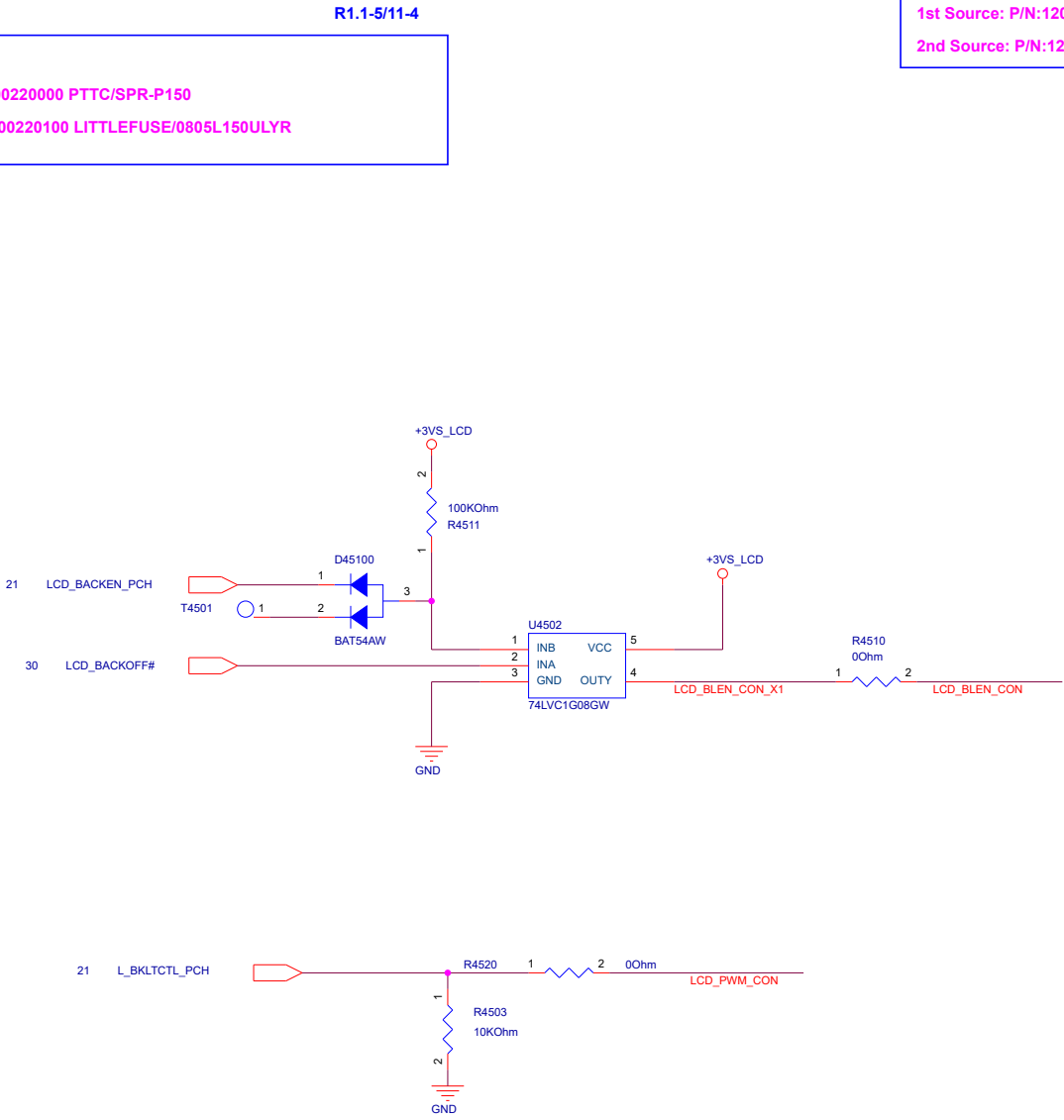
1st Source: P/N:12017-00141200 STARCONN/300E30-0010RA-G3

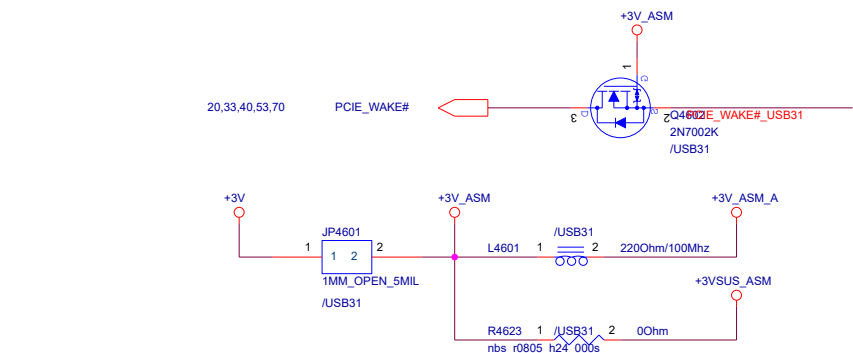
2nd Source: P/N:12017-00141100 ACES/51473-0300M-001

F4502 Poly Fuse

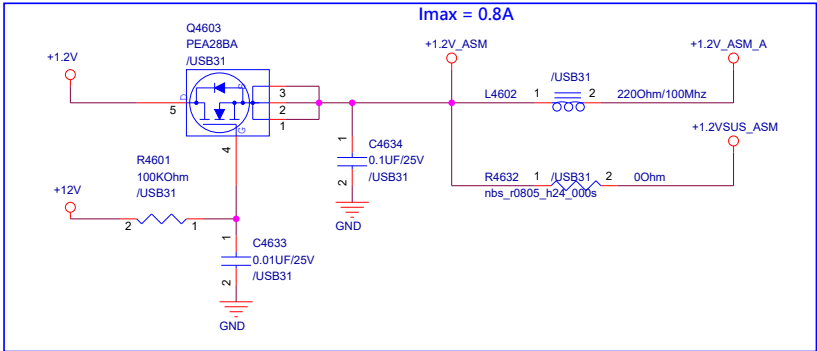
1st Source: P/N:07013-00220000 PTTC/SPR-P150

2nd Source: P/N:07013-00220100 LITTLEFUSE/0805L150ULYR

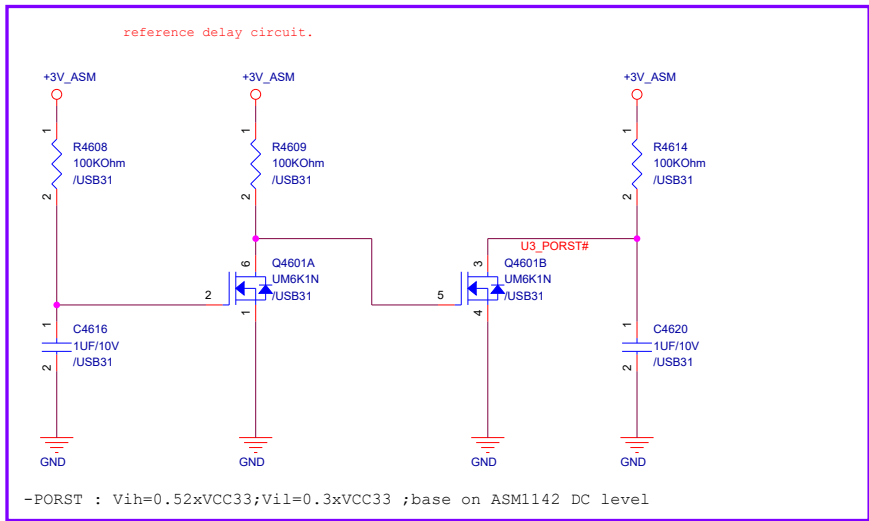
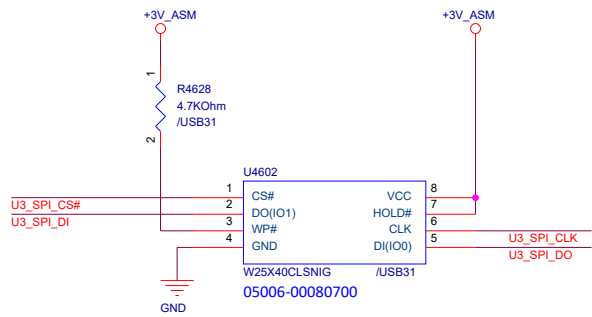




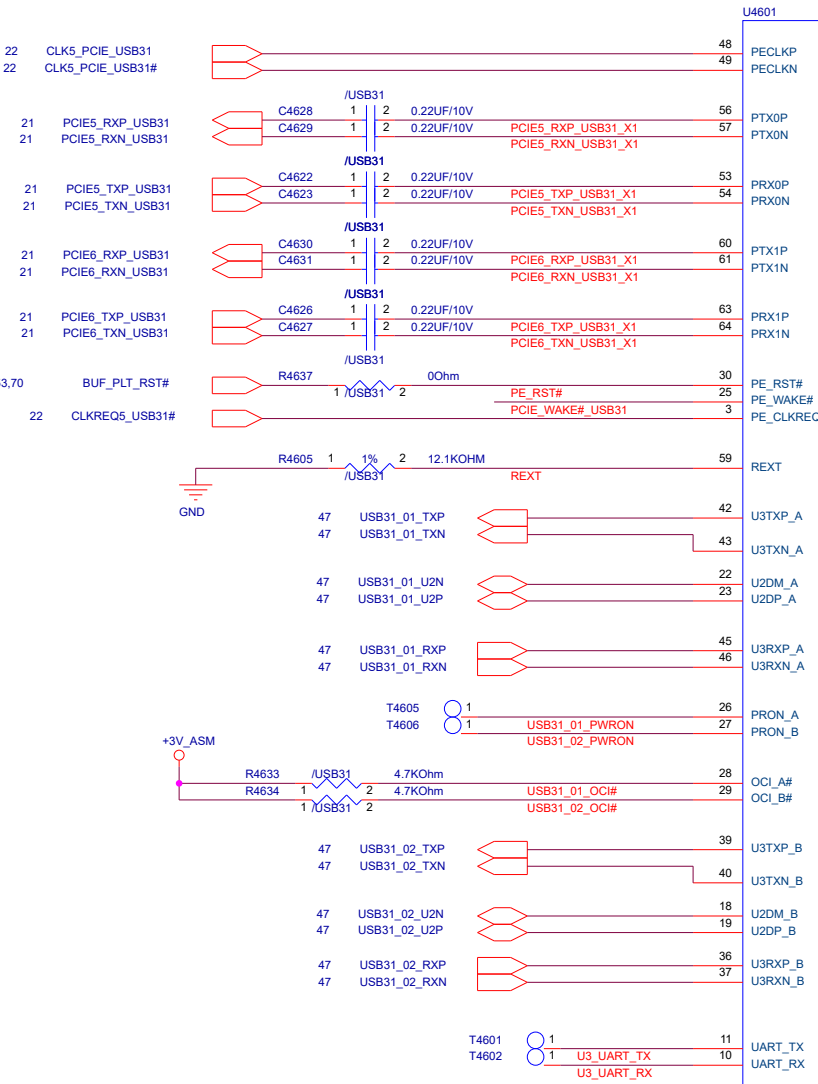
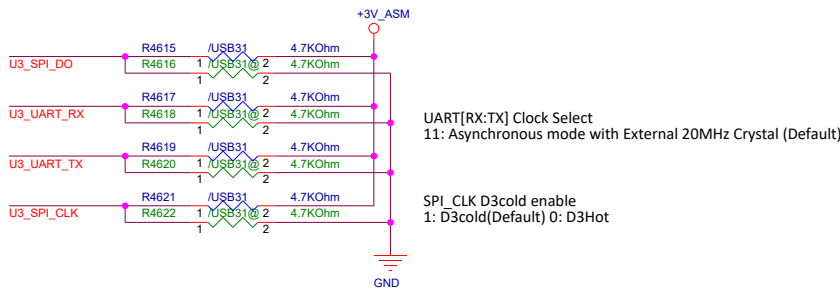
R1.1-5/12-3



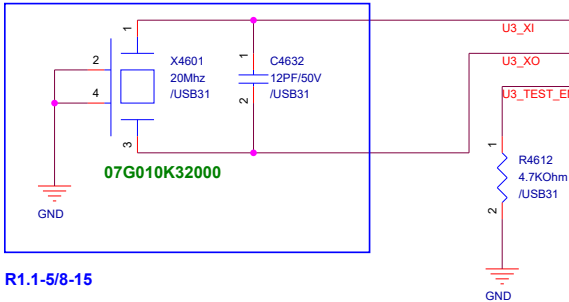
CLKREQ 目前ASM1142不支持
， 在PCH做PD



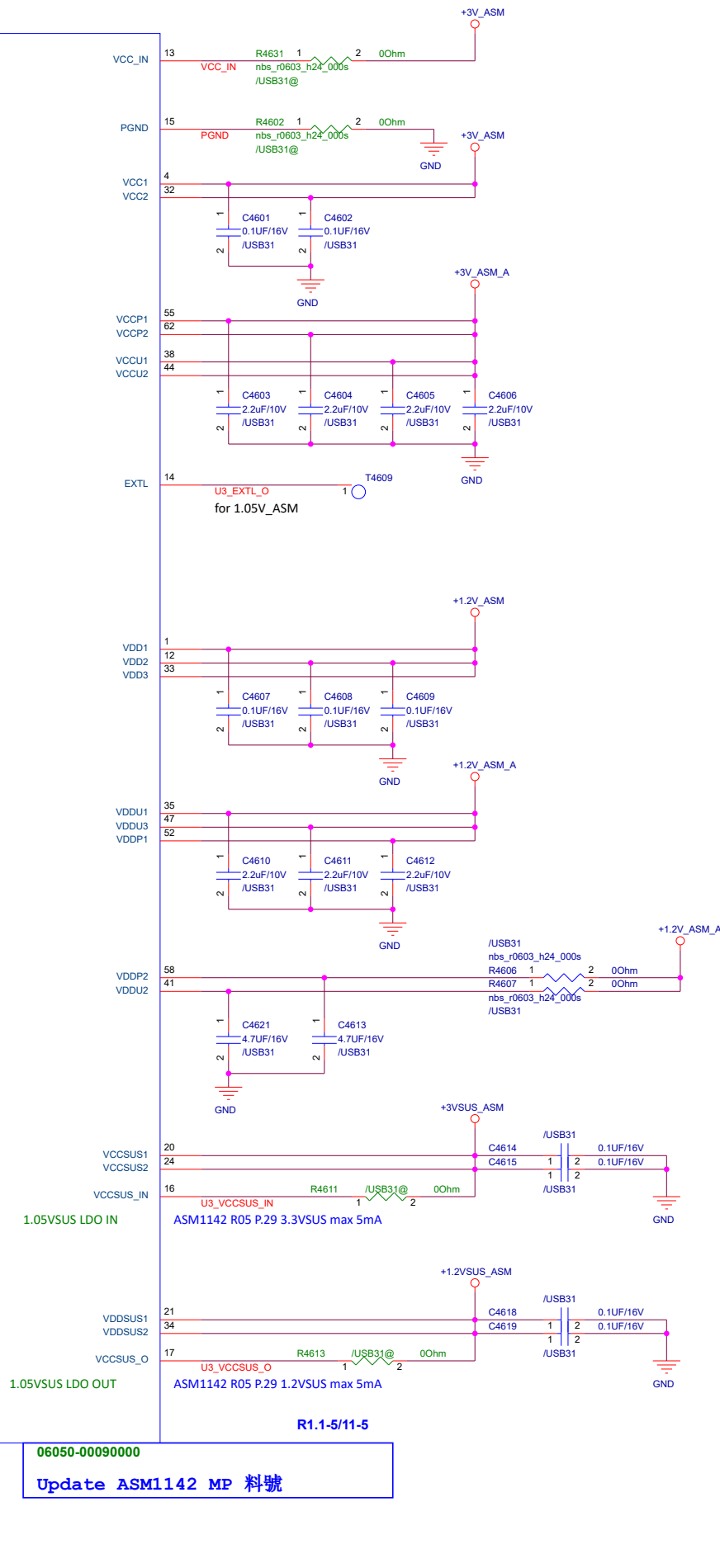
H/W Strapping



For USB3.1 Legacy support



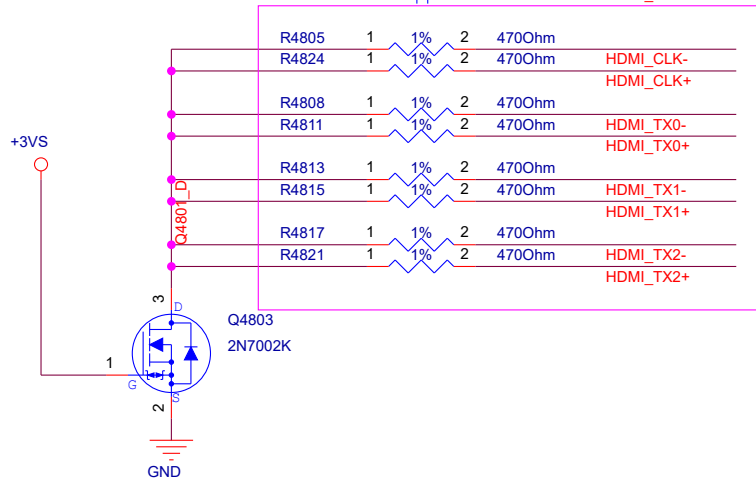
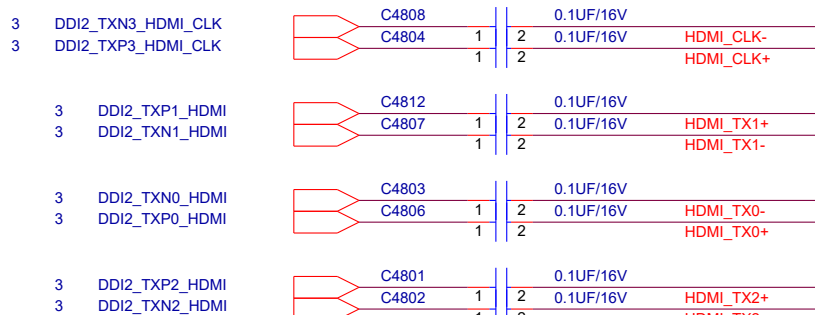
R1.1-5/8-15



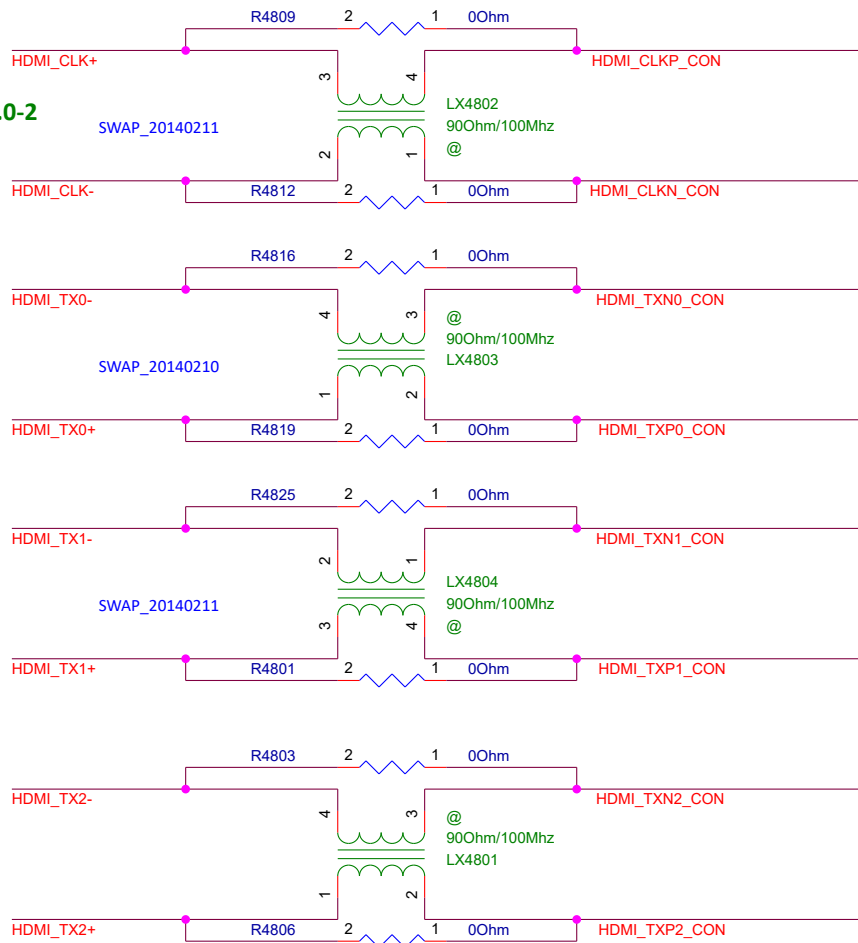
X4602 ASM 確認用料

07G010K32000	XTAL 20MHZ SMD 16PF/10PPM//SIWARD/XTL571100-G47-085	Siward	希華
07G010242000	XTAL 20MHZ 3.2*2.5 16PF/10PPM//TXC/7M20000061	TXC	台灣晶技
07009-00080800	XTAL 20MHZ SMD 16PF/10PPM SKCTECH//FSK3M200000M161	SKC	鑫谷

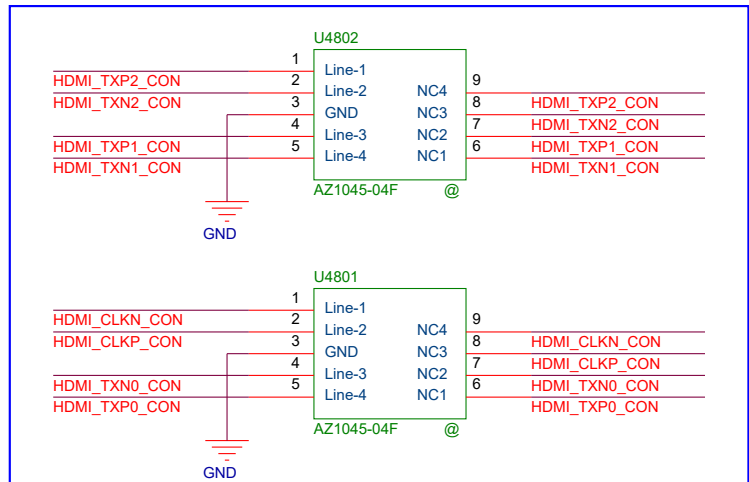
CPU DDIC



R1.0-2



R1.1-17

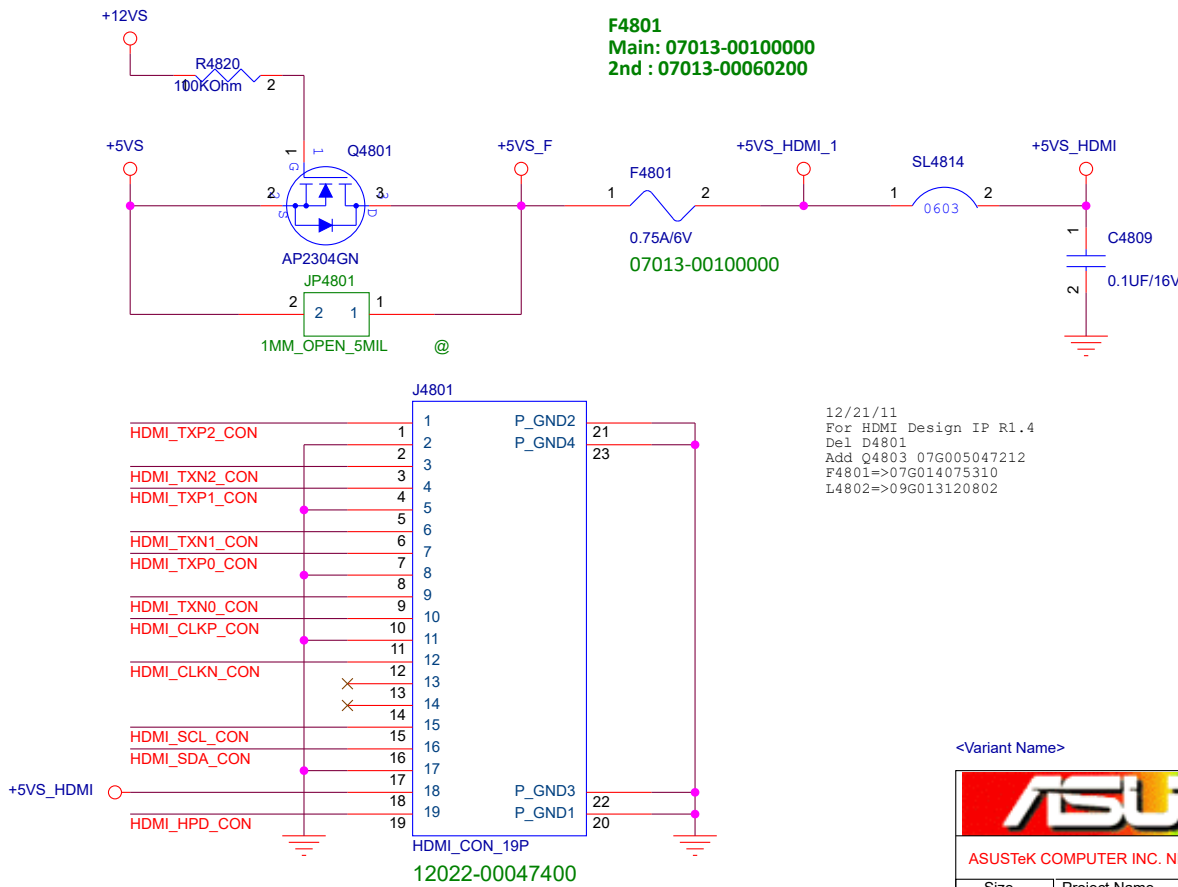
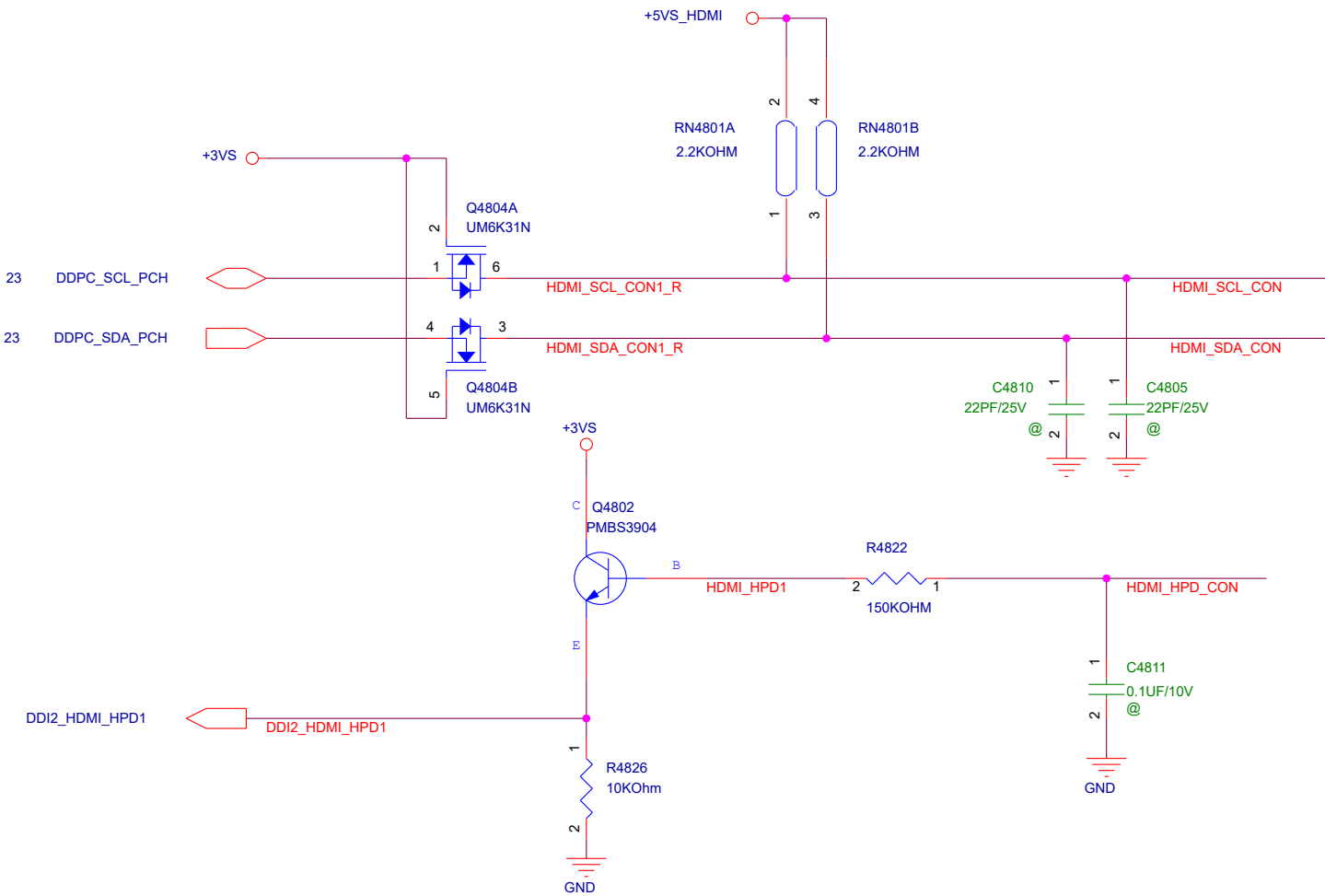


U4801 & U4802 ESD PROTECTION

1st Source: P/N:07G028076030 ESD PROTECTION AZ1045-04F

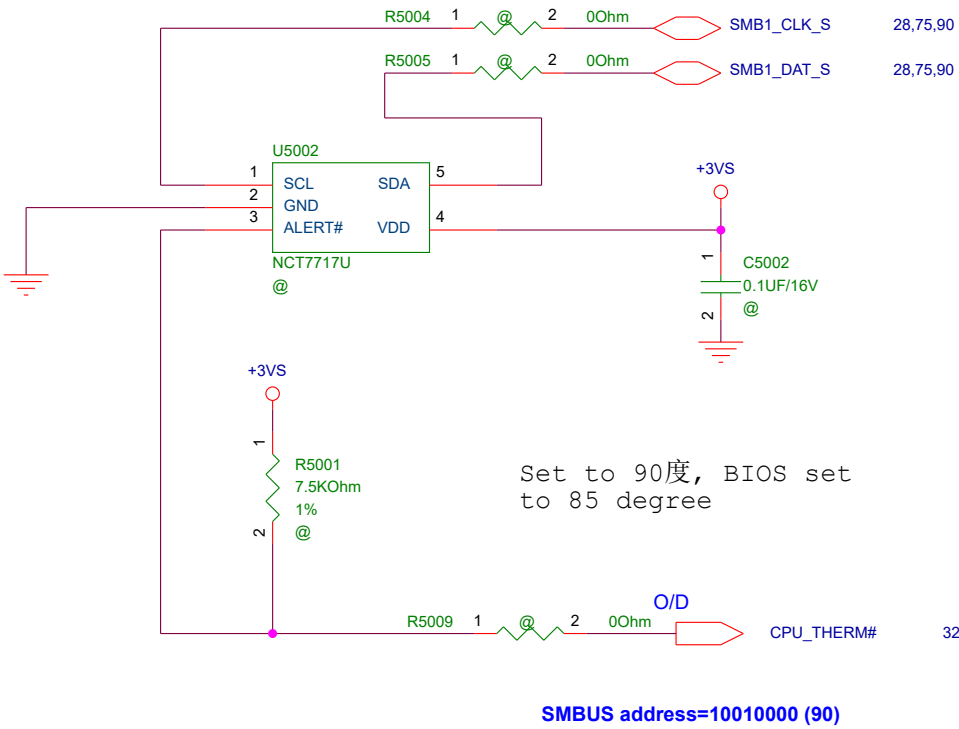
2nd Source: P/N:07G028153010 ESD PROTECTION IP4284CZ10-TB

R1.1-4/13-5

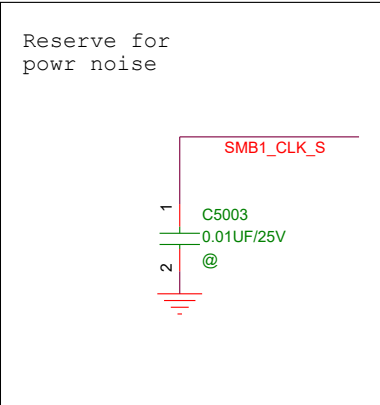


<Variant Name>

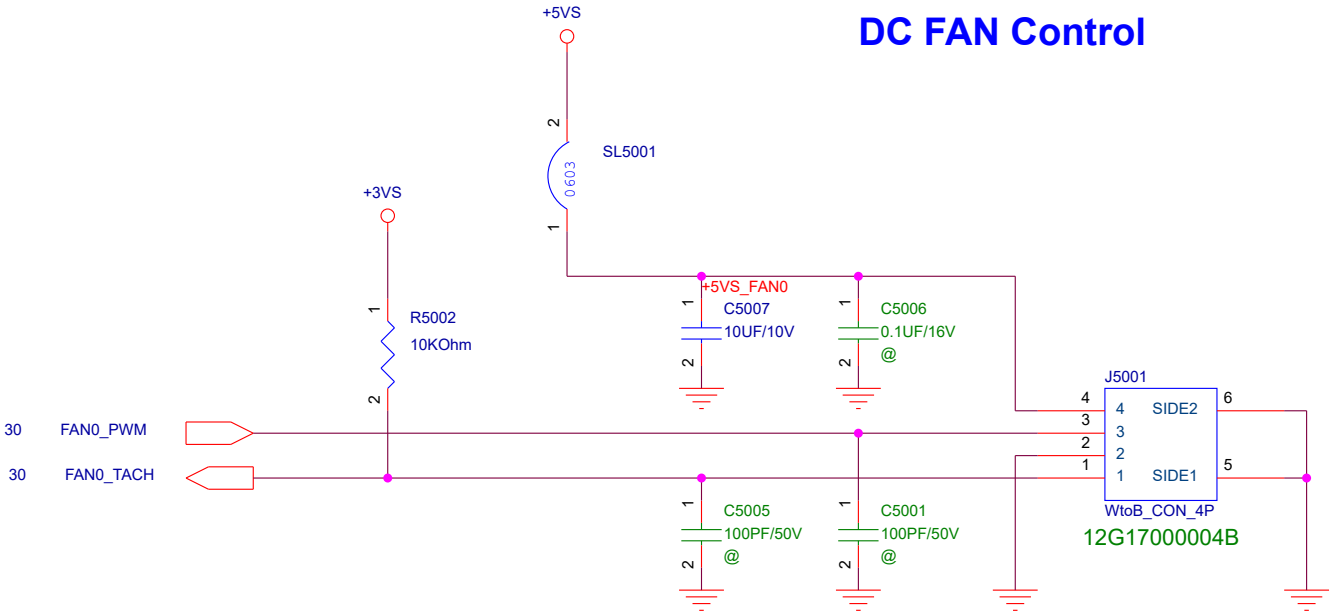
CPU Thermal Sensor



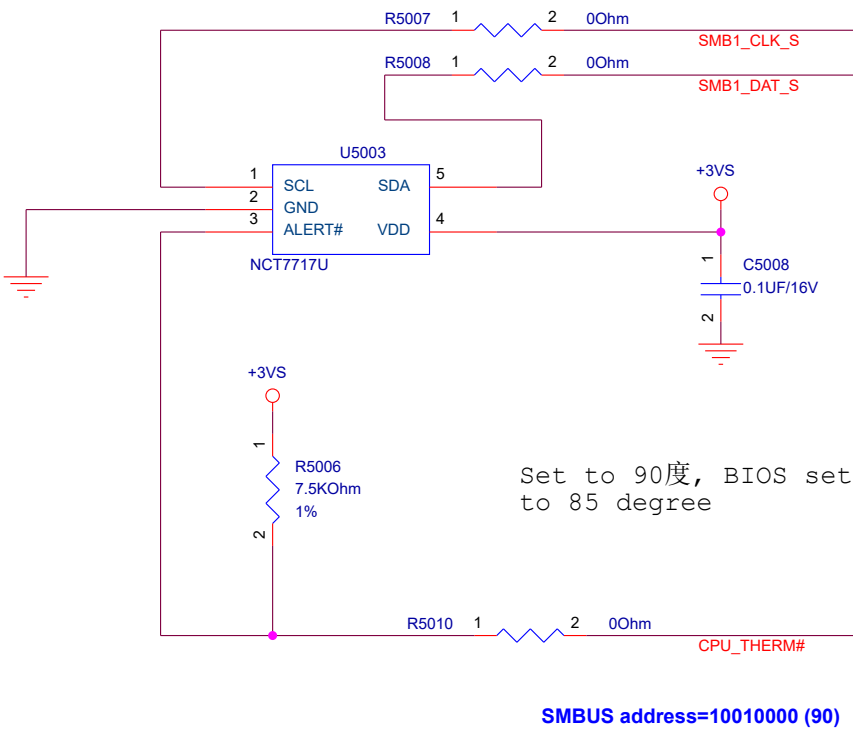
Temp.	Resistor
75	2kOhm
90	7.5kOhm
100	10.5kOhm
105	14kOhm
110	18.7kOhm



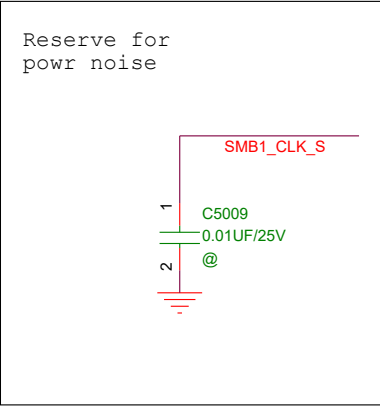
DC FAN Control



SSD Thermal Sensor Test



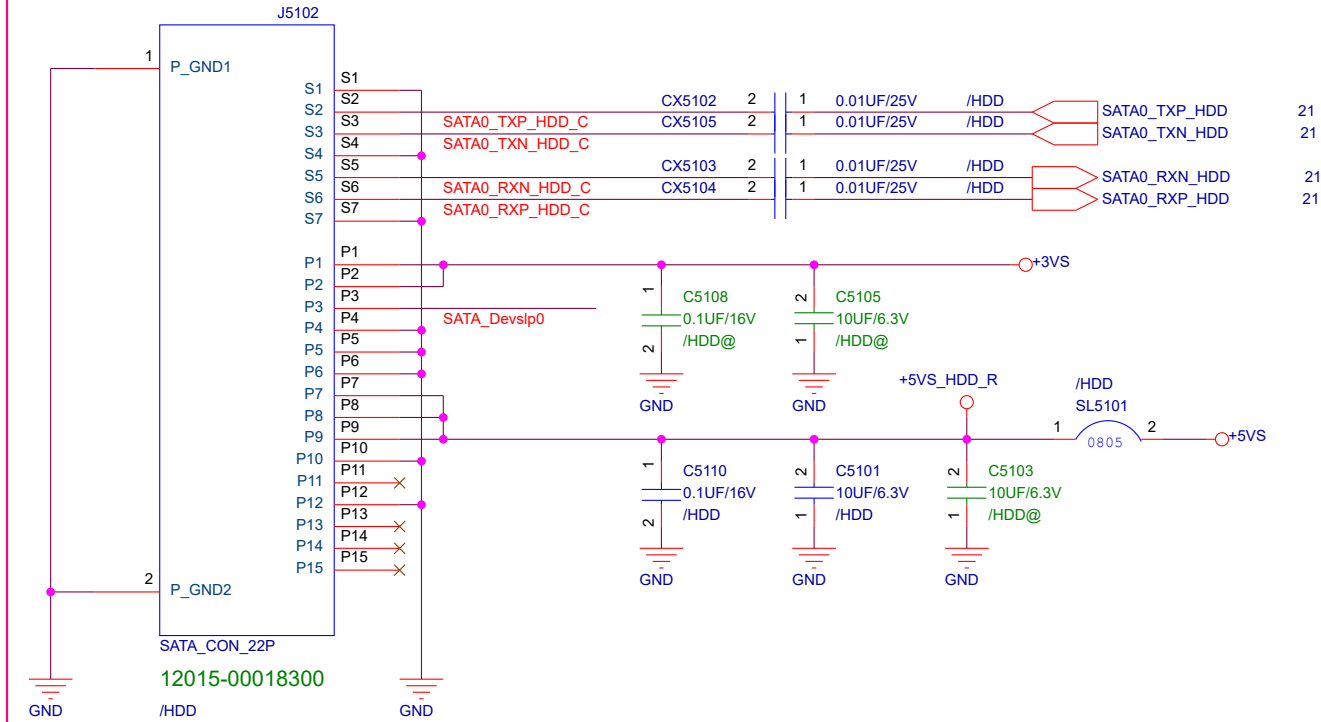
Temp.	Resistor
75	2kOhm
90	7.5kOhm
100	10.5kOhm
105	14kOhm
110	18.7kOhm



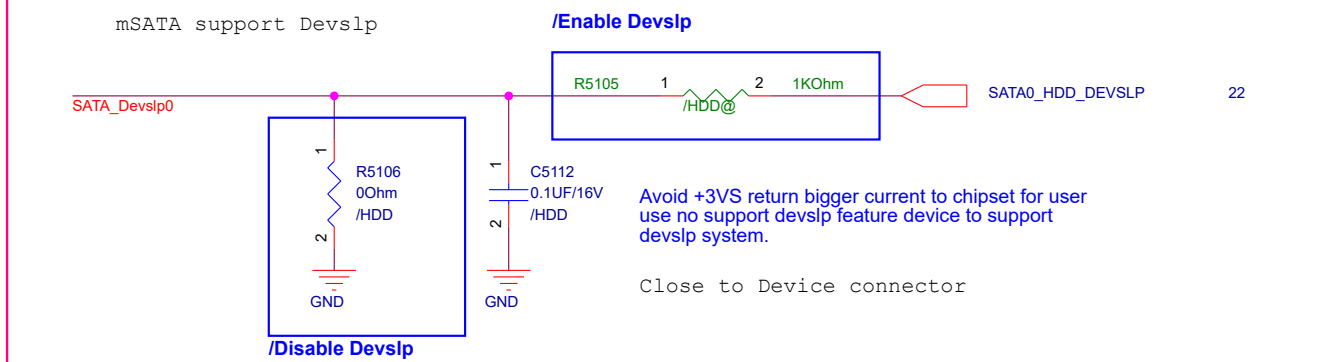
R2.0-6/23-1

<Variant Name>

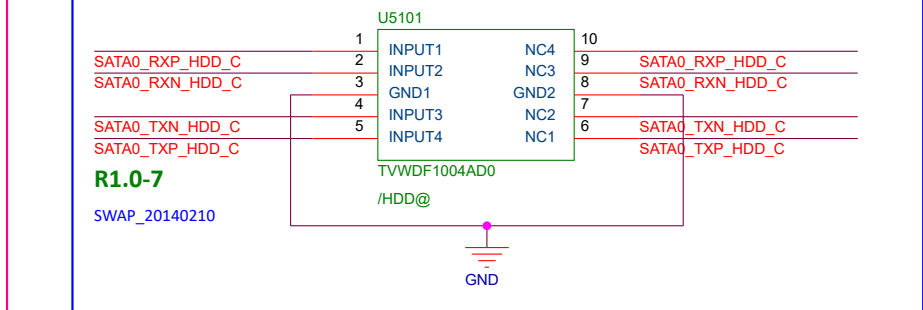
HDD



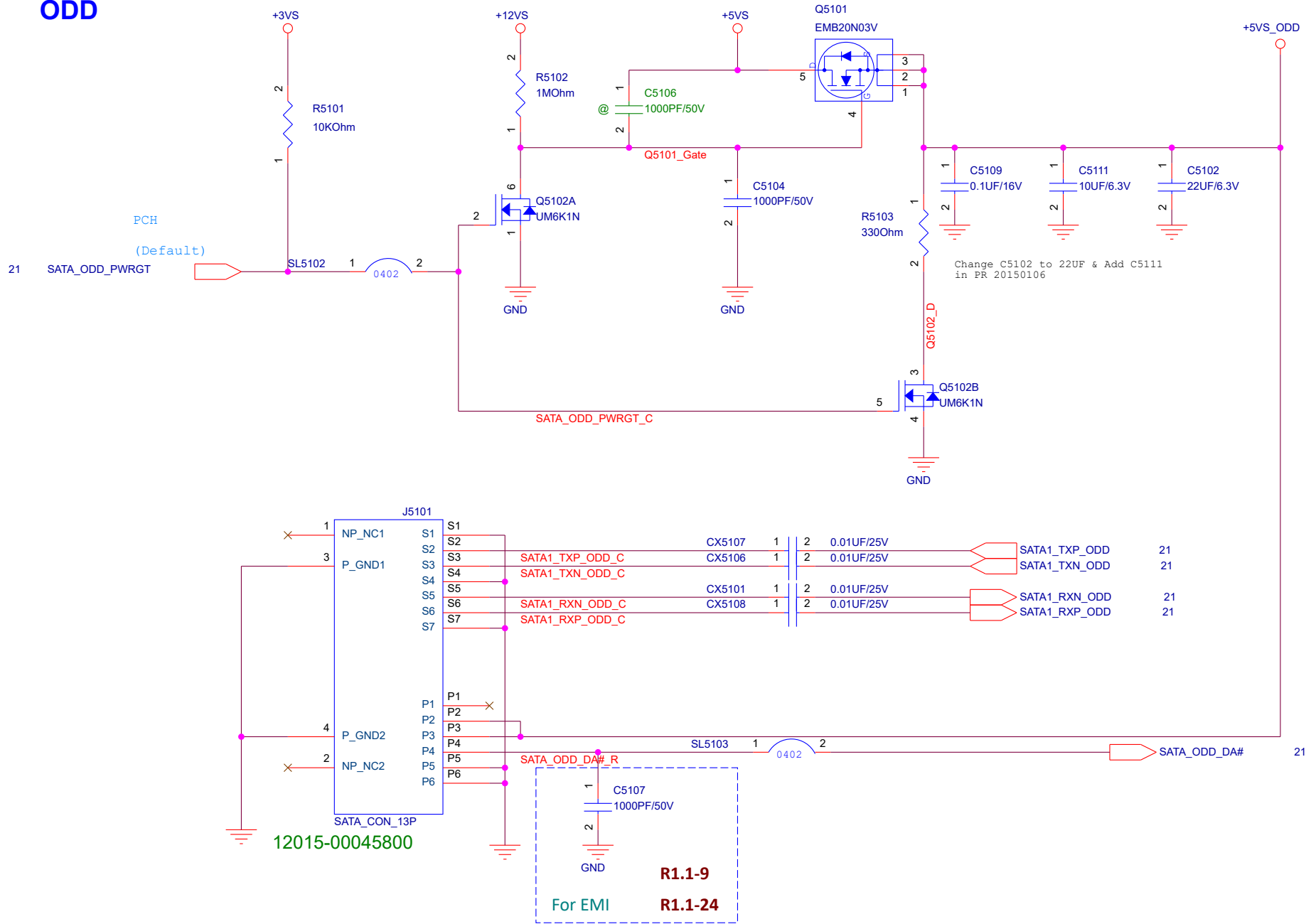
HW_Control SATA Device Sleep



For EMI



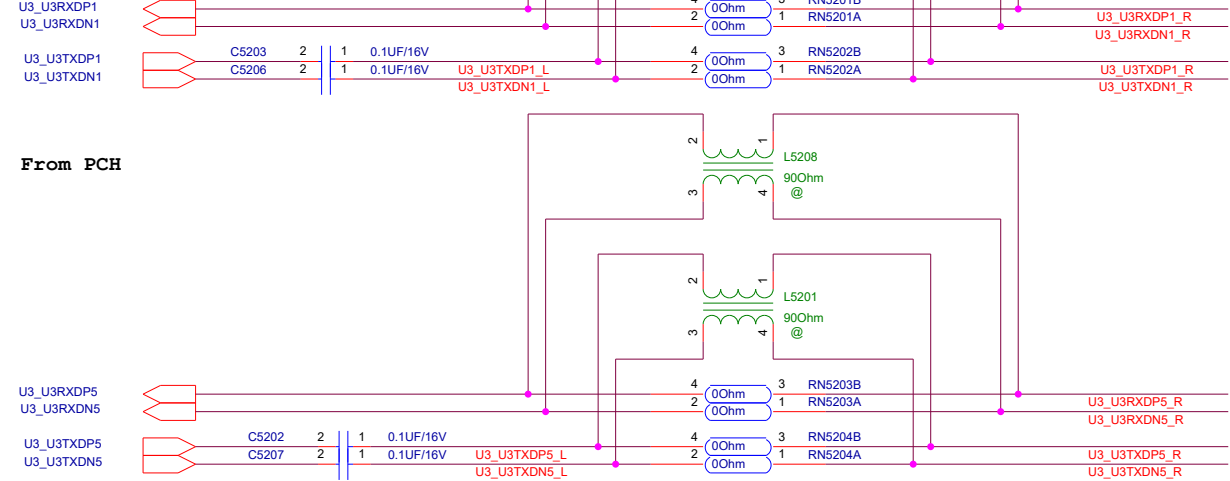
ODD



<Variant Name>

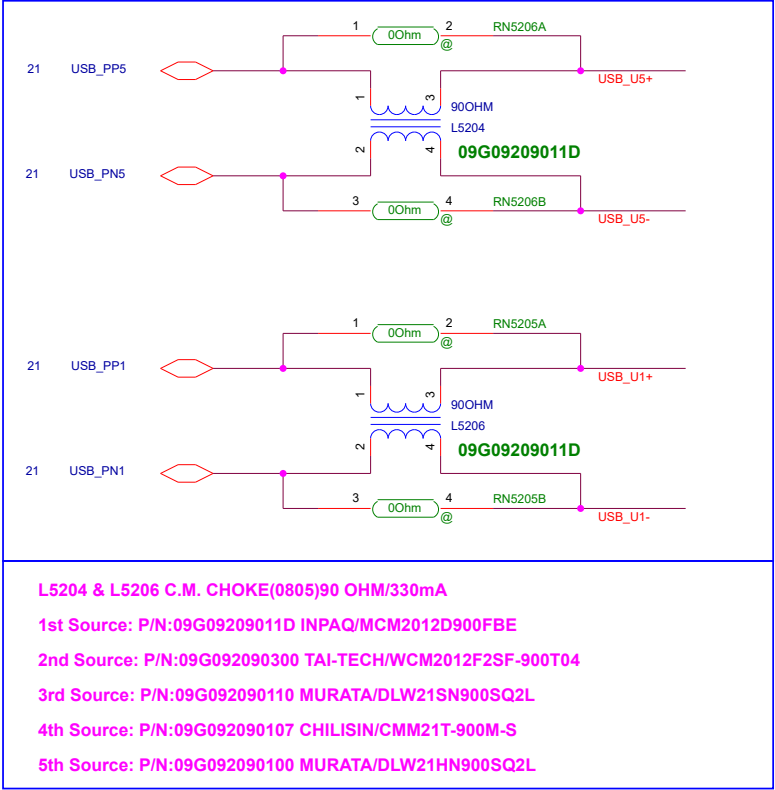
USB3.0
EMI-Protection

12/10/25
L5201, L5202, L5207, L5208
09G092090400

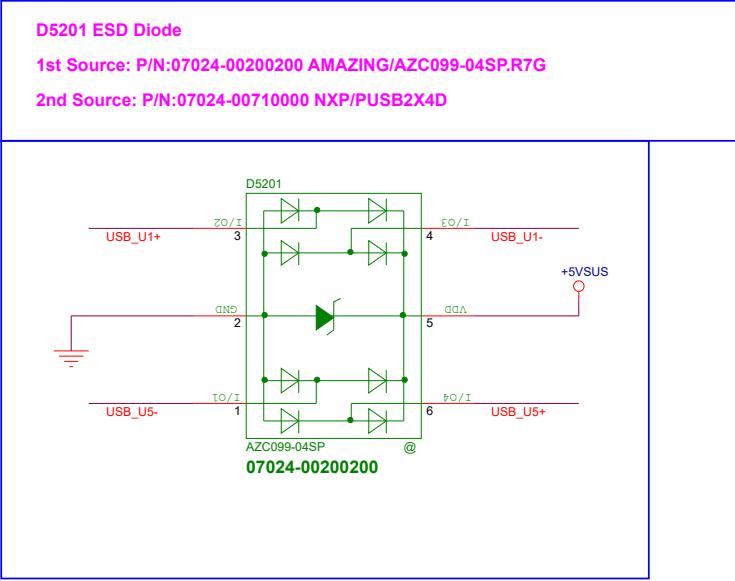


USB2.0 EMI-Protection

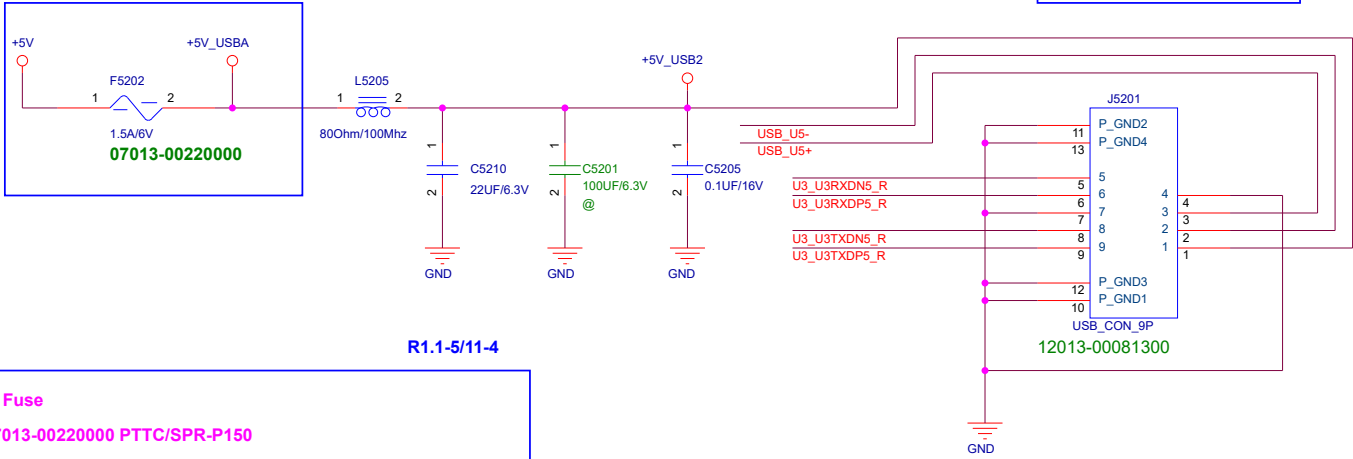
R1.1-4/13-5



R1.1-4/13-5



R1.1-5/11-4



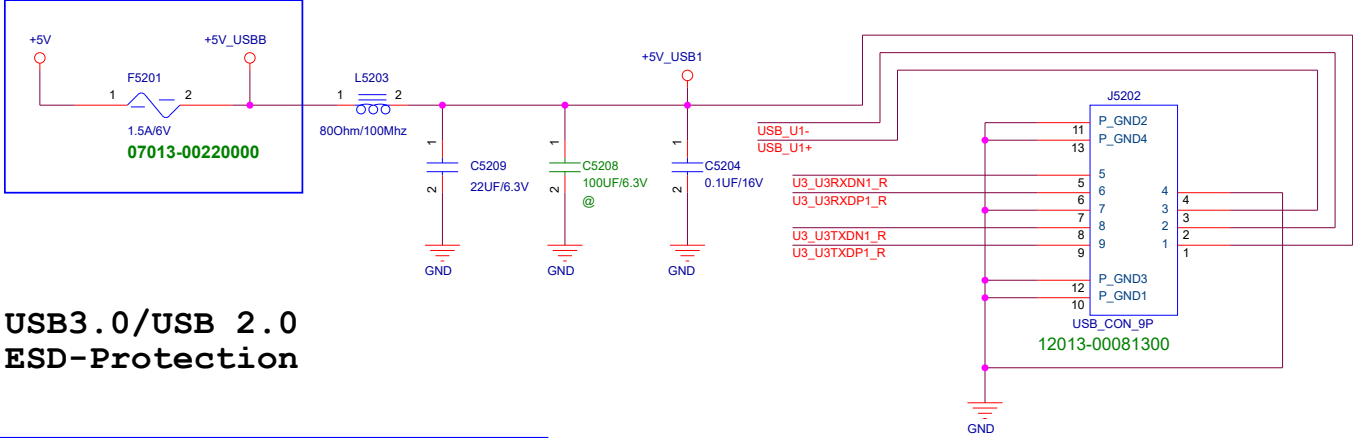
R1.1-5/11-4

F5201, F5202 Poly Fuse

1st Source: P/N:07013-00220000 PTTC/SPR-P150

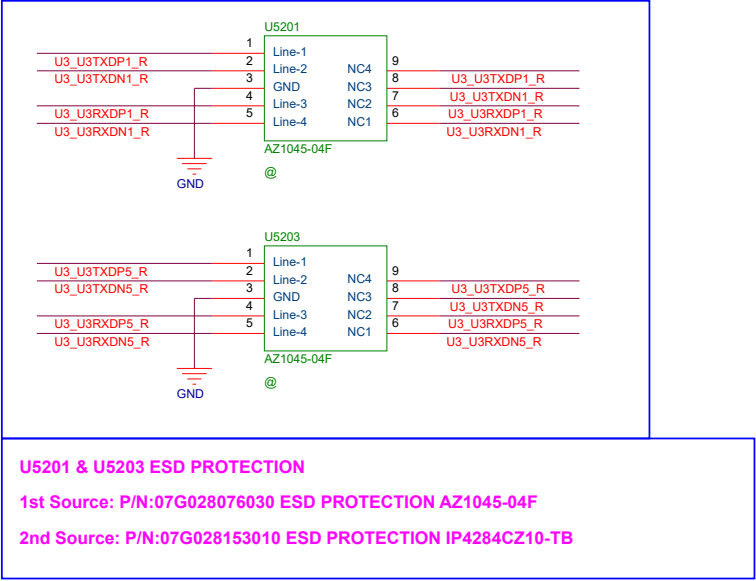
2nd Source: P/N:07013-00220100 LITTLEFUSE/0805L150ULYR

R1.1-5/11-4



USB3.0/USB 2.0
ESD-Protection

R1.1-4/13-5



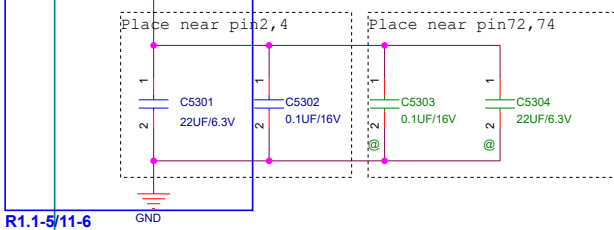
U5201 & U5203 ESD PROTECTION

1st Source: P/N:07G028076030 ESD PROTECTION AZ1045-04F

2nd Source: P/N:07G028153010 ESD PROTECTION IP4284CZ10-TB


<Variant Name>

WLAN PWR_+3V_NGFF_WLAN (Non-ISCT)



R1.1-5/11-6



		Title : WiFi/WiMax	
ASUSTek COMPUTER INC. NB1		Engineer: Mario_Jhu	
Size C	Project Name GL552VW		Rev 2.0
Date: Tuesday, June 23, 2015		Sheet 53 of 103	

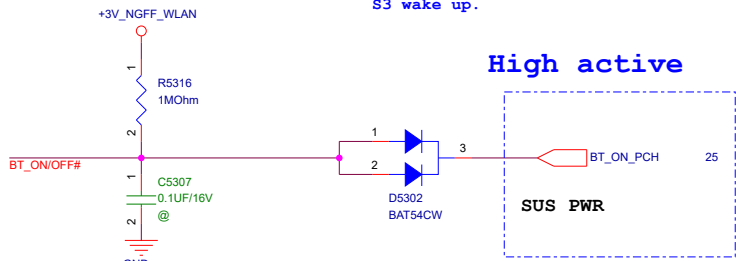
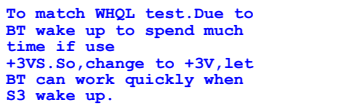
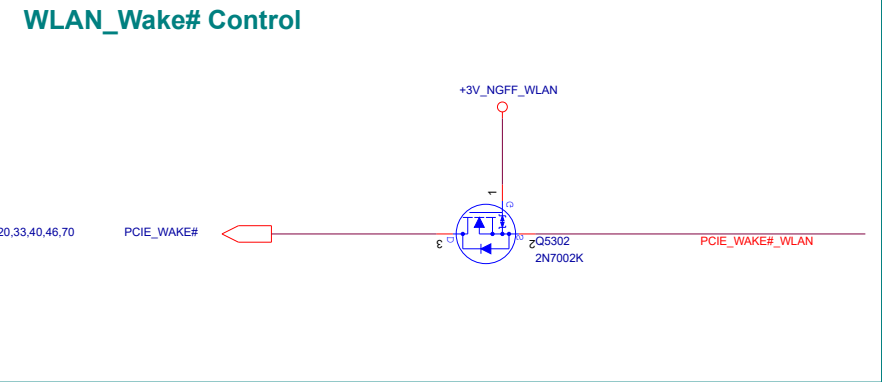


J5301_NGFF E-KEY WLAN Connector H=2.0mm

1st Source: P/N:12003-00075200 DRAGONSTATE/213EBAA2FKA

2nd Source: P/N:12003-00074900 ACES/51746-0670P-005

3rd Source: P/N:12003-00076000 ARGOSY/NASE0-S6701-TP20



Project which use the combo card schematic should make sure that BT_ON signal can't be High at S3/S4/S5 state to prevent leakage



D5309_VARISTOR 5V 100PF (0402)

1st Source: P/N:07019-00070100 INPAQ/MLV50402M04A8/SMD

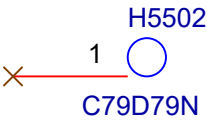
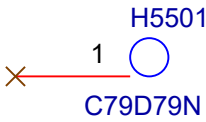
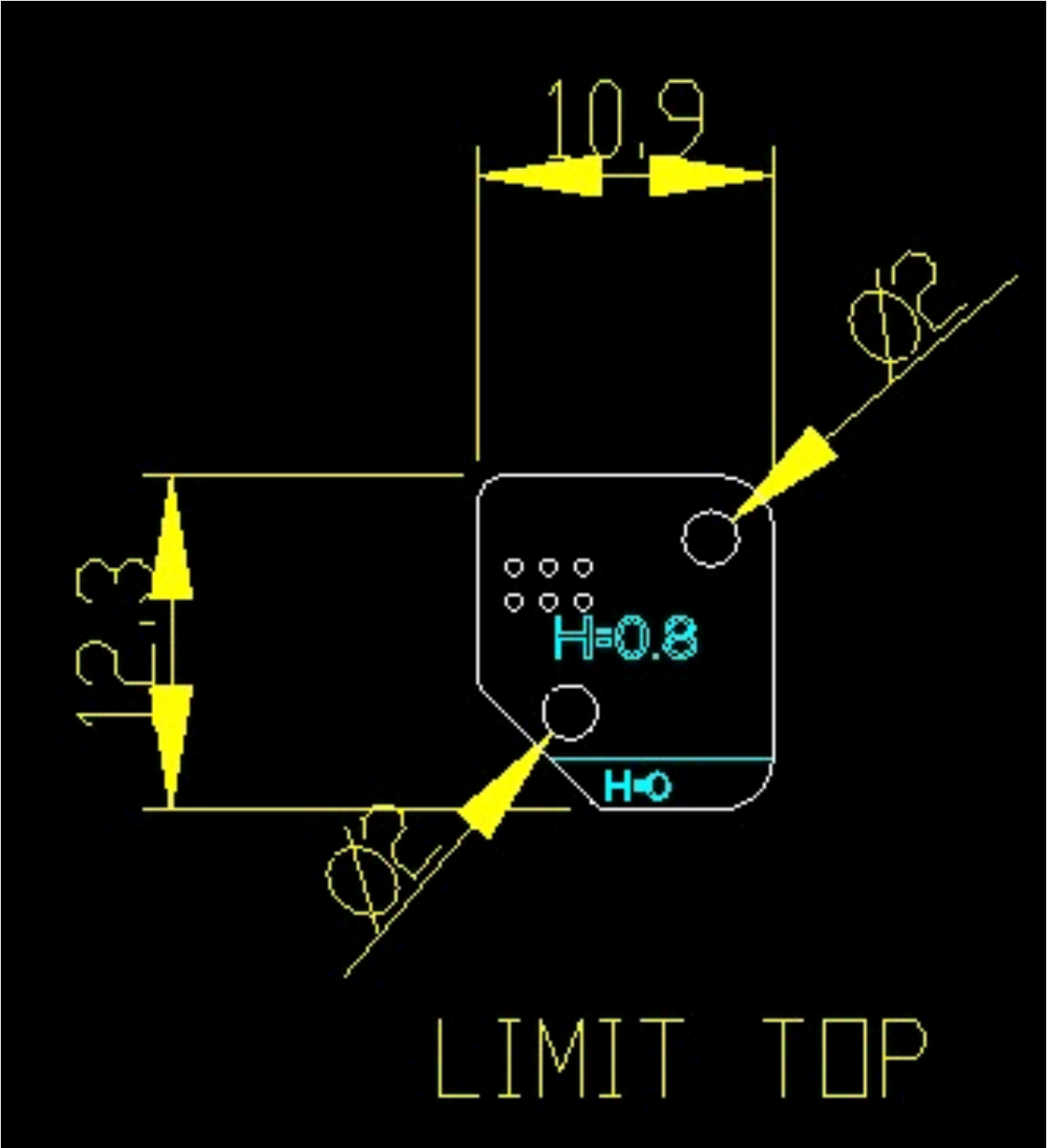
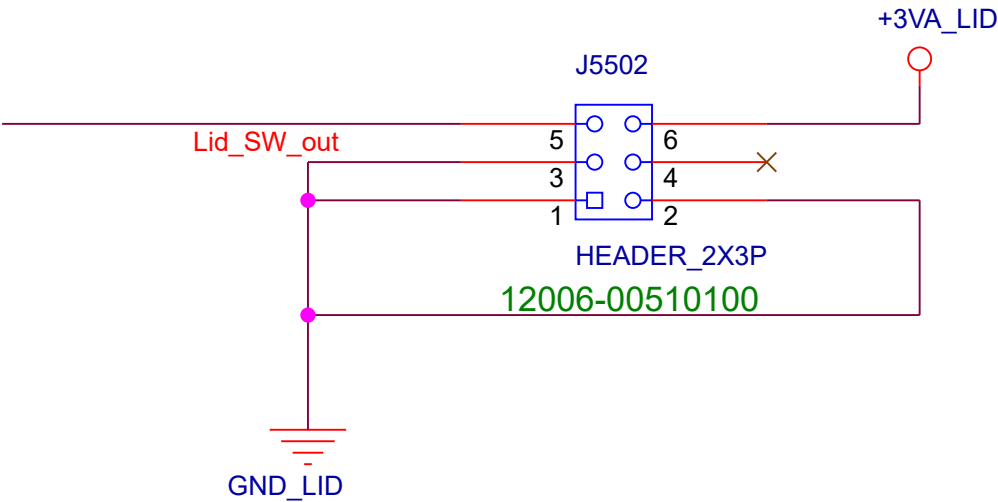
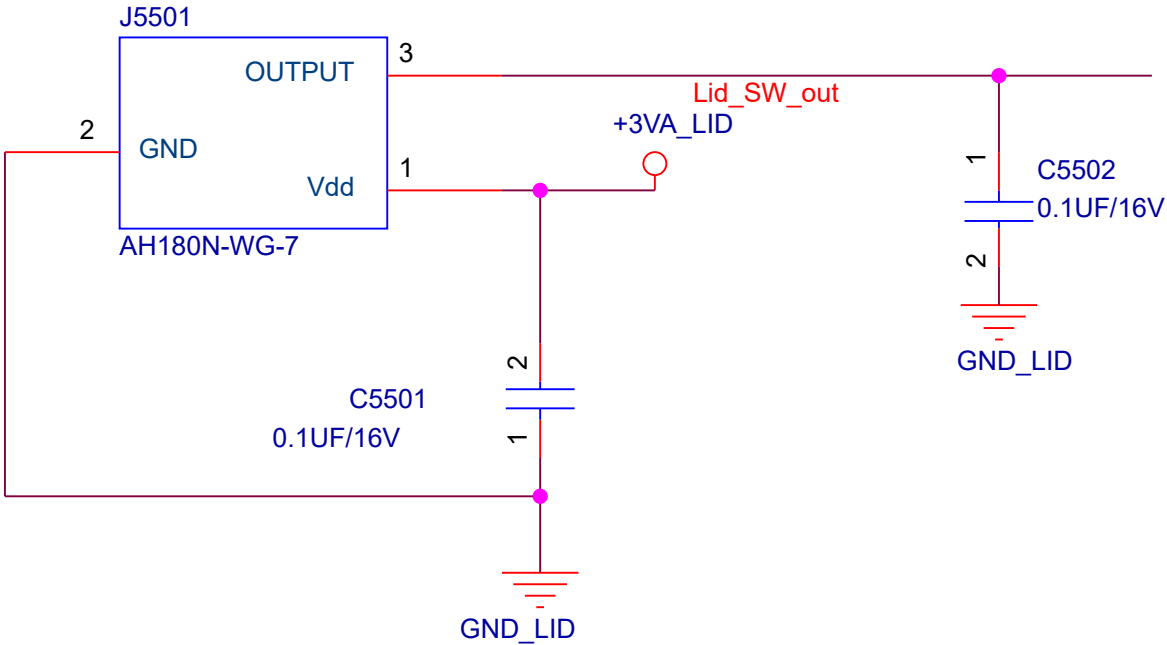
2nd Source: P/N:07G028011010 INPAQ

3rd Source: P/N:07G022005Q11 INPAQ/VPORT0402101MV05


4th Source: P/N:07G022005830 THINKING/VTVM0G5R5M261R

5th Source: P/N:07G022005830 TK5/VTVM0G5R5M101R001

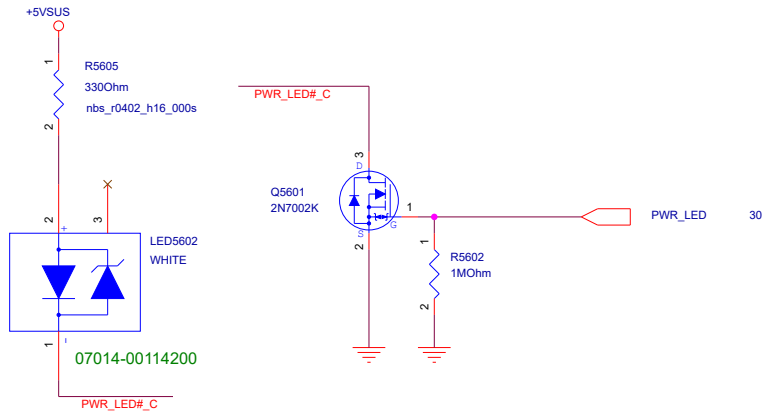
LID Switch



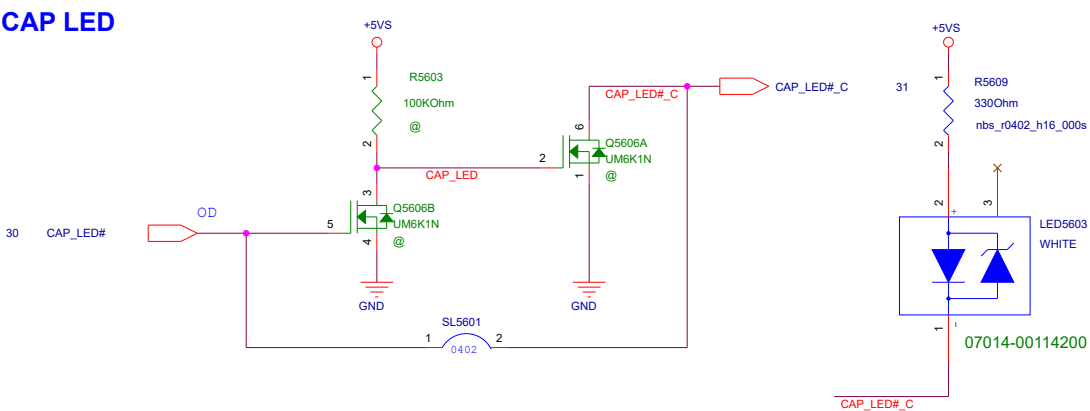
<Variant Name>

		Title : Lid_SW_BD	
ASUSTeK COMPUTER INC. NB1		Engineer: Mario_Jhu	
Size A	Project Name GL552VW		Rev 2.0
Date: Tuesday, June 23, 2015		Sheet 55	of 103

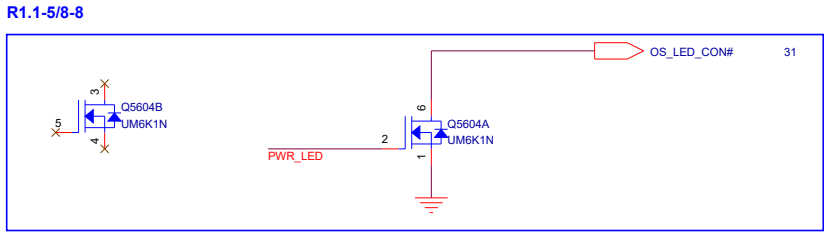
POWER LED



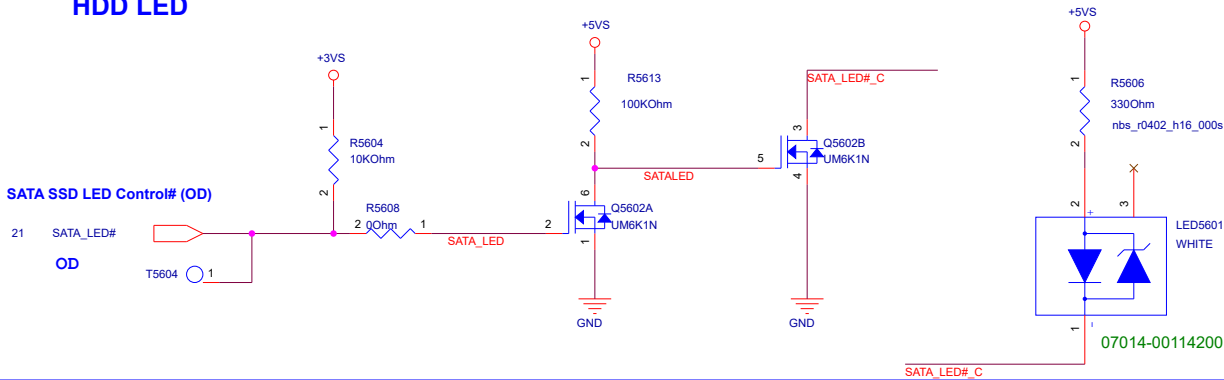
CAP LED



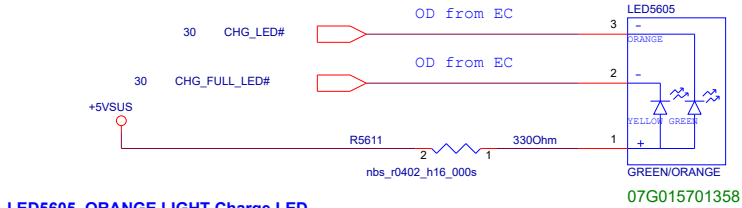
OS_LED#



HDD LED



Charger LED

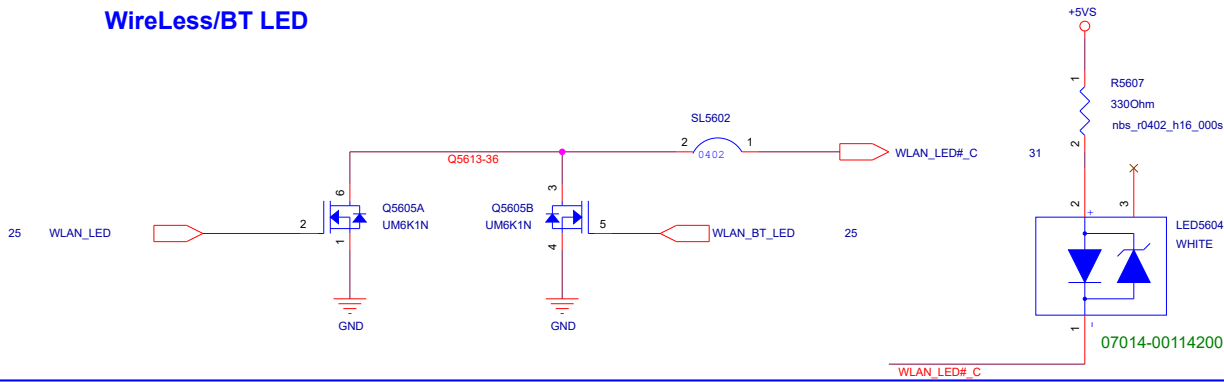


LED5605_ORANGE LIGHT Charge LED

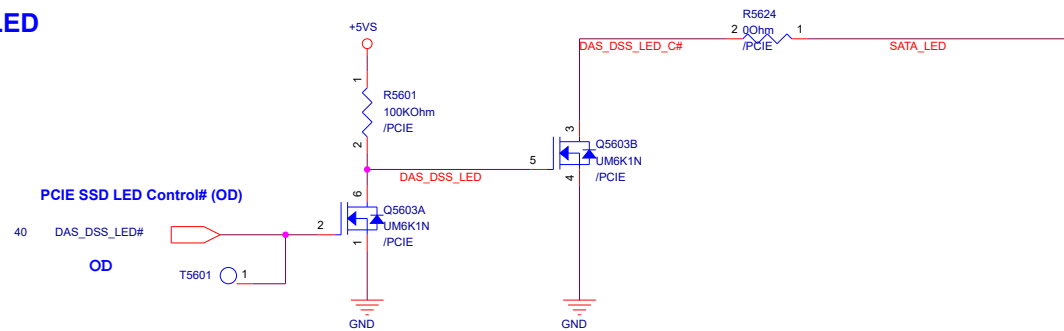
1st Source: P/N:07G015701358 12-22/S2G6C-C30/2C

2nd Source: P/N:07014-00140000 LTST-S326KGKFKT-PE

WireLess/BT LED

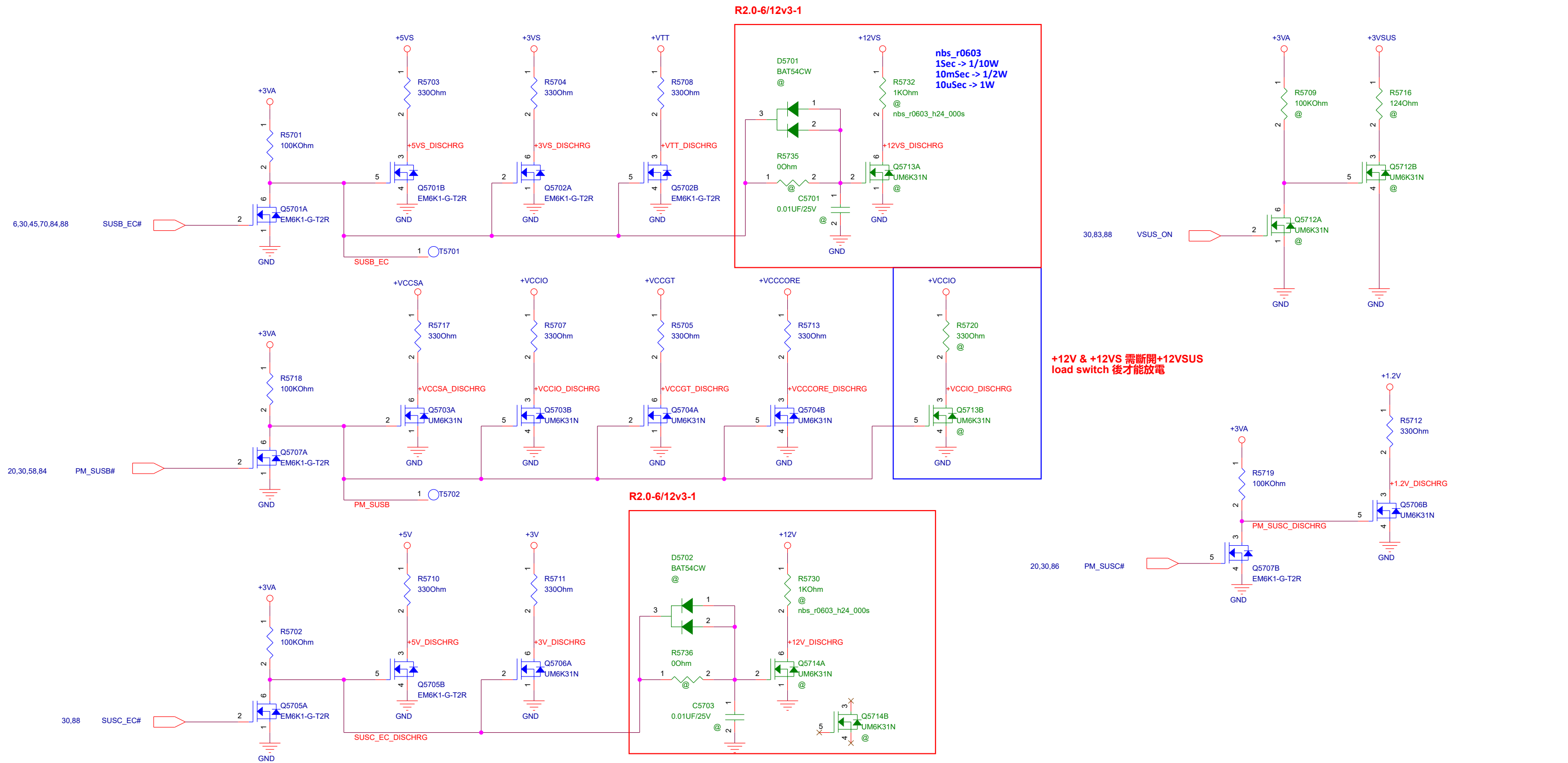


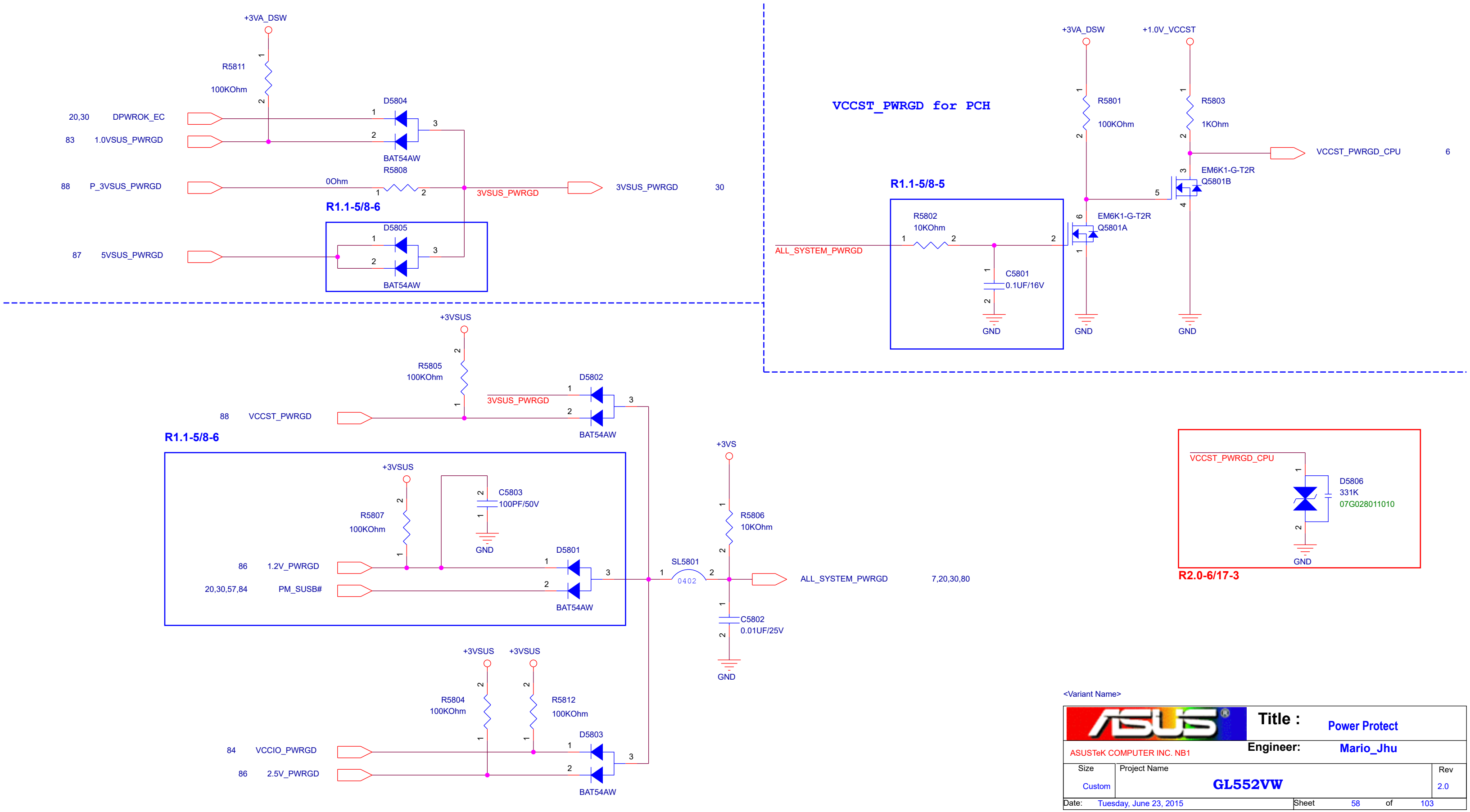
SSD LED



The default use of this pin is GPIO49.	
SATALED#	OD O
Serial ATA LED: This signal is an open-drain output pin driven during SATA command activity. It is to be connected to external circuitry that can provide the current to drive a platform LED. When active, the LED is on. When tri-stated, the LED is off. An external pull-up resistor to Vcc3_3 is required.	
SGPIO Reference Clock: The SATA controller uses rising edges of	

<Variant Name>





<Variant Name>



Title : Power Protect

ASUSTek COMPUTER INC. NB1

Engineer: Mario_Jhu

Size
Custom

Project Name
GL552VW

Rev
2.0

Date: Tuesday, June 23, 2015

Sheet 58 of 103

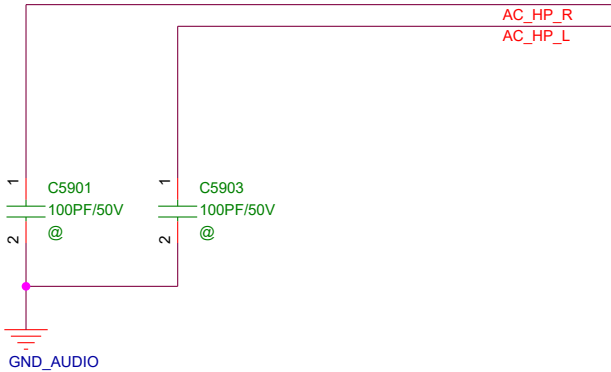
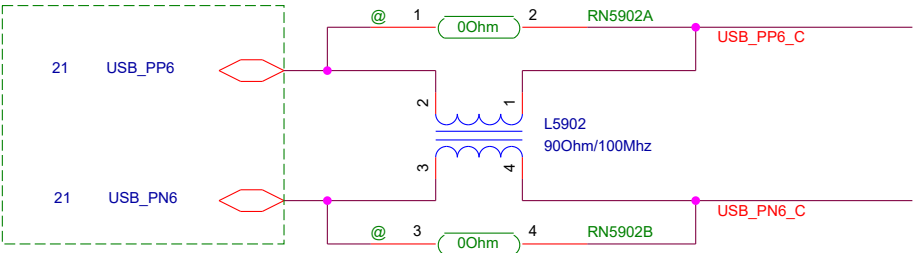
To I/O Board

R1.1-5/11-3

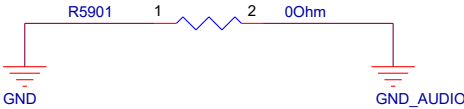
L5902 Choke

1st Source: P/N:09G092090100 MURATA/DLW21HN900SQ2L <G>

2nd Source: P/N:09G092090107 CHILISIN/CMM21T-900M-S <G>



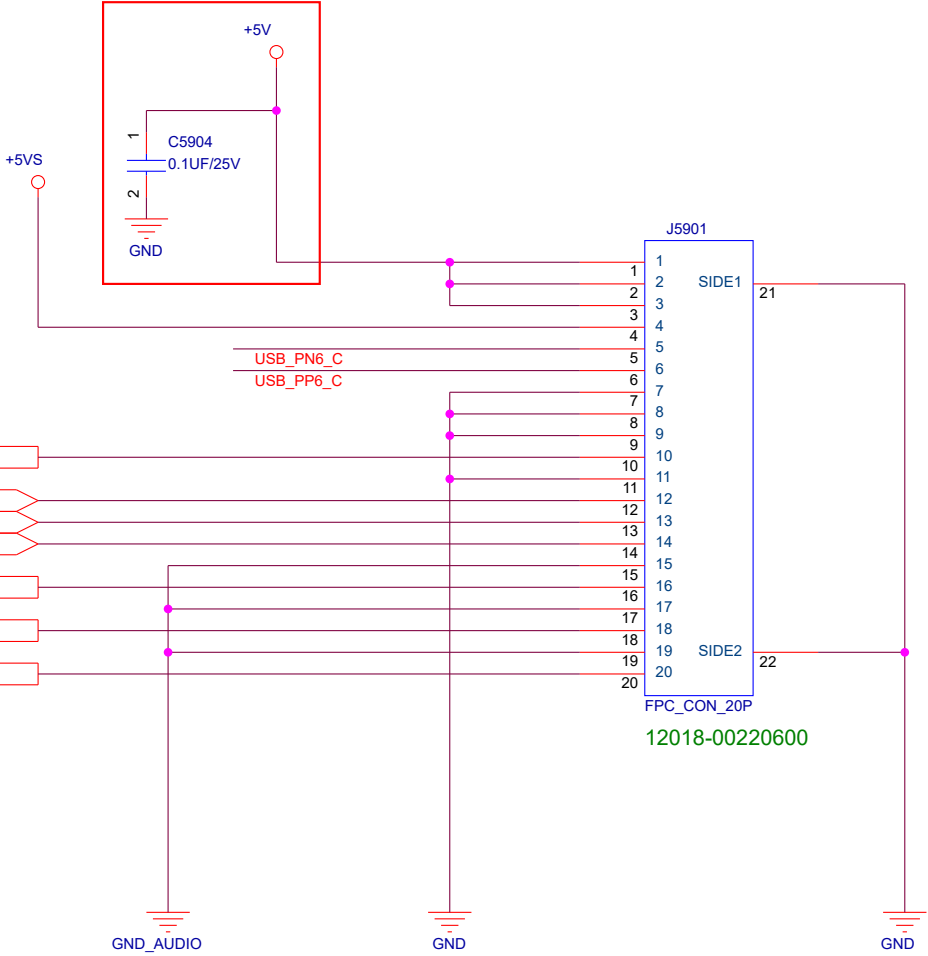
Close to connector for EMI



R1.1-5/11-3

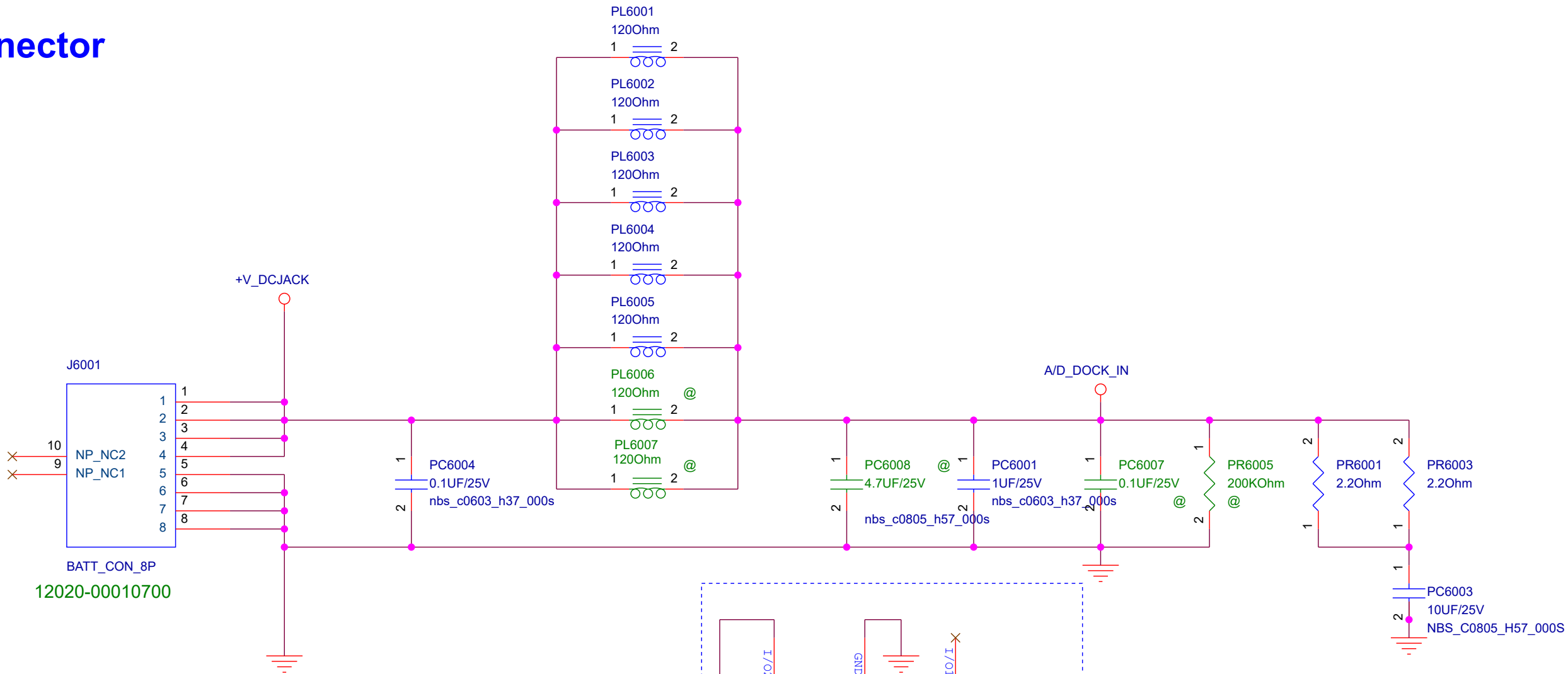
R2.0-6/9-7

- 36 SENSE_PORT_A
- 36 AC_HP_L
- 36 HGND_A
- 36 AC_HP_R
- 36 SENSE_PORT_B
- 36 MICBIASB
- 36 MIC_IN_AC_E

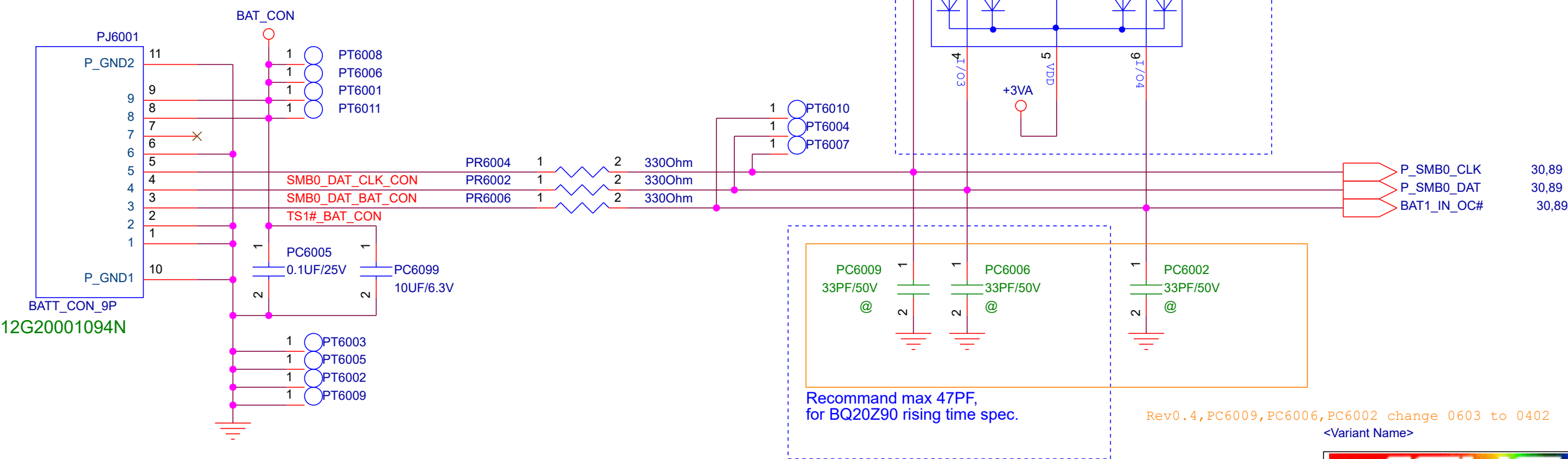


<Variant Name>

DC-IN Connector

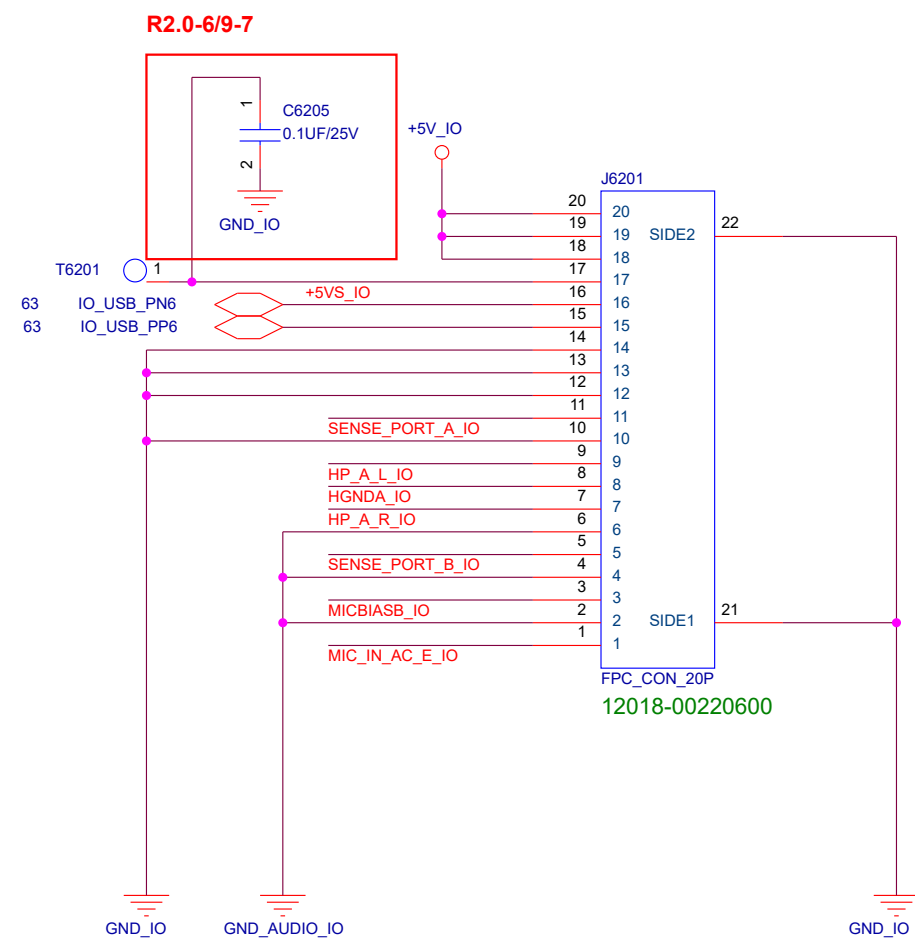


Battery Connector

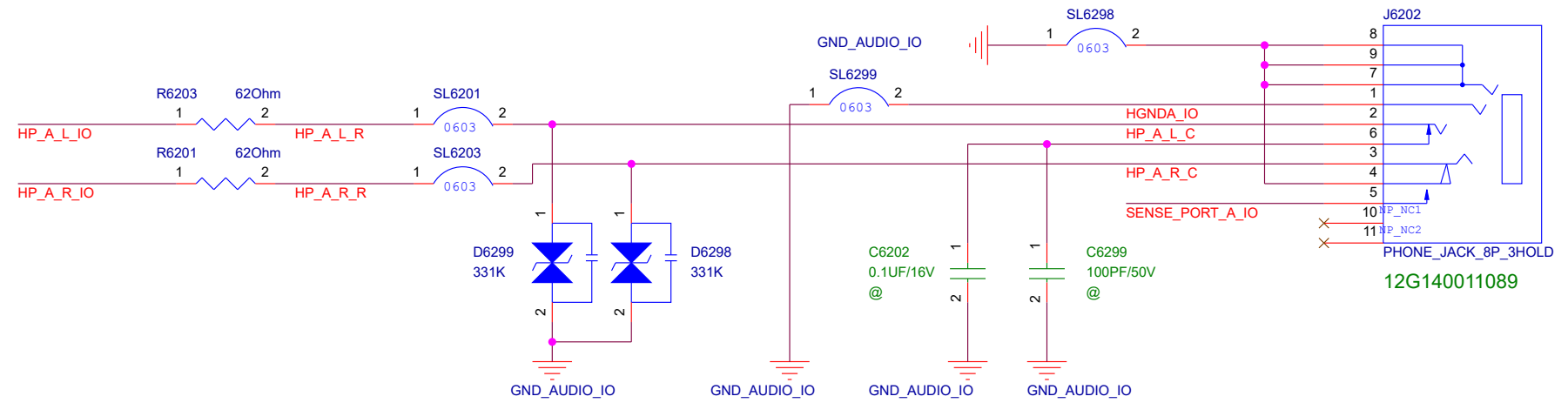


081111 -> 090604:
1. Change PD6001 from DF5A6.8FU to IP4223-CZ6 for cost down and integration.

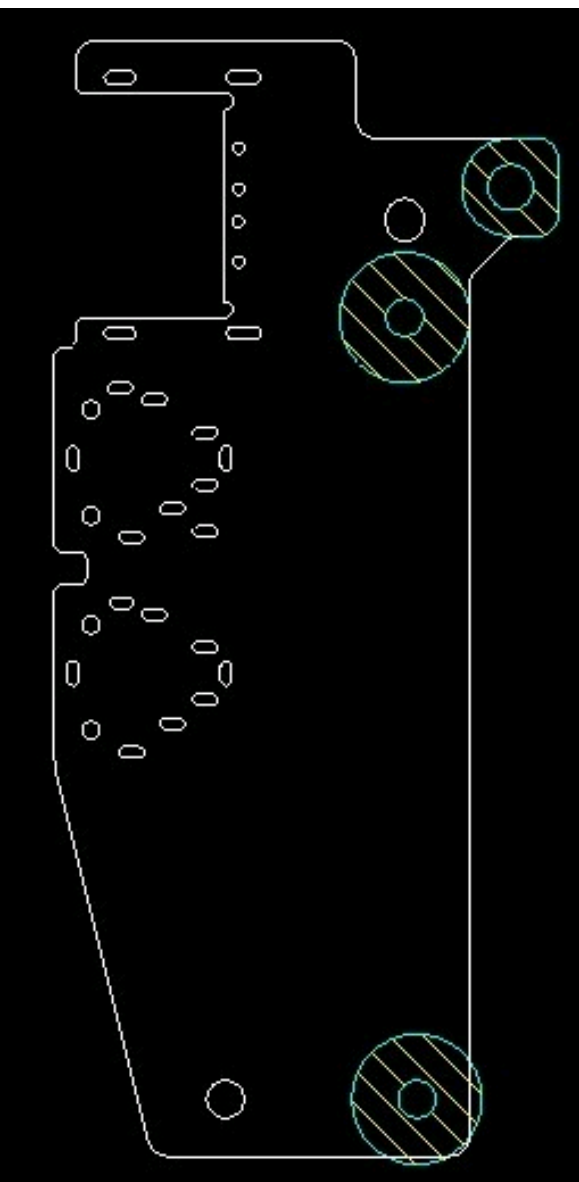
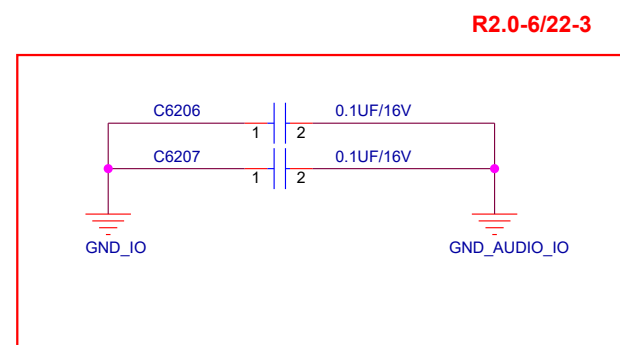
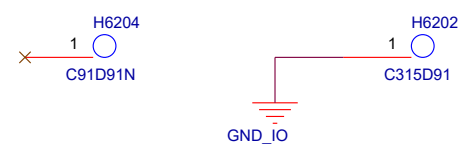
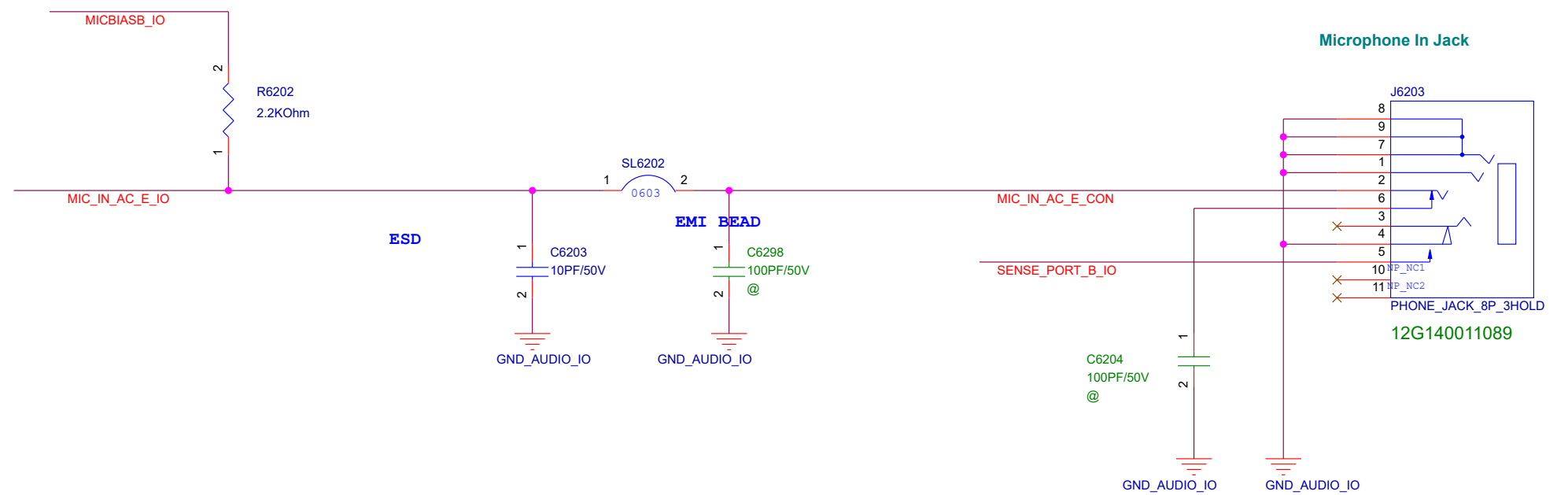
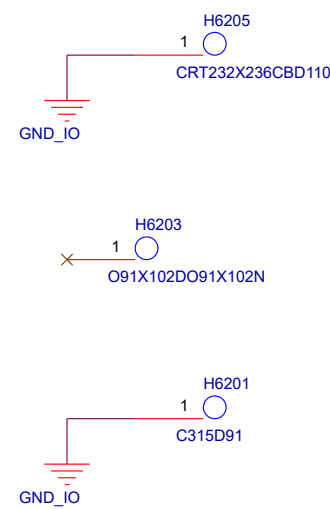
HP JACK for Dual JACK Solution

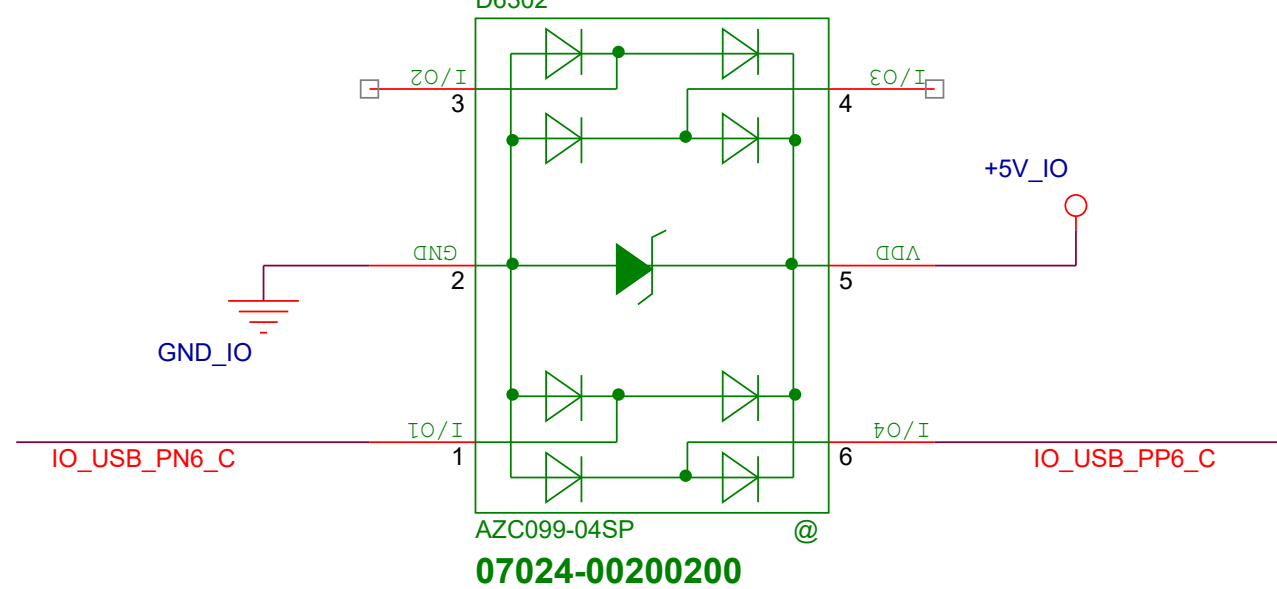
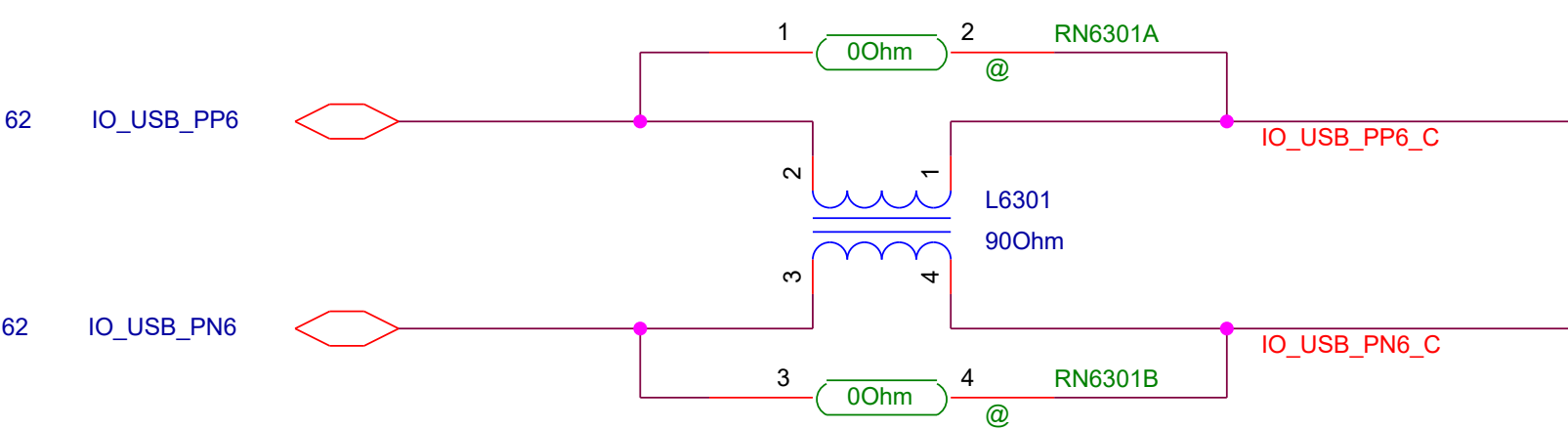


Change to 07g005000313 in
SR2 20141027



EXTERNAL MICROPHONE

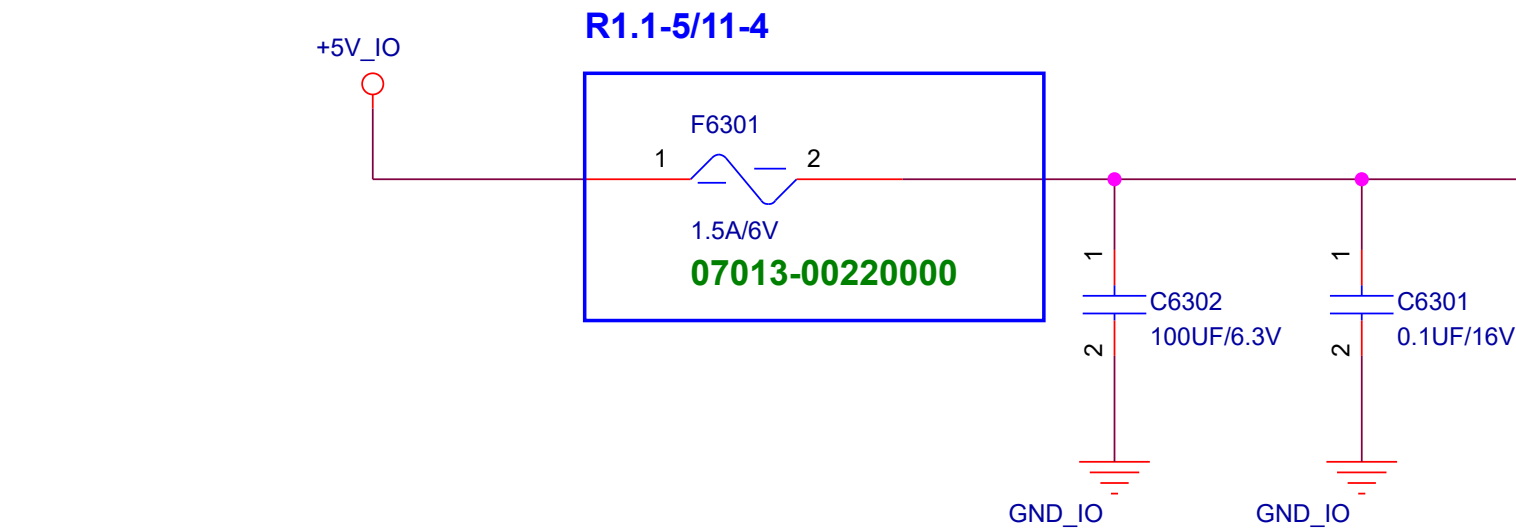




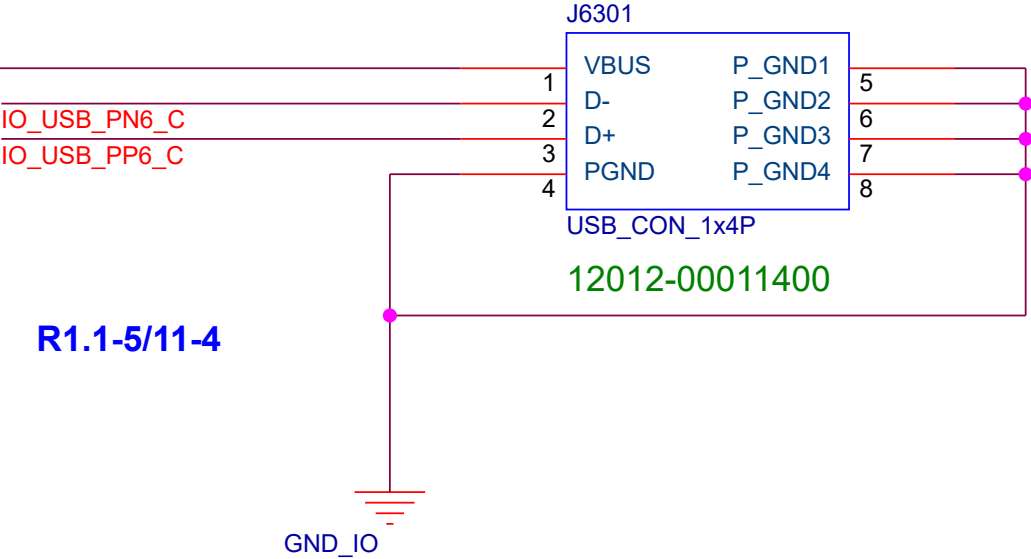
USB2.0_Port 3

R1.1-4/13-5

D6302 ESD Diode
1st Source: P/N:07024-00200200 AMAZING/AZC099-04SP.R7G
2nd Source: P/N:07024-00710000 NXP/PUSB2X4D




R1.1-5/11-4



R1.1-5/11-4

F6301 Poly Fuse
1st Source: P/N:07013-00220000 PTTC/SPR-P150
2nd Source: P/N:07013-00220100 LITTLEFUSE/0805L150ULYR

<Variant Name>

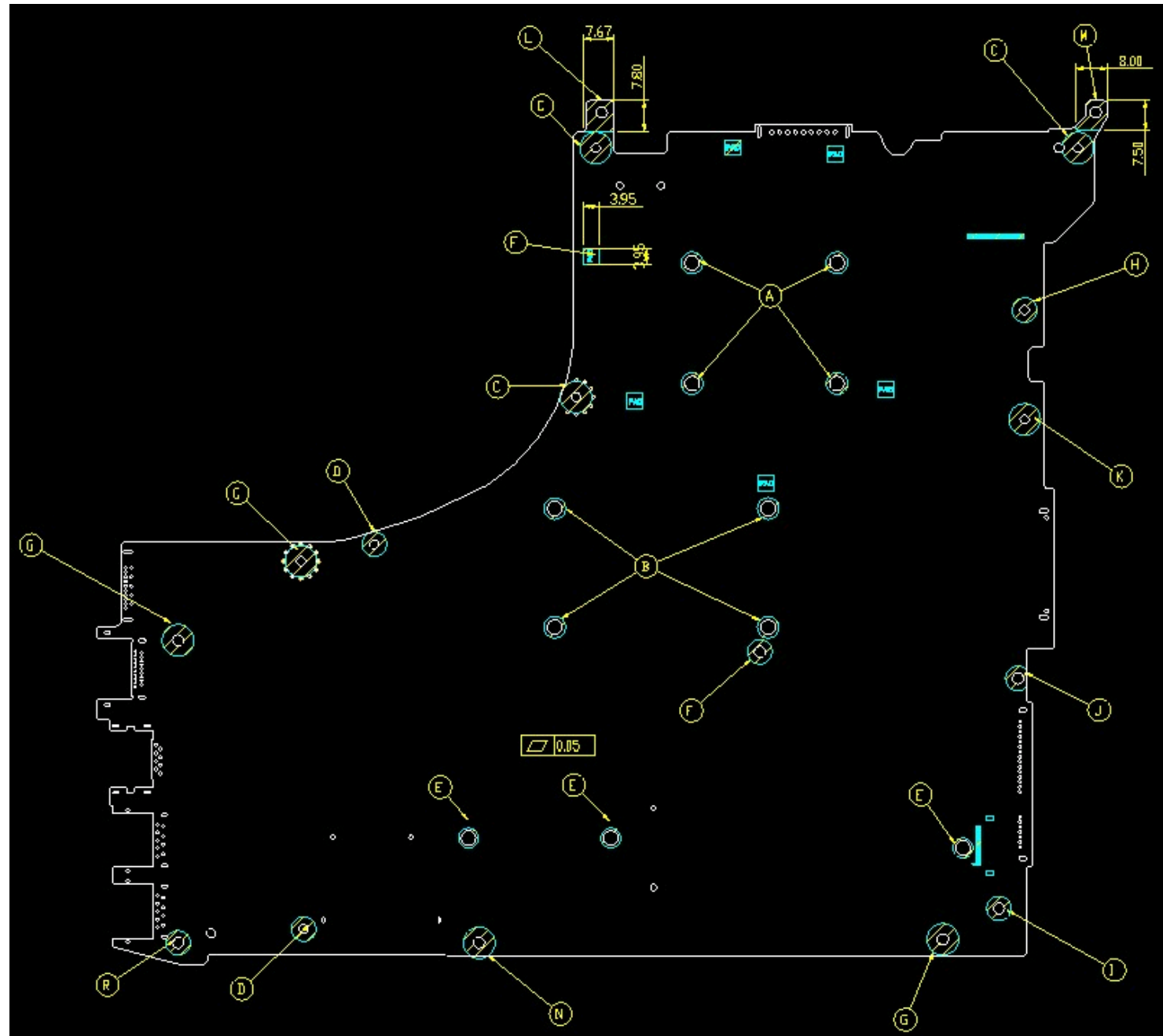
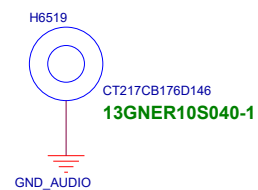
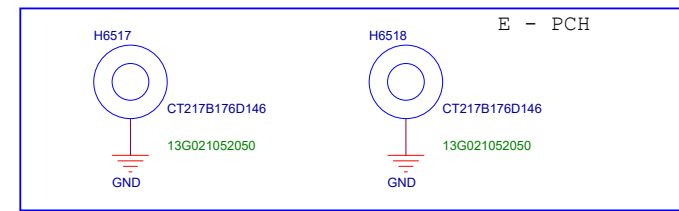
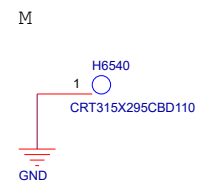
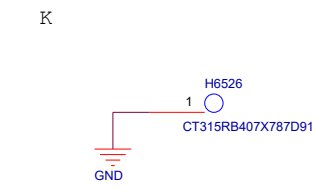
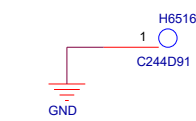
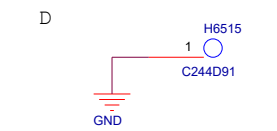
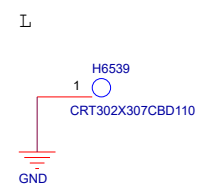
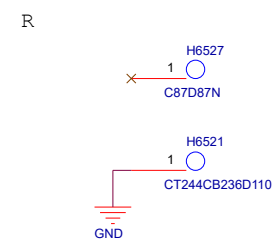
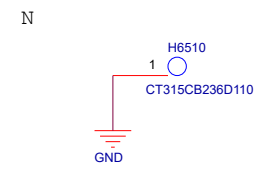
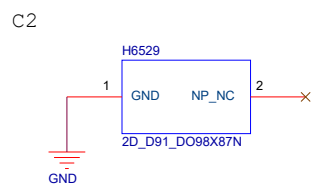
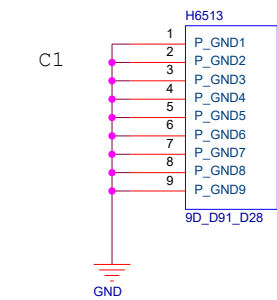
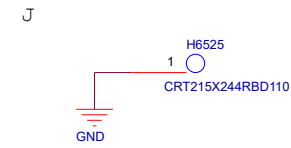
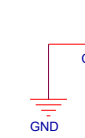
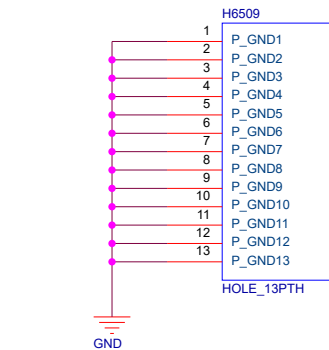
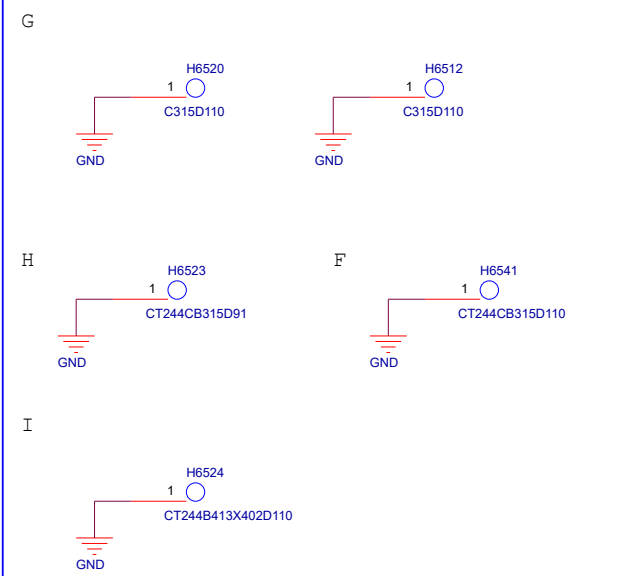
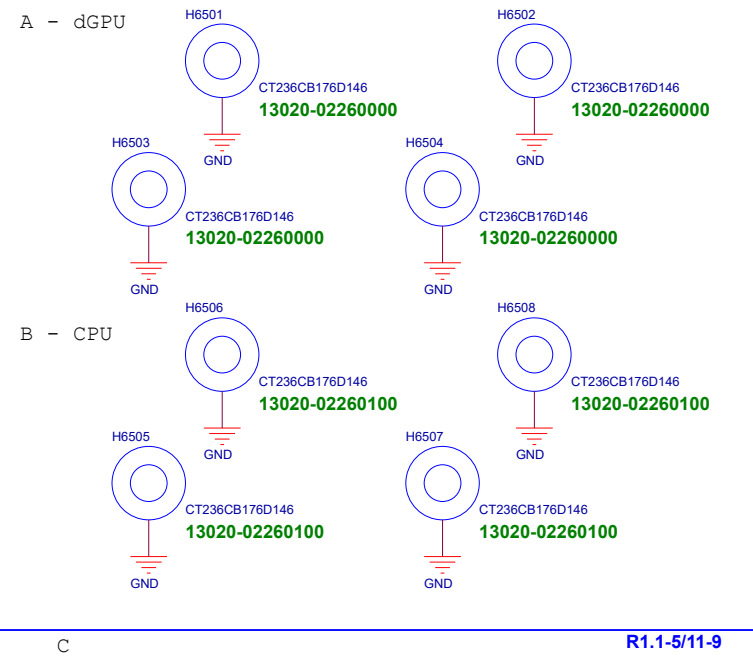
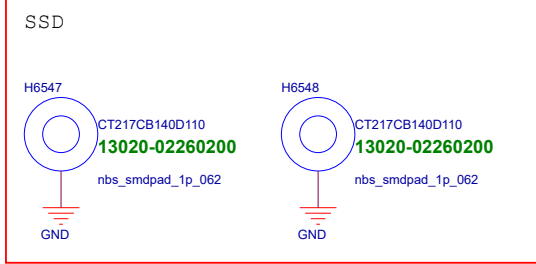
		Title : I/O board(2)_USB	
ASUSTeK COMPUTER INC. NB1		Engineer: Mario_Jhu	
Size A	Project Name GL552VW		Rev 2.0
Date: Tuesday, June 23, 2015		Sheet 63	of 103

Nut in SR2 20141031

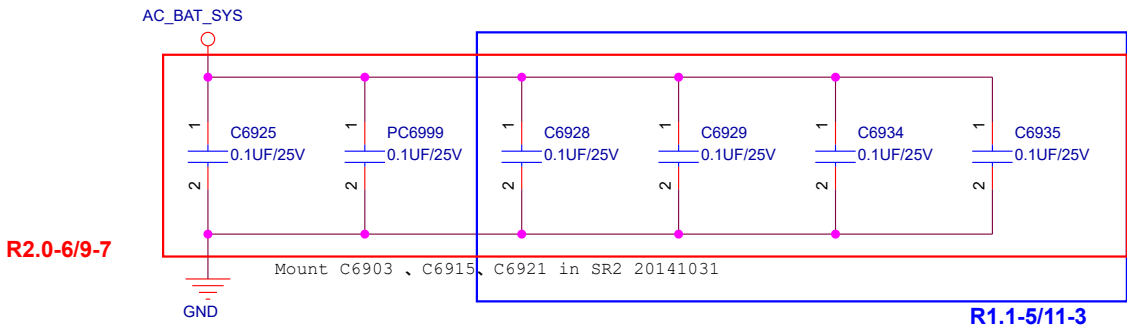
H6533 & H6537 Change to

R2.0-6/12-2

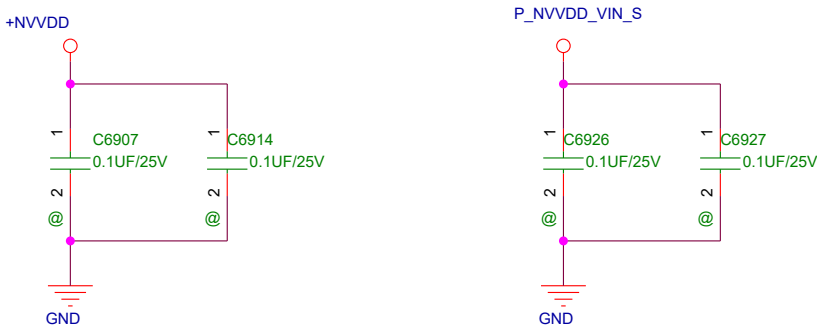
H6533 & H6537 Change to H=3.5mm Gasket in PR



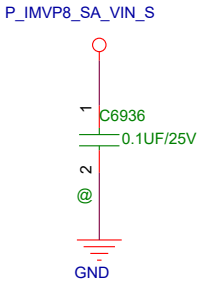
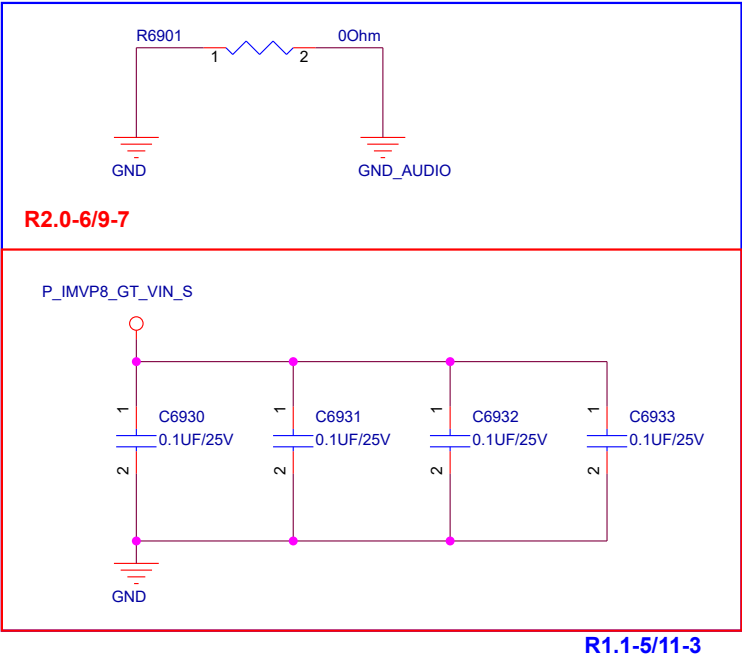
2014-02-12 Add EMI solution
(6042.00 6728.00)、(1947.00 3850.00)、
(1757.00 1852.00)、(6369.00 -299.00)



(6490.00 4706.00)、(7437.00 3852.00)

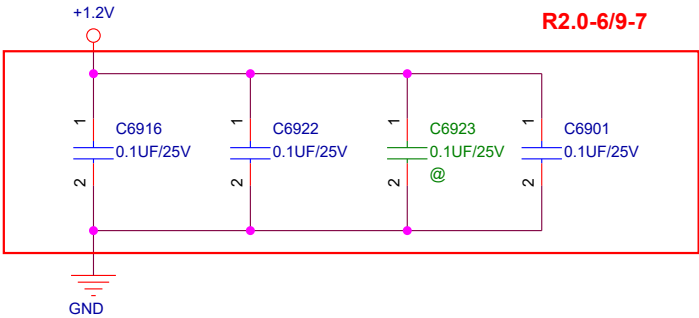


(8004.00 585.00)



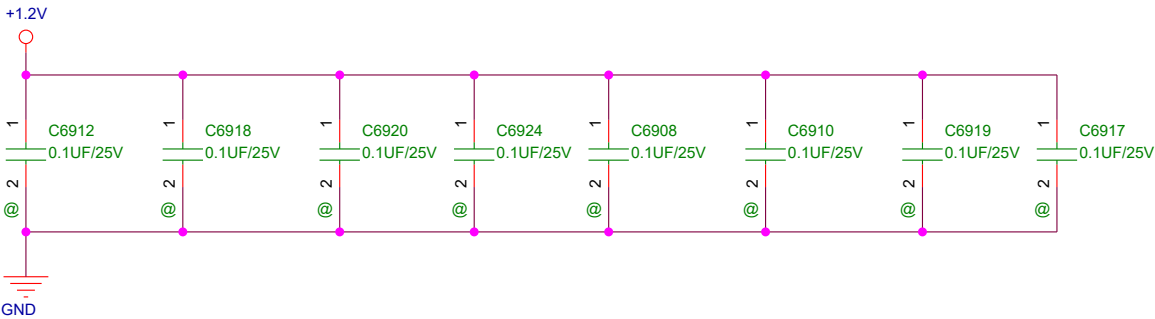
R1.0-16

2014-04-03 Add EMI solution
(3678, 2622)、(4011, 2594)、(4975, 2580)、(5169, 2585)

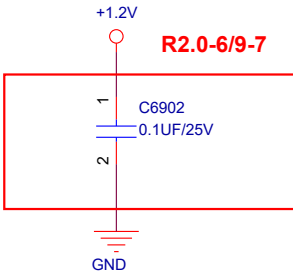


R1.1-24

2014-04-03 Add EMI solution
Top
(3541,2591)、(3339,2115)、(3807,2452)、(4030,2118)、
(3367,1670)、(3583,1965)、(3819,1953)、(4013,1650)




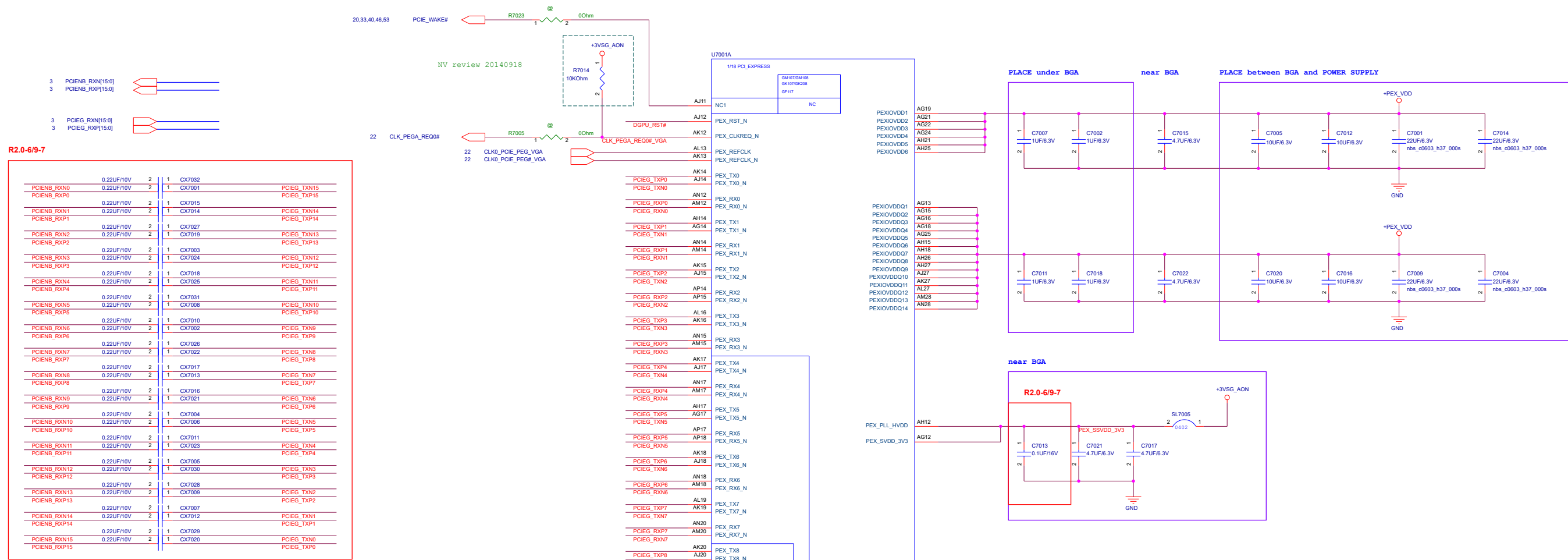
Bot (3809, 2558)



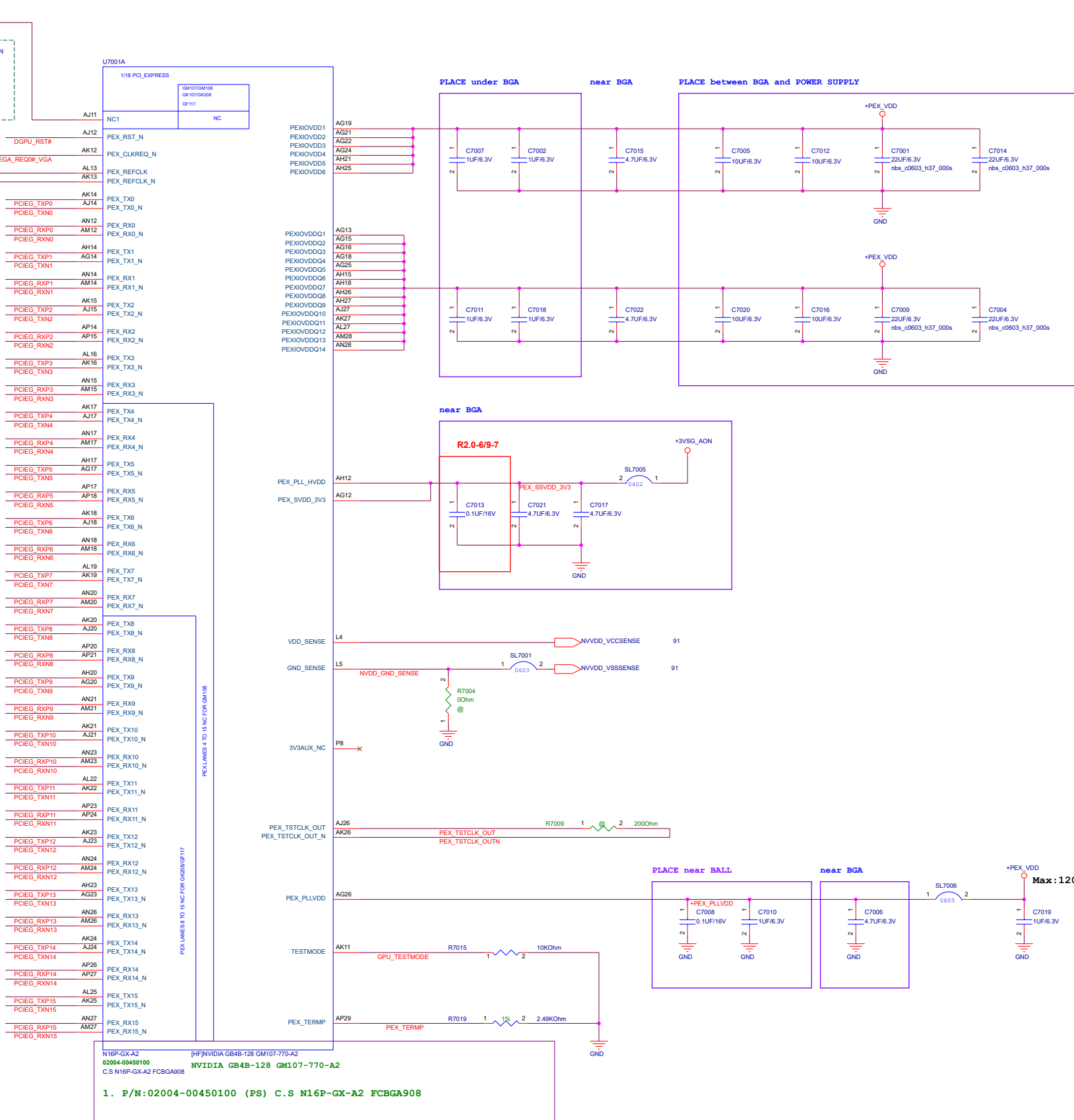
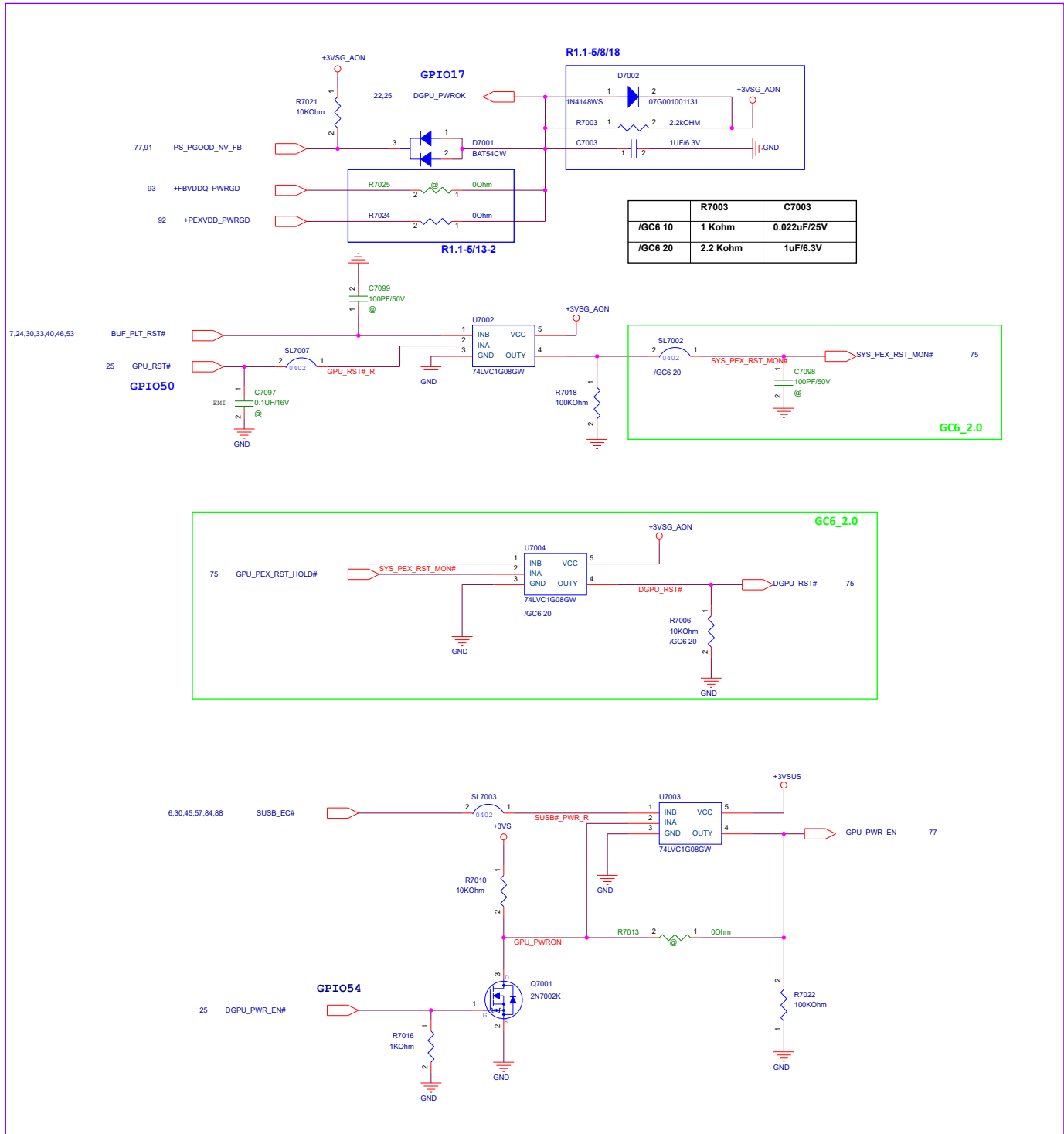
R1.1-24

<Variant Name>

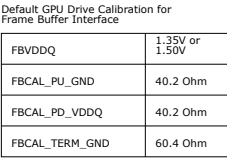
		Title : OTH_EMI	
ASUSTeK COMPUTER INC. NB1		Engineer: Mario_Jhu	
Size B	Project Name GL552VW		Rev 2.0
Date: Tuesday, June 23, 2015	Sheet	69 of 103	

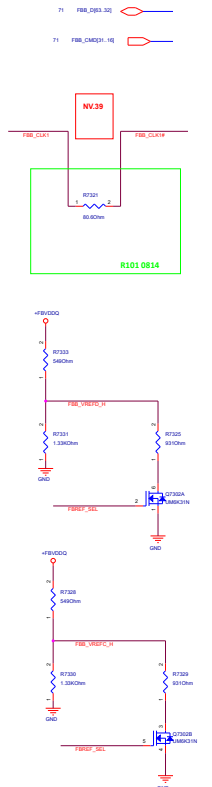
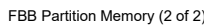
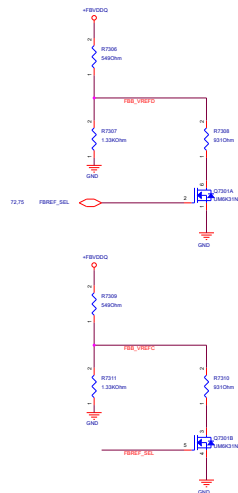


Control Signal from PCH



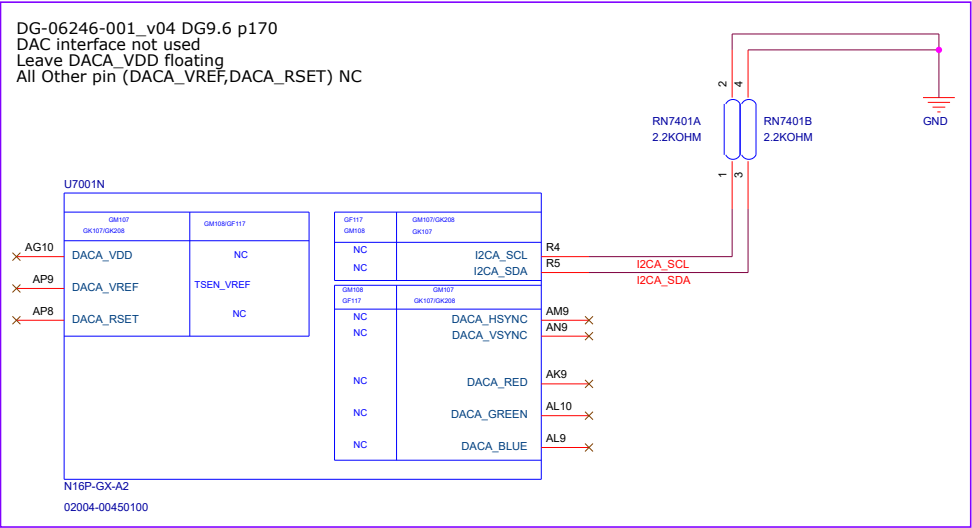
GPU MEMORY INTERFACE: PARTITION B



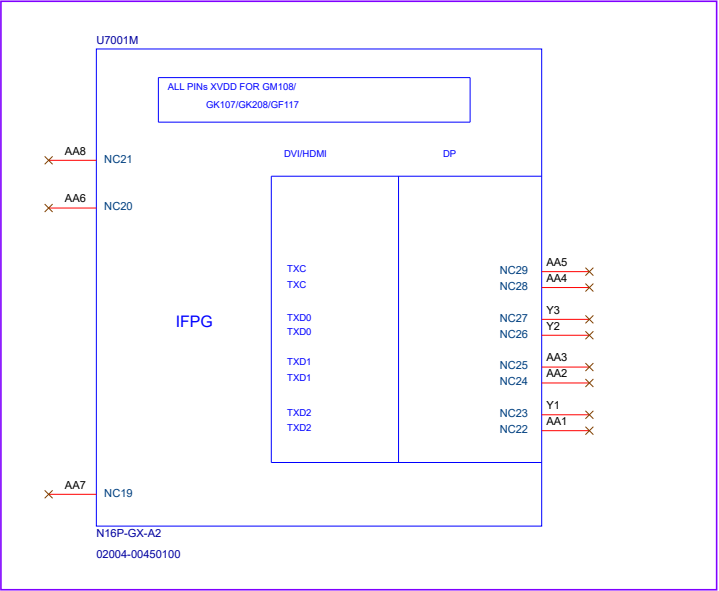
PR9310

CRT DAC_A

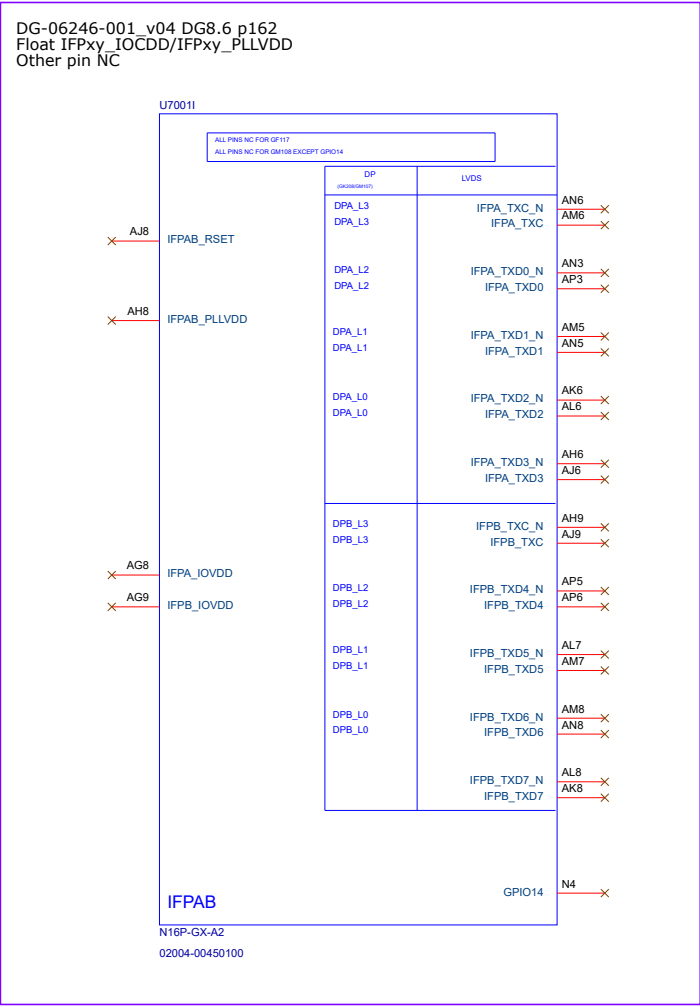
DG-06246-001_v02 DG10.2.1 p168
Unused I2C should be soft grounded or
PU 3.3V via 2.2kOhm



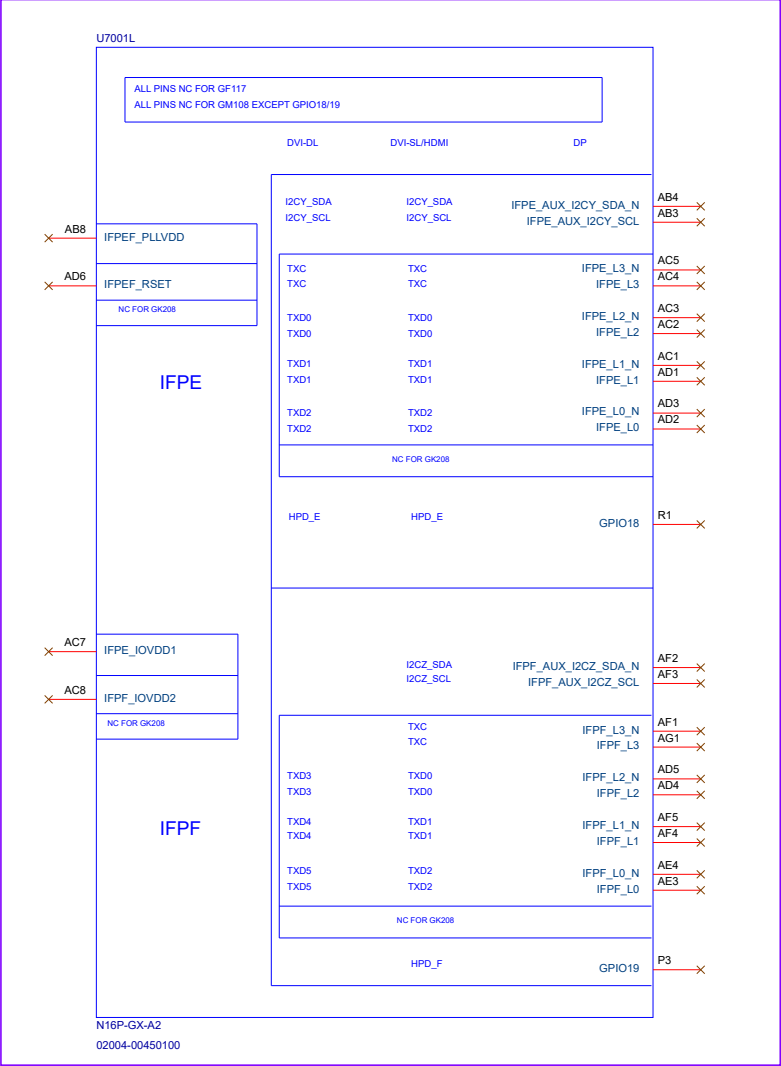
LVDS IFPG



LVDS IFPA/B

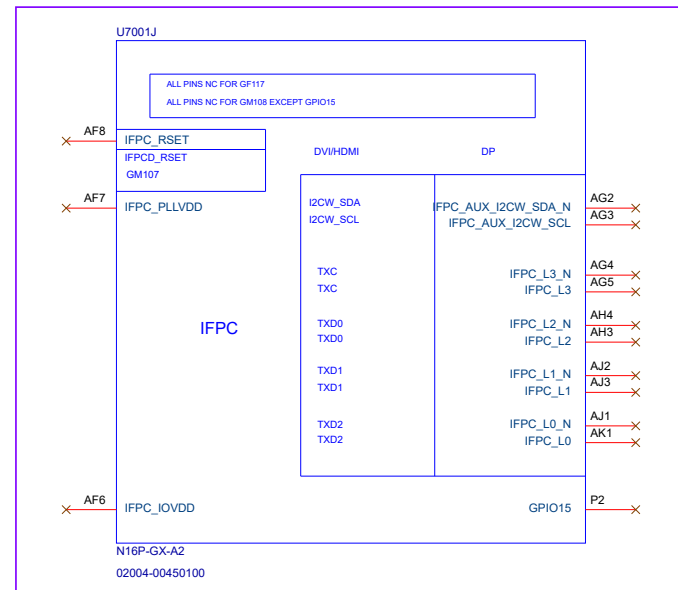


LVDS IFPE/F



<Variant Name>

DG-06246-001_v02 p157 DG8.6
 IPF not used
 IFPxy_IOCDD/IFPxy_PLLVDD 10K PD
 Other pin NC



U7001K
7/18 IFPD

ALL PINS NC FOR GF117
ALL PINS NC FOR GM108 EXCEPT GPD17

AN2 NC NC DVI/HDMI DP

AG7 IFPD_PLLVDD I2CX_SDA I2CX_SCL IFPD_AUX_I2CX_SDA_N IFPD_AUX_I2CX_SCL AK2 AK3 AK5 AK4 AL4 AL3 AM4 AM3 AM2 AM1 M6

IFPD TXC TXC IFPD_L3_N IFPD_L3 TXD0 TXD0 IFPD_L2_N IFPD_L2 TXD1 TXD1 IFPD_L1_N IFPD_L1 TXD2 TXD2 IFPD_L0_N IFPD_L0 GPIO17

AG6 IFPD_I0VDD

N16P-GX-A2
02004-00450100

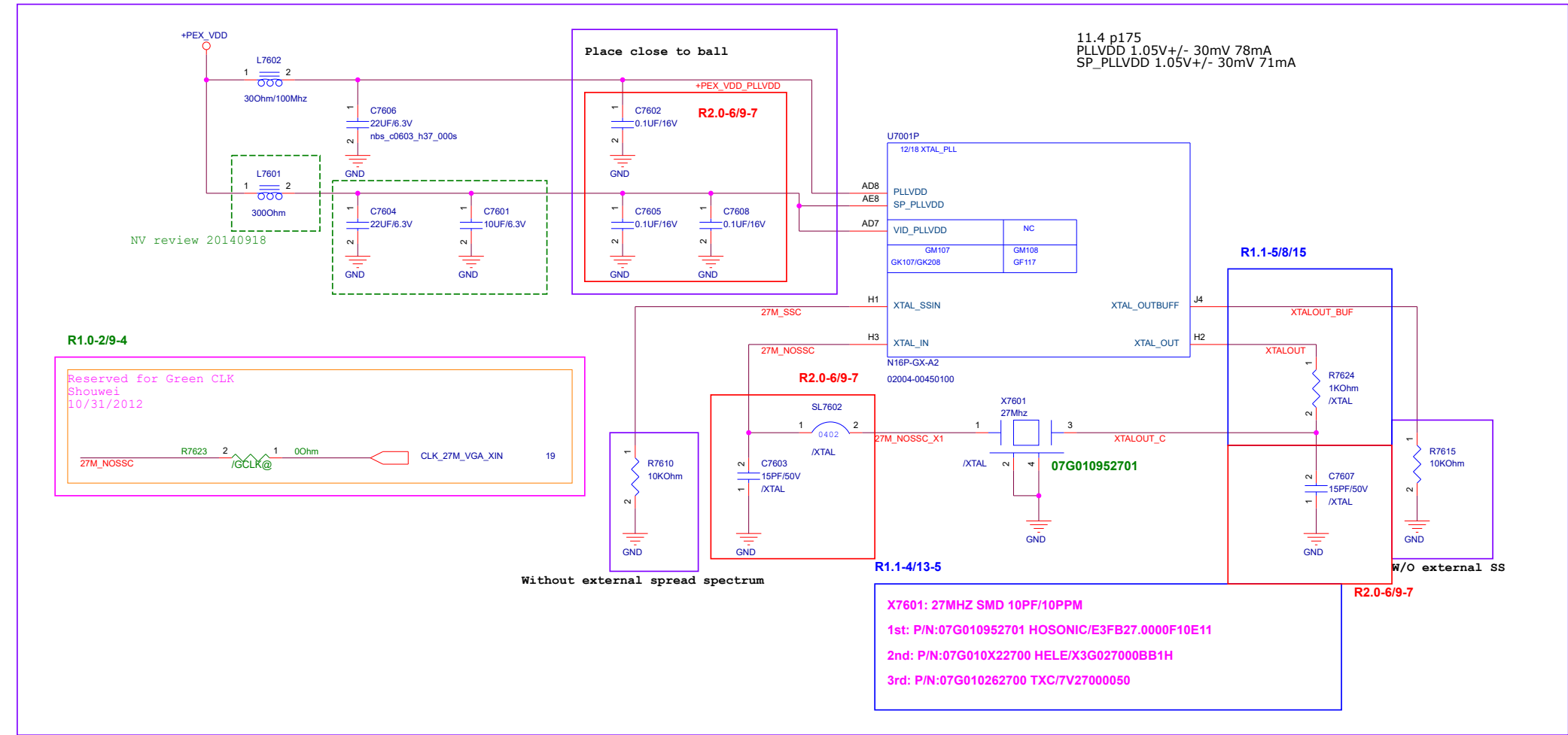
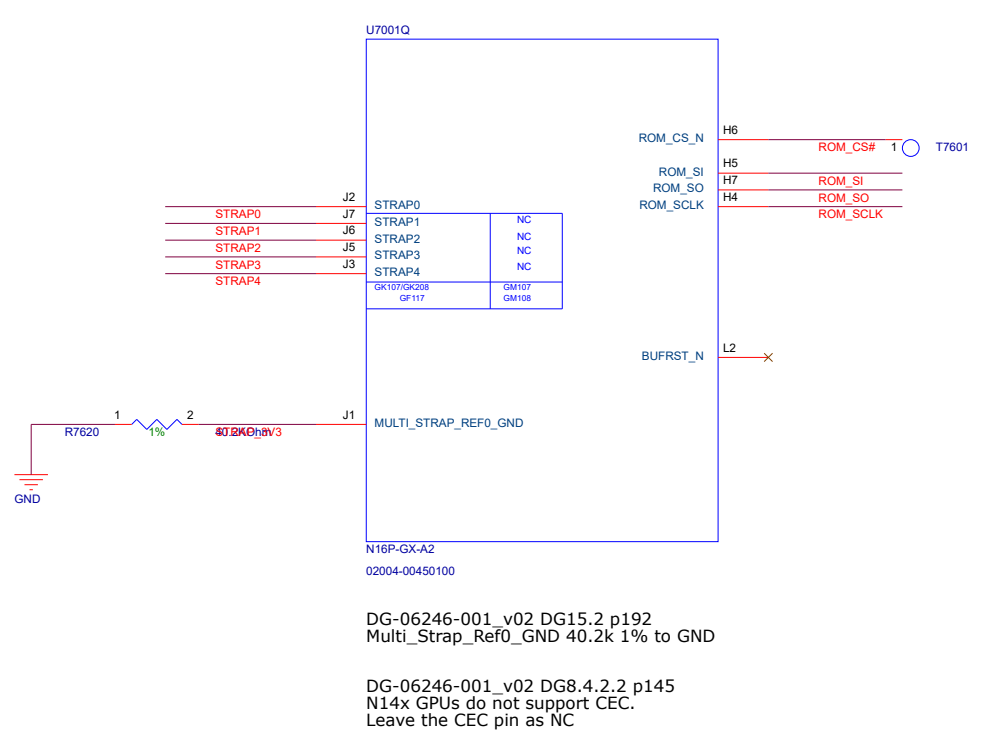
GPIO	I/O	ACTIVE	USAGE
0	OUT	Low	GC6_FBEN
1	OUT	High/Low	MEM_VDD_CTL
2	OUT	Low	LCD_BL_PWM
3	OUT	Low	LCD_VCC
4	OUT	Low	LCD_BLEN
5	OUT	High	3V3_MAIN_EN
6	IN	High	GPU_EVENT#
7	OUT	Low	3DVision
8	IN	High	SYS_PEX_RST_MON#
9	I/O	High	THERM_ALERT
10	OUT	Low	MEM_VREF_CTL
11	OUT		PWM_VID
12	IN	High	PWR_LEVEL
13	OUT	High	PSI
14	IN	Fig. 12-1	HPD_IFPAB
15	IN	Fig. 12-1	HPD_IFPC
16	IN	High	FRAME_LOCK#
17		Fig. 12-1	HPF_IFPD
18	IN	Fig. 12-1	HPD_IFPE
19	IN	Fig. 12-1	HPD_IPFFB
20			Reserved
21	OUT	High	GPU_PEX_RST_HOLD#
OVERT	I/O	High	OVERT

Temp.	Resistor
75	2kOhm
90	7.5kOhm
100	10.5kOhm
105	14kOhm
110	18.7kOhm

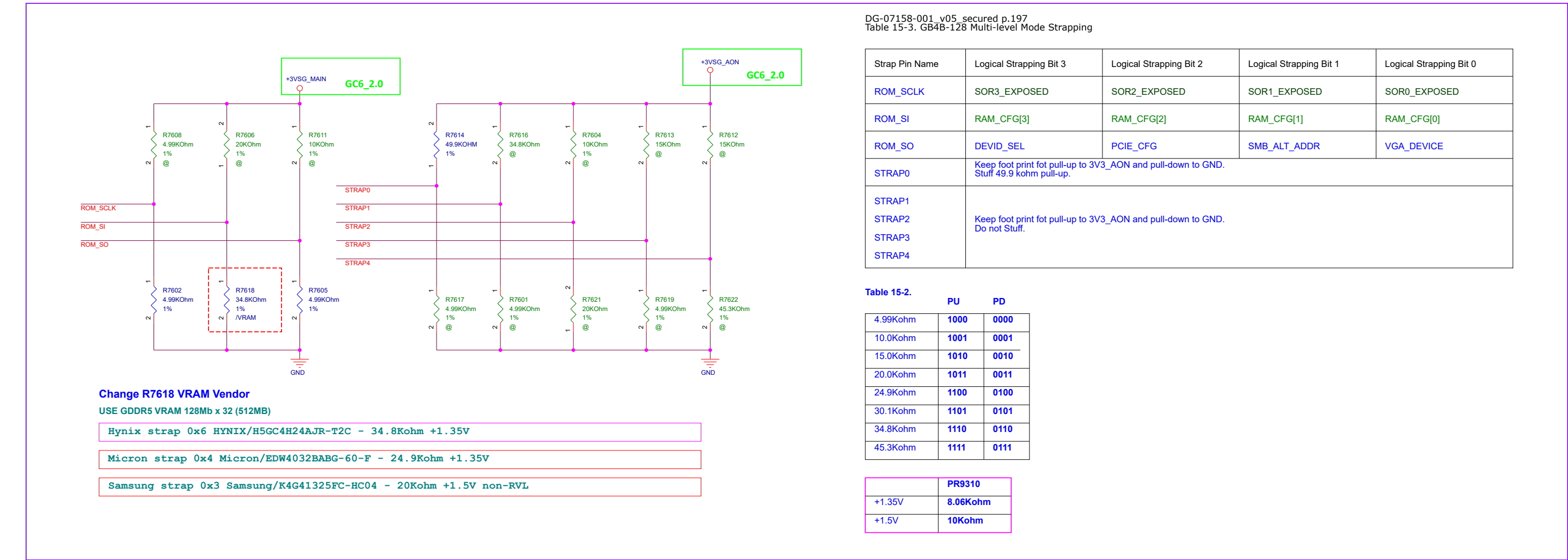
Thermal Sensor

The schematic diagram shows the Thermal Sensor circuit. The I2C interface is connected to the NCT7717U (U7502) sensor. The SCL pin (1) is connected to +3VS through R7508 (10.5kOhm). The SDA pin (5) is connected to +3VS through R7513 (2.2kOhm). The GND pin (2) is connected to ground. The VDD pin (4) is connected to +3VS through R7509 (2.2kOhm) and to a 0.1uF/16V capacitor (C7501). The sensor is also connected to the VGA_ALERT_P# signal through R7511 (0Ohm) and to the DGPU_PD# signal through R7512 (0Ohm).

XTAL

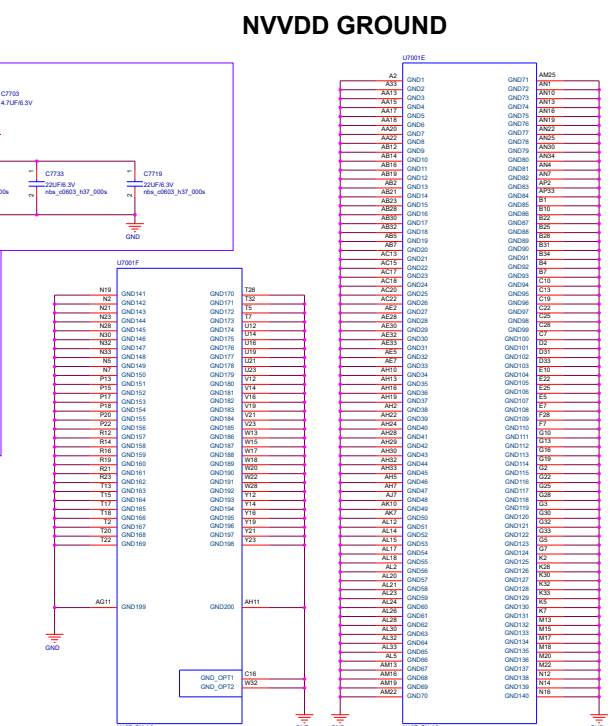
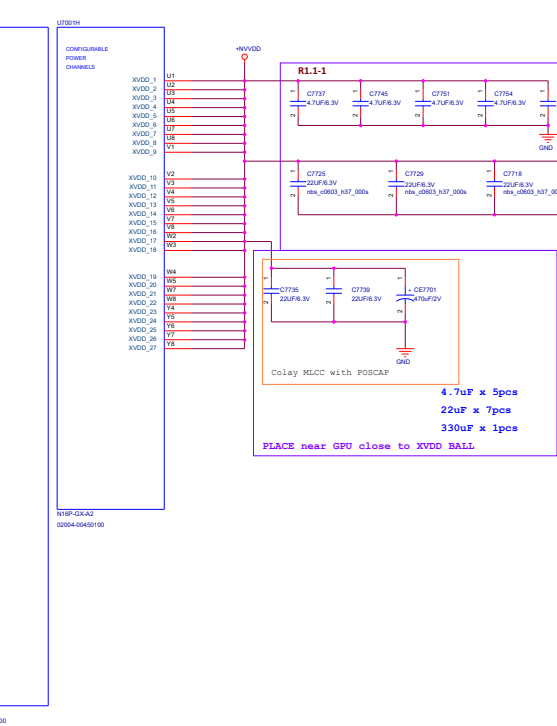
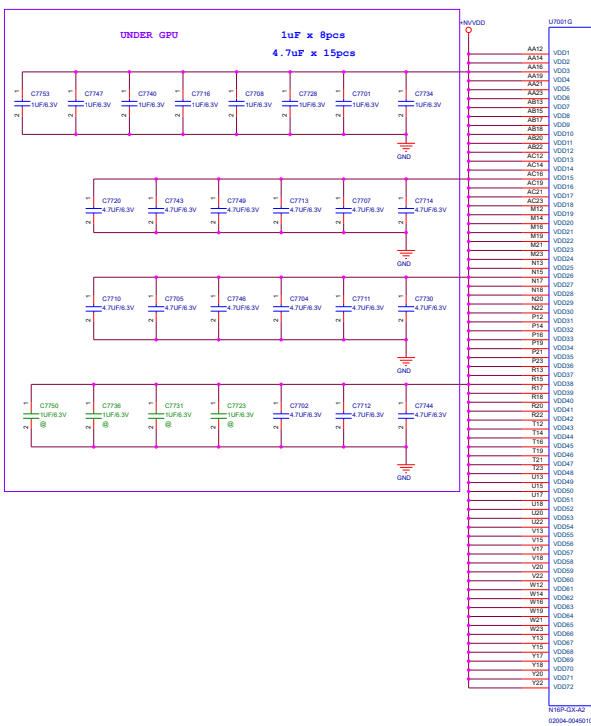


STRAPPING OPTIONS for N16P

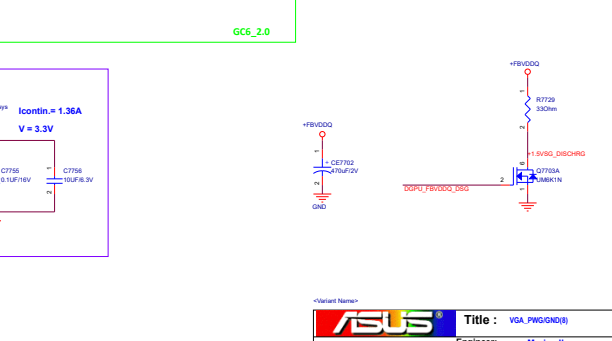
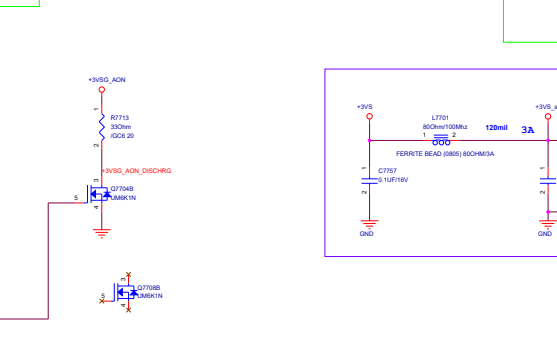
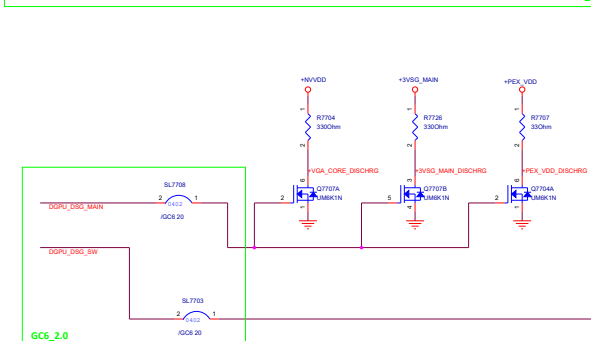
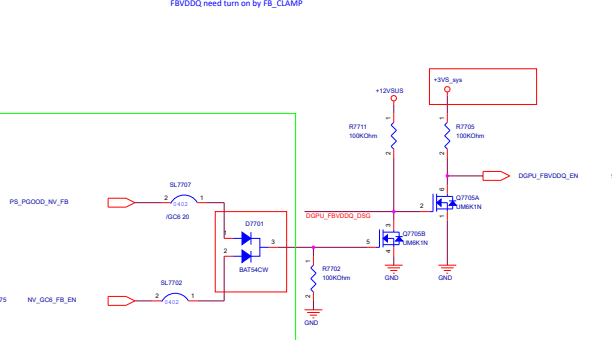
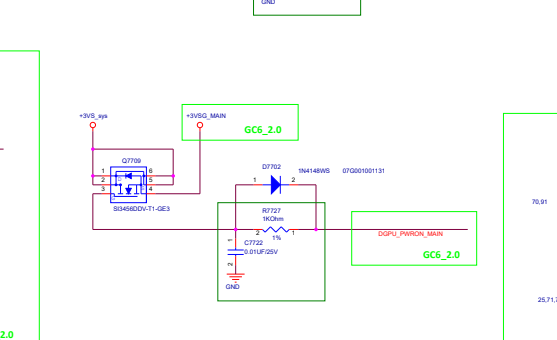
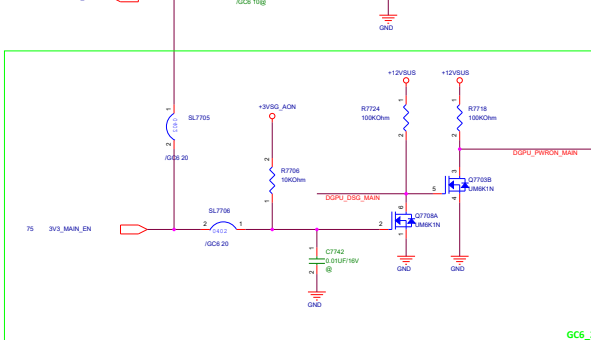
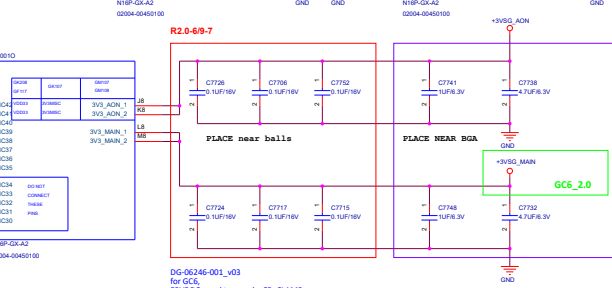
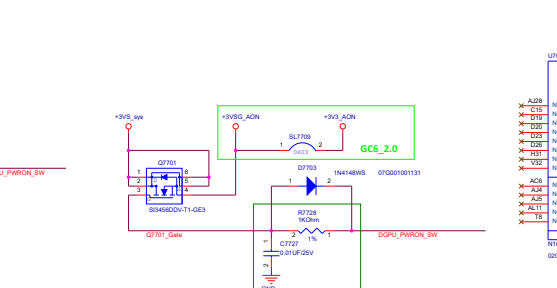
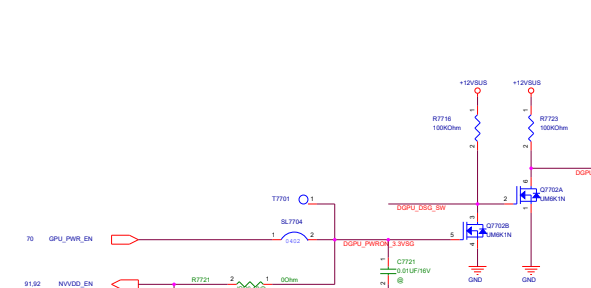


<Variant Name>

NVDD POWER AND DECOUPLING



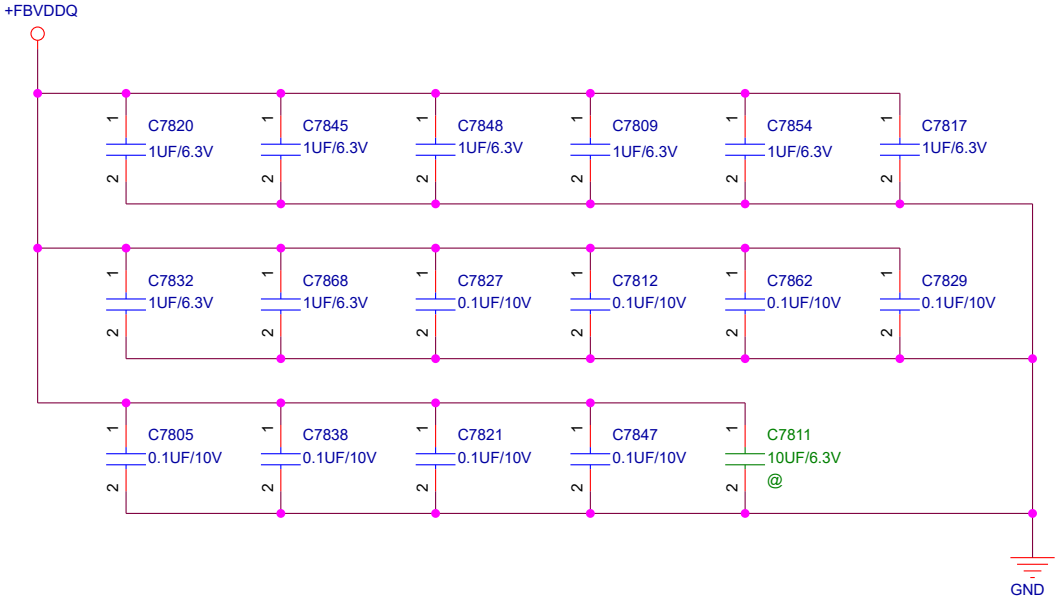
NVDD GROUND



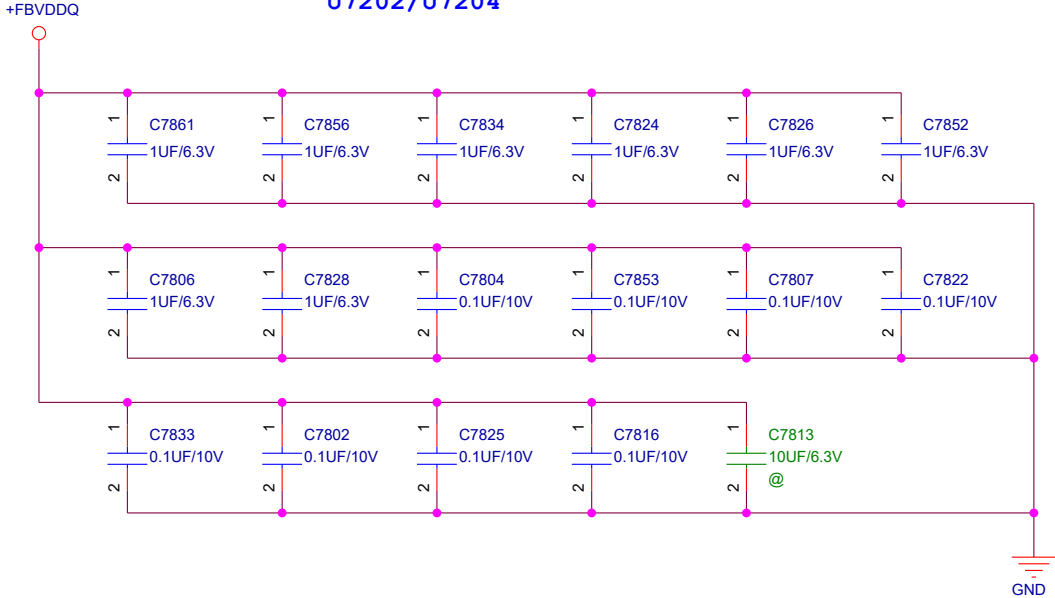
Location is close to DRAM for clamshell mode

0.1uF X8
1uF X 8

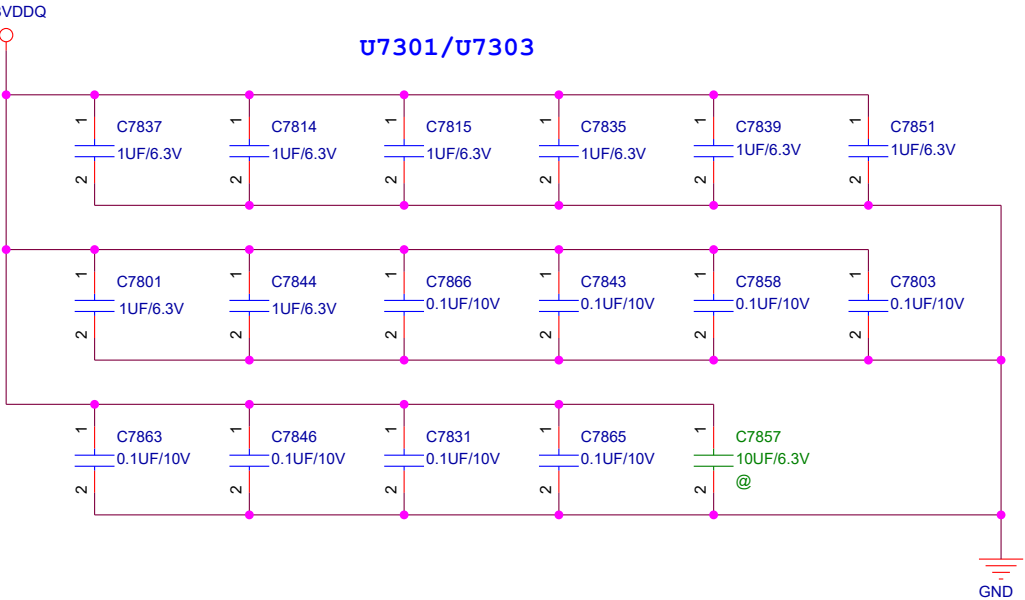
U7201/U7203



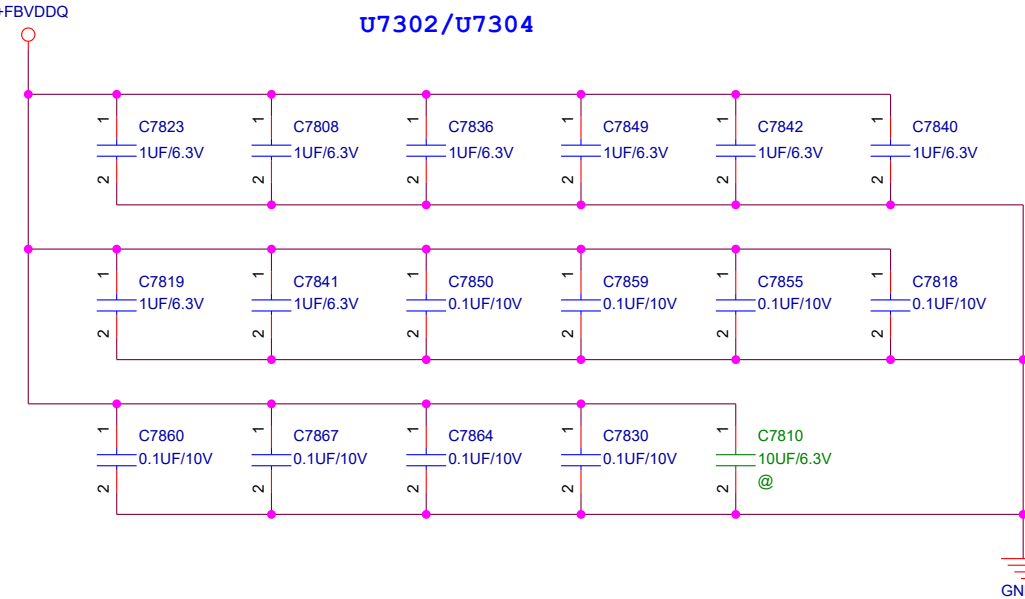
U7202/U7204




U7301/U7303



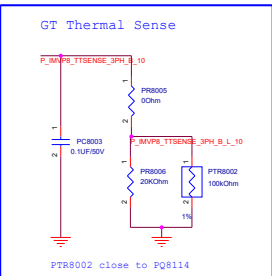
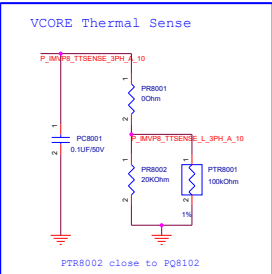
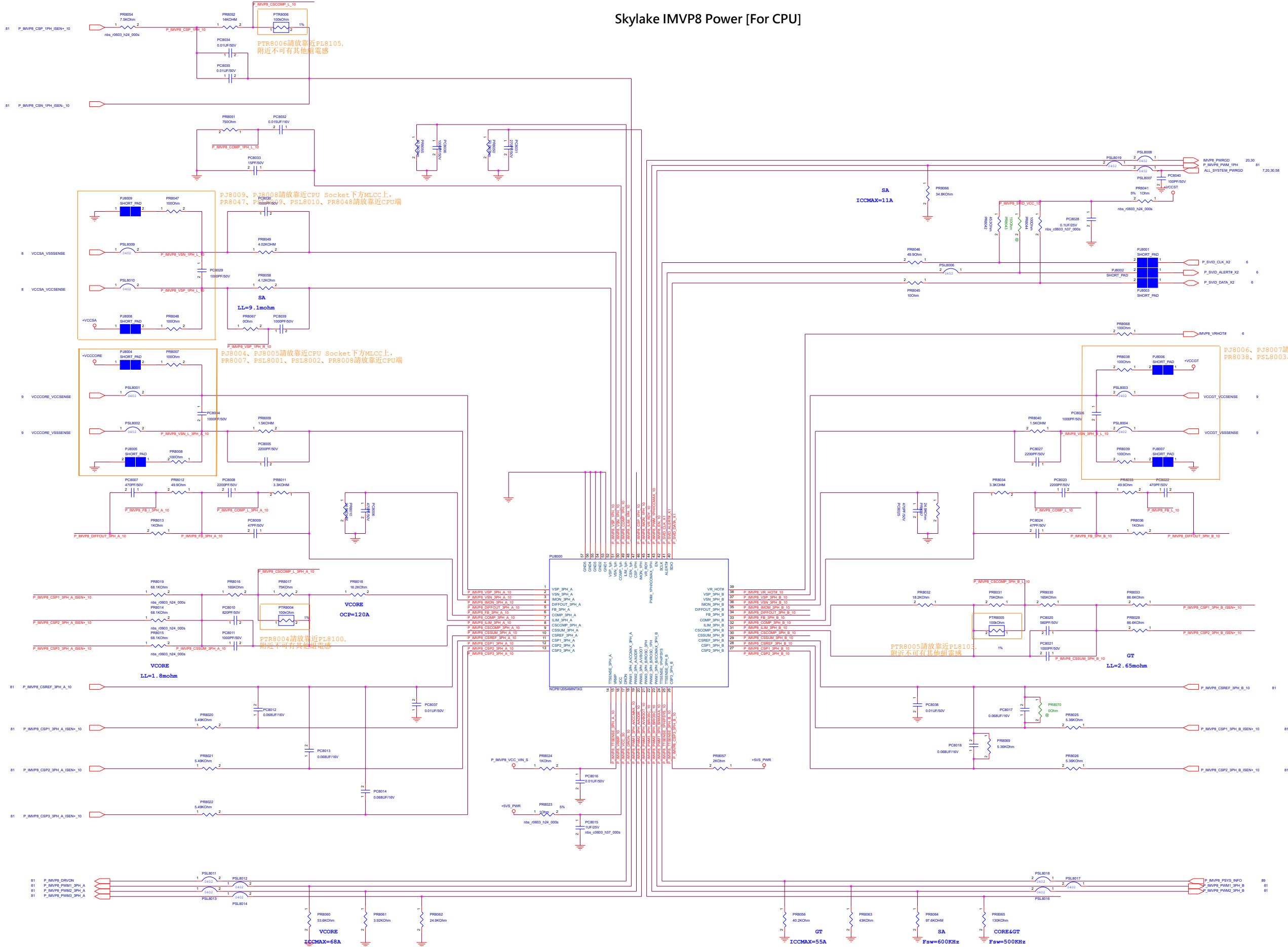
U7302/U7304



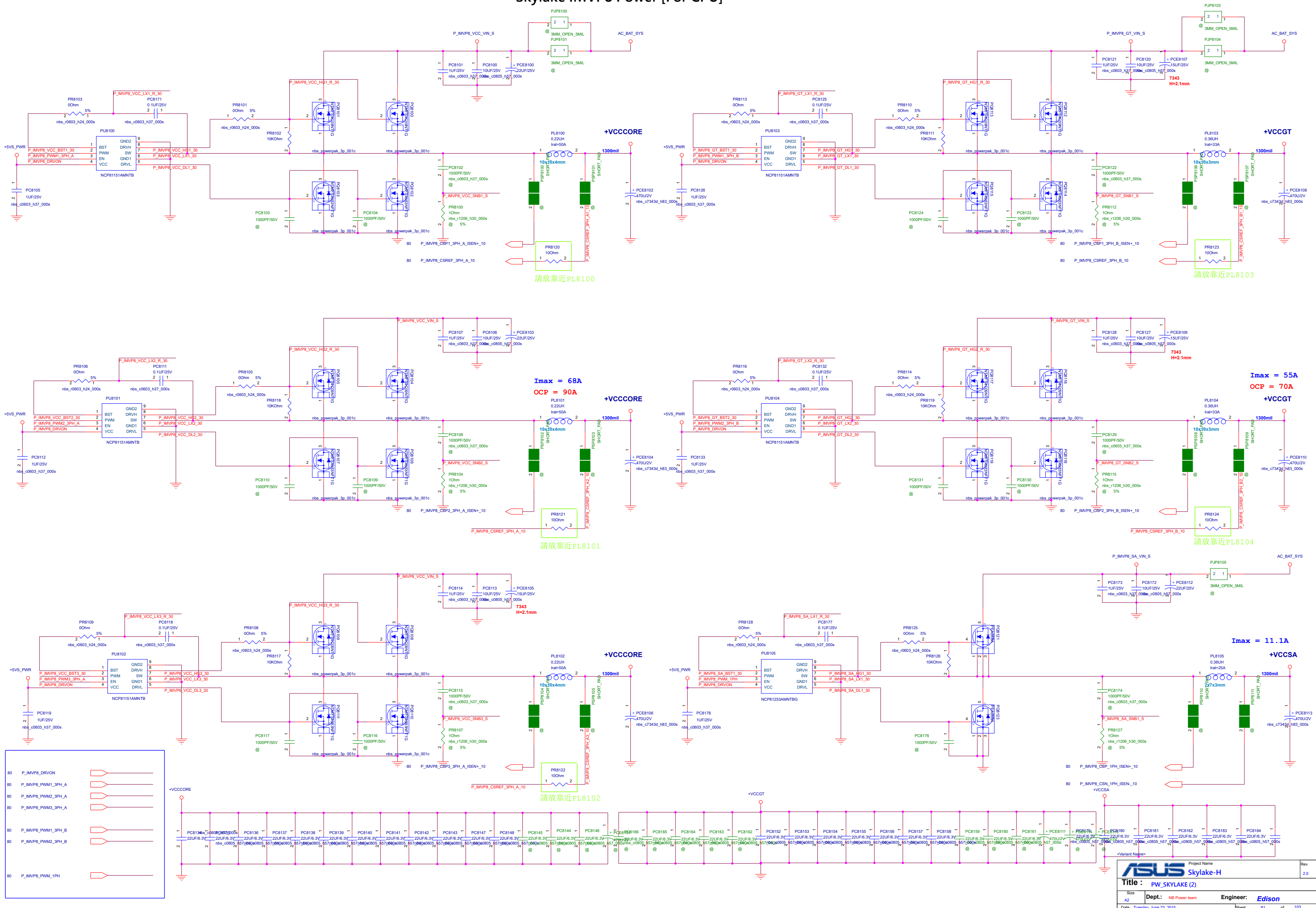
<Variant Name>

		Title : VRAM CAP	
ASUSTeK COMPUTER INC. NB1		Engineer: Mario_Jhu	
Size B	Project Name GL552VW		Rev 2.0
Date: Tuesday, June 23, 2015		Sheet 78 of 103	

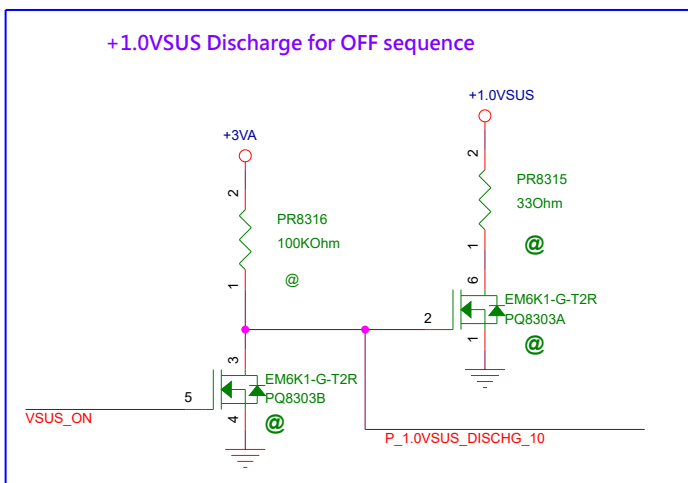
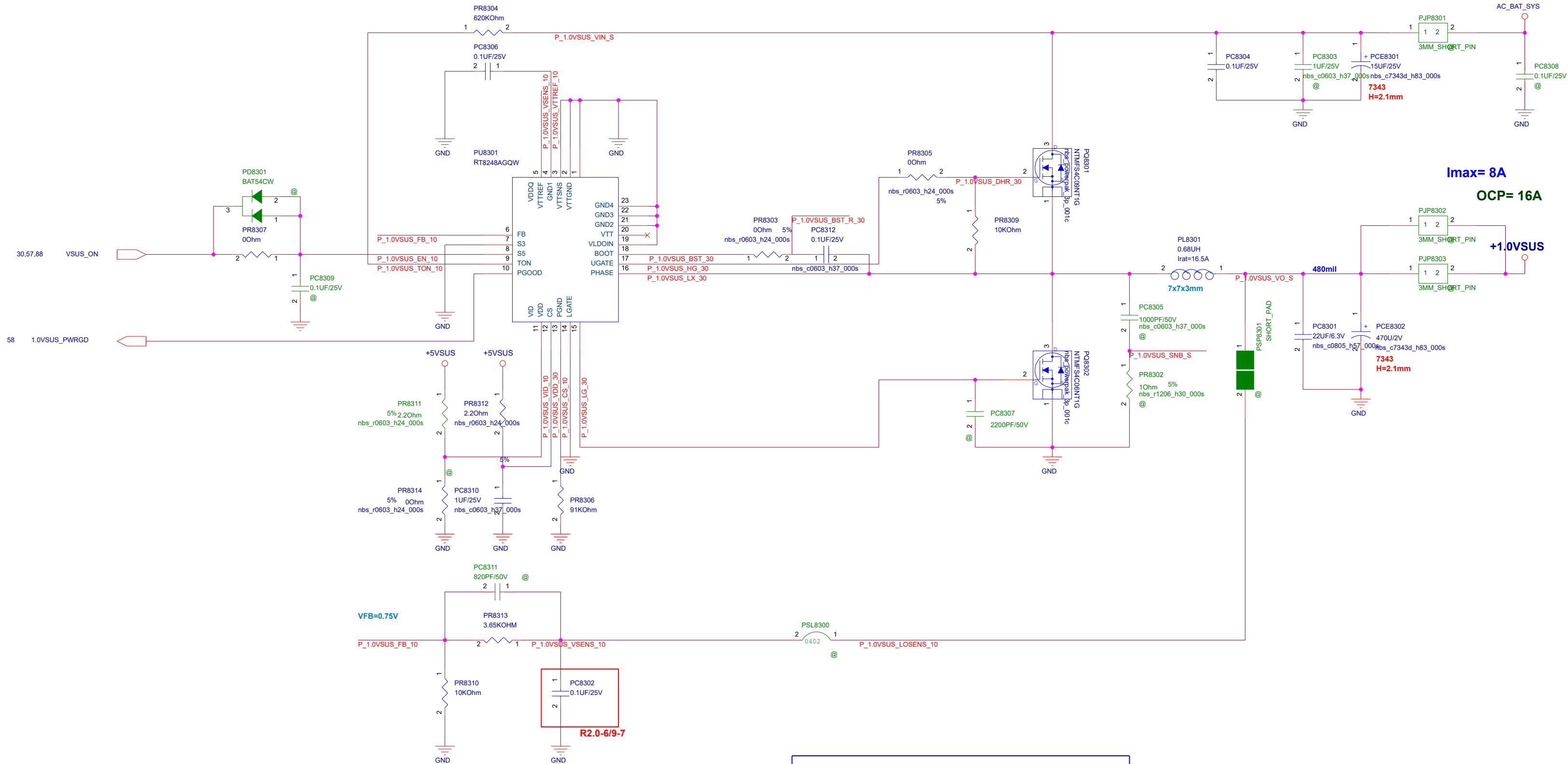
Skylake IMVP8 Power [For CPU]



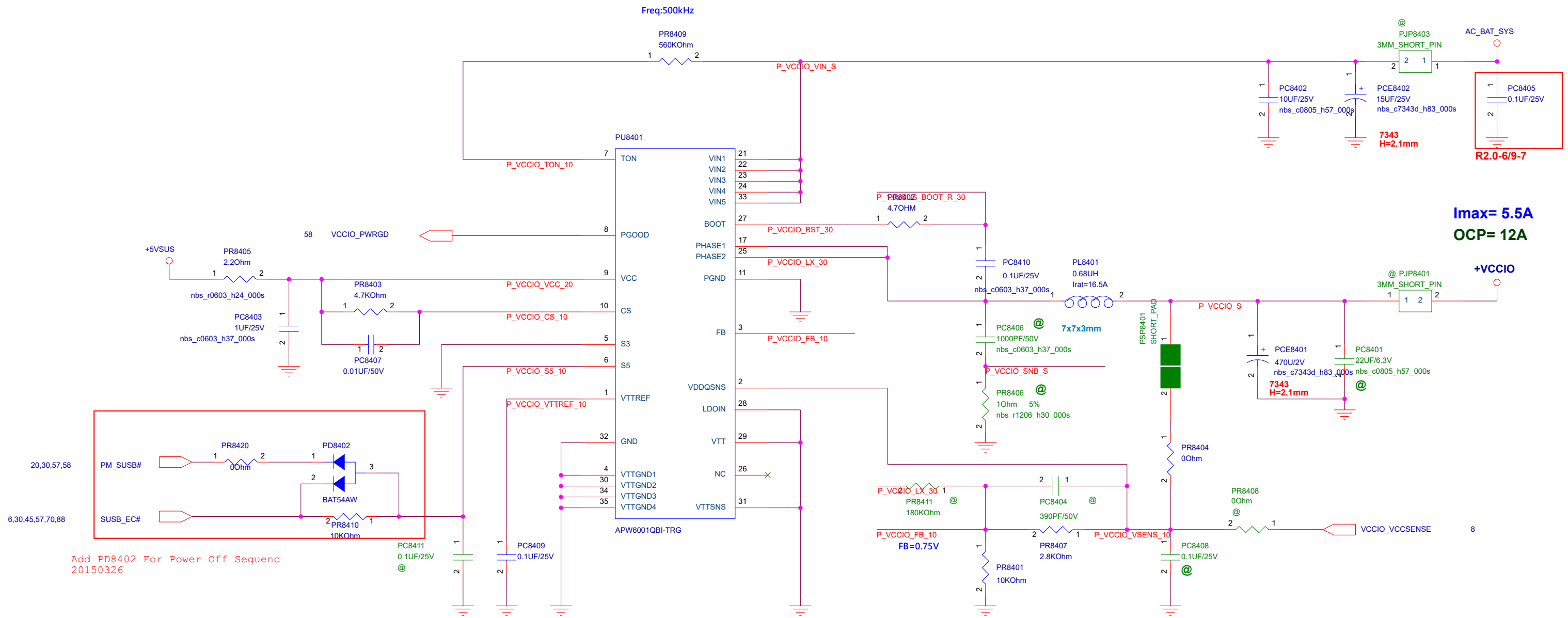
Skylake IMVP8 Power [For CPU]



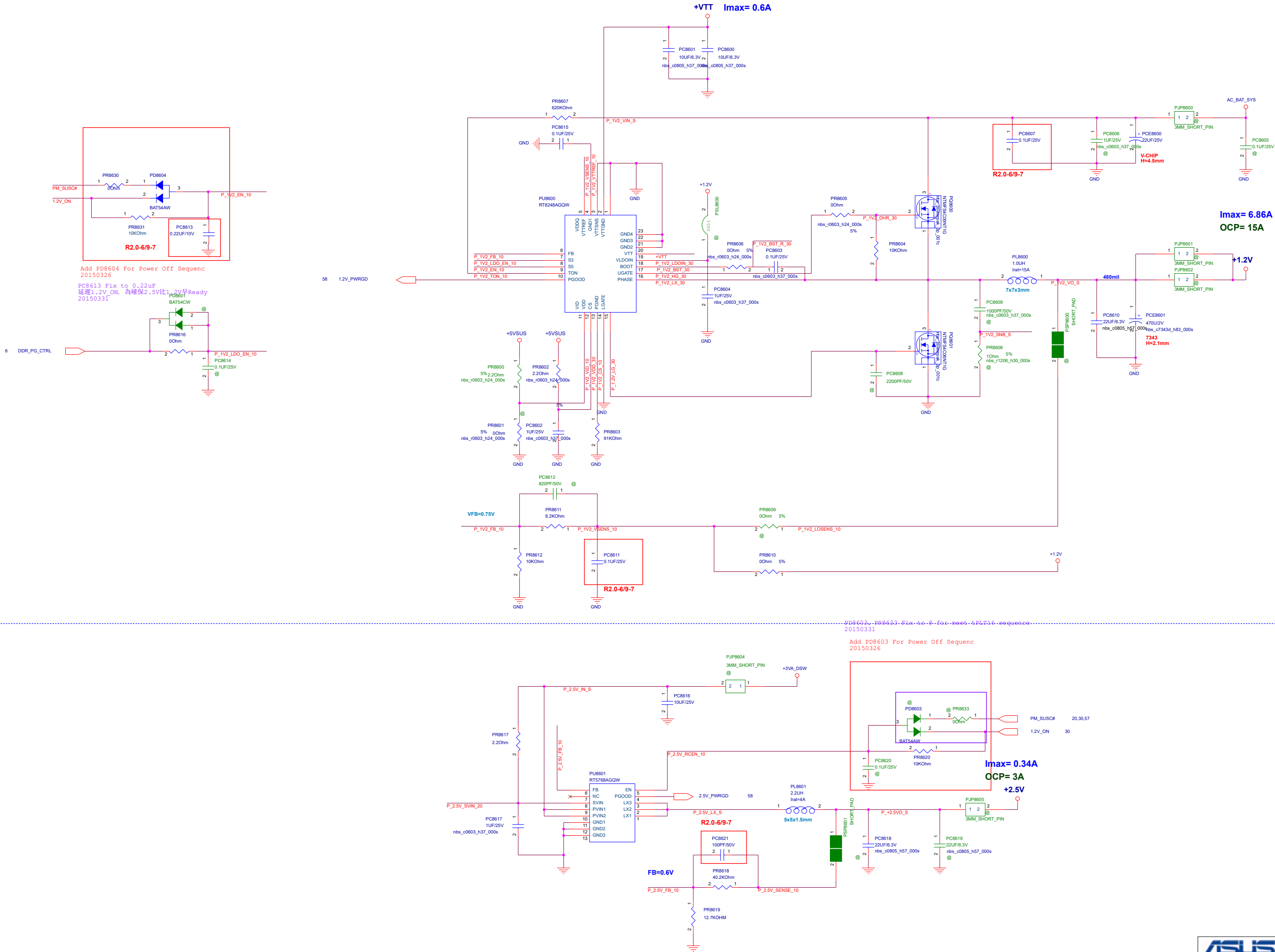
+1.0VSUS [For PCH]



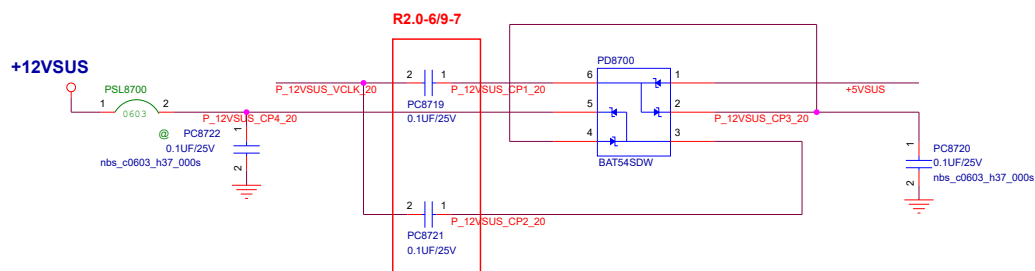
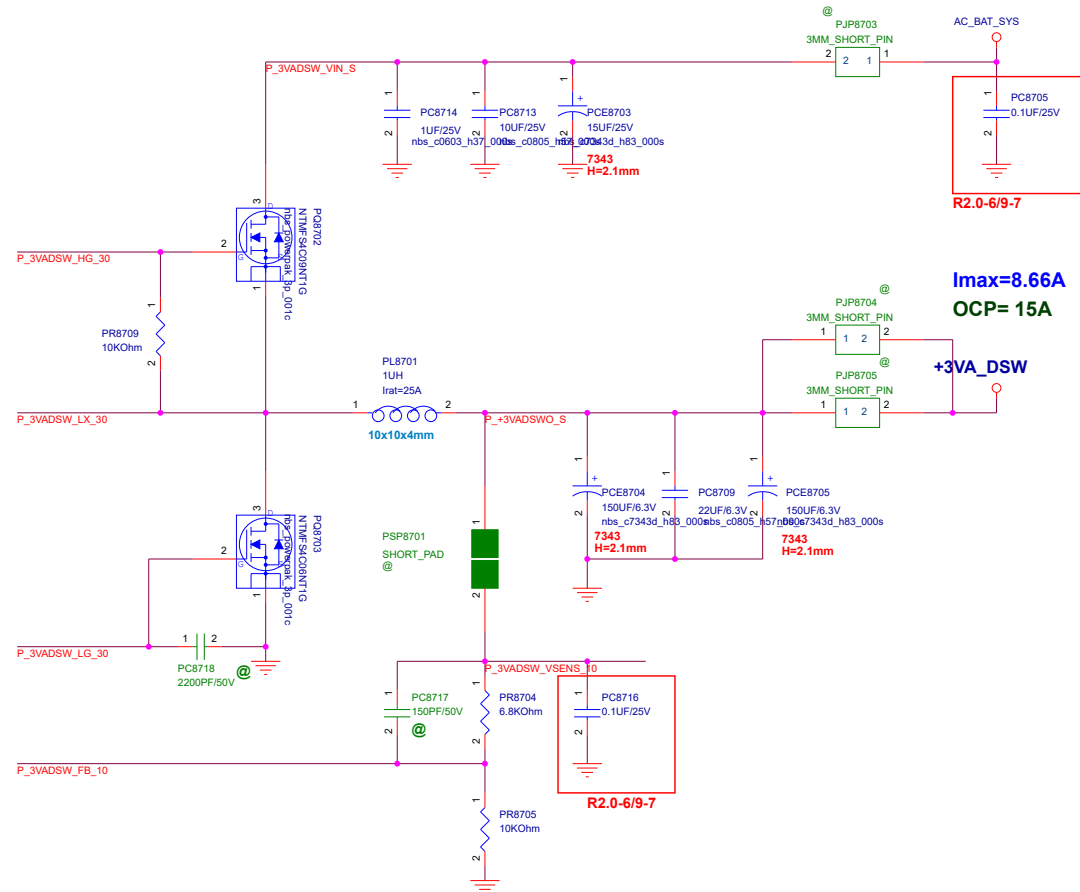
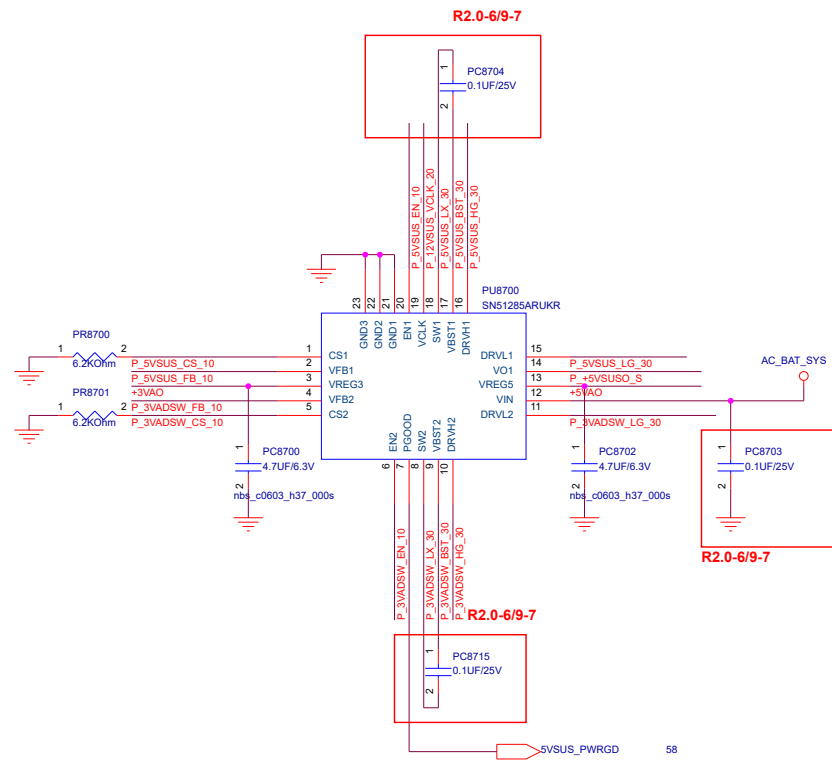
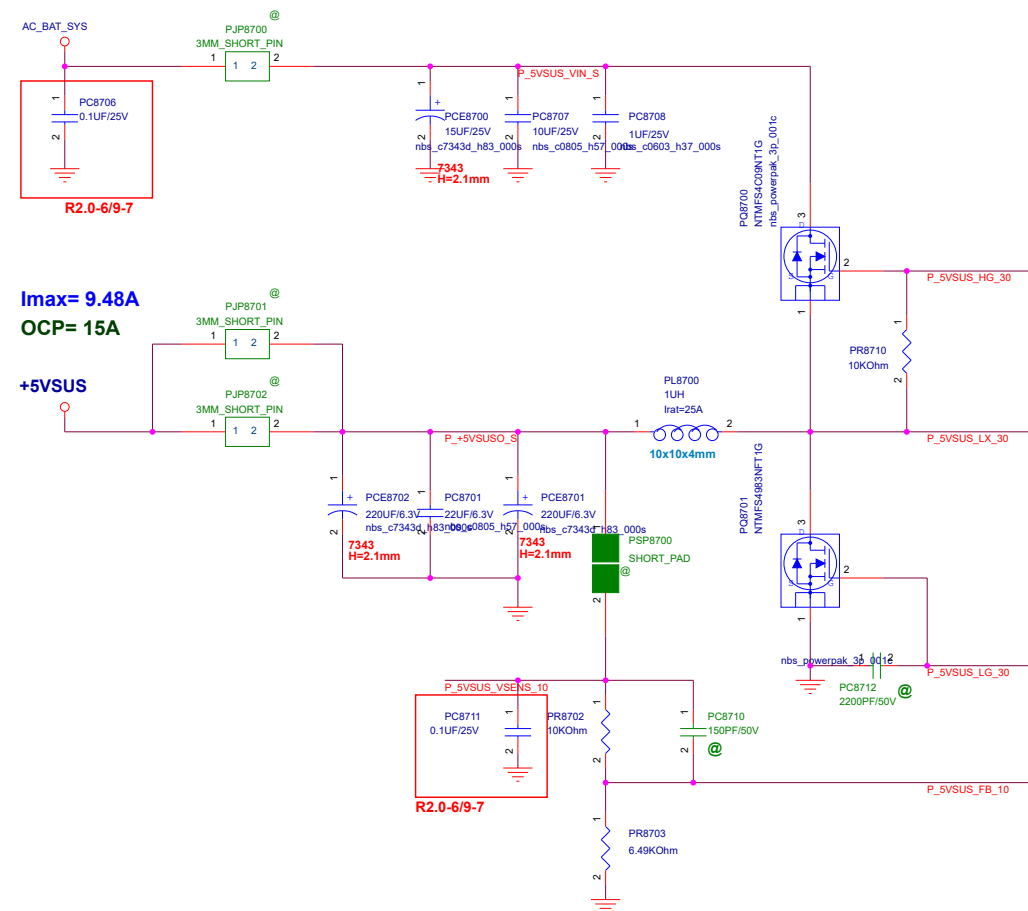
+VCCIO [For CPU]



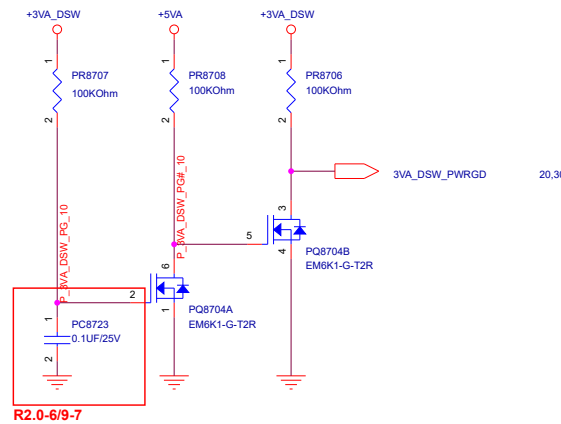
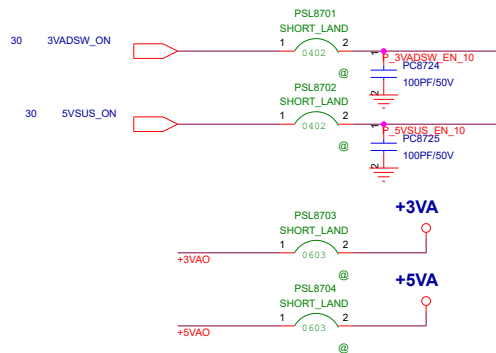
+1.2V / VTT / 2.5V[For Memory]



+3VA_DSW / +5VSUS [System Power]

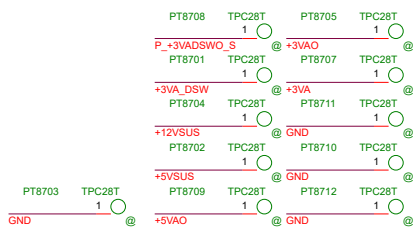


請 check 整份線路 +12VSUS total 並聯對地電阻不得小於10kOhm



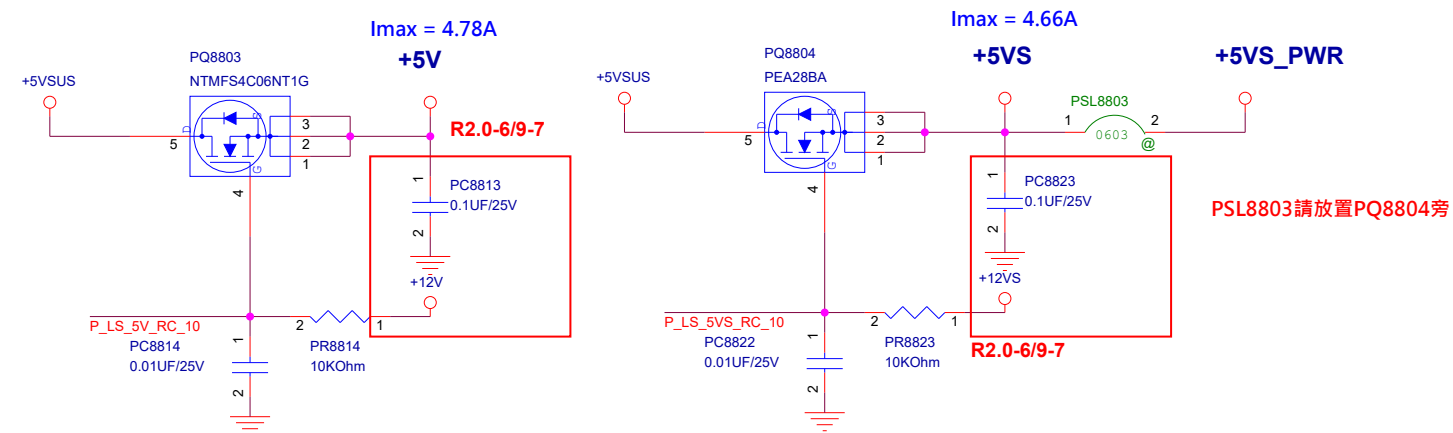
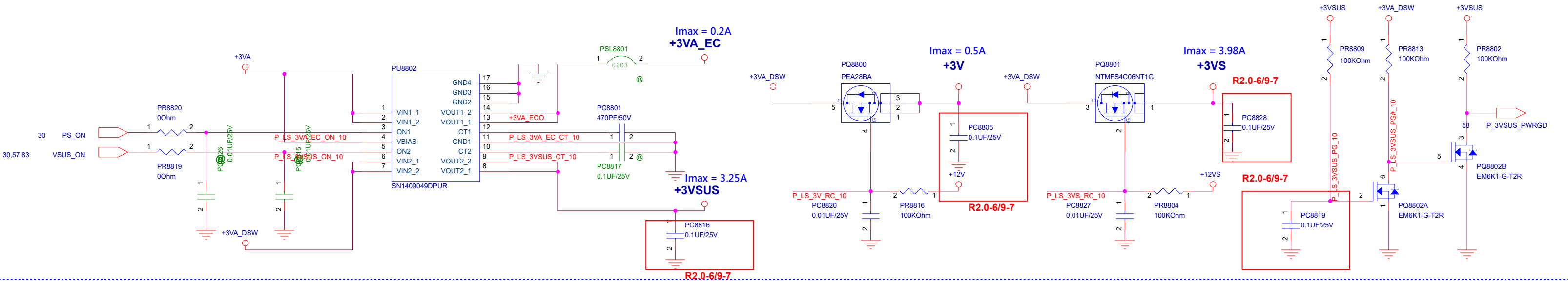
Adaptor Mode (IMVP8)							
	S0	CS	S3	DS3	S4	S5	S5 with USB Charger+
PS_ON	1	-	1	-	1	-	1
3VADSW_ON	1	-	1	-	1	-	1
3VSUS_ON	1	-	1	-	0	-	0
5VSUS_ON	1	-	1	-	1	-	1
1.35V_ON	1	-	1	-	0	-	0
SUSC_EC#	1	-	1	-	0	-	0
SUSB_EC#	1	-	0	-	0	-	0

Battery Mode (IMVP8)							
	S0	CS	S3	DS3	S4	S5	S5 with USB Charger+
PS_ON	1	-	-	1	0	0	1
3VADSW_ON	1	-	-	1	0	0	0
3VSUS_ON	1	-	-	0	0	0	0
5VSUS_ON	1	-	-	1	0	0	1
1.35V_ON	1	-	-	1	0	0	0
SUSC_EC#	1	-	-	0	0	0	0
SUSB_EC#	1	-	-	0	0	0	0



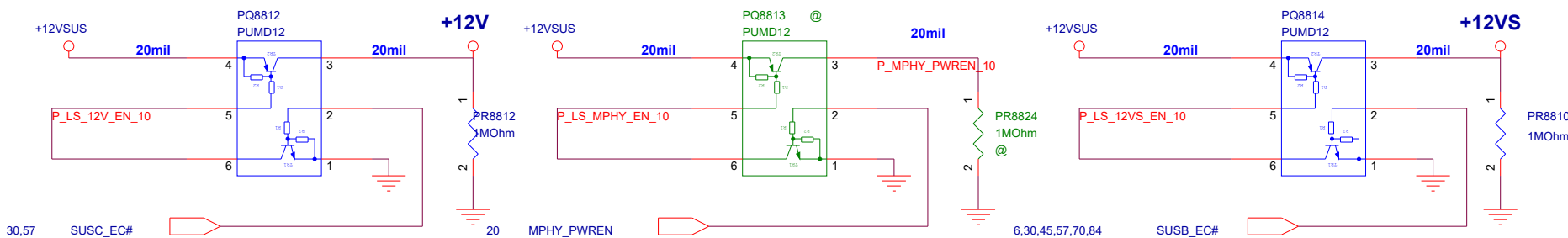
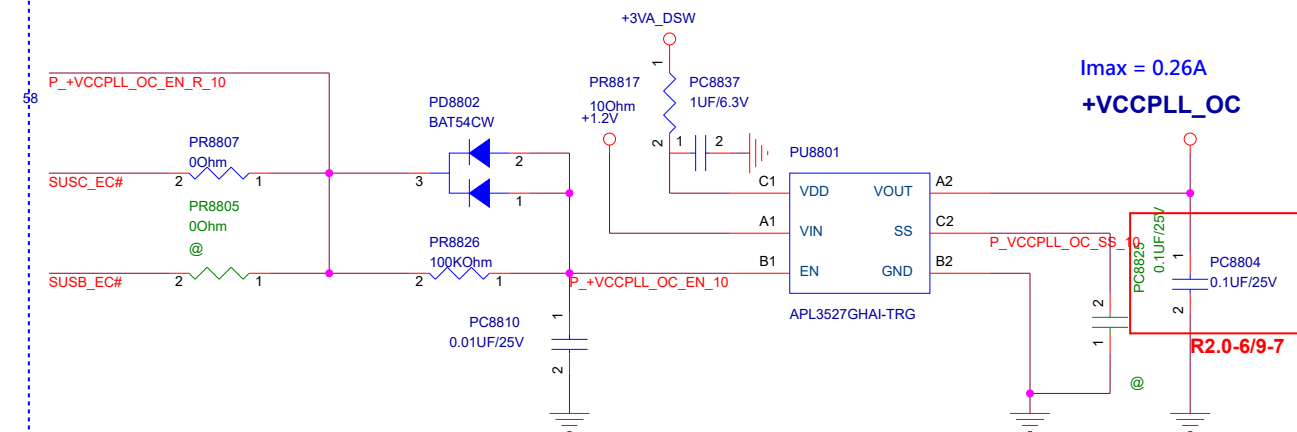
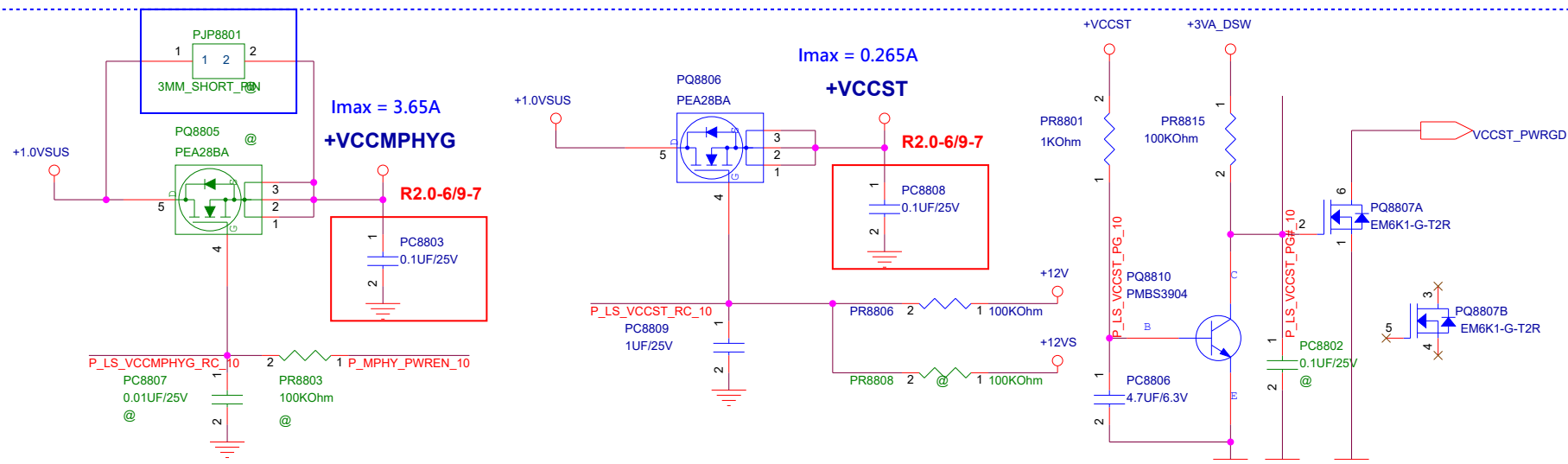
Main Board

Load Switch



PSL8803請放置PQ8804旁

R1.1-4/13-5 必上件



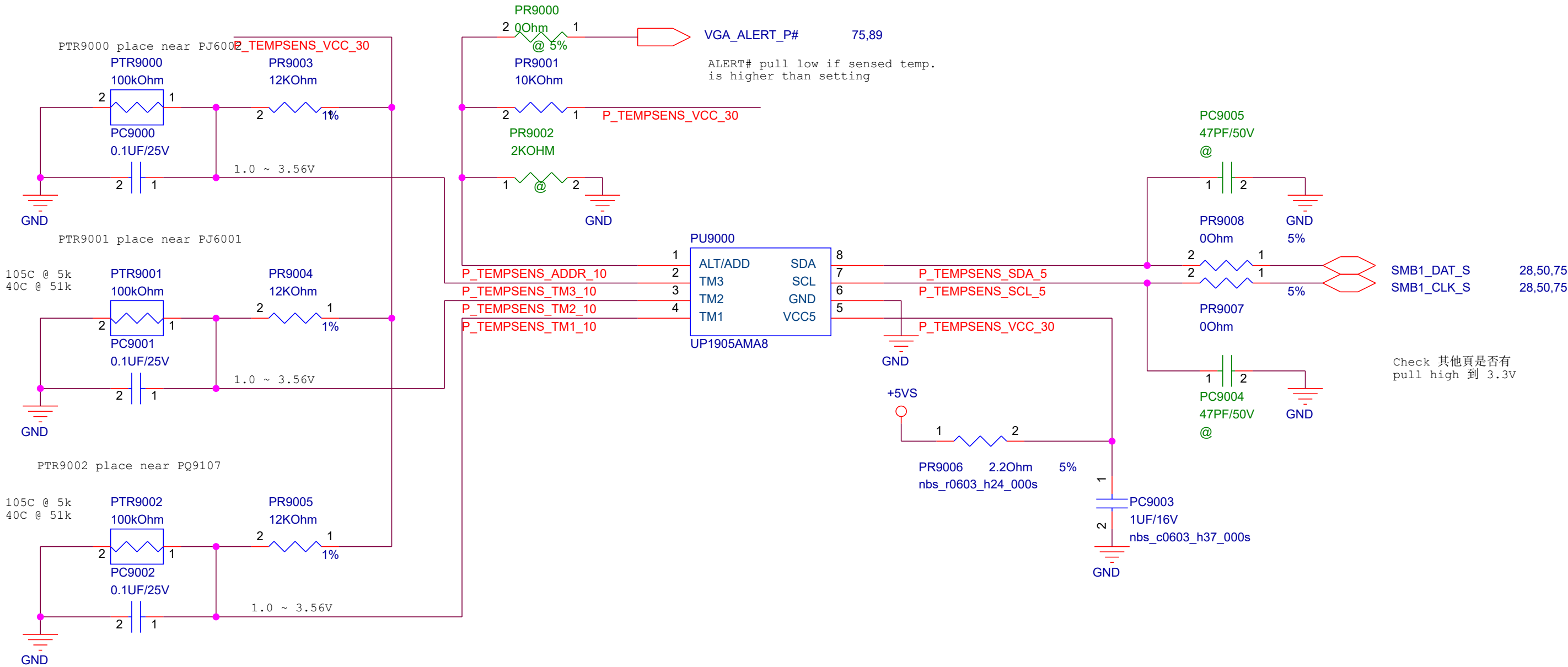
Address Selection Table

Address	0x7E	0x7C	0x7A	0x78	0x76	0x74	0x72	0x70
PR9404	10k	1.5k	2k	3.6k	3.9k	4.3k	5.1k	6k
PR9405	Open	8.2k	6.2k	6.8k	4.7k	3.6k	2.7k	2k

Register Address

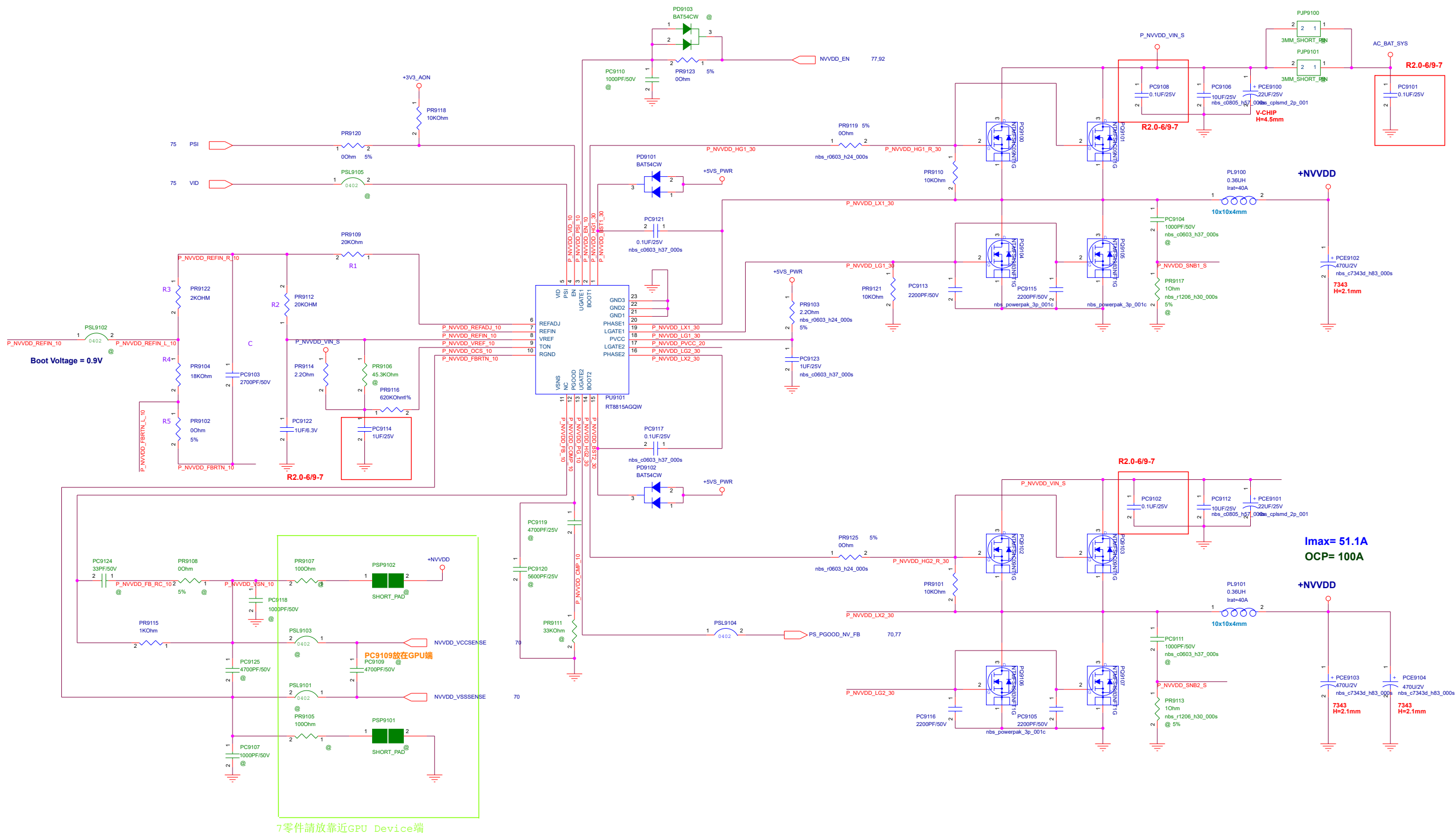
Address	0x00	0x01	0x02	0x03	0x04	0x05	0x06
R/W	W	W	W	R	R	R	R
Function	Temp. alert threshold setting			Sensed temp. data		bit 4 = 0 bit 5 = 0 bit 6 = 0 When ALERT# assert	

Main Board

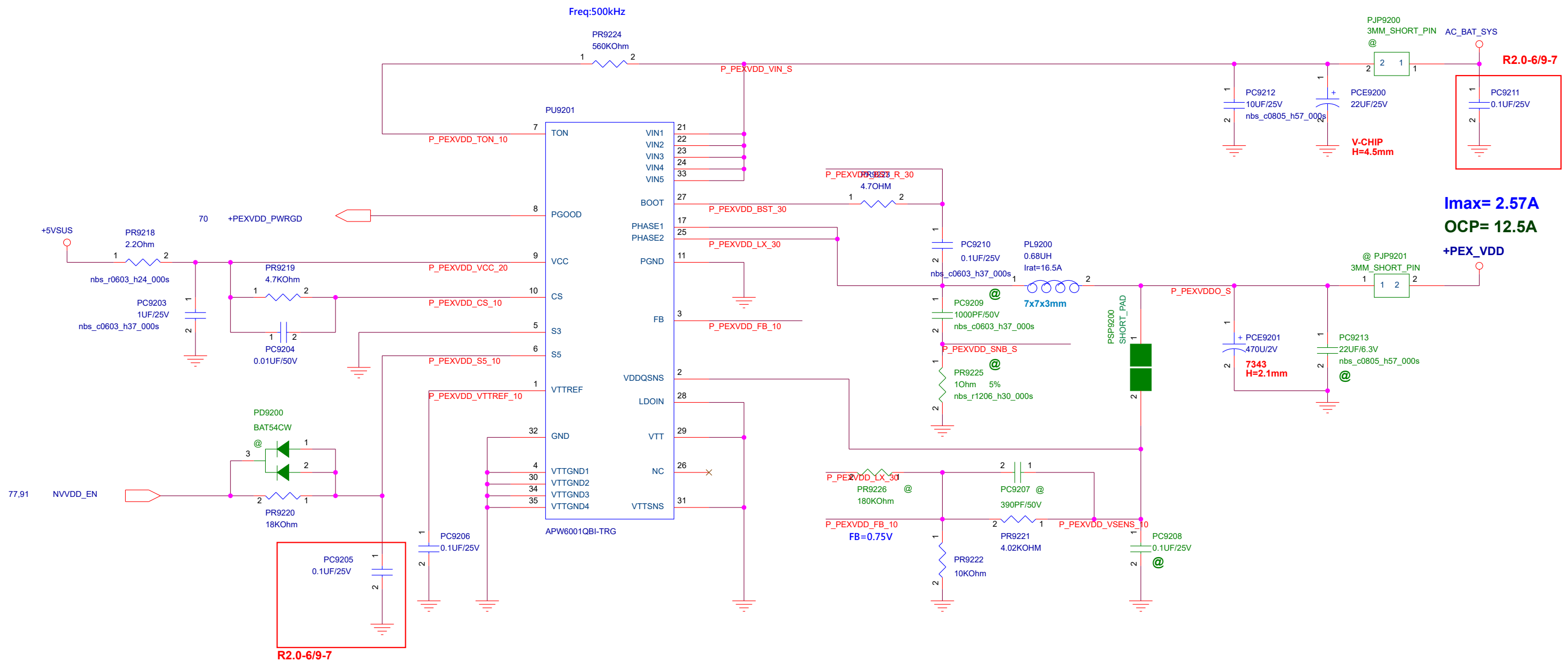


+ NVVDD [For DGPU]

PWM-VID Spec		
	Config A	Config B
R1 (kohm)	39	20
R2 (kohm)	39	20
R3 (kohm)	1.5	2
R4 (kohm)	30	18
R5 (kohm)	1.5	0
C (nF)	1.5	2.7

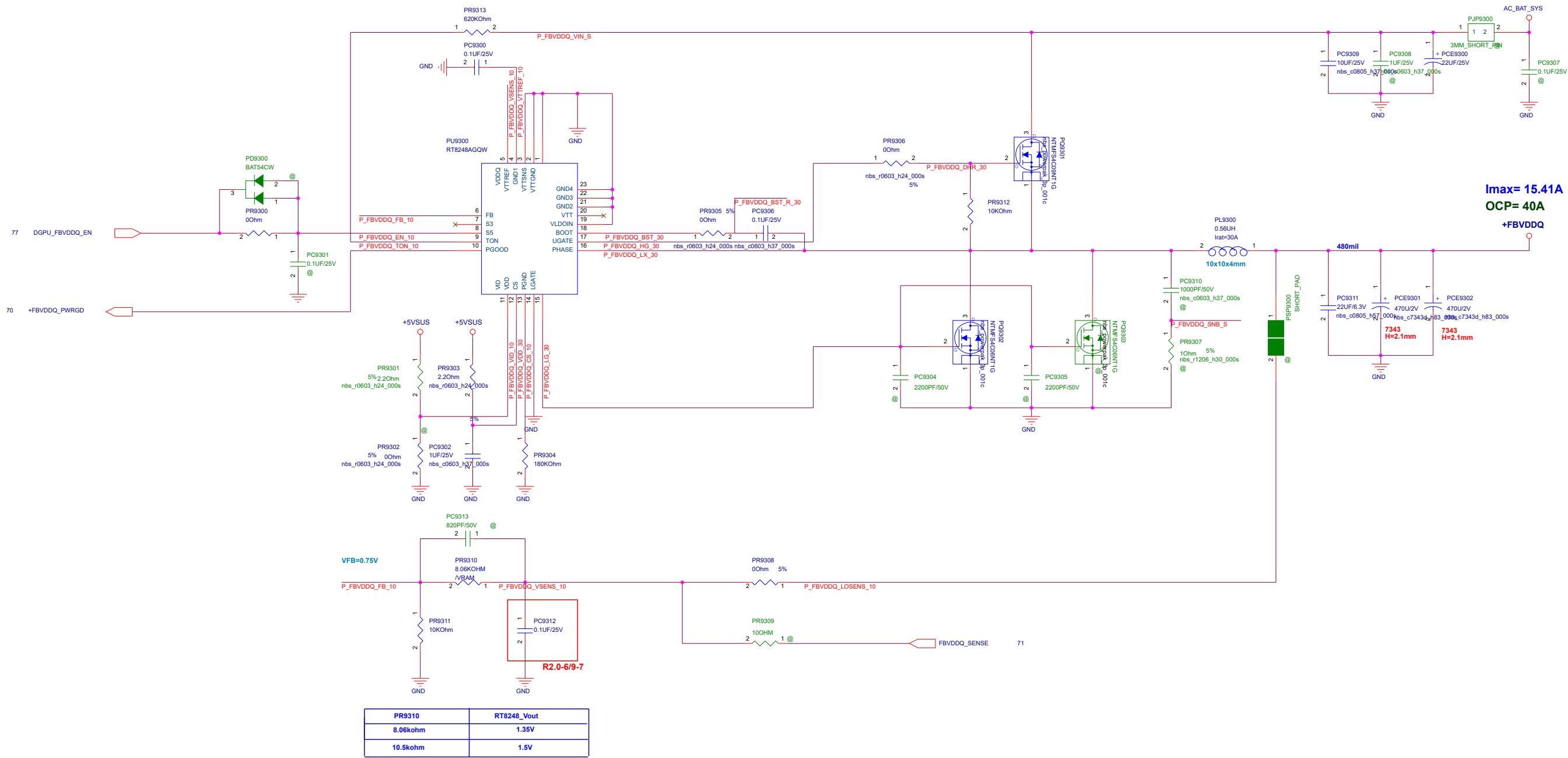


+PEX_VDD [For DGPU]



PR9221	UP1740Q_Vout
3.6kohm	1.0V
4.02kohm	1.05V
6.2kohm	1.2V
8.2kohm	1.35V
10.5kohm	1.5V

+FBVDDQ [For VRAM]



PR9310	RT8248_Vout
8.06kohm	1.35V
10.5kohm	1.5V

AC-IN Mode

- Power

Signal
- +RTCBAT

RTCRST#
- (1) +3VA/+5VA

(2) PS_ON

(3) +3VA_EC

(4) +EC_RST#

(5) +3VA_DSW

(6) 3VA_DSW_PWRGD

(7) DPWROK_EC

(8) PM_SLP_SUS#

(9) +3VSUS/+1.0VSUS

(10) +12VSUS/+5VSUS

(11) 3VSUS_PERGD

(12) PM_RSMRST#

(13) SUSWARN#

(14) ME_AC_PRESENT

(15) PCH_SUSACK#

(16) PWR_SW#

(17) PM_PWRBTN#

(18) PM_SUSC#

(19) PM_SUSB#

(20) +12V/+5V/+3V/+VCCST

(21) +12VS/+5VS/+5VS_PWR/+3VS/+VCCPLL_OC

+1.0V_VCCST,VCCPLL

+VCCSTG

+VCCPLL_OC

(22) +1.2V

(23) +2.5V

+VCCIO

DDR_VTT_CTRL

+VTT

(24) ALL_SYSTEM_PWRGD

(25) P_IMVP8_EN_10

(26) P_IMVP8_DRVON

+VCCCORE/+VCCGT/+VCCSA

(27) IMVP8_PWRGD

(28) VCCST_PWRGD_CPU

(29) PM_PWROK

(30) PM_SYSPWROK

CLK_PCH_BCLK

(31) H_CPUPWRGD

(32) PCH_PLTRST_CPU#
- The diagram illustrates the power-on sequence for the SLK H system in AC mode. It shows the timing relationships between various power rails and control signals. Key events include the assertion of PS_ON, the ramping up of +3VA and +5VA, the assertion of +EC_RST# and +3VA_DSW, and the subsequent assertion of various system power rails (+12V, +5V, +3V, +VCCST, +VCCPLL_OC, +1.2V, +2.5V, +VCCIO, +VTT). The diagram also shows the timing of the PCH_PLTRST_CPU# signal and the assertion of the H_CPUPWRGD signal. Various timing constraints are specified, such as tPCH01 > 9ms, tPCH05 > 1us, tPCH04 > 9ms, tPCH02 > 10ms, tPCH43 > 95ms, tPCH06 > 200us, tPCH07 > 0ms, tPCH03 > 10ms, tPLT01 > 200ms, tPLT02 < 0ms, tPCH00 > 1ms, tCPU04 > 100ns, tCPU03 < 25ms, tCPU18 < 35us, tCPU05 > 100ns, tCPU19 < 100ns, tCPU01 > 1ms, tCPU00 > 1ms, tPLT04 > 1ms, tCPU06 > 100ns, tCPU16 > 0ns, tPCH08 > 1ms, tCPU10 > 1ms, tPLT05: Platform dependent, tPCH41 > 1ms, tCPU08 > 1ms, tPCH45.
- SLK H Power Sequence
(AC mode)
- | | | | |
|----------------------------|------------------------------|--------------|------------|
| | | Project Name | Rev |
| Title : AC Power On Timing | | GL552VW | 2.0 |
| Size | Dept.: ASUSTek COMPUTER INC. | Engineer: | Mario_Jhu |
| Custom | Date: Tuesday, June 23, 2015 | Sheet | 100 of 103 |

AC-IN Mode

- Power

Signal
- +RTCBAT

RTCRST#
- (1) +3VA/+5VA

(2) PS_ON

(3) +3VA_EC

(4) +EC_RST#

(5) +3VA_DSW

(6) 3VA_DSW_PWRGD

(7) DPWROK_EC

(8) PM_SLP_SUS#

(9) +3VSUS/+1.0VSUS

(10) +12VSUS/+5VSUS

(11) 3VSUS_PERGD

(12) PM_RSMRST#

(13) SUSWARN#

(14) ME_AC_PRESENT

(15) PCH_SUSACK#

(16) PWR_SW#

(17) PM_PWRBTN#

(18) PM_SUSC#

(19) PM_SUSB#

(20) +12V/+5V/+3V/+VCCST

(21) +12VS/+5VS/+5VS_PWR/+3VS/+VCCPLL_OC

+1.0V_VCCST,VCCPLL

+VCCSTG

+VCCPLL_OC

(22) +1.2V

(23) +2.5V

+VCCIO

DDR_VTT_CTRL

+VTT

(24) ALL_SYSTEM_PWRGD

(25) P_IMVP8_EN_10

(26) P_IMVP8_DRVON

+VCCCORE/+VCCGT/+VCCSA

(27) IMVP8_PWRGD

(28) VCCST_PWRGD_CPU

(29) PM_PWROK

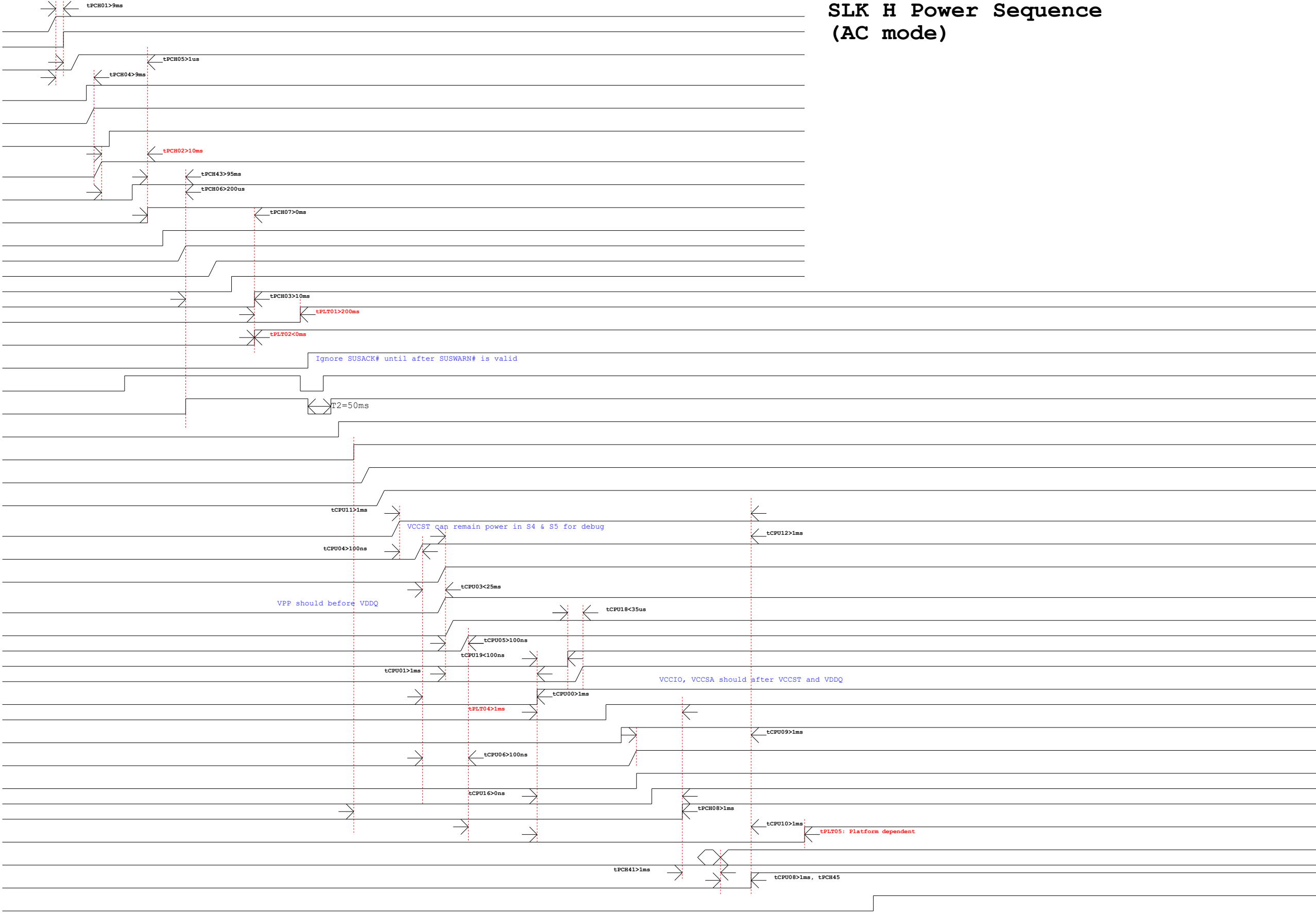
(30) PM_SYSPWROK

CLK_PCH_BCLK

(31) H_CPUPWRGD

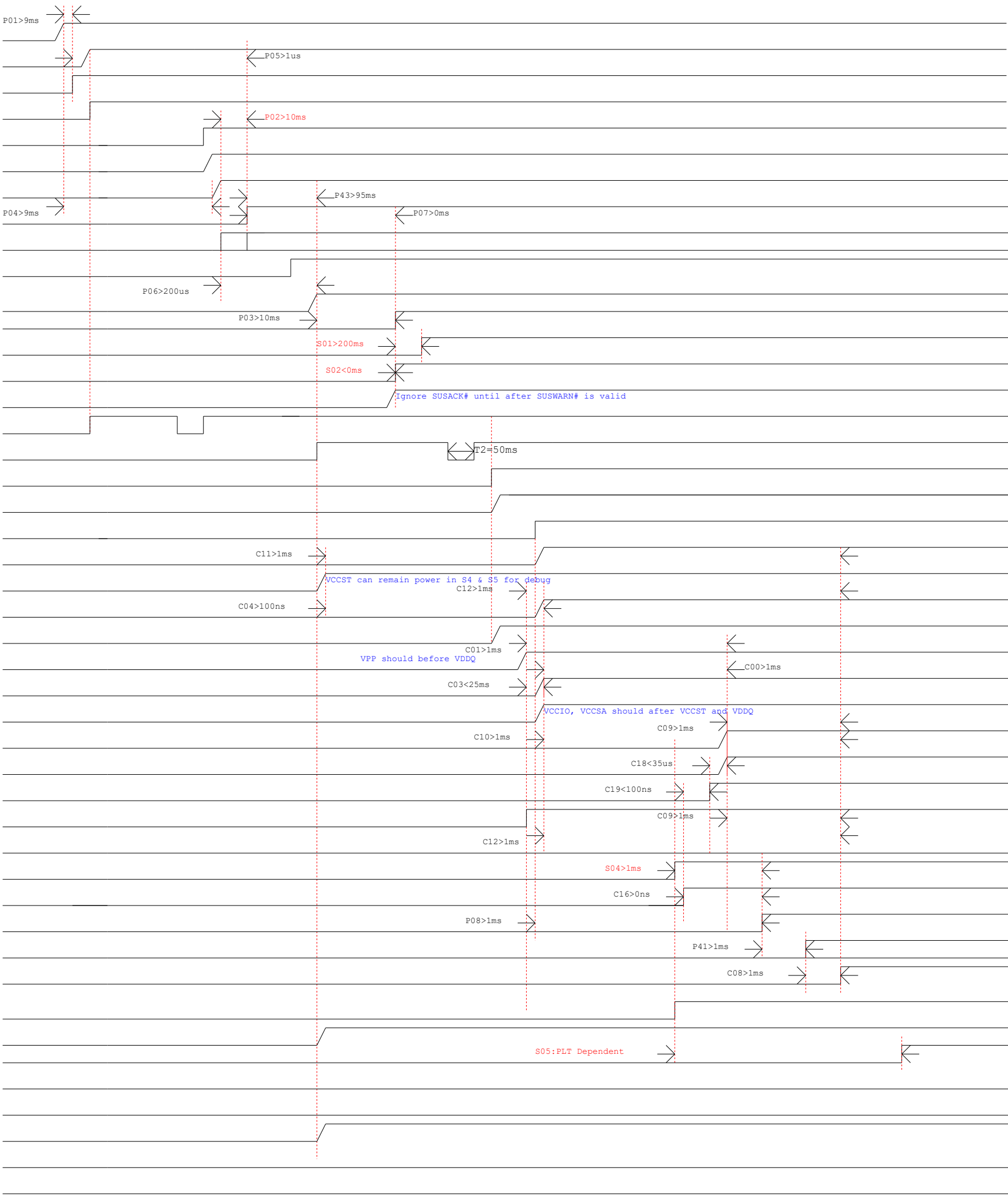
(32) PCH_PLTRST_CPU#

SLK H Power Sequence
(AC mode)



DC-IN Mode

C:CPU (+RTCBAT)+3VA_RTC
P:PCH (AC_BAT_SYS)+3VA/+5VA
S:PLT (+3VA_RTC) RTCRST# (PCH)
Power (Power) AC_IN_OC# (EC)
Signal (EC) PS_ON (+3VA_EC)
(PS_ON)+3VA_EC (EC)
(3VADSW_ON)+3VA_DSW (3VA_DSW_PWRGD)
(EC) DPWROK_EC (PCH)
(+3VA_DSW) PM_BATLOW# (PCH)
(PCH) PM_SLP_SUS# (EC)
(VSUS_ON)+1.0VSUS_VCCPRIM (1.0VSUS_PWRGD)
(EC) PM_RSMRST#_PCH (PCH)
(PCH) SUSWARN# (EC)
(EC) ME_AC_PRESENT_PCH (PCH)
(EC) PCH_SUSACK# (PCH)
(PWR Switch) PWR_SW# (EC)
(EC) PM_PWRBTN# (PCH)
(EC) SUSC_EC# (Power)
(SUSC_EC#)+12V/+5V/+3V
(EC) SUSB_EC# (Power)
(SUSB_EC#)+12VS/+5VS/+3VS
(VSUS_ON)+1.0V_VCCST,VCCPLL (VCCST_PWRGD)
(+VCCIO)+VCCSTG
(1.2V_ON)+2.5V (2.5V_PWRGD)
(1.2V_ON)+VDDQ_CPU (1.2V_PWRGD)
(+12VS)+VCCPLL_OC
(SUSB_EC#)+VCCIO (VCCIO_PWRGD)
(ALL_SYSTEM_PWRGD)+VCCSA (IMVP8_PWRGD)
(DDR_VTT_CTRL)+0.6V
(CPU) DDR_VTT_CTRL (Power)
(Power) 1.2V_PWRGD (AND)
(Power) IMVP8_PWRGD
(AND) ALL_SYSTEM_PWRGD (CPU/PCH/EC/Power)
(ALL_SYSTEM_PWRGD) VCCST_PWRGD_CPU (CPU)
(EC) PM_PWROK_PCH (PCH)
(PCH) CLK_PCH_BCLK (CPU)
(PCH) H_CPUPWRGD (CPU)
(ALL_SYSTEM_PWRGD) P_IMVP8_EN_10 (Power)
(CPU) P_SVID_DATA_X2 (Power)
(EC) PM_SYSPWROK_PCH (PCH)
(PCH) PLT_RST# (CPU/EC/Device)
(P_IMVP8_DRVON)+VCCCORE (IMVP8_PWRGD)
(CPU) H_THERMTRIP# (PCH)
(PCH) DDR4_DRAMRST# (Memory)
+VCCGT



SLK H Power Sequence
(DC mode)

Rev	Date	Description
2.0 <div>Red</div> <div></div>	06/09/2015 First Release	1. Update Power schematic, 詳見GL552VW_PSR_DSN這修改事項 20150609 2. 修改DDR_VTT_CTRL power plane to +3VS for 漏電issue at p. 6 3. 修改Power Thermal sensor power protection at p. 28 4. change HDA power plane to +3VS power with Intel confirm at p. 26 5. change R2080 & R2005 to 3.3KOHM pull-high follow VC at p. 20 6. Change net name SUS_CLK# to SUS_CLK_X1 at p. 20 7. fix Samsung 禁周料 at p. 3, 6, 22, 40, 47, 59, 62, 69, 70, 71, 76, 77, 83, 84, 86, 87, 88, 91, 92, 93 8. add Intel QS sample ASUS P/N at p. 3 & 20
	06/10/2015	1. mont R7599 for Power request at p. 75 2. unmont SPI IO3 circuit for Intel QS Sample at p. 28 3. Update Power schematic, 詳見GL552VW_PSR_DSN這修改事項 20150610
	06/12/2015	1. change [ARGOSY] Type-C Connector to Pin 長 1.1mm at p.47 2. change SSD NUT at p. 65
	06/12/2015 v2	1. PU8801由POWER SW. UP9020BFB6-00(06016-01110000)上件 改為POWER SW. APL3527GHA1-TRG(06016-00160300)上件 2. PC8837由MLCC 4UF/16V(0603)X7R 10%(11G233110511030)上件 改為MLCC 4.7UF/16V (0603) X5R 10%(11204-0003F000)上件
	06/12/2015 v3	1. add DSG circuit for +12V & +12VS follow VC at p. 57
	06/17/2015	1. DRAMRST# issue, change C2008, C1402 & C1501 for EMI & VC at p. 14, 15 & 20. 2. 預留 CLK_24M 0 ohm EMI at p. 22 3. Add Varistor for EMI request at p. 6, 20, 30, 40, 58
	06/18/2015	1. PR8056由RES 20K OHM 1/16W (0402) 1%(10G212200214030)上件改為 RES 40.2K OHM 1/16W (0402) 1%(10G212402214010)上件 2. Update GPIO Table at p. 2
	06/22/2015	1. 預留SPI_IO3 PU電阻 R2851 for Intel at p. 28 2. change RTC to small at p. 20 3. change 0 Ohm to 0.1uF for EA Audio test at p. 62 4. PR8817由RES 2.2 OHM 1/10W(0603)5%(10G2132R2003010)上件改為 RES 10 OHM 1/16W (0402) 1%(10G21210R014030)上件 5. PC8837由MLCC 4.7UF/16V (0603) X5R 10%(11204-0003F000)上件 改為MLCC 4.7UF/16.3V (0402) X5R 10%(11G232210515070)上件
	06/23/2015	1. SSD Thermal Sensor 上件, CPU Thermal Sensor 不上件 at p. 50 2. 預留0 Ohm for EMI BCLK at p. 20 3. change 0 Ohm to 5.1 Ohm for EMI request at p. 6
	06/23/2015 v2	1. change 5.1 Ohm to PCH for EMI request at p. 6 & 22 2. PCE8402 CAP PL 15UF/25V 7343 SMD(11020-00275100)由不上件改上件 3. PCE9200 CAP PL 22UF/25V 4.6*6.3 20%(11032-0008F000) 由不上件改上件

Rev	Date	Description

Rev	Date	Description

Rev	Date	Description

+RTCBAT->3.3V
RTCCCLK->on
RTC_RST->High

AC-IN Mode
AC_IN_OC->Low

GL552VW Power On Sequence Diagram Rev.1.0

